PIC16F84A
Data Sheet

18-pin Enhanced FLASH/EEPROM
8-bit Microcontroller

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PIC16F84A

18-pin *Enhanced* FLASH/EEPROM 8-Bit Microcontroller

High Performance RISC CPU Features:

- Only 35 single word instructions to learn
- All instructions single-cycle except for program branches which are two-cycle
- Operating speed: DC - 20 MHz clock input
  DC - 200 ns instruction cycle
- 1024 words of program memory
- 68 bytes of Data RAM
- 64 bytes of Data EEPROM
- 14-bit wide instruction words
- 8-bit wide data bytes
- 15 Special Function Hardware registers
- Eight-level deep hardware stack
- Direct, indirect and relative addressing modes
- Four interrupt sources:
  - External RB0/INT pin
  - TMR0 timer overflow
  - PORTB<7:4> interrupt-on-change
  - Data EEPROM write complete

Peripheral Features:

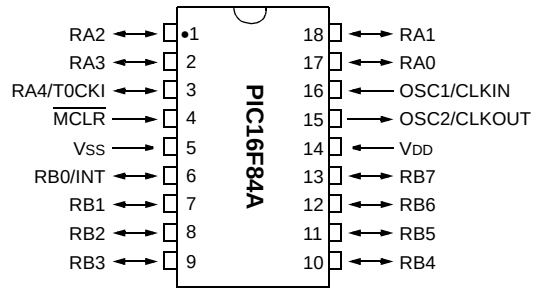
- 13 I/O pins with individual direction control
- High current sink/source for direct LED drive
  - 25 mA sink max. per pin
  - 25 mA source max. per pin
- TMR0: 8-bit timer/counter with 8-bit programmable prescaler

Special Microcontroller Features:

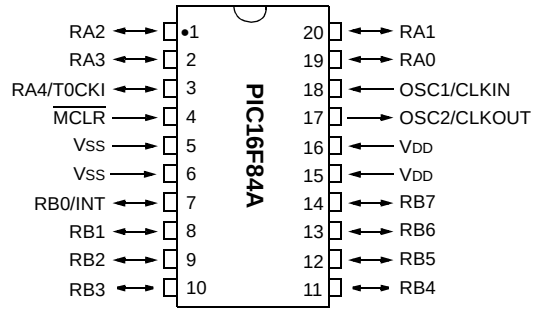
- 10,000 erase/write cycles *Enhanced* FLASH Program memory typical
- 10,000,000 typical erase/write cycles EEPROM Data memory typical
- EEPROM Data Retention > 40 years
- In-Circuit Serial Programming™ (ICSP™) - via two pins
- Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own On-Chip RC Oscillator for reliable operation
- Code protection
- Power saving SLEEP mode
- Selectable oscillator options

Pin Diagrams

PDIP, SOIC



SSOP



CMOS Enhanced FLASH/EEPROM Technology:

- Low power, high speed technology
- Fully static design
- Wide operating voltage range:
  - Commercial: 2.0V to 5.5V
  - Industrial: 2.0V to 5.5V
- Low power consumption:
  - < 2 mA typical @ 5V, 4 MHz
  - 15 μA typical @ 2V, 32 kHz
  - < 0.5 μA typical standby current @ 2V

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1.0 DEVICE OVERVIEW

This document contains device specific information for the operation of the PIC16F84A device. Additional information may be found in the PICmicro™ Mid-Range Reference Manual, (DS33023), which may be downloaded from the Microchip website. The Reference Manual should be considered a complementary document to this data sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

The PIC16F84A belongs to the mid-range family of the PICmicro® microcontroller devices. A block diagram of the device is shown in Figure 1-1.

The program memory contains 1K words, which translates to 1024 instructions, since each 14-bit program memory word is the same width as each device instruction. The data memory (RAM) contains 68 bytes. Data EEPROM is 64 bytes.

There are also 13 I/O pins that are user-configured on a pin-to-pin basis. Some pins are multiplexed with other device functions. These functions include:

- External interrupt
- Change on PORTB interrupt
- Timer0 clock input

Table 1-1 details the pinout of the device with descriptions and details for each pin.

FIGURE 1-1: PIC16F84A BLOCK DIAGRAM

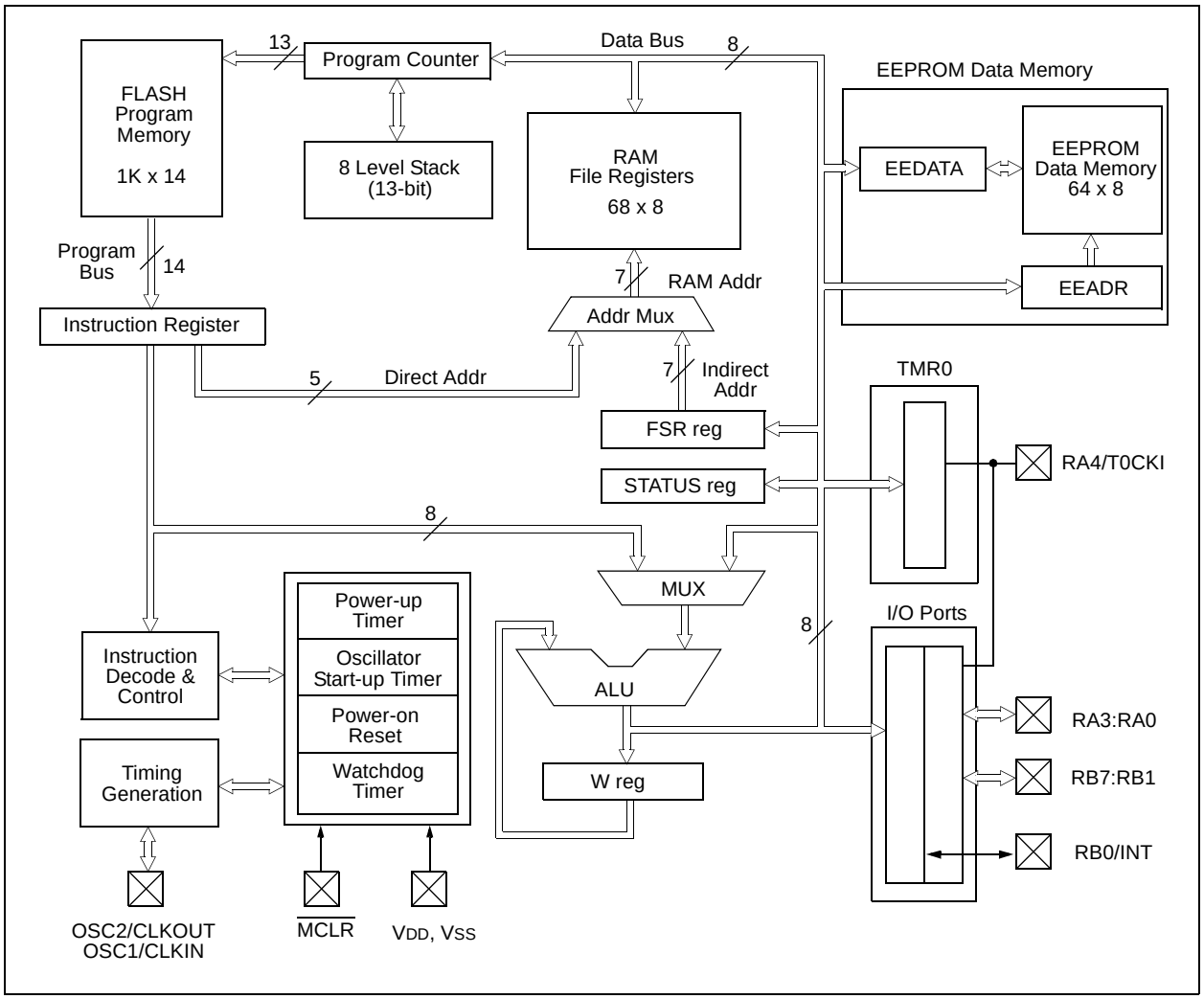


TABLE 1-1: PIC16F84A PINOUT DESCRIPTION

Pin Name	PDIP No.	SOIC No.	SSOP No.	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	16	16	18	I	ST/CMOS(3)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	19	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
$\overline{MCLR}$	4	4	4	I/P	ST	Master Clear (Reset) input/programming voltage input. This pin is an active low RESET to the device.
						PORTA is a bi-directional I/O port.
RA0	17	17	19	I/O	TTL	
RA1	18	18	20	I/O	TTL	
RA2	1	1	1	I/O	TTL	
RA3	2	2	2	I/O	TTL	
RA4/T0CKI	3	3	3	I/O	ST	Can also be selected to be the clock input to the TMR0 timer/counter. Output is open drain type.
						PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	6	6	7	I/O	TTL/ST(1)	RB0/INT can also be selected as an external interrupt pin.
RB1	7	7	8	I/O	TTL	
RB2	8	8	9	I/O	TTL	
RB3	9	9	10	I/O	TTL	
RB4	10	10	11	I/O	TTL	Interrupt-on-change pin.
RB5	11	11	12	I/O	TTL	Interrupt-on-change pin.
RB6	12	12	13	I/O	TTL/ST(2)	Interrupt-on-change pin. Serial programming clock.
RB7	13	13	14	I/O	TTL/ST(2)	Interrupt-on-change pin. Serial programming data.
VSS	5	5	5,6	P	—	Ground reference for logic and I/O pins.
VDD	14	14	15,16	P	—	Positive supply for logic and I/O pins.

Legend: I= input O = Output I/O = Input/Output P = Power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

2.0 MEMORY ORGANIZATION

There are two memory blocks in the PIC16F84A. These are the program memory and the data memory. Each block has its own bus, so that access to each block can occur during the same oscillator cycle.

The data memory can further be broken down into the general purpose RAM and the Special Function Registers (SFRs). The operation of the SFRs that control the “core” are described here. The SFRs used to control the peripheral modules are described in the section discussing each individual peripheral module.

The data memory area also contains the data EEPROM memory. This memory is not directly mapped into the data memory, but is indirectly mapped. That is, an indirect address pointer specifies the address of the data EEPROM memory to read/write. The 64 bytes of data EEPROM memory have the address range 0h-3Fh. More details on the EEPROM memory can be found in Section 3.0.

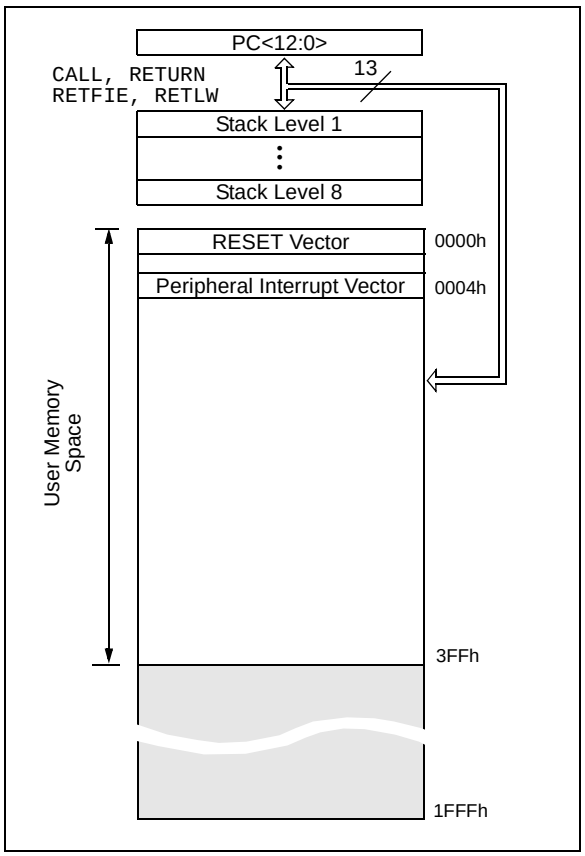
Additional information on device memory may be found in the PICmicro™ Mid-Range Reference Manual, (DS33023).

2.1 Program Memory Organization

The PIC16FXX has a 13-bit program counter capable of addressing an 8K x 14 program memory space. For the PIC16F84A, the first 1K x 14 (0000h-03FFh) are physically implemented (Figure 2-1). Accessing a location above the physically implemented address will cause a wraparound. For example, for locations 20h, 420h, 820h, C20h, 1020h, 1420h, 1820h, and 1C20h, the instruction will be the same.

The RESET vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK - PIC16F84A



2.2 Data Memory Organization

The data memory is partitioned into two areas. The first is the Special Function Registers (SFR) area, while the second is the General Purpose Registers (GPR) area. The SFRs control the operation of the device.

Portions of data memory are banked. This is for both the SFR area and the GPR area. The GPR area is banked to allow greater than 116 bytes of general purpose RAM. The banked areas of the SFR are for the registers that control the peripheral functions. Banking requires the use of control bits for bank selection. These control bits are located in the STATUS Register. Figure 2-2 shows the data memory map organization.

Instructions MOVWF and MOVF can move values from the W register to any location in the register file ("F"), and vice-versa.

The entire data memory can be accessed either directly using the absolute address of each register file or indirectly through the File Select Register (FSR) (Section 2.5). Indirect addressing uses the present value of the RP0 bit for access into the banked areas of data memory.

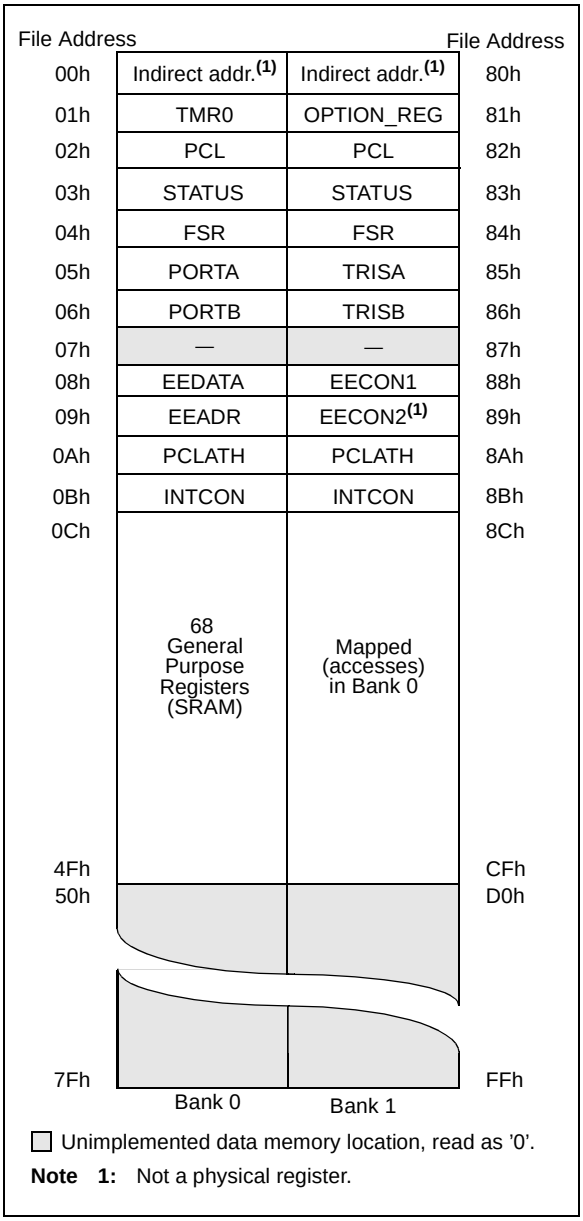
Data memory is partitioned into two banks which contain the general purpose registers and the special function registers. Bank 0 is selected by clearing the RP0 bit (STATUS<5>). Setting the RP0 bit selects Bank 1. Each Bank extends up to 7Fh (128 bytes). The first twelve locations of each Bank are reserved for the Special Function Registers. The remainder are General Purpose Registers, implemented as static RAM.

2.2.1 GENERAL PURPOSE REGISTER FILE

Each General Purpose Register (GPR) is 8-bits wide and is accessed either directly or indirectly through the FSR (Section 2.5).

The GPR addresses in Bank 1 are mapped to addresses in Bank 0. As an example, addressing location 0Ch or 8Ch will access the same GPR.

FIGURE 2-2: REGISTER FILE MAP - PIC16F84A



2.3 Special Function Registers

The Special Function Registers (Figure 2-2 and Table 2-1) are used by the CPU and Peripheral functions to control the device operation. These registers are static RAM.

The special function registers can be classified into two sets, core and peripheral. Those associated with the core functions are described in this section. Those related to the operation of the peripheral features are described in the section for that specific feature.

TABLE 2-1: SPECIAL FUNCTION REGISTER FILE SUMMARY

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on RESET	Details on page
Bank 0											
00h	INDF	Uses contents of FSR to address Data Memory (not a physical register)								---- ----	11
01h	TMR0	8-bit Real-Time Clock/Counter								xxxx xxxx	20
02h	PCL	Low Order 8 bits of the Program Counter (PC)								0000 0000	11
03h	STATUS(2)	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	8
04h	FSR	Indirect Data Memory Address Pointer 0								xxxx xxxx	11
05h	PORTA(4)	—	—	—	RA4/T0CKI	RA3	RA2	RA1	RA0	---x xxxx	16
06h	PORTB(5)	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0/INT	xxxx xxxx	18
07h	—	Unimplemented location, read as '0'								—	—
08h	EEDATA	EEPROM Data Register								xxxx xxxx	13,14
09h	EEADR	EEPROM Address Register								xxxx xxxx	13,14
0Ah	PCLATH	—	—	—	Write Buffer for upper 5 bits of the PC(1)					---0 0000	11
0Bh	INTCON	GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	10
Bank 1											
80h	INDF	Uses Contents of FSR to address Data Memory (not a physical register)								---- ----	11
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	9
82h	PCL	Low order 8 bits of Program Counter (PC)								0000 0000	11
83h	STATUS (2)	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	8
84h	FSR	Indirect data memory address pointer 0								xxxx xxxx	11
85h	TRISA	—	—	—	PORTA Data Direction Register					---1 1111	16
86h	TRISB	PORTB Data Direction Register								1111 1111	18
87h	—	Unimplemented location, read as '0'								—	—
88h	EECON1	—	—	—	EEIF	WRERR	WREN	WR	RD	---0 x000	13
89h	EECON2	EEPROM Control Register 2 (not a physical register)								---- ----	14
0Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of the PC(1)					---0 0000	11
0Bh	INTCON	GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	10

Legend: x = unknown, u = unchanged. - = unimplemented, read as '0', q = value depends on condition

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a slave register for PC<12:8>. The contents of PCLATH can be transferred to the upper byte of the program counter, but the contents of PC<12:8> are never transferred to PCLATH.

2: The $\overline{TO}$ and $\overline{PD}$ status bits in the STATUS register are not affected by a $\overline{MCLR}$ Reset.

3: Other (non power-up) RESETS include: external RESET through $\overline{MCLR}$ and the Watchdog Timer Reset.

4: On any device RESET, these pins are configured as inputs.

5: This is the value that will be in the port output latch.

2.3.1 STATUS REGISTER

The STATUS register contains the arithmetic status of the ALU, the RESET status and the bank select bit for data memory.

As with any register, the STATUS register can be the destination for any instruction. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where u = unchanged).

Only the `BCF, BSF, SWAPF` and `MOVWF` instructions should be used to alter the STATUS register (Table 7-2), because these instructions do not affect any status bit.

Note 1: The IRP and RP1 bits (STATUS<7:6>) are not used by the PIC16F84A and should be programmed as cleared. Use of these bits as general purpose R/W bits is NOT recommended, since this may affect upward compatibility with future products.

2: The C and DC bits operate as a $\overline{borrow}$ and digit borrow out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

3: When the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. The specified bit(s) will be updated according to device logic

REGISTER 2-1: STATUS REGISTER (ADDRESS 03h, 83h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

bit 7-6 **Unimplemented:** Maintain as '0'

bit 5 **RP0**: Register Bank Select bits (used for direct addressing)
01 = Bank 1 (80h - FFh)
00 = Bank 0 (00h - 7Fh)

bit 4 **$\overline{TO}$**: Time-out bit
1 = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
0 = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-down bit
1 = After power-up or by the `CLRWDT` instruction
0 = By execution of the `SLEEP` instruction

bit 2 **Z**: Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for $\overline{borrow}$, the polarity is reversed)
1 = A carry-out from the 4th low order bit of the result occurred
0 = No carry-out from the 4th low order bit of the result

bit 0 **C**: Carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for $\overline{borrow}$, the polarity is reversed)
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note: A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.3.2 OPTION REGISTER

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external INT interrupt, TMR0, and the weak pull-ups on PORTB.

Note:	When the prescaler is assigned to the WDT (PSA = '1'), TMR0 has a 1:1 prescaler assignment.

REGISTER 2-2: OPTION REGISTER (ADDRESS 81h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

bit 7 **$\overline{\text{RBPU}}$:** PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6 **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5 **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4 **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3 **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.3.3 INTCON REGISTER

The INTCON register is a readable and writable register that contains the various enable bits for all interrupt sources.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

REGISTER 2-3: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF
bit 7							bit 0

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6 **EEIE**: EE Write Complete Interrupt Enable bit
1 = Enables the EE Write Complete interrupts
0 = Disables the EE Write Complete interrupt

bit 5 **T0IE**: TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 interrupt
0 = Disables the TMR0 interrupt

bit 4 **INTE**: RB0/INT External Interrupt Enable bit
1 = Enables the RB0/INT external interrupt
0 = Disables the RB0/INT external interrupt

bit 3 **RBIE**: RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2 **T0IF**: TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INTF**: RB0/INT External Interrupt Flag bit
1 = The RB0/INT external interrupt occurred (must be cleared in software)
0 = The RB0/INT external interrupt did not occur

bit 0 **RBIF**: RB Port Change Interrupt Flag bit
1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)
0 = None of the RB7:RB4 pins have changed state

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.4 PCL and PCLATH

The program counter (PC) specifies the address of the instruction to fetch for execution. The PC is 13 bits wide. The low byte is called the PCL register. This register is readable and writable. The high byte is called the PCH register. This register contains the PC<12:8> bits and is not directly readable or writable. If the program counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP. All updates to the PCH register go through the PCLATH register.

2.4.1 STACK

The stack allows a combination of up to 8 program calls and interrupts to occur. The stack contains the return address from this branch in program execution.

Mid-range devices have an 8 level deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not modified when the stack is PUSHed or POPed.

After the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

2.5 Indirect Addressing; INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 2-1: INDIRECT ADDRESSING

- Register file 05 contains the value 10h
- Register file 06 contains the value 0Ah
- Load the value 05 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 06)
- A read of the INDF register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected).

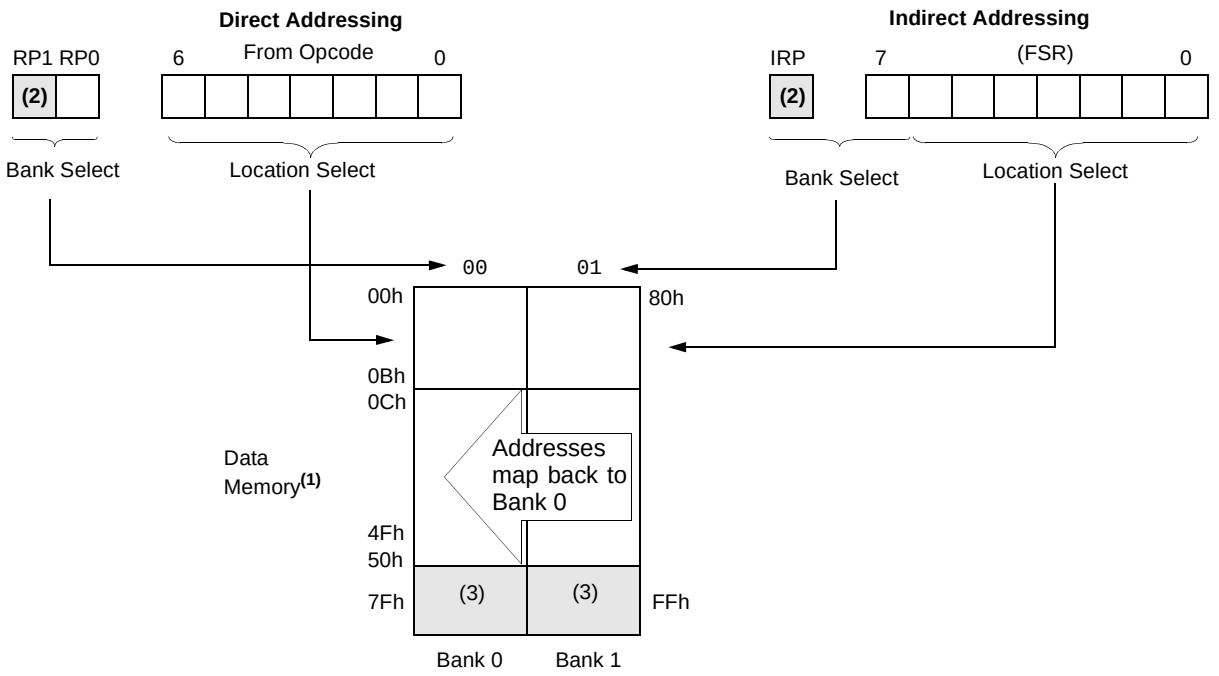
A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 2-2.

EXAMPLE 2-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

```
        movlw   0x20    ;initialize pointer
        movwf   FSR     ;to RAM
NEXT    clrf    INDF    ;clear INDF register
        incf    FSR     ;inc pointer
        btfss   FSR,4   ;all done?
        goto    NEXT    ;NO, clear next
CONTINUE
         :              ;YES, continue
```

An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 2-3. However, IRP is not used in the PIC16F84A.

FIGURE 2-3: DIRECT/INDIRECT ADDRESSING



Note 1: For memory map detail, see Figure 2-2.

2: Maintain as clear for upward compatibility with future products.

3: Not implemented.

3.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full V_{DD} range). This memory is not directly mapped in the register file space. Instead it is indirectly addressed through the Special Function Registers. There are four SFRs used to read and write this memory. These registers are:

- EECON1
- EECON2 (not a physically implemented register)
- EEDATA
- EEADR

EEDATA holds the 8-bit data for read/write, and EEADR holds the address of the EEPROM location being accessed. PIC16F84A devices have 64 bytes of data EEPROM with an address range from 0h to 3Fh.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write-time will vary with voltage and temperature as well as from chip to chip. Please refer to AC specifications for exact limits.

When the device is code protected, the CPU may continue to read and write the data EEPROM memory. The device programmer can no longer access this memory.

Additional information on the Data EEPROM is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

REGISTER 3-1: EECON1 REGISTER (ADDRESS 88h)

U-0	U-0	U-0	R/W-0	R/W-x	R/W-0	R/S-0	R/S-0
—	—	—	EEIF	WRERR	WREN	WR	RD
bit 7							bit 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **EEIF:** EEPROM Write Operation Interrupt Flag bit
1 = The write operation completed (must be cleared in software)
0 = The write operation is not complete or has not been started

bit 3 **WRERR:** EEPROM Error Flag bit
1 = A write operation is prematurely terminated
(any $\overline{\text{MCLR}}$ Reset or any WDT Reset during normal operation)
0 = The write operation completed

bit 2 **WREN:** EEPROM Write Enable bit
1 = Allows write cycles
0 = Inhibits write to the EEPROM

bit 1 **WR:** Write Control bit
1 = Initiates a write cycle. The bit is cleared by hardware once write is complete. The WR bit can only be set (not cleared) in software.
0 = Write cycle to the EEPROM is complete

bit 0 **RD:** Read Control bit
1 = Initiates an EEPROM read RD is cleared in hardware. The RD bit can only be set (not cleared) in software.
0 = Does not initiate an EEPROM read

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

3.1 Reading the EEPROM Data Memory

To read a data memory location, the user must write the address to the EEADR register and then set control bit RD (EECON1<0>). The data is available, in the very next cycle, in the EEDATA register; therefore, it can be read in the next instruction. EEDATA will hold this value until another read or until it is written to by the user (during a write operation).

EXAMPLE 3-1: DATA EEPROM READ

```
BCF     STATUS, RP0  ; Bank 0
MOVLW   CONFIG_ADDR  ;
MOVWF   EEADR        ; Address to read
BSF     STATUS, RP0  ; Bank 1
BSF     EECON1, RD   ; EE Read
BCF     STATUS, RP0  ; Bank 0
MOVF    EEDATA, W    ; W = EEDATA
```

3.2 Writing to the EEPROM Data Memory

To write an EEPROM data location, the user must first write the address to the EEADR register and the data to the EEDATA register. Then the user must follow a specific sequence to initiate the write for each byte.

EXAMPLE 3-2: DATA EEPROM WRITE

```
        BSF     STATUS, RP0  ; Bank 1
        BCF     INTCON, GIE  ; Disable INTs.
        BSF     EECON1, WREN ; Enable Write
        MOVLW   55h          ;
Required
Sequence
        MOVWF   EECON2       ; Write 55h
        MOVLW   AAh          ;
        MOVWF   EECON2       ; Write AAh
        BSF     EECON1,WR    ; Set WR bit
                             ;   begin write
        BSF     INTCON, GIE  ; Enable INTs.
```

The write will not initiate if the above sequence is not exactly followed (write 55h to EECON2, write AAh to EECON2, then set WR bit) for each byte. We strongly recommend that interrupts be disabled during this code segment.

Additionally, the WREN bit in EECON1 must be set to enable write. This mechanism prevents accidental writes to data EEPROM due to errant (unexpected) code execution (i.e., lost programs). The user should keep the WREN bit clear at all times, except when updating EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, clearing the WREN bit will not affect this write cycle. The WR bit will be inhibited from being set unless the WREN bit is set.

At the completion of the write cycle, the WR bit is cleared in hardware and the EE Write Complete Interrupt Flag bit (EEIF) is set. The user can either enable this interrupt or poll this bit. EEIF must be cleared by software.

3.3 Write Verify

Depending on the application, good programming practice may dictate that the value written to the Data EEPROM should be verified (Example 3-3) to the desired value to be written. This should be used in applications where an EEPROM bit will be stressed near the specification limit.

Generally, the EEPROM write failure will be a bit which was written as a '0', but reads back as a '1' (due to leakage off the bit).

EXAMPLE 3-3: WRITE VERIFY

```
      BCF   STATUS,RP0 ; Bank 0
      :                ; Any code
      :                ; can go here
      MOVF  EEDATA,W   ; Must be in Bank 0
      BSF   STATUS,RP0 ; Bank 1
READ
      BSF   EECON1, RD ; YES, Read the
                       ; value written
      BCF   STATUS, RP0 ; Bank 0
                       ;
                       ; Is the value written
                       ; (in W reg) and
                       ; read (in EEDATA)
                       ; the same?
                       ;
      SUBWF EEDATA, W  ;
      BTFSS STATUS, Z  ; Is difference 0?
      GOTO  WRITE_ERR  ; NO, Write error
```

TABLE 3-1: REGISTERS/BITS ASSOCIATED WITH DATA EEPROM

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other RESETS
08h	EEDATA	EEPROM Data Register								xxxx xxxx	uuuu uuuu
09h	EEADR	EEPROM Address Register								xxxx xxxx	uuuu uuuu
88h	EECON1	—	—	—	EEIF	WRERR	WREN	WR	RD	---0 x000	---0 q000
89h	EECON2	EEPROM Control Register 2								---- ----	---- ----

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0', q = value depends upon condition.
Shaded cells are not used by data EEPROM.

4.0 I/O PORTS

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

Additional information on I/O ports may be found in the PICmicro™ Mid-Range Reference Manual (DS33023).

4.1 PORTA and TRISA Registers

PORTA is a 5-bit wide, bi-directional port. The corresponding data direction register is TRISA. Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output (i.e., put the contents of the output latch on the selected pin).

Note:	On a Power-on Reset, these pins are configured as inputs and read as '0'.

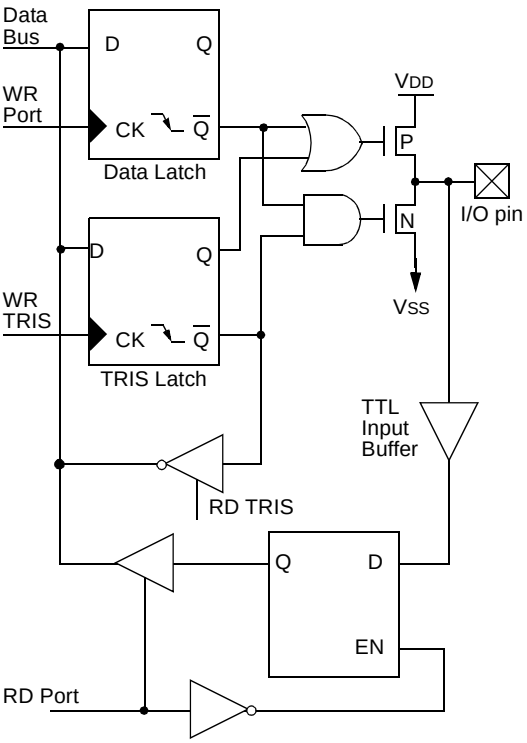
Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read. This value is modified and then written to the port data latch.

Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin. The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers.

EXAMPLE 4-1: INITIALIZING PORTA

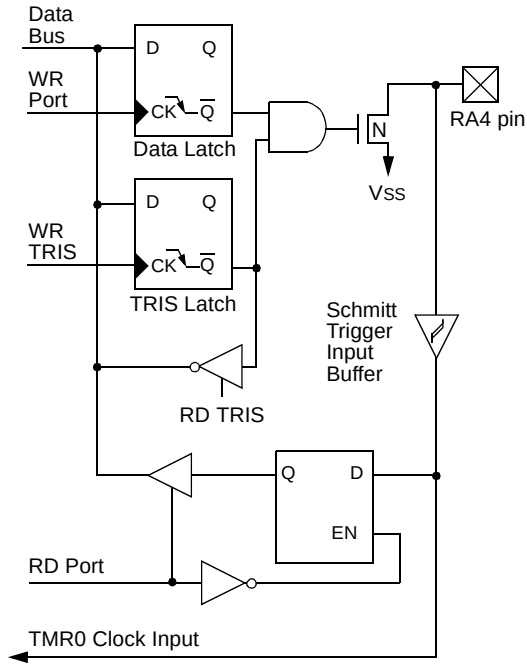
```
BCF     STATUS, RP0 ;
CLRF    PORTA       ; Initialize PORTA by
                    ; clearing output
                    ; data latches
BSF     STATUS, RP0 ; Select Bank 1
MOVLW   0x0F        ; Value used to
                    ; initialize data
                    ; direction
MOVWF   TRISA       ; Set RA<3:0> as inputs
                    ; RA4 as output
                    ; TRISA<7:5> are always
                    ; read as '0'.
```

FIGURE 4-1: BLOCK DIAGRAM OF PINS RA3:RA0



Note: I/O pins have protection diodes to VDD and VSS.

FIGURE 4-2: BLOCK DIAGRAM OF PIN RA4



Note: I/O pins have protection diodes to VDD and VSS.

TABLE 4-1: PORTA FUNCTIONS

Name	Bit0	Buffer Type	Function
RA0	bit0	TTL	Input/output
RA1	bit1	TTL	Input/output
RA2	bit2	TTL	Input/output
RA3	bit3	TTL	Input/output
RA4/T0CKI	bit4	ST	Input/output or external clock input for TMR0. Output is open drain type.

Legend: TTL = TTL input, ST = Schmitt Trigger input

TABLE 4-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other RESETS
05h	PORTA	—	—	—	RA4/T0CKI	RA3	RA2	RA1	RA0	---x xxxx	---u uuuu
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are unimplemented, read as '0'.

4.2 PORTB and TRISB Registers

PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., put the contents of the output latch on the selected pin).

EXAMPLE 4-2: INITIALIZING PORTB

```
BCF     STATUS, RP0 ;
CLRF    PORTB       ; Initialize PORTB by
                    ; clearing output
                    ; data latches
BSF     STATUS, RP0 ; Select Bank 1
MOVLW   0xCF        ; Value used to
                    ; initialize data
                    ; direction
MOVWF   TRISB       ; Set RB<3:0> as inputs
                    ; RB<5:4> as outputs
                    ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{RBPU}$ (OPTION<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

Four of PORTB's pins, RB7:RB4, have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt-on-change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

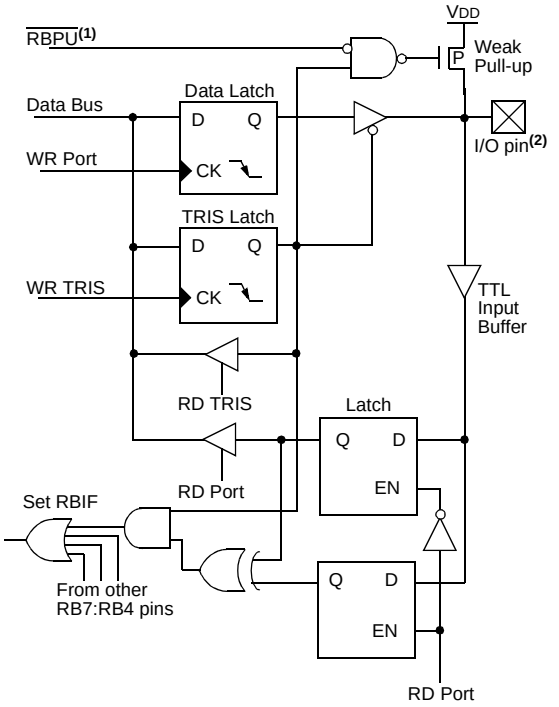
a) Any read or write of PORTB. This will end the mismatch condition.

b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

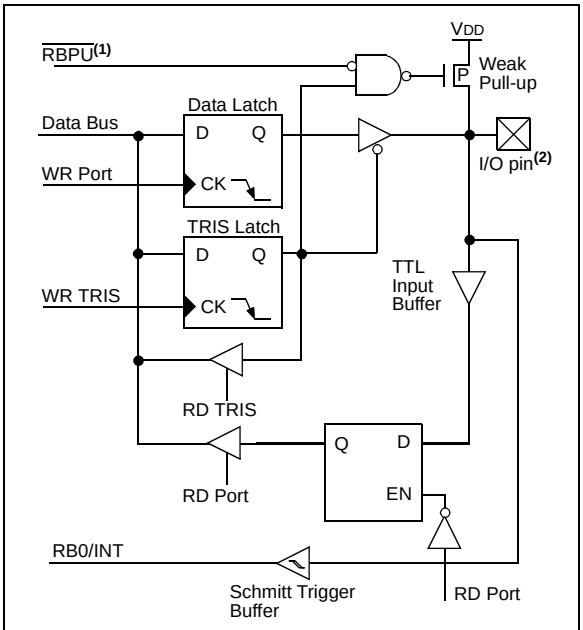
FIGURE 4-3: BLOCK DIAGRAM OF PINS RB7:RB4



Note 1: TRISB = '1' enables weak pull-up (if $\overline{RBPU}$ = '0' in the OPTION_REG register).

2: I/O pins have diode protection to VDD and VSS.

FIGURE 4-4: BLOCK DIAGRAM OF PINS RB3:RB0



Note 1: TRISB = '1' enables weak pull-up (if $\overline{RBPU}$ = '0' in the OPTION_REG register).

2: I/O pins have diode protection to VDD and VSS.

TABLE 4-3: PORTB FUNCTIONS

Name	Bit	Buffer Type	I/O Consistency Function
RB0/INT	bit0	TTL/ST(1)	Input/output pin or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	TTL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3	bit3	TTL	Input/output pin. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST(2)	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming clock.
RB7	bit7	TTL/ST(2)	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming data.

Legend: TTL = TTL input, ST = Schmitt Trigger.

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

TABLE 4-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other RESETS
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0/INT	xxxx xxxx	uuuu uuuu
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
0Bh,8Bh	INTCON	GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u

Legend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.

5.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- Internal or external clock select
- Edge select for external clock
- 8-bit software programmable prescaler
- Interrupt-on-overflow from FFh to 00h

Figure 5-1 is a simplified block diagram of the Timer0 module.

Additional information on timer modules is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

5.1 Timer0 Operation

Timer0 can operate as a timer or as a counter.

Timer mode is selected by clearing bit T0CS (OPTION_REG<5>). In Timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If the TMR0 register is written, the increment is inhibited for the following two instruction cycles. The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting bit T0CS (OPTION_REG<5>). In Counter mode, Timer0 will increment, either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the Timer0 Source Edge Select bit, T0SE (OPTION_REG<4>). Clearing bit T0SE selects the rising edge. Restrictions on the external clock input are discussed below.

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (TOSC). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

Additional information on external clock requirements is available in the PICmicro™ Mid-Range Reference Manual, (DS33023).

5.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer, respectively (Figure 5-2). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that there is only one prescaler available which is mutually exclusively shared between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer, and vice-versa.

The prescaler is not readable or writable.

The PSA and PS2:PS0 bits (OPTION_REG<3:0>) determine the prescaler assignment and prescale ratio.

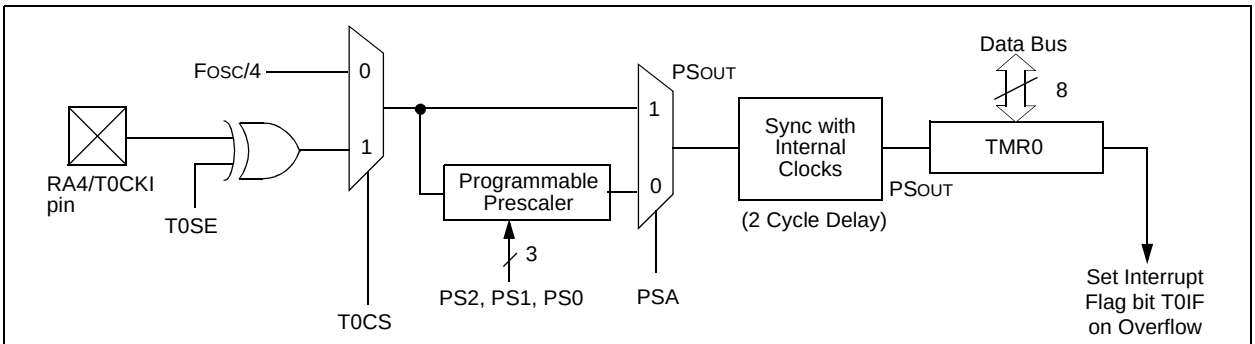
Clearing bit PSA will assign the prescaler to the Timer0 module. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4, ..., 1:256 are selectable.

Setting bit PSA will assign the prescaler to the Watchdog Timer (WDT). When the prescaler is assigned to the WDT, prescale values of 1:1, 1:2, ..., 1:128 are selectable.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., `CLRF 1, MOVWF 1, BSF 1,` etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the WDT.

Note:	Writing to TMR0 when the prescaler is assigned to Timer0 will clear the prescaler count, but will not change the prescaler assignment.

FIGURE 5-1: TIMER0 BLOCK DIAGRAM



Note 1: T0CS, T0SE, PSA, PS2:PS0 (OPTION_REG<5:0>).
2: The prescaler is shared with Watchdog Timer (refer to Figure 5-2 for detailed block diagram).

5.2.1 SWITCHING PRESCALER ASSIGNMENT

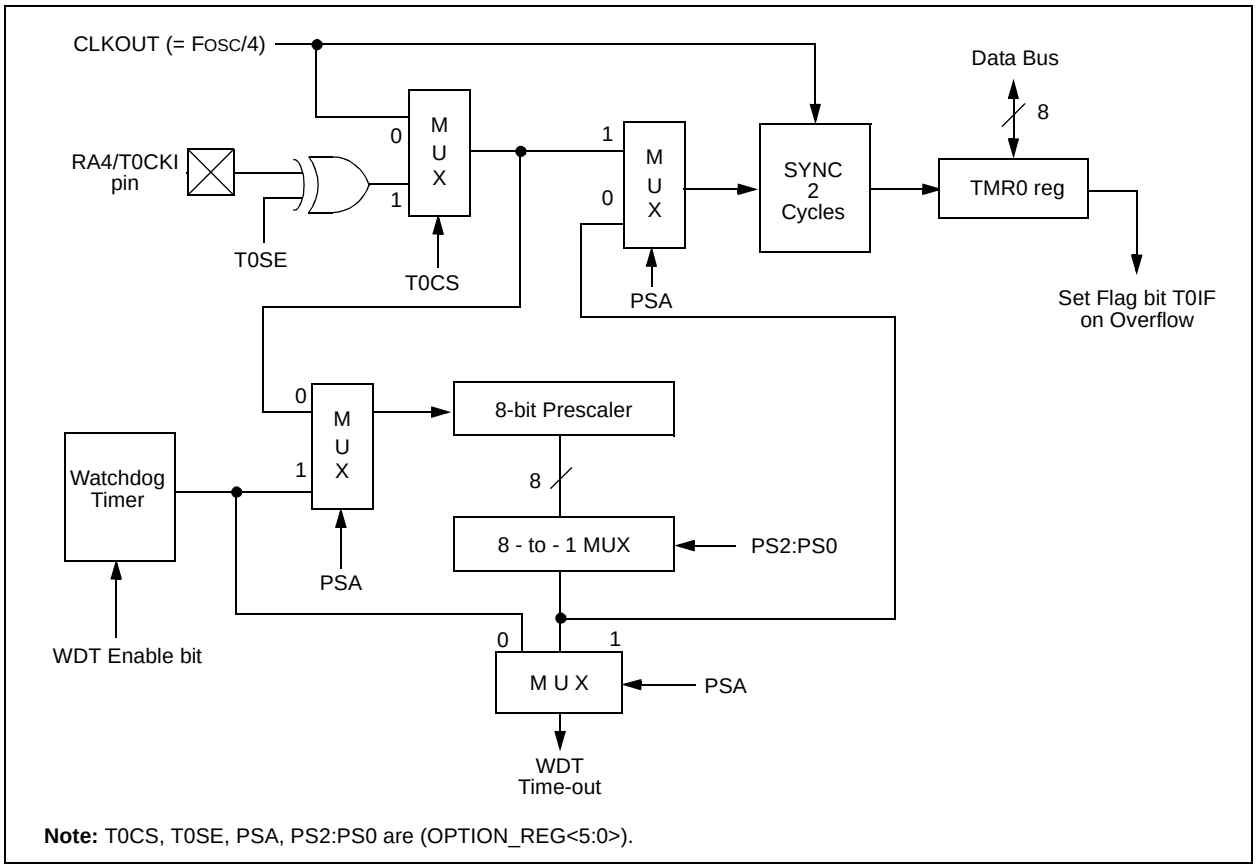
The prescaler assignment is fully under software control (i.e., it can be changed “on the fly” during program execution).

Note:	To avoid an unintended device RESET, a specific instruction sequence (shown in the PICmicro™ Mid-Range Reference Manual, DS33023) must be executed when changing the prescaler assignment from Timer0 to the WDT. This sequence must be followed even if the WDT is disabled.

5.3 Timer0 Interrupt

The TMR0 interrupt is generated when the TMR0 register overflows from FFh to 00h. This overflow sets bit T0IF (INTCON<2>). The interrupt can be masked by clearing bit T0IE (INTCON<5>). Bit T0IF must be cleared in software by the Timer0 module Interrupt Service Routine before re-enabling this interrupt. The TMR0 interrupt cannot awaken the processor from SLEEP since the timer is shut-off during SLEEP.

FIGURE 5-2: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0CS, T0SE, PSA, PS2:PS0 are (OPTION_REG<5:0>).

TABLE 5-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other RESETS
01h	TMR0	Timer0 Module Register								xxxx xxxx	uuuu uuuu
0Bh,8Bh	INTCON	GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	—	PORTA Data Direction Register					---1 1111	---1 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

6.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits to deal with the needs of real time applications. The PIC16F84A has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These features are:

- OSC Selection
- RESET
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
- Interrupts
- Watchdog Timer (WDT)
- SLEEP
- Code Protection
- ID Locations
- In-Circuit Serial Programming™ (ICSP™)

The PIC16F84A has a Watchdog Timer which can be shut-off only through configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only. This design keeps the device in RESET while the power supply stabilizes. With these two timers on-chip, most applications need no external RESET circuitry.

SLEEP mode offers a very low current power-down mode. The user can wake-up from SLEEP through external RESET, Watchdog Timer Time-out or through an interrupt. Several oscillator options are provided to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select the various options.

Additional information on special features is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

6.1 Configuration Bits

The configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1'), to select various device configurations. These bits are mapped in program memory location 2007h.

Address 2007h is beyond the user program memory space and it belongs to the special test/configuration memory space (2000h - 3FFFh). This space can only be accessed during programming.

REGISTER 6-1: PIC16F84A CONFIGURATION WORD

R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u
CP	CP	CP	CP	CP	CP	CP	CP	CP	CP	$\overline{\text{PWRTE}}$	WDTE	F0SC1	F0SC0
bit13													bit0

bit 13-4 **CP:** Code Protection bit
1 = Code protection disabled
0 = All program memory is code protected

bit 3 **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit
1 = Power-up Timer is disabled
0 = Power-up Timer is enabled

bit 2 **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0 **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

6.2 Oscillator Configurations

6.2.1 OSCILLATOR TYPES

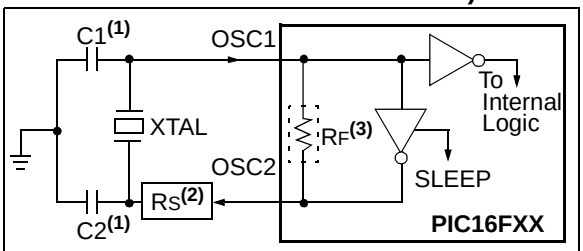
The PIC16F84A can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

6.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP, or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 6-1).

FIGURE 6-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 6-1 for recommended values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

The PIC16F84A oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP, or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 6-2).

FIGURE 6-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

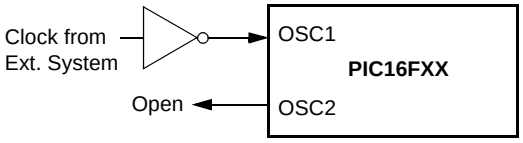


TABLE 6-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq**	**OSC1/C1**	**OSC2/C2**
XT	455 kHz	47 - 100 pF	47 - 100 pF
	2.0 MHz	15 - 33 pF	15 - 33 pF
	4.0 MHz	15 - 33 pF	15 - 33 pF
HS	8.0 MHz	15 - 33 pF	15 - 33 pF
	10.0 MHz	15 - 33 pF	15 - 33 pF

Note: Recommended values of C1 and C2 are identical to the ranges tested in this table. Higher capacitance increases the stability of the oscillator, but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for the appropriate values of external components.

Note: When using resonators with frequencies above 3.5 MHz, the use of HS mode rather than XT mode, is recommended. HS mode may be used at any VDD for which the controller is rated.

TABLE 6-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

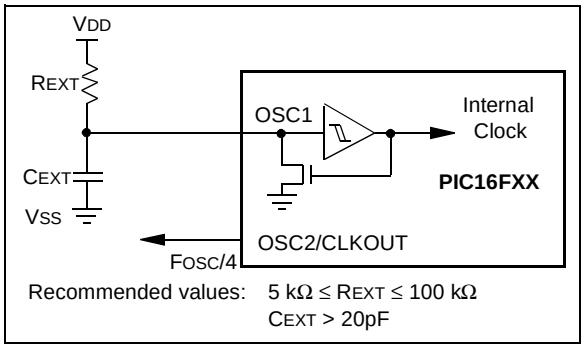
Mode	Freq	OSC1/C1	OSC2/C2
LP	32 kHz	68 - 100 pF	68 - 100 pF
	200 kHz	15 - 33 pF	15 - 33 pF
XT	100 kHz	100 - 150 pF	100 - 150 pF
	2 MHz	15 - 33 pF	15 - 33 pF
	4 MHz	15 - 33 pF	15 - 33 pF
HS	4 MHz	15 - 33 pF	15 - 33 pF
	20 MHz	15 - 33 pF	15 - 33 pF

Note: Higher capacitance increases the stability of the oscillator, but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.
For V_{DD} > 4.5V, C1 = C2 ≈ 30 pF is recommended.

6.2.3 RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) values, capacitor (C_{EXT}) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types also affects the oscillation frequency, especially for low C_{EXT} values. The user needs to take into account variation, due to tolerance of the external R and C components. Figure 6-3 shows how an R/C combination is connected to the PIC16F84A.

FIGURE 6-3: RC OSCILLATOR MODE



6.3 RESET

The PIC16F84A differentiates between various kinds of RESET:

- Power-on Reset (POR)
- $\overline{MCLR}$ during normal operation
- $\overline{MCLR}$ during SLEEP
- WDT Reset (during normal operation)
- WDT Wake-up (during SLEEP)

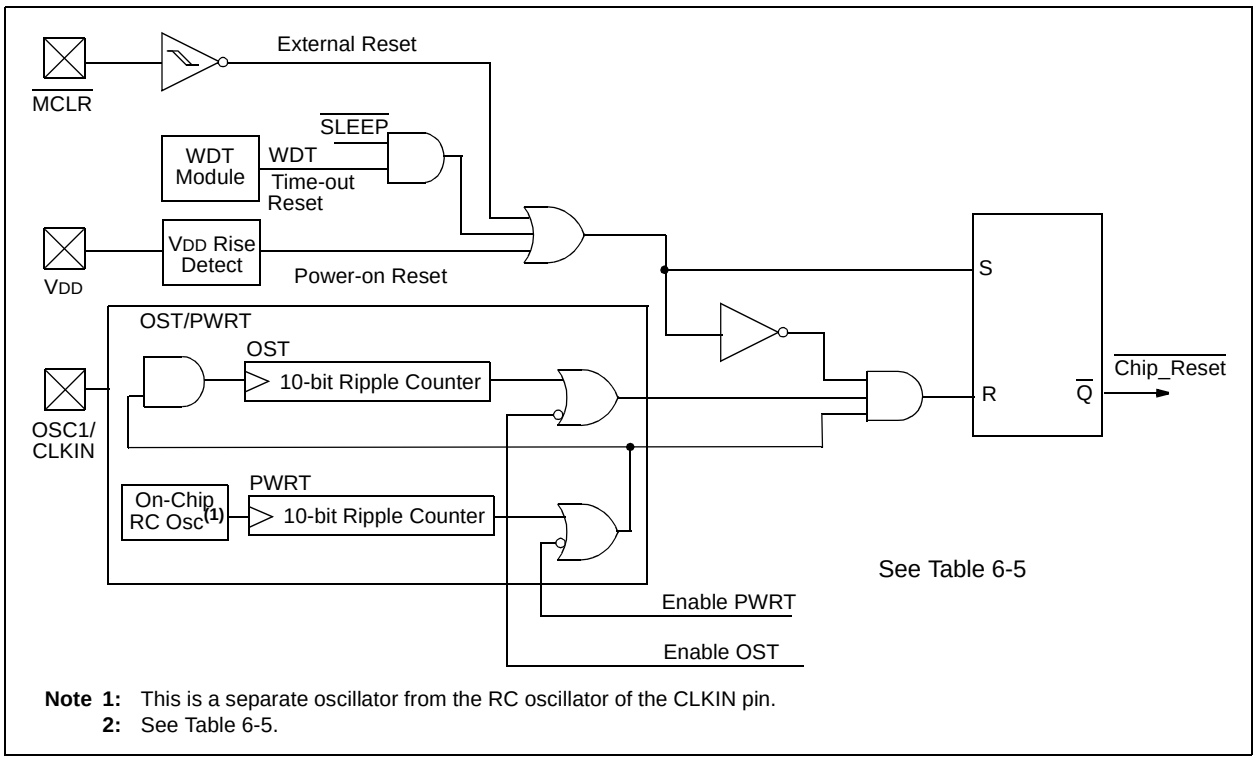
Figure 6-4 shows a simplified block diagram of the On-Chip RESET Circuit. The $\overline{MCLR}$ Reset path has a noise filter to ignore small pulses. The electrical specifications state the pulse width requirements for the $\overline{MCLR}$ pin.

Some registers are not affected in any RESET condition; their status is unknown on a POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on POR, $\overline{MCLR}$ or WDT Reset during normal operation and on $\overline{MCLR}$ during SLEEP. They are not affected by a WDT Reset during SLEEP, since this RESET is viewed as the resumption of normal operation.

Table 6-3 gives a description of RESET conditions for the program counter (PC) and the STATUS register. Table 6-4 gives a full description of RESET states for all registers.

The $\overline{TO}$ and $\overline{PD}$ bits are set or cleared differently in different RESET situations (Section 6.7). These bits are used in software to determine the nature of the RESET.

FIGURE 6-4: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: This is a separate oscillator from the RC oscillator of the CLKIN pin.
2: See Table 6-5.

TABLE 6-3: RESET CONDITION FOR PROGRAM COUNTER AND THE STATUS REGISTER

Condition	Program Counter	STATUS Register
Power-on Reset	000h	0001 1xxx
$\overline{MCLR}$ during normal operation	000h	000u uuuu
$\overline{MCLR}$ during SLEEP	000h	0001 0uuu
WDT Reset (during normal operation)	000h	0000 1uuu
WDT Wake-up	PC + 1	uuu0 0uuu
Interrupt wake-up from SLEEP	PC + 1(1)	uuu1 0uuu

Legend: u = unchanged, x = unknown
Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

TABLE 6-4: RESET CONDITIONS FOR ALL REGISTERS

Register	Address	Power-on Reset	$\overline{\text{MCLR}}$ during: – normal operation – SLEEP WDT Reset during normal operation	Wake-up from SLEEP: – through interrupt – through WDT Time-out
W	—	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	00h	---- ----	---- ----	---- ----
TMR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h	0000 0000	0000 0000	PC + 1(2)
STATUS	03h	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	04h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA(4)	05h	---x xxxx	---u uuuu	---u uuuu
PORTB(5)	06h	xxxx xxxx	uuuu uuuu	uuuu uuuu
EEDATA	08h	xxxx xxxx	uuuu uuuu	uuuu uuuu
EEADR	09h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCLATH	0Ah	---0 0000	---0 0000	---u uuuu
INTCON	0Bh	0000 000x	0000 000u	uuuu uuuu(1)
INDF	80h	---- ----	---- ----	---- ----
OPTION_REG	81h	1111 1111	1111 1111	uuuu uuuu
PCL	82h	0000 0000	0000 0000	PC + 1(2)
STATUS	83h	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	84h	xxxx xxxx	uuuu uuuu	uuuu uuuu
TRISA	85h	---1 1111	---1 1111	---u uuuu
TRISB	86h	1111 1111	1111 1111	uuuu uuuu
EECON1	88h	---0 x000	---0 q000	---0 uuuu
EECON2	89h	---- ----	---- ----	---- ----
PCLATH	8Ah	---0 0000	---0 0000	---u uuuu
INTCON	8Bh	0000 000x	0000 000u	uuuu uuuu(1)

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: Table 6-3 lists the RESET value for each specific condition.

4: On any device RESET, these pins are configured as inputs.

5: This is the value that will be in the port output latch.

6.4 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.2V - 1.7V). To take advantage of the POR, just tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A minimum rise time for VDD must be met for this to operate properly. See Electrical Specifications for details.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting*."

The POR circuit does not produce an internal RESET when VDD declines.

6.5 Power-up Timer (PWRT)

The Power-up Timer (PWRT) provides a fixed 72 ms nominal time-out (TPWRT) from POR (Figures 6-6 through 6-9). The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level (possible exception shown in Figure 6-9).

A configuration bit, PWRTE, can enable/disable the PWRT. See Register 6-1 for the operation of the PWRTE bit for a particular device.

The power-up time delay TPWRT will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

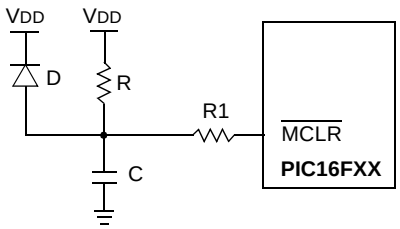
6.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle delay (from OSC1 input) after the PWRT delay ends (Figure 6-6, Figure 6-7, Figure 6-8 and Figure 6-9). This ensures the crystal oscillator or resonator has started and stabilized.

The OST time-out (TOST) is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

When VDD rises very slowly, it is possible that the TPWRT time-out and TOST time-out will expire before VDD has reached its final value. In this case (Figure 6-9), an external Power-on Reset circuit may be necessary (Figure 6-5).

FIGURE 6-5: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if VDD power-up rate is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that voltage drop across R does not exceed 0.2V (max leakage current spec on MCLR pin is 5 µA). A larger voltage drop will degrade VIH level on the MCLR pin.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C, in the event of a MCLR pin breakdown due to ESD or EOS.

FIGURE 6-6: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

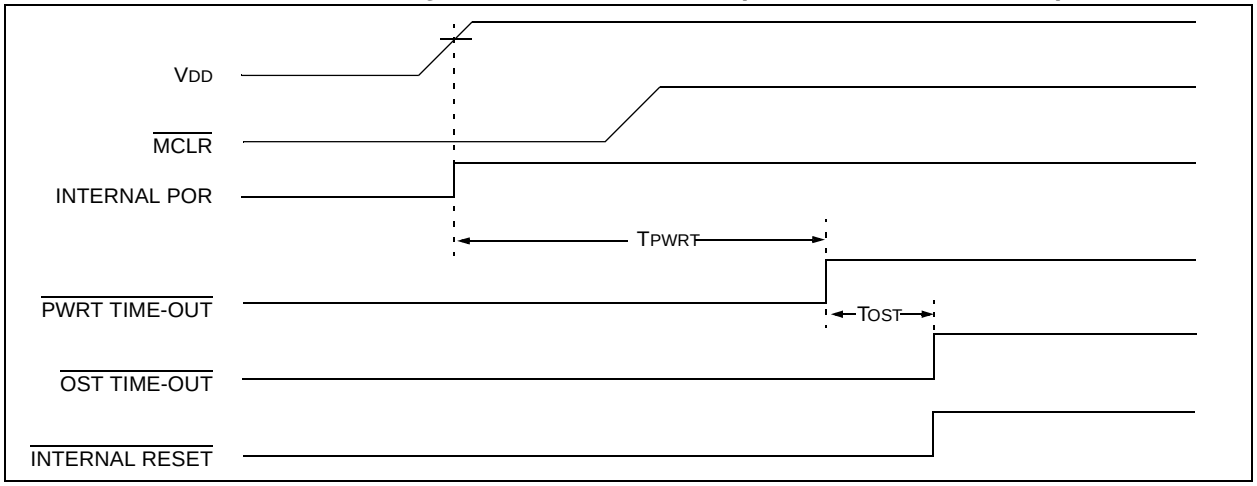


FIGURE 6-7: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2

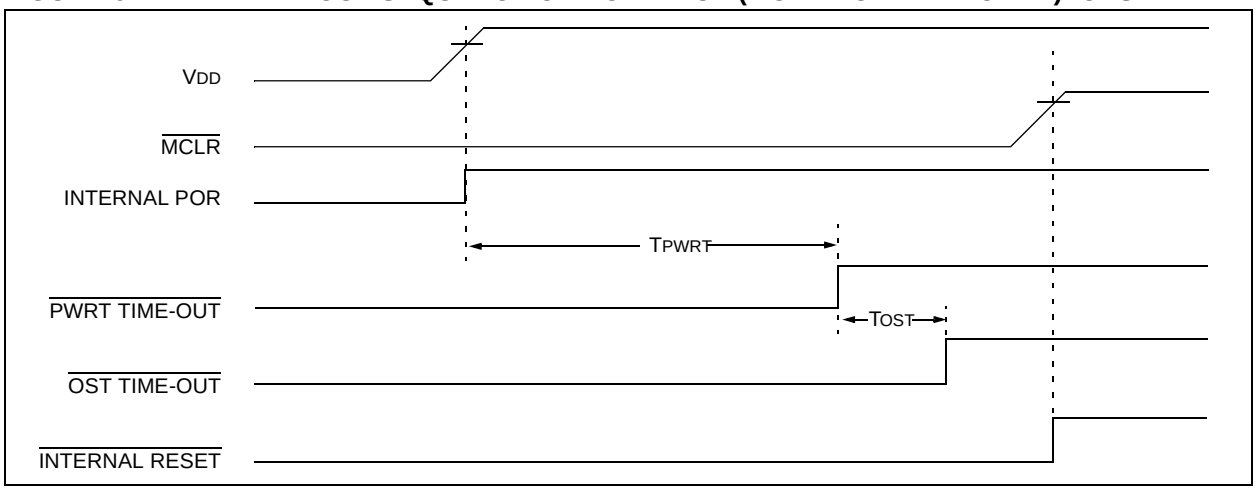


FIGURE 6-8: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD}): FAST V_{DD} RISE TIME

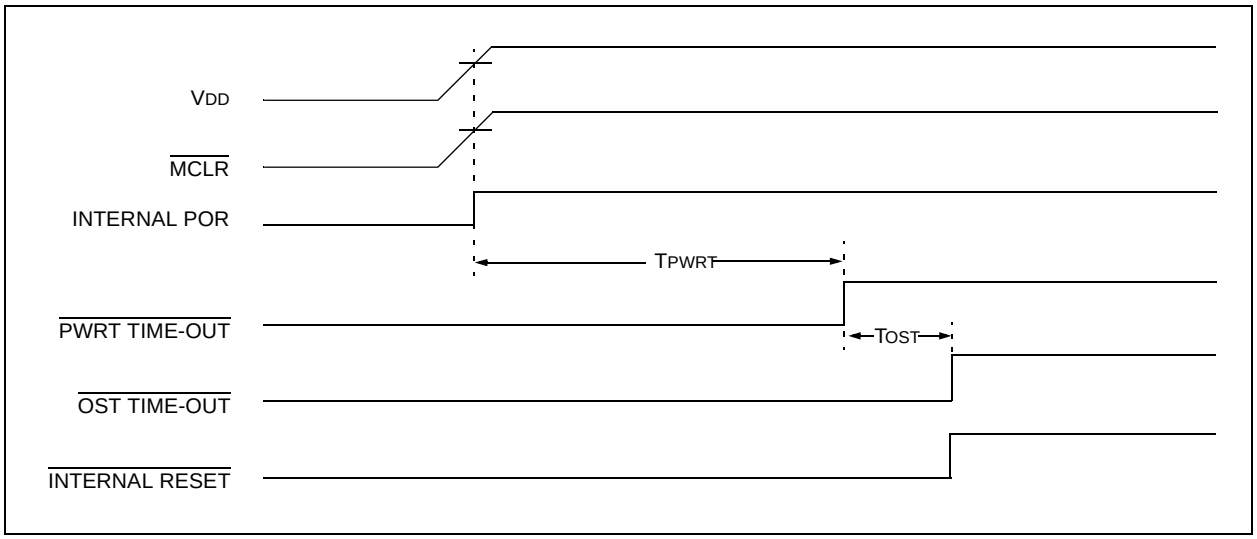
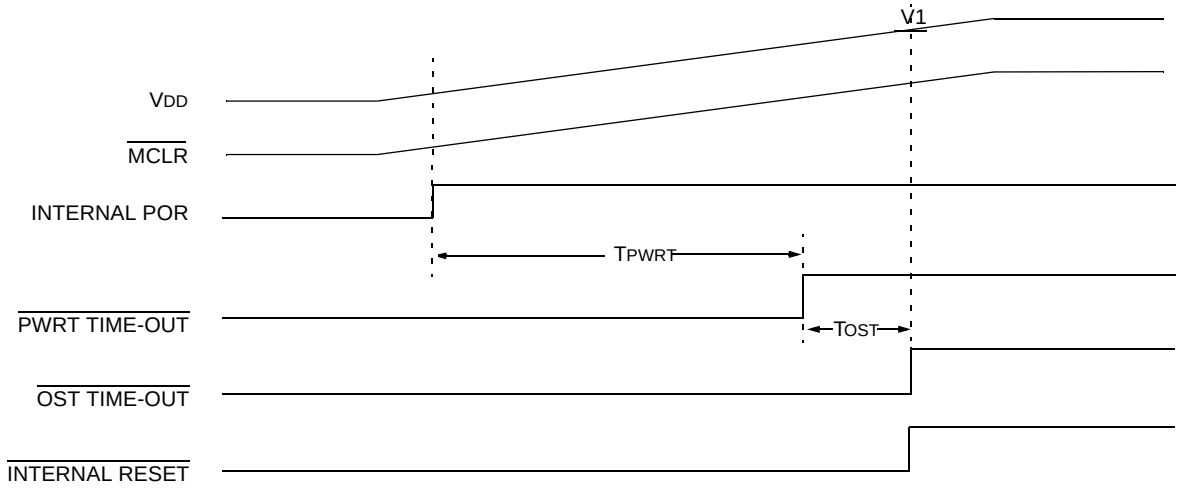


FIGURE 6-9: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD}): SLOW V_{DD} RISE TIME



When V_{DD} rises very slowly, it is possible that the T_{PWRT} time-out and T_{OST} time-out will expire before V_{DD} has reached its final value. In this example, the chip will reset properly if, and only if, V1 ≥ V_{DD} min.

6.7 Time-out Sequence and Power-down Status Bits ($\overline{TO}$/$\overline{PD}$)

On power-up (Figures 6-6 through 6-9), the time-out sequence is as follows:

1. PWRT time-out is invoked after a POR has expired.
2. Then, the OST is activated.

The total time-out will vary based on oscillator configuration and PWRTE configuration bit status. For example, in RC mode with the PWRT disabled, there will be no time-out at all.

TABLE 6-5: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Wake-up from SLEEP
	PWRT Enabled	PWRT Disabled	
XT, HS, LP	72 ms + 1024TOSC	1024TOSC	1024TOSC
RC	72 ms	—	—

Since the time-outs occur from the POR pulse, if $\overline{MCLR}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{MCLR}$ high, execution will begin immediately (Figure 6-6). This is useful for testing purposes or to synchronize more than one PIC16F84A device when operating in parallel.

Table 6-6 shows the significance of the $\overline{TO}$ and $\overline{PD}$ bits. Table 6-3 lists the RESET conditions for some special registers, while Table 6-4 lists the RESET conditions for all the registers.

TABLE 6-6: STATUS BITS AND THEIR SIGNIFICANCE

$\overline{TO}$	$\overline{PD}$	Condition
1	1	Power-on Reset
0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
0	1	WDT Reset (during normal operation)
0	0	WDT Wake-up
1	1	$\overline{MCLR}$ during normal operation
1	0	$\overline{MCLR}$ during SLEEP or interrupt wake-up from SLEEP

6.8 Interrupts

The PIC16F84A has 4 sources of interrupt:

- External interrupt RB0/INT pin
- TMR0 overflow interrupt
- PORTB change interrupts (pins RB7:RB4)
- Data EEPROM write complete interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also contains the individual and global interrupt enable bits.

The global interrupt enable bit, GIE (INTCON<7>), enables (if set) all unmasked interrupts or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register. Bit GIE is cleared on RESET.

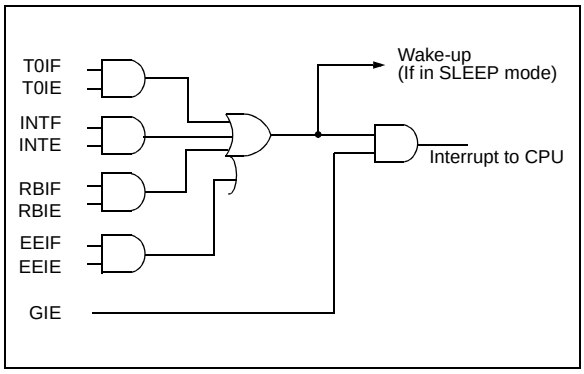
The "return from interrupt" instruction, `RETFIE`, exits interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. For external interrupt events, such as the RB0/INT pin or PORTB change interrupt, the interrupt latency will be three to four instruction cycles. The exact latency depends when the interrupt event occurs. The latency is the same for both one and two cycle instructions. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid infinite interrupt requests.

Note:	Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

FIGURE 6-10: INTERRUPT LOGIC



6.8.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if INTEDG bit (OPTION_REG<6>) is set, or falling if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing control bit INTE (INTCON<4>). Flag bit INTF must be cleared in software via the Interrupt Service Routine before re-enabling this interrupt. The INT interrupt can wake the processor from SLEEP (Section 6.11) only if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether the processor branches to the interrupt vector following wake-up.

6.8.2 TMR0 INTERRUPT

An overflow (FFh $\rightarrow$ 00h) in TMR0 will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>) (Section 5.0).

6.8.3 PORTB INTERRUPT

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<3>) (Section 4.2).

Note:	For a change on the I/O pin to be recognized, the pulse width must be at least T_{CY} wide.

6.8.4 DATA EEPROM INTERRUPT

At the completion of a data EEPROM write cycle, flag bit EEIF (EECON1<4>) will be set. The interrupt can be enabled/disabled by setting/clearing enable bit EEIE (INTCON<6>) (Section 3.0).

6.9 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users wish to save key register values during an interrupt (e.g., W register and STATUS register). This is implemented in software.

The code in Example 6-1 stores and restores the STATUS and W register's values. The user defined registers, W_TEMP and STATUS_TEMP are the temporary storage locations for the W and STATUS registers values.

Example 6-1 does the following:

a) Stores the W register.
b) Stores the STATUS register in STATUS_TEMP.
c) Executes the Interrupt Service Routine code.
d) Restores the STATUS (and bank select bit) register.
e) Restores the W register.

EXAMPLE 6-1: SAVING STATUS AND W REGISTERS IN RAM

```
PUSH    MOVWF   W_TEMP              ; Copy W to TEMP register,
        SWAPF   STATUS,     W       ; Swap status to be saved into W
        MOVWF   STATUS_TEMP         ; Save status to STATUS_TEMP register
ISR     :                           :
        :                           ; Interrupt Service Routine
        :                           ; should configure Bank as required
        :                           ;
POP     SWAPF   STATUS_TEMP,W       ; Swap nibbles in STATUS_TEMP register
                                    ; and place result into W
        MOVWF   STATUS              ; Move W into STATUS register
                                    ; (sets bank to original state)
        SWAPF   W_TEMP,     F       ; Swap nibbles in W_TEMP and place result in W_TEMP
        SWAPF   W_TEMP,     W       ; Swap nibbles in W_TEMP and place result into W
```

6.10 Watchdog Timer (WDT)

The Watchdog Timer is a free running On-Chip RC Oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time-out generates a device RESET. If the device is in SLEEP mode, a WDT wake-up causes the device to wake-up and continue with normal operation. The WDT can be permanently disabled by programming configuration bit WDTE as a '0' (Section 6.1).

6.10.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, V_{DD} and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION_REG register. Thus, time-out periods up to 2.3 seconds can be realized.

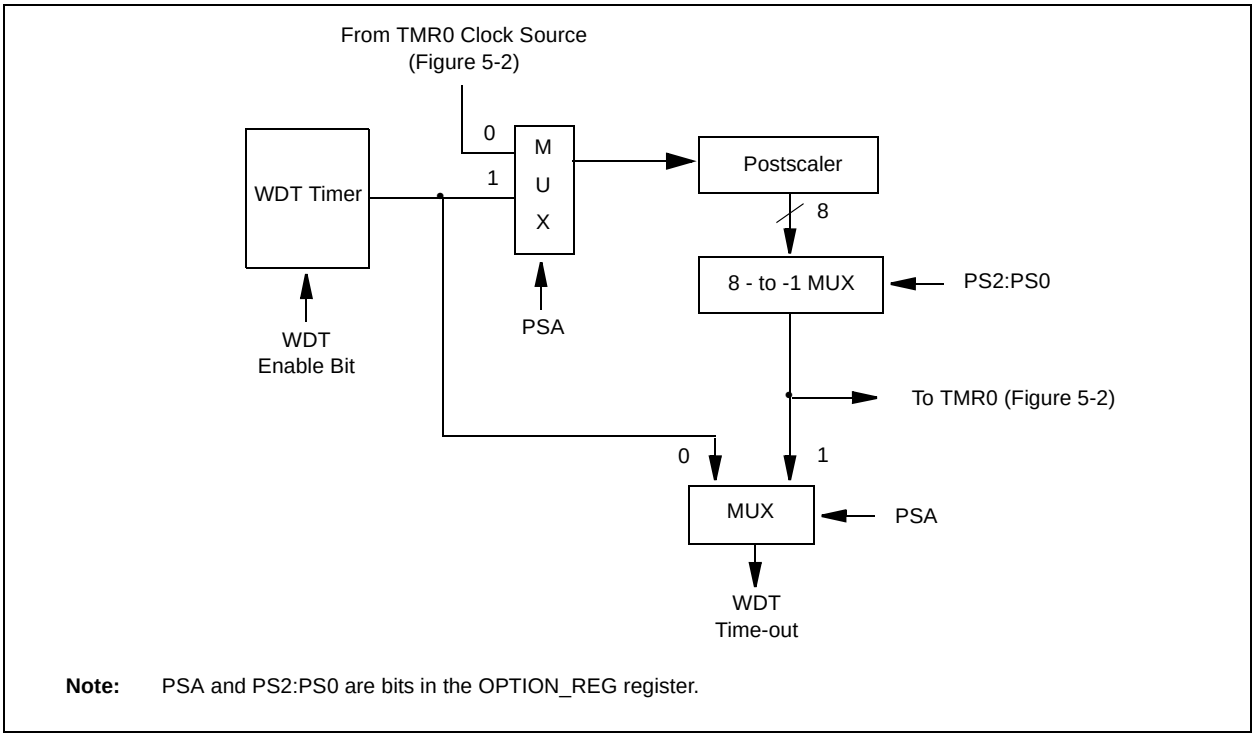
The CLRWDT and SLEEP instructions clear the WDT and the postscaler (if assigned to the WDT) and prevent it from timing out and generating a device RESET condition.

The $\overline{TO}$ bit in the STATUS register will be cleared upon a WDT time-out.

6.10.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken into account that under worst case conditions (V_{DD} = Min., Temperature = Max., Max. WDT Prescaler), it may take several seconds before a WDT time-out occurs.

FIGURE 6-11: WATCHDOG TIMER BLOCK DIAGRAM



Note: PSA and PS2:PS0 are bits in the OPTION_REG register.

TABLE 6-7: SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other RESETS
2007h	Config. bits	(2)	(2)	(2)	(2)	$\overline{\text{PWRTE}}$(1)	WDTE	FOSC1	FOSC0	(2)	
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: x = unknown. Shaded cells are not used by the WDT.

Note 1: See Register 6-1 for operation of the $\overline{\text{PWRTE}}$ bit.

2: See Register 6-1 and Section 6.12 for operation of the code and data protection bits.

6.11 Power-down Mode (SLEEP)

A device may be powered down (SLEEP) and later powered up (wake-up from SLEEP).

6.11.1 SLEEP

The Power-down mode is entered by executing the SLEEP instruction.

If enabled, the Watchdog Timer is cleared (but keeps running), the $\overline{PD}$ bit (STATUS<3>) is cleared, the $\overline{TO}$ bit (STATUS<4>) is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For the lowest current consumption in SLEEP mode, place all I/O pins at either V_{DD} or V_{SS}, with no external circuitry drawing current from the I/O pins, and disable external clocks. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS}. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level (V_{IHMC}).

It should be noted that a RESET generated by a WDT time-out does not drive the $\overline{MCLR}$ pin low.

6.11.2 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

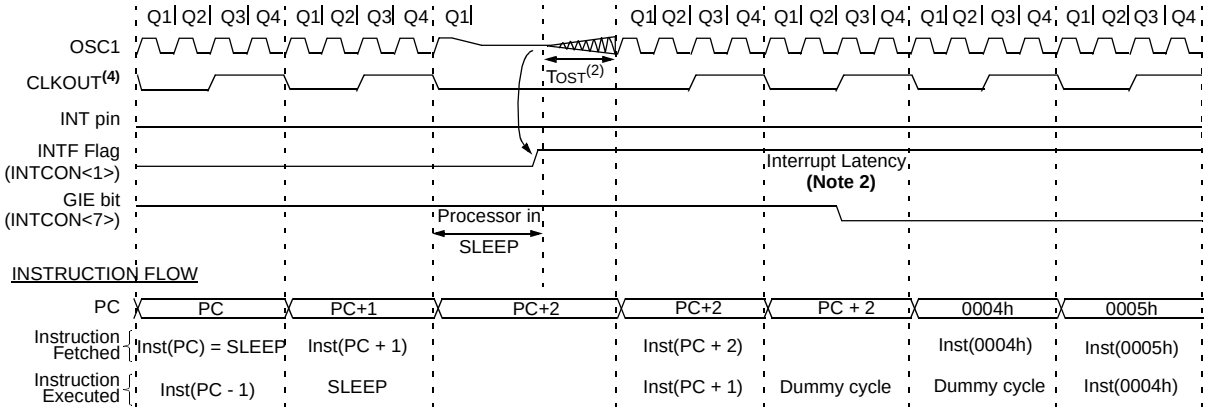
1. External RESET input on $\overline{MCLR}$ pin.
2. WDT wake-up (if WDT was enabled).
3. Interrupt from RB0/INT pin, RB port change, or data EEPROM write complete.

Peripherals cannot generate interrupts during SLEEP, since no on-chip Q clocks are present.

The first event ($\overline{MCLR}$ Reset) will cause a device RESET. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits can be used to determine the cause of a device RESET. The $\overline{PD}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The $\overline{TO}$ bit is cleared if a WDT time-out occurred (and caused wake-up).

While the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up occurs regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

FIGURE 6-12: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS, or LP oscillator mode assumed.
2: T_{OST} = 1024T_{OSC} (drawing not to scale). This delay will not be there for RC osc mode.
3: GIE = '1' assumed. In this case after wake-up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

6.11.3 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{TO}$ bit will not be set and $\overline{PD}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from SLEEP. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

6.12 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

6.13 ID Locations

Four memory locations (2000h - 2004h) are designated as ID locations to store checksum or other code identification numbers. These locations are not accessible during normal execution but are readable and writable only during program/verify. Only the four Least Significant bits of ID location are usable.

6.14 In-Circuit Serial Programming

PIC16F84A microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. Customers can manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product, allowing the most recent firmware or custom firmware to be programmed.

For complete details of Serial Programming, please refer to the In-Circuit Serial Programming™ (ICSP™) Guide, (DS30277).

NOTES:

7.0 INSTRUCTION SET SUMMARY

Each PIC16CXX instruction is a 14-bit word, divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CXX instruction set summary in Table 7-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 7-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the address of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 7-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
PC	Program Counter
TO	Time-out bit
PD	Power-down bit

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 µs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 µs.

Table 7-2 lists the instructions recognized by the MPASM™ Assembler.

Figure 7-1 shows the general formats that the instructions can have.

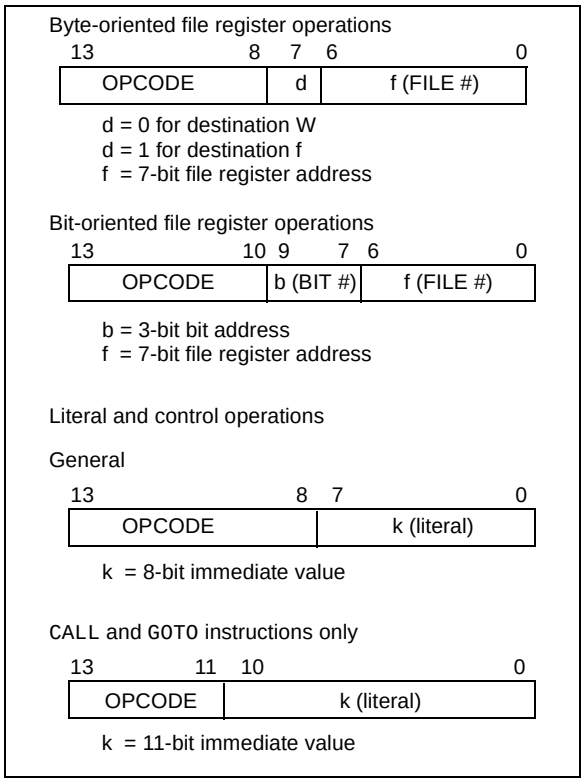
Note: To maintain upward compatibility with future PIC16CXX products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 7-1: GENERAL FORMAT FOR INSTRUCTIONS



A description of each instruction is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

TABLE 7-2: PIC16CXXX INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb			LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1 (2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1 (2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL AND CONTROL OPERATIONS									
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	$\overline{TO}$,$\overline{PD}$	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	$\overline{TO}$,$\overline{PD}$	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

Note: Additional information on the mid-range instruction set is available in the PICmicro™ Mid-Range MCU Family Reference Manual (DS33023).

7.1 Instruction Descriptions

ADDLW	Add Literal and W
Syntax:	[*label*] ADDLW k
Operands:	$0 \le k \le 255$
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the eight-bit literal 'k' and the result is placed in the W register.

ADDWF	Add W and f
Syntax:	[*label*] ADDWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

ANDLW	AND Literal with W
Syntax:	[*label*] ANDLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.

ANDWF	AND W with f
Syntax:	[*label*] ANDWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

BCF	Bit Clear f
Syntax:	[*label*] BCF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BSF	Bit Set f
Syntax:	[*label*] BSF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

BTFSS	Bit Test f, Skip if Set
Syntax:	[*label*] BTFSS f,b
Operands:	$0 \le f \le 127$ $0 \le b < 7$
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2TCY instruction.

BTFSC **Bit Test, Skip if Clear**

Syntax: [*label*] BTFSC f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: skip if (f<b>) = 0

Status Affected: None

Description: If bit 'b' in register 'f' is '1', the next instruction is executed.
If bit 'b' in register 'f' is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2TCY instruction.

CALL **Call Subroutine**

Syntax: [*label*] CALL k

Operands: $0 \le k \le 2047$

Operation: (PC)+ 1→ TOS,
k → PC<10:0>,
(PCLATH<4:3>) → PC<12:11>

Status Affected: None

Description: Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction.

CLRF **Clear f**

Syntax: [*label*] CLRF f

Operands: $0 \le f \le 127$

Operation: 00h → (f)
1 → Z

Status Affected: Z

Description: The contents of register 'f' are cleared and the Z bit is set.

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Description: W register is cleared. Zero bit (Z) is set.

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT
0 → WDT prescaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF **Complement f**

Syntax: [*label*] COMF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: $(\bar{f}) \rightarrow$ (destination)

Status Affected: Z

Description: The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.

DECF **Decrement f**

Syntax: [*label*] DECF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - 1 → (destination)

Status Affected: Z

Description: Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

DECFSZ **Decrement f, Skip if 0**

Syntax: [*label*] DECFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - 1 → (destination);
skip if result = 0

Status Affected: None

Description: The contents of register 'f' are decremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
If the result is 1, the next instruction is executed. If the result is 0, then a NOP is executed instead, making it a 2TCY instruction.

GOTO **Unconditional Branch**

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 2047$

Operation: k → PC<10:0>
PCLATH<4:3> → PC<12:11>

Status Affected: None

Description: GOTO is an unconditional branch. The eleven-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two-cycle instruction.

INCF **Increment f**

Syntax: [*label*] INCF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (destination)

Status Affected: Z

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

INCFSZ **Increment f, Skip if 0**

Syntax: [*label*] INCFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (destination),
skip if result = 0

Status Affected: None

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
If the result is 1, the next instruction is executed. If the result is 0, a NOP is executed instead, making it a 2TCY instruction.

IORLW **Inclusive OR Literal with W**

Syntax: [*label*] IORLW k

Operands: $0 \le k \le 255$

Operation: (W) .OR. k → (W)

Status Affected: Z

Description: The contents of the W register are OR'ed with the eight-bit literal 'k'. The result is placed in the W register.

IORWF **Inclusive OR W with f**

Syntax: [*label*] IORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .OR. (f) → (destination)

Status Affected: Z

Description: Inclusive OR the W register with register 'f'. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

MOVF	Move f
Syntax:	[*label*] MOVF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) → (destination)
Status Affected:	Z
Description:	The contents of register f are moved to a destination dependant upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register, since status flag Z is affected.

MOVLW	Move Literal to W
Syntax:	[*label*] MOVLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W)
Status Affected:	None
Description:	The eight-bit literal 'k' is loaded into W register. The don't cares will assemble as 0's.

MOVWF	Move W to f
Syntax:	[*label*] MOVWF f
Operands:	$0 \le f \le 127$
Operation:	(W) → (f)
Status Affected:	None
Description:	Move data from W register to register 'f'.

NOP	No Operation
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.

RETFIE	Return from Interrupt
Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None

RETLW	Return with Literal in W
Syntax:	[*label*] RETLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W); TOS → PC
Status Affected:	None
Description:	The W register is loaded with the eight-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.

RETURN	Return from Subroutine
Syntax:	[*label*] RETURN
Operands:	None
Operation:	TOS → PC
Status Affected:	None
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.

RLF **Rotate Left f through Carry**

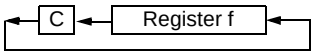
Syntax: [*label*] RLF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.



RRF **Rotate Right f through Carry**

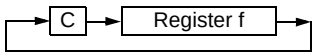
Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.



SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Description: The power-down status bit, $\overline{PD}$ is cleared. Time-out status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped.

SUBLW **Subtract W from Literal**

Syntax: [*label*] SUBLW k

Operands: $0 \le k \le 255$

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Description: The W register is subtracted (2's complement method) from the eight-bit literal 'k'. The result is placed in the W register.

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (destination)

Status Affected: C, DC, Z

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (destination<7:4>),
(f<7:4>) → (destination<3:0>)

Status Affected: None

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.

XORLW	Exclusive OR Literal with W
Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k $\rightarrow$ (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

XORWF	Exclusive OR W with f
Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) $\rightarrow$ (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

8.0 DEVELOPMENT SUPPORT

The PICmicro® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

8.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PICmicro emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

8.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PICmicro MCU’s.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

8.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

8.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK object linker combines relocatable objects created by the MPASM assembler and the MPLAB C17 and MPLAB C18 C compilers. It can also link relocatable objects from pre-compiled libraries, using directives from a linker script.

The MPLIB object librarian is a librarian for pre-compiled code to be used with the MPLINK object linker. When a routine from a library is called from another source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications. The MPLIB object librarian manages the creation and modification of library files.

The MPLINK object linker features include:

- Integration with MPASM assembler and MPLAB C17 and MPLAB C18 C compilers.
- Allows all memory areas to be defined as sections to provide link-time flexibility.

The MPLIB object librarian features include:

- Easier linking because single libraries can be included instead of many smaller files.
- Helps keep code maintainable by grouping related modules together.
- Allows libraries to be created and modules to be added, listed, replaced, deleted or extracted.

8.5 MPLAB SIM Software Simulator

The MPLAB SIM software simulator allows code development in a PC-hosted environment by simulating the PICmicro series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user-defined key press, to any of the pins. The execution can be performed in single step, execute until break, or trace mode.

The MPLAB SIM simulator fully supports symbolic debugging using the MPLAB C17 and the MPLAB C18 C compilers and the MPASM assembler. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent multi-project software development tool.

8.6 MPLAB ICE High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB ICE universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro microcontrollers (MCUs). Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment (IDE), which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PICmicro microcontrollers.

The MPLAB ICE in-circuit emulator system has been designed as a real-time emulation system, with advanced features that are generally found on more expensive development tools. The PC platform and Microsoft® Windows® environment were chosen to best make these features available to you, the end user.

8.7 ICEPIC In-Circuit Emulator

The ICEPIC low cost, in-circuit emulator is a solution for the Microchip Technology PIC16C5X, PIC16C6X, PIC16C7X and PIC16CXXX families of 8-bit One-Time-Programmable (OTP) microcontrollers. The modular system can support different subsets of PIC16C5X or PIC16CXXX products through the use of interchangeable personality modules, or daughter boards. The emulator is capable of emulating without target application circuitry being present.

8.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PICmicro MCUs and can be used to develop for this and other PICmicro microcontrollers. The MPLAB ICD utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial Programming™ protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

8.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable V_{DD} and V_{PP} supplies, which allow it to verify programmed memory at V_{DD} min and V_{DD} max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In stand-alone mode, the PRO MATE II device programmer can read, verify, or program PICmicro devices. It can also set code protection in this mode.

8.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PICmicro devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

8.11 PICDEM 1 Low Cost PICmicro Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE in-circuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

8.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I2CTM bus and separate headers for connection to an LCD module and a keypad.

8.13 PICDEM 3 Low Cost PIC16CXXX Demonstration Board

The PICDEM 3 demonstration board is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with an LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 3 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer with an adapter socket, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 3 demonstration board to test firmware. A prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM 3 demonstration board is a LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM 3 demonstration board provides an additional RS-232 interface and Windows software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

8.14 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. All necessary hardware is included to run basic demo programs, which are supplied on a 3.5-inch disk. A programmed sample is included and the user may erase it and program it with the other sample programs using the PRO MATE II device programmer, or the PICSTART Plus development programmer, and easily debug and test the sample code. In addition, the PICDEM 17 demonstration board supports downloading of programs to and executing out of external FLASH memory on board. The PICDEM 17 demonstration board is also usable with the MPLAB ICE in-circuit emulator, or the PICMASTER emulator and all of the sample programs can be run and modified using either emulator. Additionally, a generous prototype area is available for user hardware.

8.15 KEELOQ Evaluation and Programming Tools

KEELOQ evaluation and programming tools support Microchip's HCS Secure Data Products. The HCS evaluation kit includes a LCD display to show changing codes, a decoder to decode transmissions and a programming interface to program test transmitters.

TABLE 8-1: DEVELOPMENT TOOLS FROM MICROCHIP

		PIC12CXXX	PIC14000	PIC16C5X	PIC16C6X	PIC16CXXX	PIC16F62X	PIC16C7X	PIC16C7XX	PIC16C8X	PIC16F8XX	PIC16C9XX	PIC17C4X	PIC17C7XX	PIC18CXX2	PIC18FXXX	24CXX/ 25CXX/ 93CXX	HCSXXX	MCRFXXX	MCP2510
Software Tools	MPLAB® Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	MPLAB® C17 C Compiler			✓									✓	✓						
	MPLAB® C18 C Compiler			✓											✓	✓				
	MPASM™ Assembler/ MPLINK™ Object Linker	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Emulators	MPLAB® ICE In-Circuit Emulator	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	ICEPIC™ In-Circuit Emulator	✓		✓	✓	✓		✓	✓	✓		✓								
Debugger	MPLAB® ICD In-Circuit Debugger				✓*			✓*			✓					✓				
Programmers	PICSTART® Plus Entry Level Development Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓			
	PRO MATE® II Universal Device Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Demo Boards and Eval Kits	PICDEM™ 1 Demonstration Board			✓		✓		✓†		✓			✓							
	PICDEM™ 2 Demonstration Board				✓†	✓		✓†							✓					
	PICDEM™ 3 Demonstration Board											✓								
	PICDEM™ 14A Demonstration Board		✓																	
	PICDEM™ 17 Demonstration Board													✓						
	KEELOQ® Evaluation Kit																✓			
	KEELOQ® Transponder Kit																✓			
	microID™ Programmer's Kit																	✓		
	125 kHz microID™ Developer's Kit																	✓		
	125 kHz Anticollision microID™ Developer's Kit																	✓		
	13.56 MHz Anticollision microID™ Developer's Kit																	✓		
	MCP2510 CAN Developer's Kit																			✓

* Contact the Microchip Technology Inc. web site at www.microchip.com for information on how to use the MPLAB® ICD In-Circuit Debugger (DV164001) with PIC16C62, 63, 64, 65, 72, 73, 74, 76, 77.

** Contact Microchip Technology Inc. for availability date.

† Development tool is available on select devices.

NOTES:

9.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55°C to +125°C

Storage temperature ..... -65°C to +150°C

Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$, and RA4) ..... -0.3V to (V_{DD} + 0.3V)

Voltage on V_{DD} with respect to V_{SS} ..... -0.3 to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} **(1)** ..... -0.3 to +14V

Voltage on RA4 with respect to V_{SS} ..... -0.3 to +8.5V

Total power dissipation **(2)** ..... 800 mW

Maximum current out of V_{SS} pin ..... 150 mA

Maximum current into V_{DD} pin ..... 100 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ± 20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ± 20 mA

Maximum output current sunk by any I/O pin ..... 25 mA

Maximum output current sourced by any I/O pin ..... 25 mA

Maximum current sunk by PORTA ..... 80 mA

Maximum current sourced by PORTA ..... 50 mA

Maximum current sunk by PORTB ..... 150 mA

Maximum current sourced by PORTB ..... 100 mA

Note 1: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

2: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{ol} \times I_{OL})$.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 9-1: PIC16F84A-20 VOLTAGE-FREQUENCY GRAPH

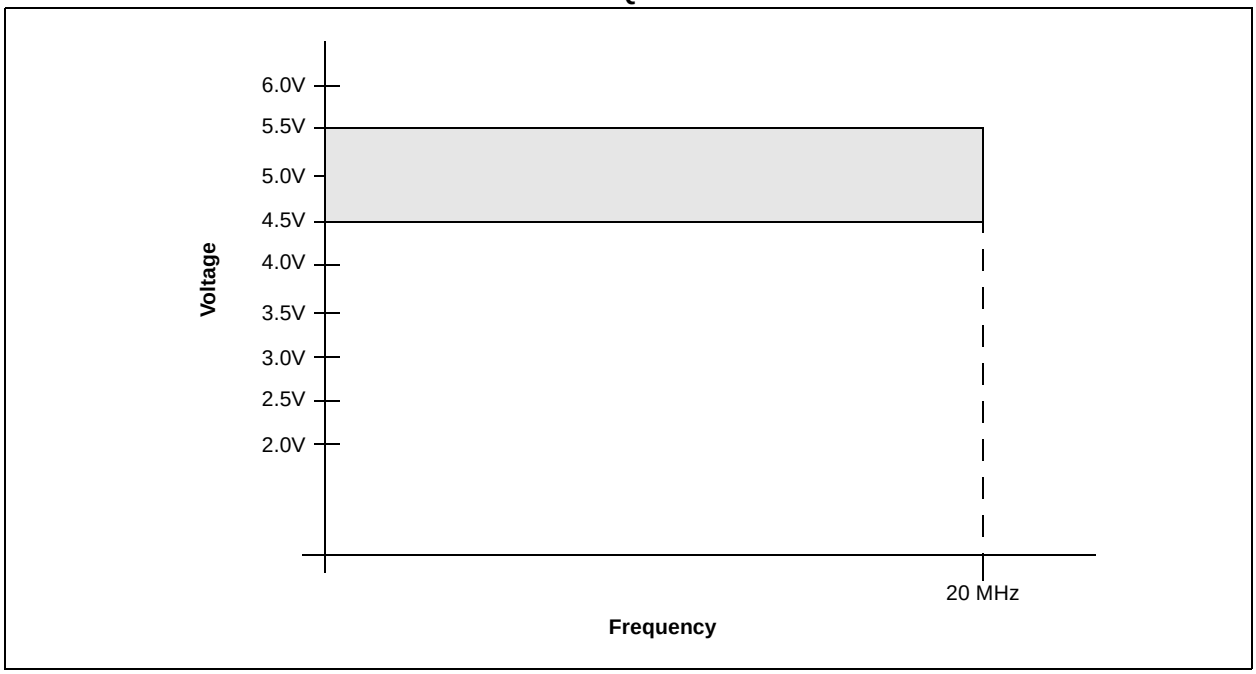
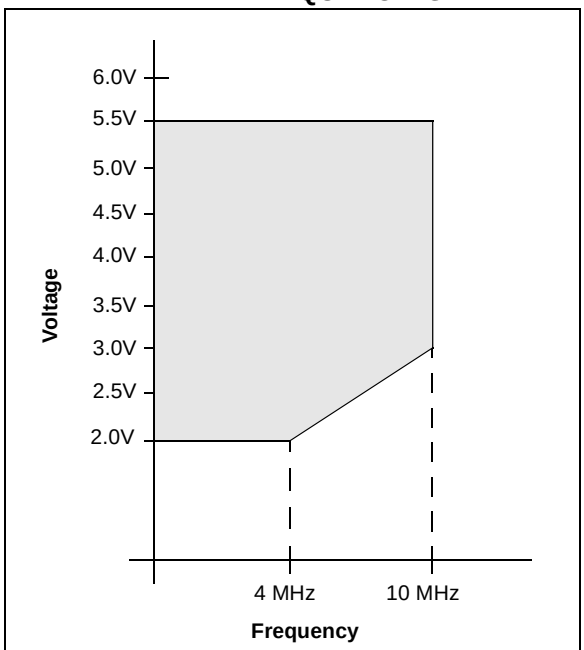


FIGURE 9-2: PIC16LF84A-04 VOLTAGE-FREQUENCY GRAPH

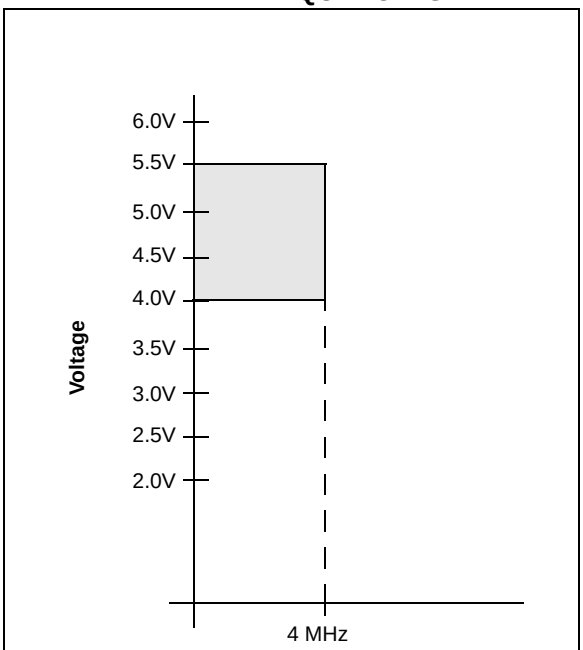


FMAX = (6.0 MHz/V) (VDDAPPMIN - 2.0V) + 4 MHz

Note 1: VDDAPPMIN is the minimum voltage of the PICmicro® device in the application.

2: FMAX has a maximum frequency of 10 MHz.

FIGURE 9-3: PIC16F84A-04 VOLTAGE-FREQUENCY GRAPH



9.1 DC Characteristics

PIC16LF84A-04 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
PIC16F84A-04 (Commercial, Industrial, Extended) **PIC16F84A-20** (Commercial, Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		16LF84A	2.0	—	5.5	V	XT, RC, and LP osc configuration
D001		16F84A	4.0	—	5.5	V	XT, RC and LP osc configuration
D001A			4.5	—	5.5	V	HS osc configuration
D002	VDR	**RAM Data Retention Voltage (Note 1)**	1.5	—	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	Vss	—	V	See section on Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	
	IDD	**Supply Current (Note 2)**					
D010		16LF84A	—	1	4	mA	RC and XT osc configuration **(Note 4)** FOSC = 2.0 MHz, VDD = 5.5V
D010		16F84A	—	1.8	4.5	mA	RC and XT osc configuration **(Note 4)** FOSC = 4.0 MHz, VDD = 5.5V
D010A			—	3	10	mA	RC and XT osc configuration **(Note 4)** FOSC = 4.0 MHz, VDD = 5.5V (During FLASH programming)
D013			—	10	20	mA	HS osc configuration (PIC16F84A-20) FOSC = 20 MHz, VDD = 5.5V
D014		16LF84A	—	15	45	µA	LP osc configuration FOSC = 32 kHz, VDD = 2.0V, WDT disabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

NR Not rated for operation.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,
T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula IR = VDD/2REXT (mA) with REXT in kOhm.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD measurement.

9.1 DC Characteristics (Continued)

PIC16LF84A-04 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
PIC16F84A-04 (Commercial, Industrial, Extended) **PIC16F84A-20** (Commercial, Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IPD	**Power-down Current (Note 3)**					
D020		16LF84A					
D020		16F84A-20 16F84A-04					
D021A		16LF84A	—	0.4	1.0	µA	VDD = 2.0V, WDT disabled, industrial
D021A		16F84A-20	—	1.5	3.5	µA	VDD = 4.5V, WDT disabled, industrial
		16F84A-04	—	1.0	3.0	µA	VDD = 4.0V, WDT disabled, industrial
D021B		16F84A-20	—	1.5	5.5	µA	VDD = 4.5V, WDT disabled, extended
		16F84A-04	—	1.0	5.0	µA	VDD = 4.0V, WDT disabled, extended
		Module Differential Current (Note 5)					
D022	ΔIWDT	Watchdog Timer	—	.20	16	µA	VDD = 2.0V, Industrial, Commercial
			—	3.5	20	µA	VDD = 4.0V, Commercial
			—	3.5	28	µA	VDD = 4.0V, Industrial, Extended
			—	4.8	25	µA	VDD = 4.5V, Commercial
			—	4.8	30	µA	VDD = 4.5V, Industrial, Extended

Legend: Rows with standard voltage device data only are shaded for improved readability.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

NR Not rated for operation.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,

T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula IR = VDD/2REXT (mA) with REXT in kOhm.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD measurement.

9.2 DC Characteristics: PIC16F84A-04 (Commercial, Industrial) PIC16F84A-20 (Commercial, Industrial) PIC16LF84A-04 (Commercial, Industrial)

DC Characteristics All Pins Except Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) Operating voltage VDD range as described in DC specifications (Section 9.1)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports:					
D030		with TTL buffer	VSS	—	0.8	V	4.5V ≤ VDD ≤ 5.5V **(Note 4)**
D030A			VSS	—	0.16VDD	V	Entire range **(Note 4)**
D031		with Schmitt Trigger buffer	VSS	—	0.2VDD	V	Entire range
D032		$\overline{MCLR}$, RA4/T0CKI	VSS	—	0.2VDD	V	
D033		OSC1 (XT, HS and LP modes)	VSS	—	0.3VDD	V	**(Note 1)**
D034		OSC1 (RC mode)	VSS	—	0.1VDD	V	
	VIH	**Input High Voltage**					
		I/O ports:		—			
D040		with TTL buffer	2.0	—	VDD	V	4.5V ≤ VDD ≤ 5.5V **(Note 4)**
D040A			0.25VDD+0.8	—	VDD	V	Entire range **(Note 4)**
D041		with Schmitt Trigger buffer	0.8 VDD	—	VDD		Entire range
D042		$\overline{MCLR}$,	0.8 VDD	—	VDD	V	
D042A		RA4/T0CKI	0.8 VDD	—	8.5	V	
D043		OSC1 (XT, HS and LP modes)	0.8 VDD	—	VDD	V	**(Note 1)**
D043A		OSC1 (RC mode)	0.9 VDD		VDD	V	
D050	VHYS	**Hysteresis of Schmitt Trigger Inputs**	—	0.1	—	V	
D070	IPURB	**PORTB Weak Pull-up Current**	50	250	400	µA	VDD = 5.0V, VPIN = VSS
	IIL	**Input Leakage Current (Notes 2, 3)**					
D060		I/O ports	—	—	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061		$\overline{MCLR}$, RA4/T0CKI	—	—	±5	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	—	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. Do not drive the PIC16F84A with an external clock while the device is in RC mode, or chip damage may result.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: The user may choose the better of the two specs.

9.2 DC Characteristics: PIC16F84A-04 (Commercial, Industrial) PIC16F84A-20 (Commercial, Industrial) PIC16LF84A-04 (Commercial, Industrial) (Continued)

DC Characteristics All Pins Except Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) Operating voltage VDD range as described in DC specifications (Section 9.1)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V
D083		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, (RC mode only)
	VOH	**Output High Voltage**					
D090		I/O ports **(Note 3)**	VDD-0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V
D092		OSC2/CLKOUT **(Note 3)**	VDD-0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V (RC mode only)
	VOD	**Open Drain High Voltage**					
D150		RA4 pin	—	—	8.5	V	
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101	CIO	All I/O pins and OSC2 (RC mode)	—	—	50	pF	
		Data EEPROM Memory					
D120	ED	Endurance	1M	10M	—	E/W	25°C at 5V
D121	VDRW	VDD for read/write	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D122	TDEW	Erase/Write cycle time	—	4	8	ms	
		Program FLASH Memory					
D130	EP	Endurance	1000	10K	—	E/W	
D131	VPR	VDD for read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132	VPEW	VDD for erase/write	4.5	—	5.5	V	
D133	TPEW	Erase/Write cycle time	—	4	8	ms	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. Do not drive the PIC16F84A with an external clock while the device is in RC mode, or chip damage may result.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: The user may choose the better of the two specs.

9.3 AC (Timing) Characteristics

9.3.1 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
2	to	os, osc	OSC1
ck	CLKOUT	ost	oscillator start-up timer
cy	cycle time	pwrt	power-up timer
io	I/O port	rbt	RBx pins
inp	INT pin	t0	T0CKI
mp	$\overline{\text{MCLR}}$	wdt	watchdog timer

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (high impedance)	V	Valid
L	Low	Z	High Impedance

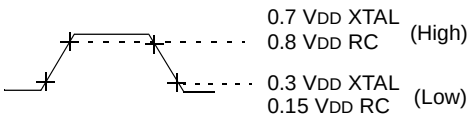
9.3.2 TIMING CONDITIONS

The temperature and voltages specified in Table 9-1 apply to all timing specifications unless otherwise noted. All timings are measured between high and low measurement points as indicated in Figure 9-4. Figure 9-5 specifies the load conditions for the timing specifications.

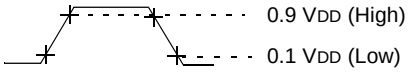
TABLE 9-1: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

AC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial Operating voltage VDD range as described in DC specifications (Section 9.1)

FIGURE 9-4: PARAMETER MEASUREMENT INFORMATION



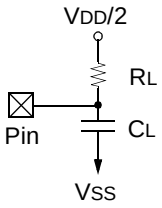
OSC1 Measurement Points



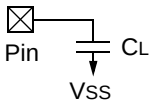
I/O Port Measurement Points

FIGURE 9-5: LOAD CONDITIONS

Load Condition 1



Load Condition 2



RL = 464Ω

CL = 50 pF for all pins except OSC2

15 pF for OSC2 output

9.3.3 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 9-6: EXTERNAL CLOCK TIMING

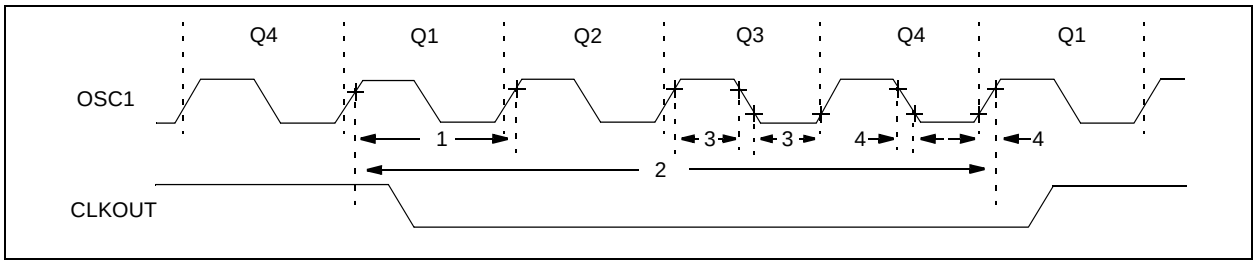


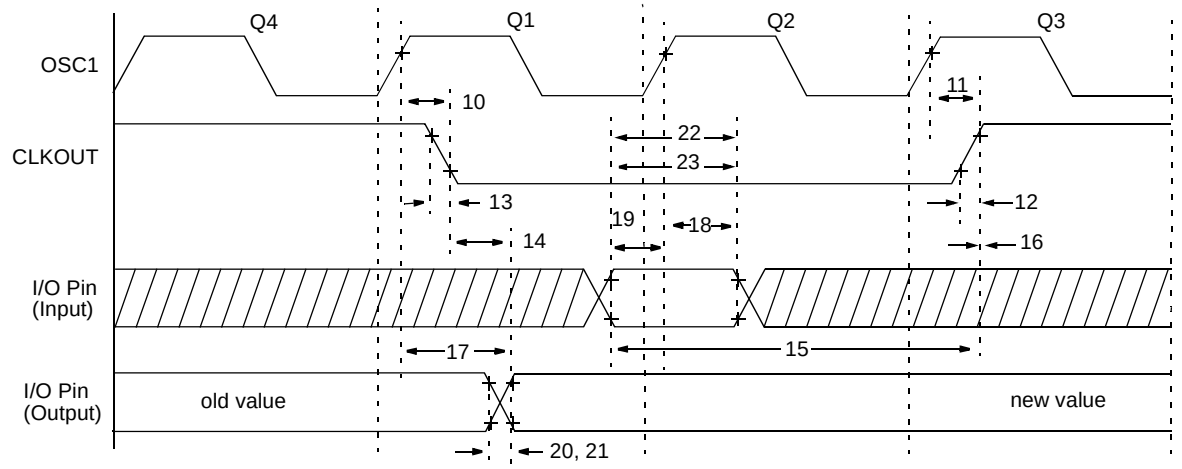
TABLE 9-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions	
	FOSC	**External CLKIN Frequency(1)**	DC	—	2	MHz	XT, RC osc	(-04, LF)
			DC	—	4	MHz	XT, RC osc	(-04)
			DC	—	20	MHz	HS osc	(-20)
			DC	—	200	kHz	LP osc	(-04, LF)
		Oscillator Frequency(1)	DC	—	2	MHz	RC osc	(-04, LF)
			DC	—	4	MHz	RC osc	(-04)
			0.1	—	2	MHz	XT osc	(-04, LF)
			0.1	—	4	MHz	XT osc	(-04)
			1.0	—	20	MHz	HS osc	(-20)
			DC	—	200	kHz	LP osc	(-04, LF)
1	TOSC	**External CLKIN Period(1)**	500	—	—	ns	XT, RC osc	(-04, LF)
			250	—	—	ns	XT, RC osc	(-04)
			50	—	—	ns	HS osc	(-20)
			5.0	—	—	µs	LP osc	(-04, LF)
		Oscillator Period(1)	500	—	—	ns	RC osc	(-04, LF)
			250	—	—	ns	RC osc	(-04)
			500	—	10,000	ns	XT osc	(-04, LF)
			250	—	10,000	ns	XT osc	(-04)
			50	—	1,000	ns	HS osc	(-20)
			5.0	—	—	µs	LP osc	(-04, LF)
2	TCY	**Instruction Cycle Time(1)**	0.2	4/FOSC	DC	µs		
3	TosL, TosH	**Clock in (OSC1) High or Low Time**	60	—	—	ns	XT osc	(-04, LF)
			50	—	—	ns	XT osc	(-04)
			2.0	—	—	µs	LP osc	(-04, LF)
			17.5	—	—	ns	HS osc	(-20)
4	TosR, TosF	**Clock in (OSC1) Rise or Fall Time**	25	—	—	ns	XT osc	(-04)
			50	—	—	ns	LP osc	(-04, LF)
			7.5	—	—	ns	HS osc	(-20)

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Min." values with an external clock applied to the OSC1 pin.
When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 9-7: CLKOUT AND I/O TIMING



Note: All tests must be done with specified capacitive loads (Figure 9-5) 50 pF on I/O pins and CLKOUT.

TABLE 9-3: CLKOUT AND I/O TIMING REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓	Standard	—	15	30	ns	**(Note 1)**
10A			Extended (LF)	—	15	120	ns	**(Note 1)**
11	TosH2ckH	OSC1↑ to CLKOUT↑	Standard	—	15	30	ns	**(Note 1)**
11A			Extended (LF)	—	15	120	ns	**(Note 1)**
12	TckR	CLKOUT rise time	Standard	—	15	30	ns	**(Note 1)**
12A			Extended (LF)	—	15	100	ns	**(Note 1)**
13	TckF	CLKOUT fall time	Standard	—	15	30	ns	**(Note 1)**
13A			Extended (LF)	—	15	100	ns	**(Note 1)**
14	TckL2ioV	CLKOUT ↓ to Port out valid		—	—	0.5TCY +20	ns	**(Note 1)**
15	TioV2ckH	Port in valid before CLKOUT ↑	Standard	0.30TCY + 30	—	—	ns	**(Note 1)**
			Extended (LF)	0.30TCY + 80	—	—	ns	**(Note 1)**
16	TckH2ioI	Port in hold after CLKOUT ↑		0	—	—	ns	**(Note 1)**
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	Standard	—	—	125	ns	
			Extended (LF)	—	—	250	ns	
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	Standard	10	—	—	ns	
			Extended (LF)	10	—	—	ns	
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	Standard	-75	—	—	ns	
			Extended (LF)	-175	—	—	ns	
20	TioR	Port output rise time	Standard	—	10	35	ns	
20A			Extended (LF)	—	10	70	ns	
21	TioF	Port output fall time	Standard	—	10	35	ns	
21A			Extended (LF)	—	10	70	ns	
22	TINP	INT pin high or low time	Standard	20	—	—	ns	
22A			Extended (LF)	55	—	—	ns	
23	TRBP	RB7:RB4 change INT high or low time	Standard	TOSC§	—	—	ns	
23A			Extended (LF)	TOSC§	—	—	ns	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ By design.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

FIGURE 9-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

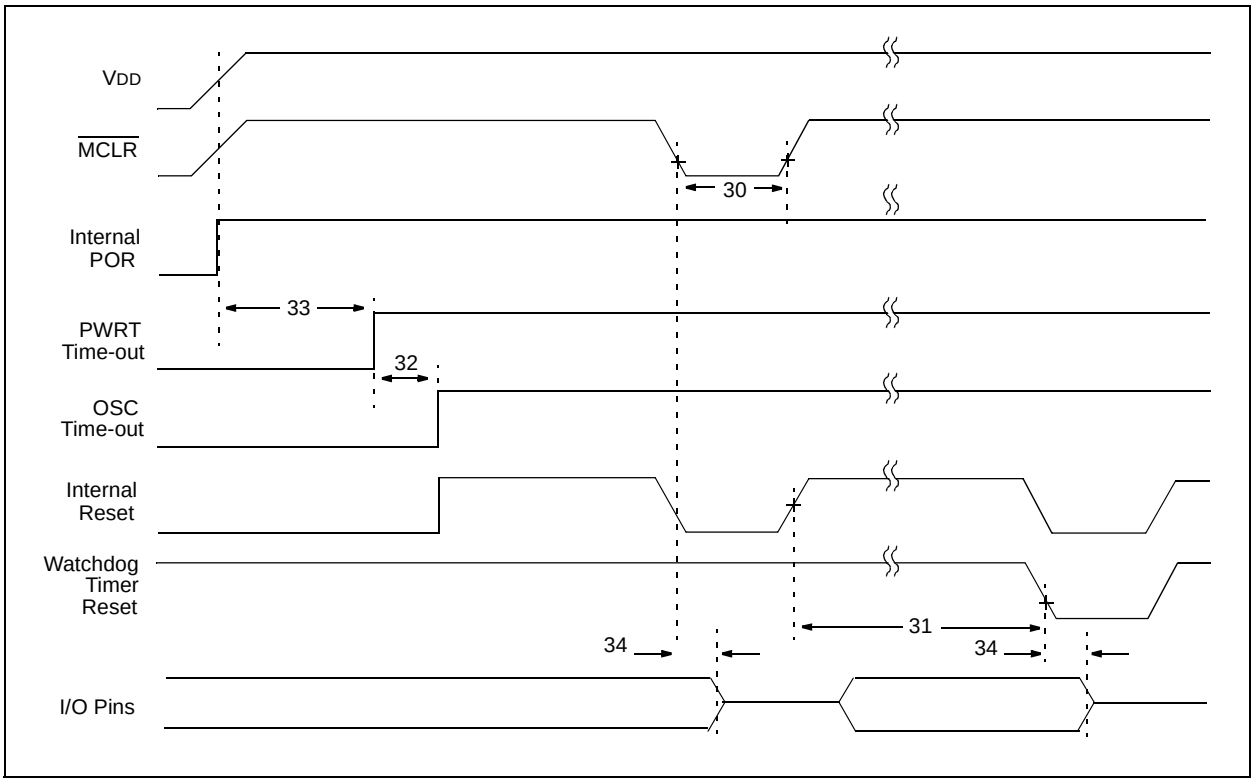


TABLE 9-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	VDD = 5.0V
31	TWDT	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5.0V
32	TOST	Oscillation Start-up Timer Period		1024TOSC		ms	TOSC = OSC1 period
33	TPWRT	Power-up Timer Period	28	72	132	ms	VDD = 5.0V
34	TIOZ	I/O hi-impedance from $\overline{\text{MCLR}}$ Low or RESET	—	—	100	ns	

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 9-9: TIMER0 CLOCK TIMINGS

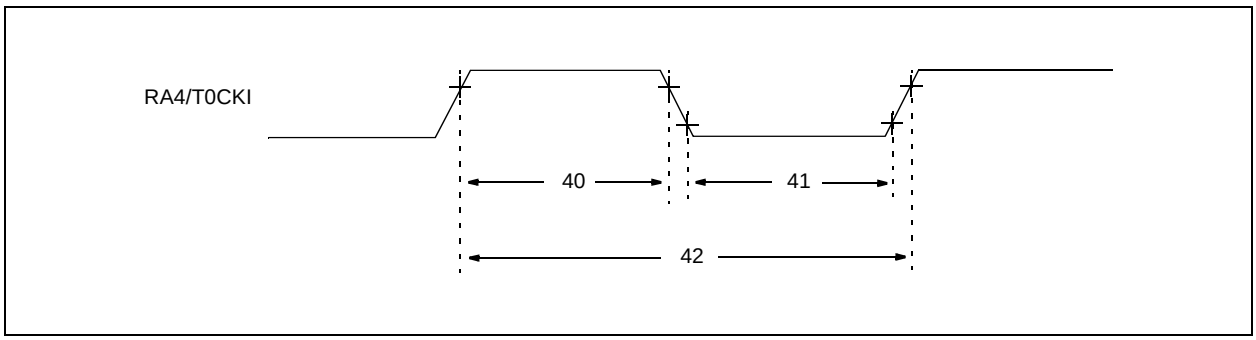


TABLE 9-5: TIMER0 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	50	—	—	ns	2.0V ≤ VDD ≤ 3.0V
				30	—	—	ns	3.0V ≤ VDD ≤ 6.0V
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	50	—	—	ns	2.0V ≤ VDD ≤ 3.0V
				20	—	—	ns	3.0V ≤ VDD ≤ 6.0V
42	Tt0P	T0CKI Period		$\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value (2, 4, ..., 256)

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

10.0 DC/AC CHARACTERISTIC GRAPHS

The graphs provided in this section are for **design guidance** and are **not tested**.

In some graphs, the data presented are **outside specified operating range** (i.e., outside specified V_{DD} range). This is for **information only** and devices are ensured to operate properly only within the specified range.

The data presented in this section is a **statistical summary** of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at 25°C. 'Max' or 'Min' represents (mean + 3σ) or (mean - 3σ), respectively, where σ is a standard deviation over the whole temperature range.

FIGURE 10-1: TYPICAL IDD vs. FOSC OVER VDD (HS MODE, 25°C)

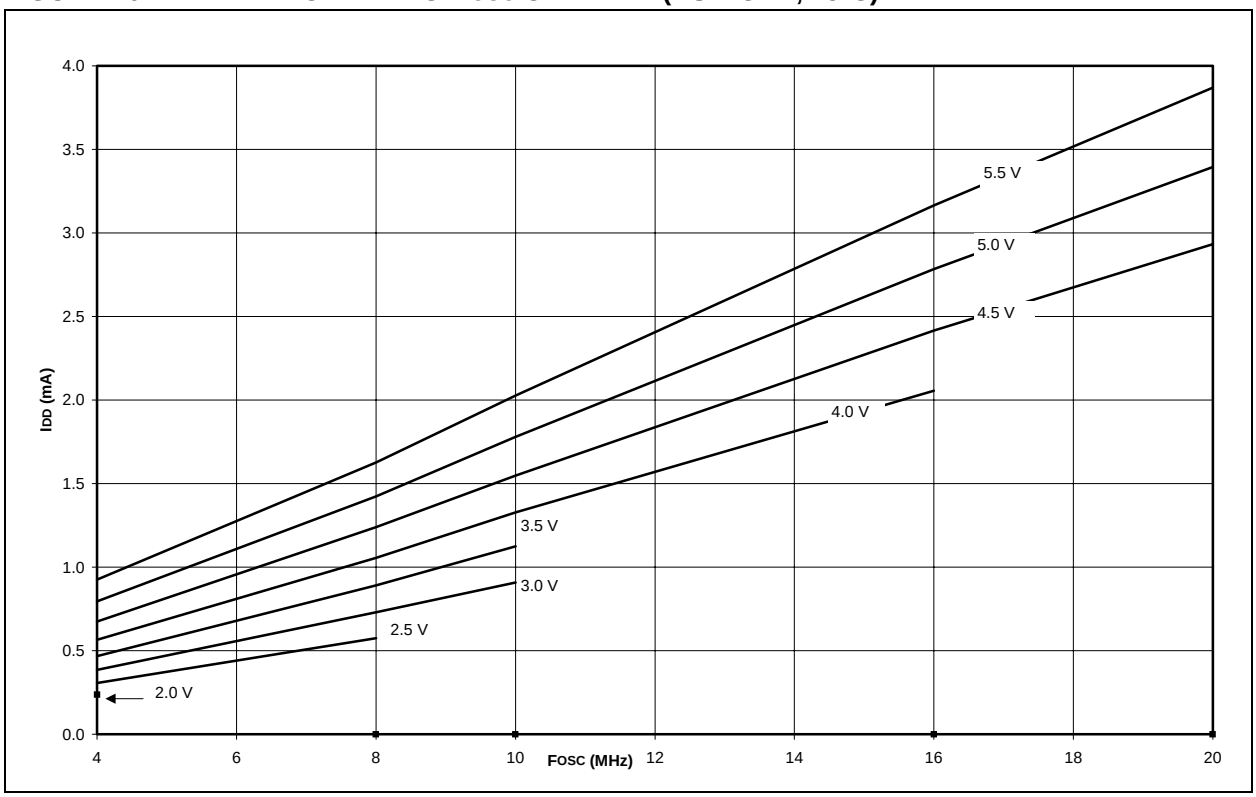


FIGURE 10-2: MAXIMUM IDD vs. FOSC OVER VDD (HS MODE, -40° TO +125°C)

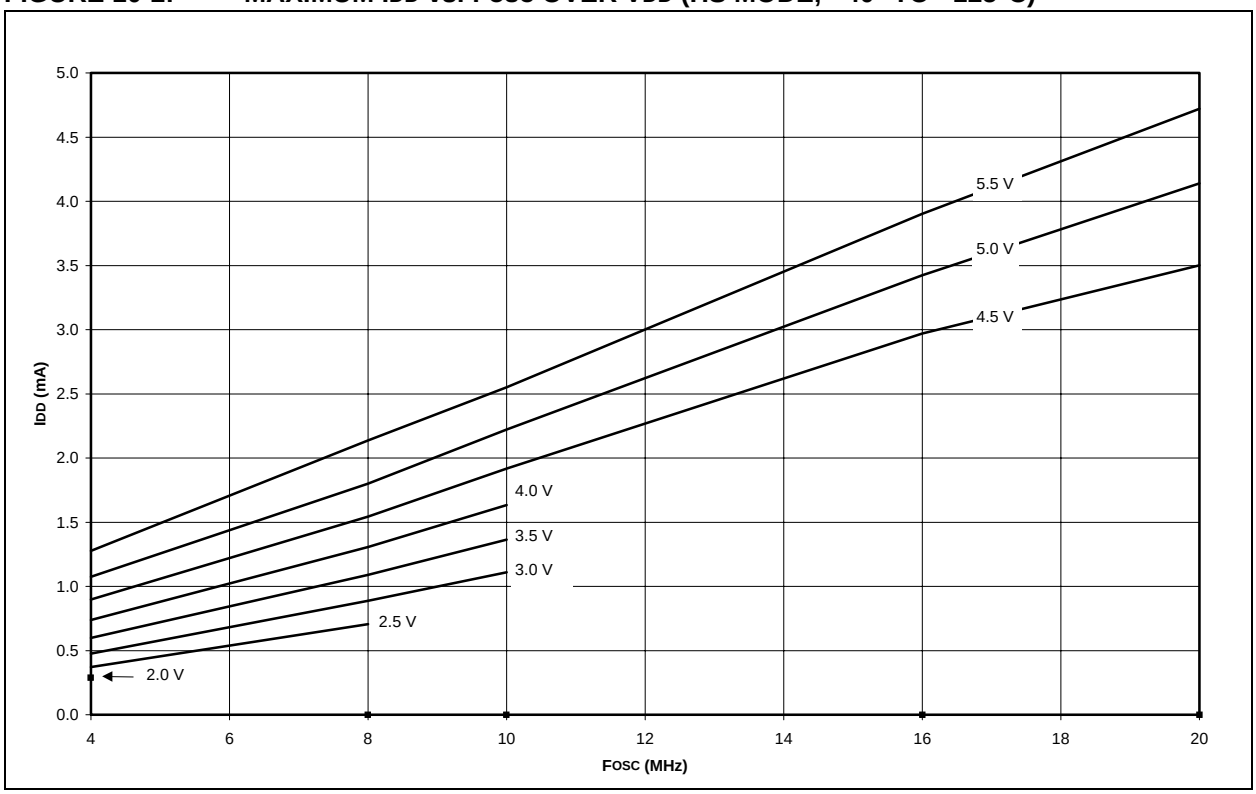


FIGURE 10-3: TYPICAL IDD vs. FOSC OVER VDD (XT MODE, 25°C)

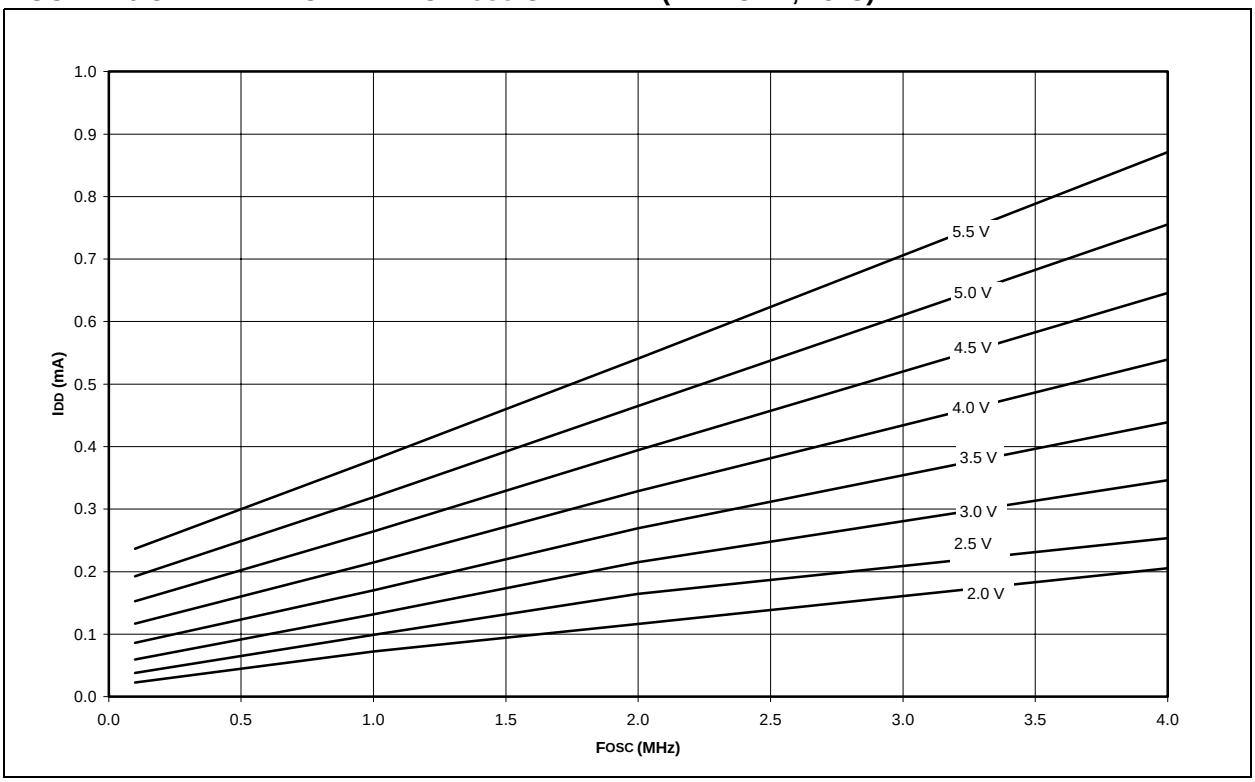


FIGURE 10-4: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE, -40° TO +125°C)

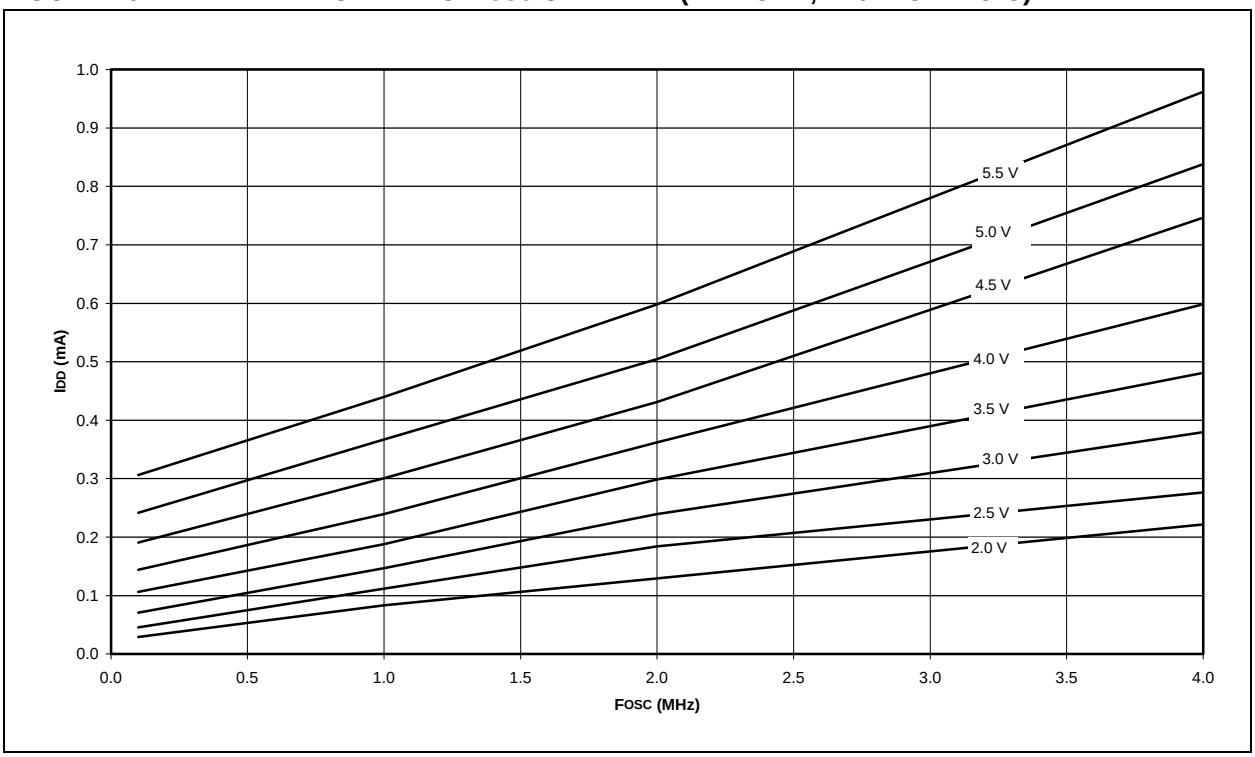


FIGURE 10-5: TYPICAL IDD vs. FOSC OVER VDD (LP MODE, 25°C)

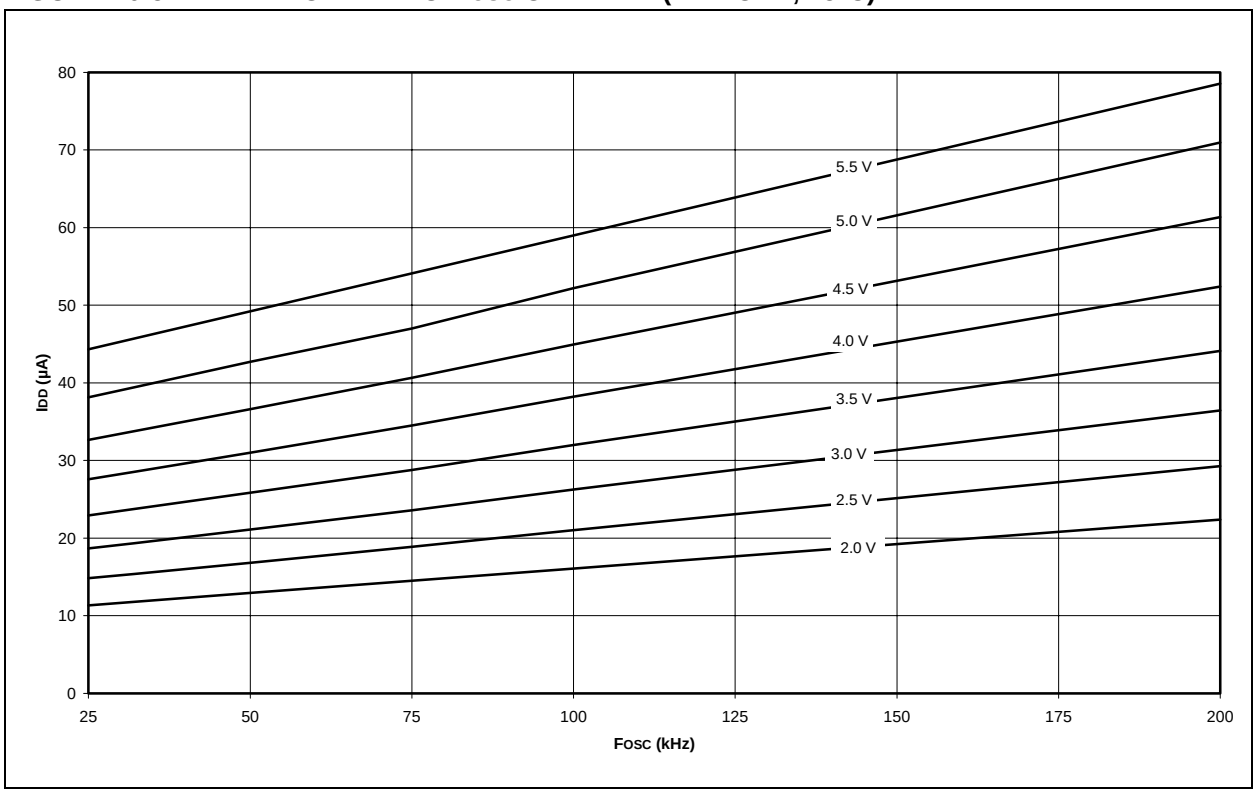


FIGURE 10-6: MAXIMUM IDD vs. FOSC OVER VDD (LP MODE, -40° TO +125°C)

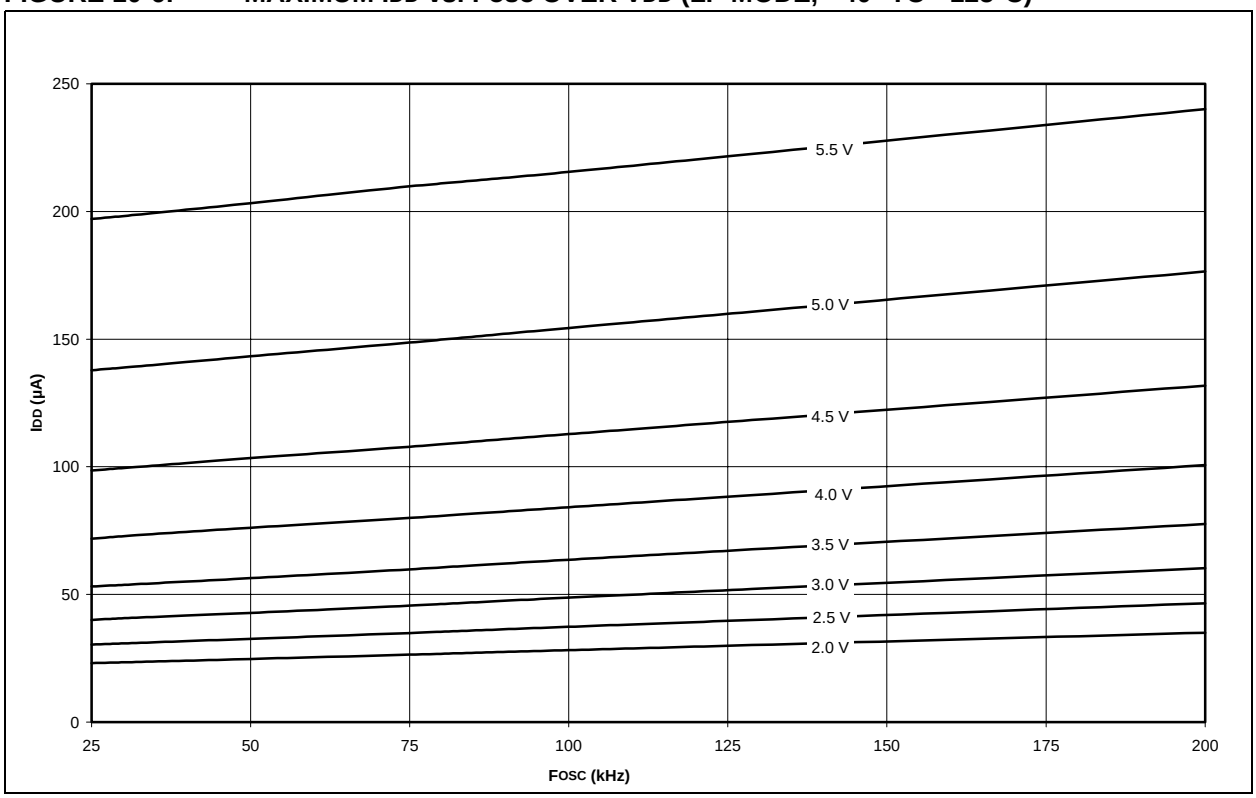


FIGURE 10-7: AVERAGE FOSC vs. VDD FOR R (RC MODE, C = 22 pF, 25°C)

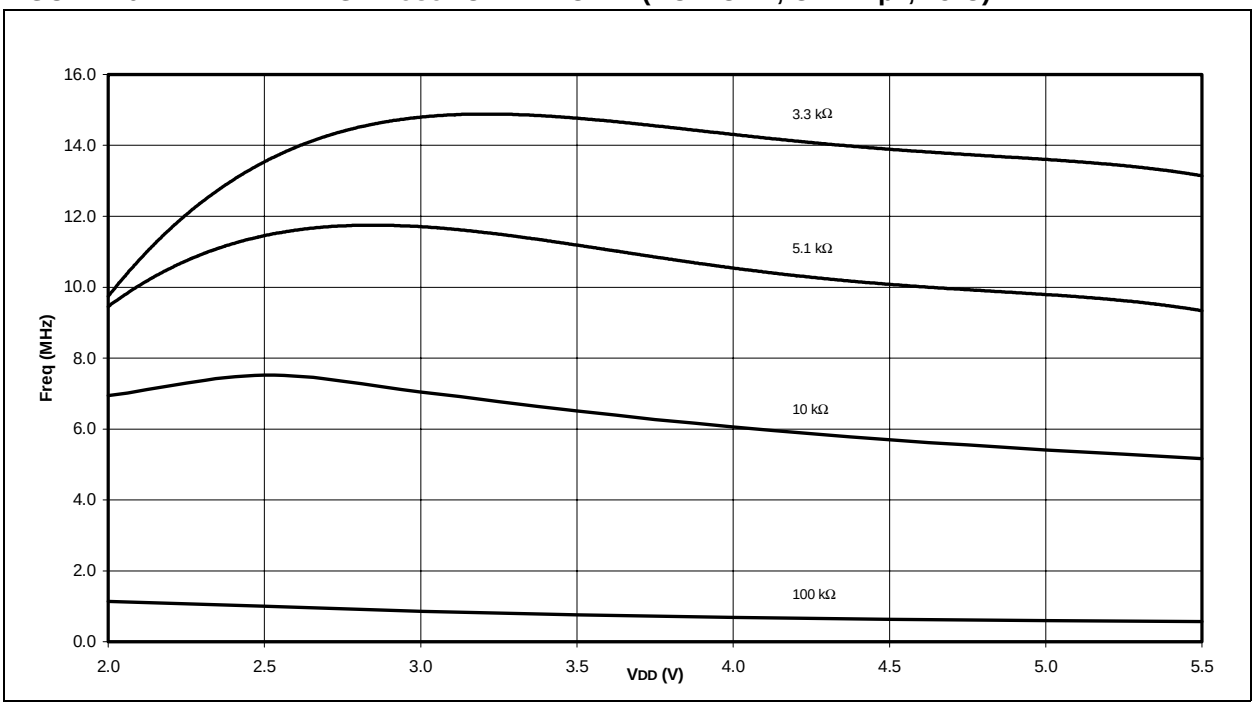


FIGURE 10-8: AVERAGE FOSC vs. VDD FOR R (RC MODE, C = 100 pF, 25°C)

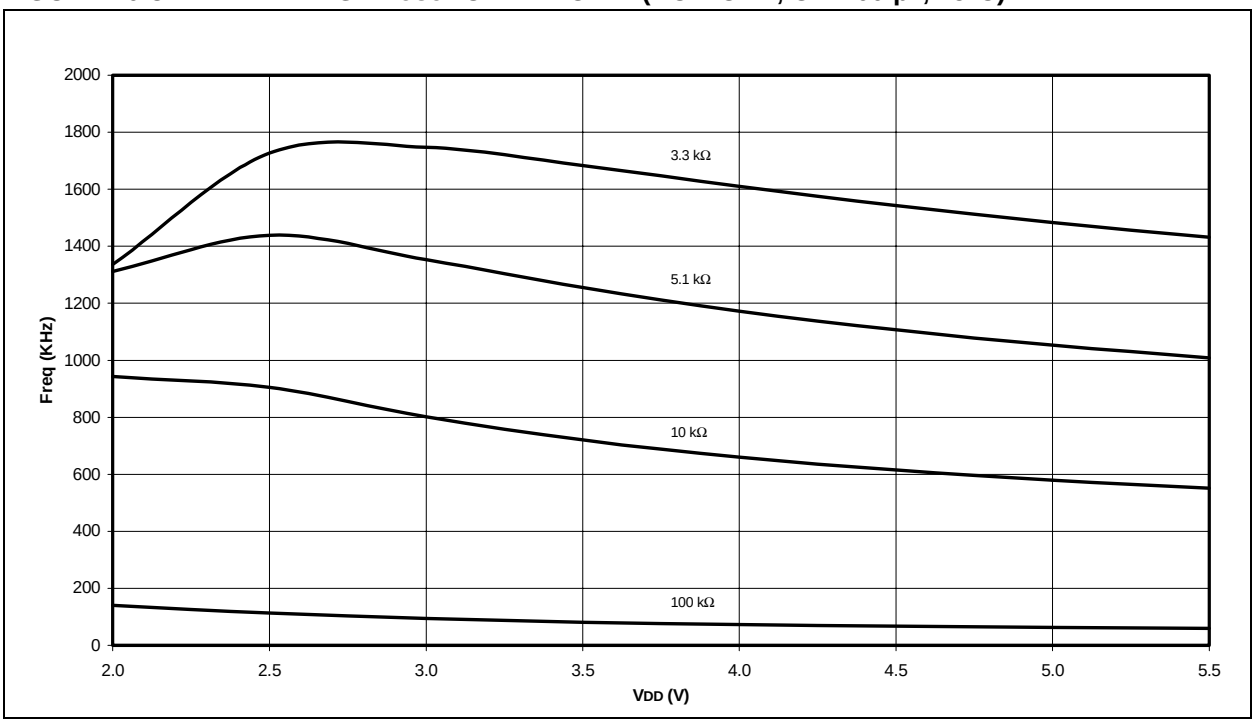


FIGURE 10-9: AVERAGE FOSC vs. VDD FOR R (RC MODE, C = 300 pF, 25°C)

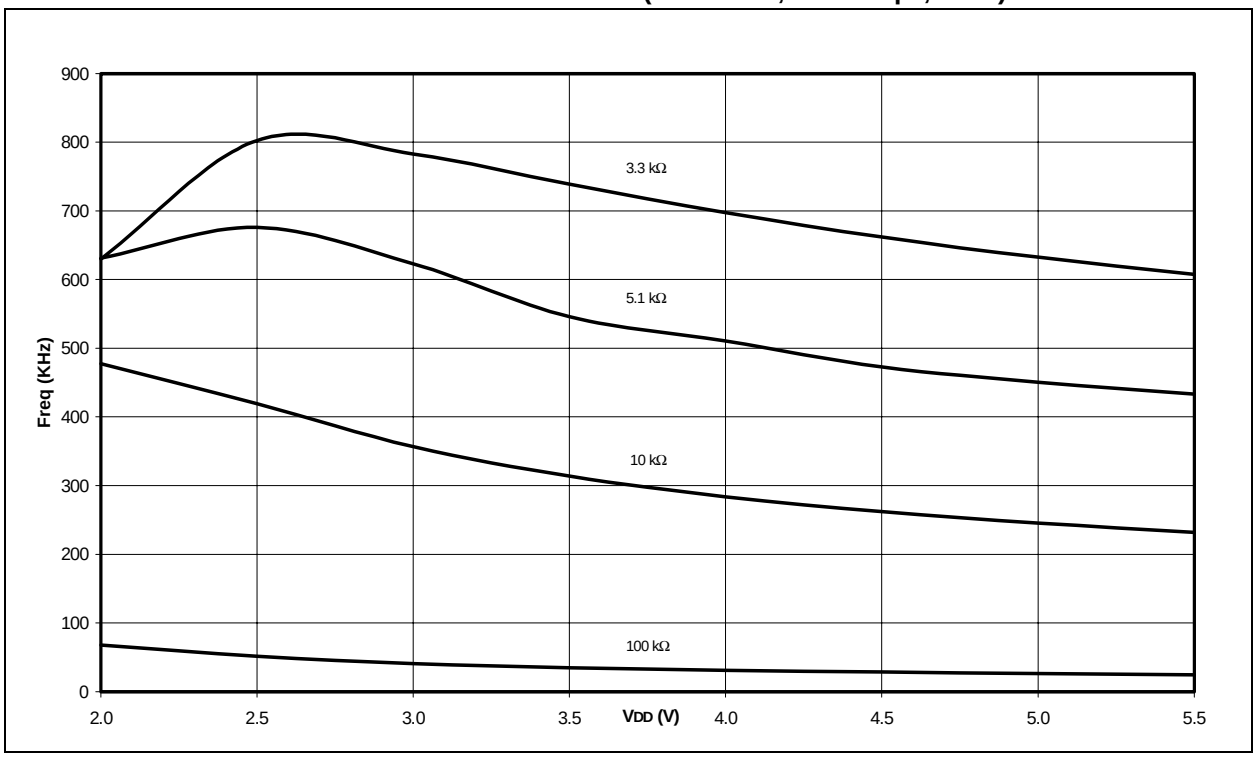


FIGURE 10-10: IPD vs. VDD (SLEEP MODE, ALL PERIPHERALS DISABLED)

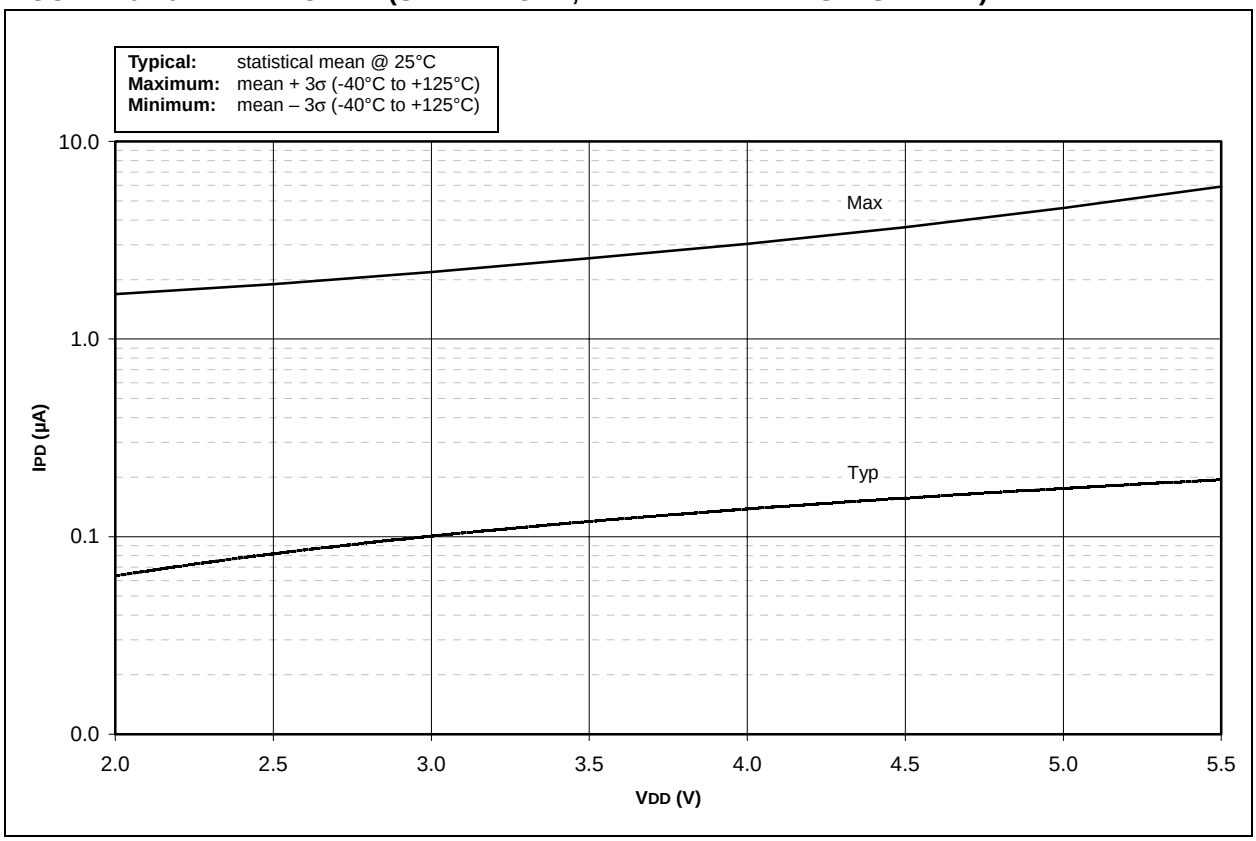


FIGURE 10-11: IPD vs. VDD (WDT MODE)

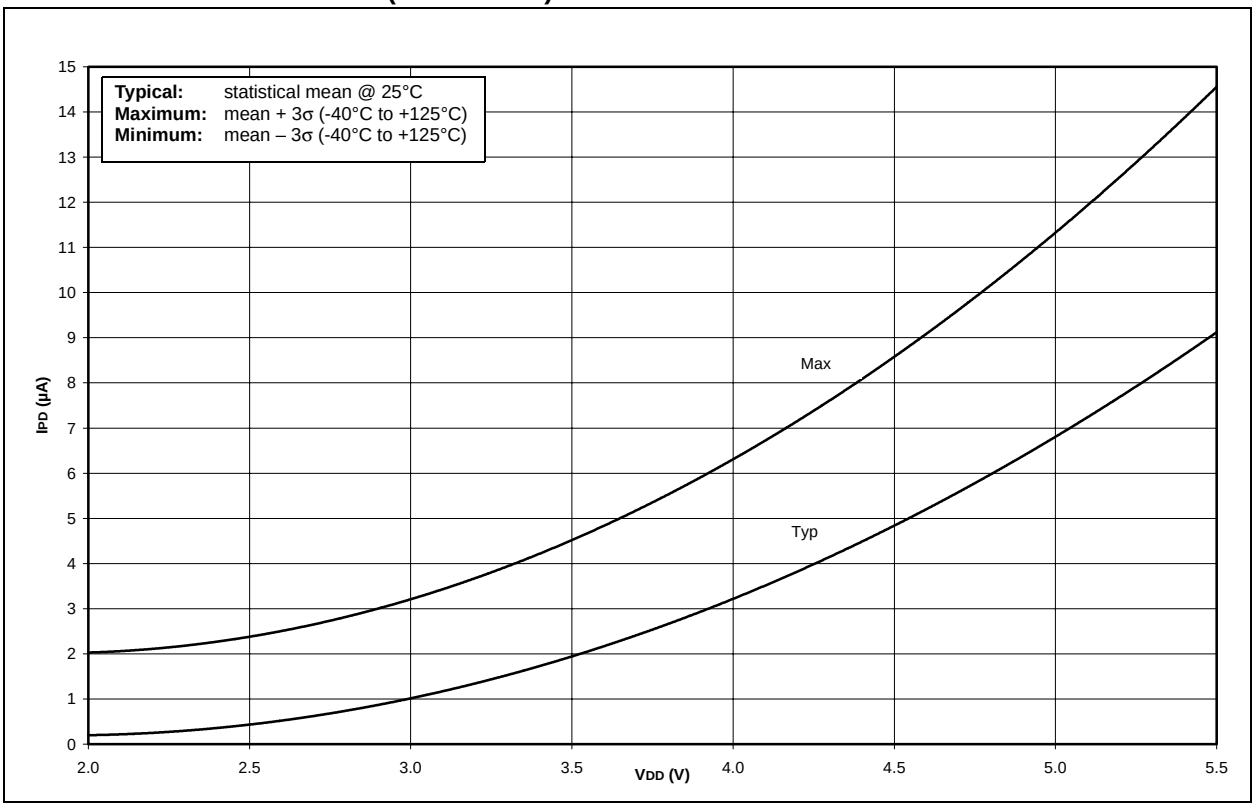


FIGURE 10-12: TYPICAL, MINIMUM, AND MAXIMUM WDT PERIOD vs. VDD OVER TEMP

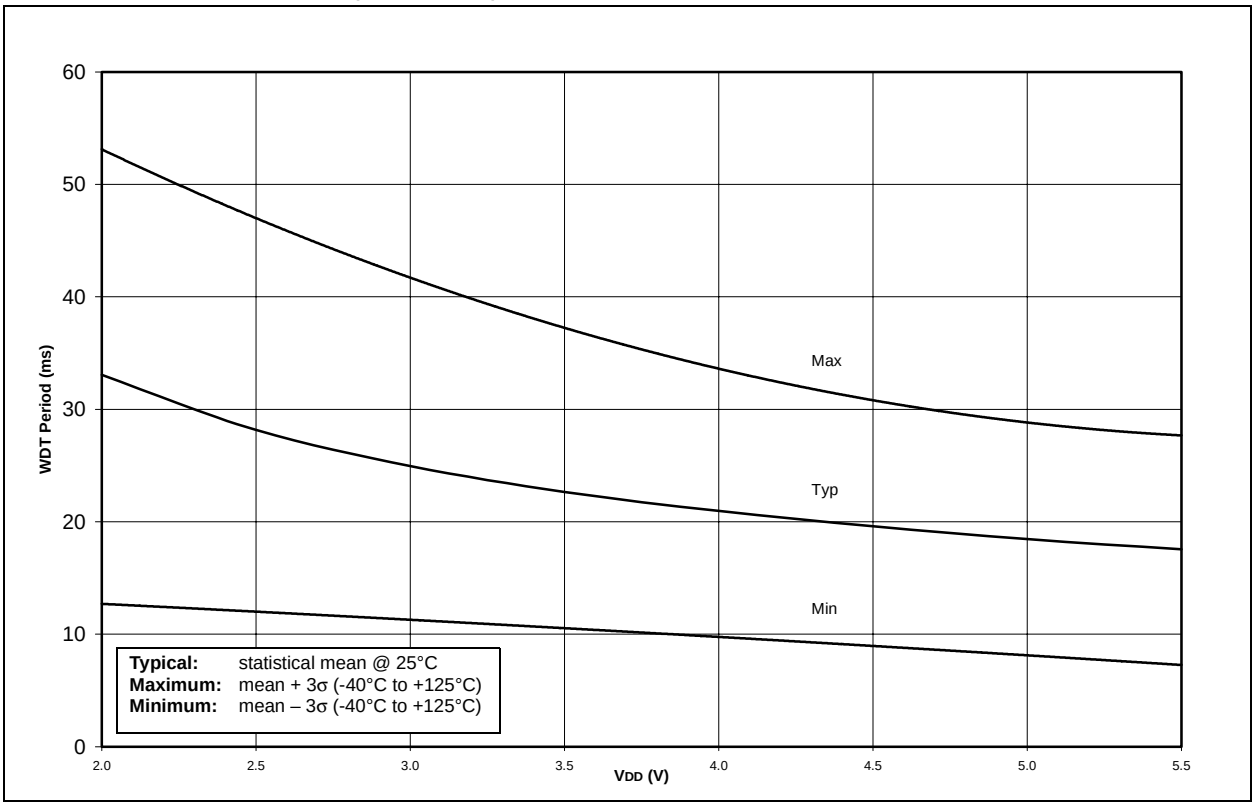


FIGURE 10-13: TYPICAL, MINIMUM AND MAXIMUM V_{OH} vs. I_{OH} (V_{DD} = 5V, -40°C TO +125°C)

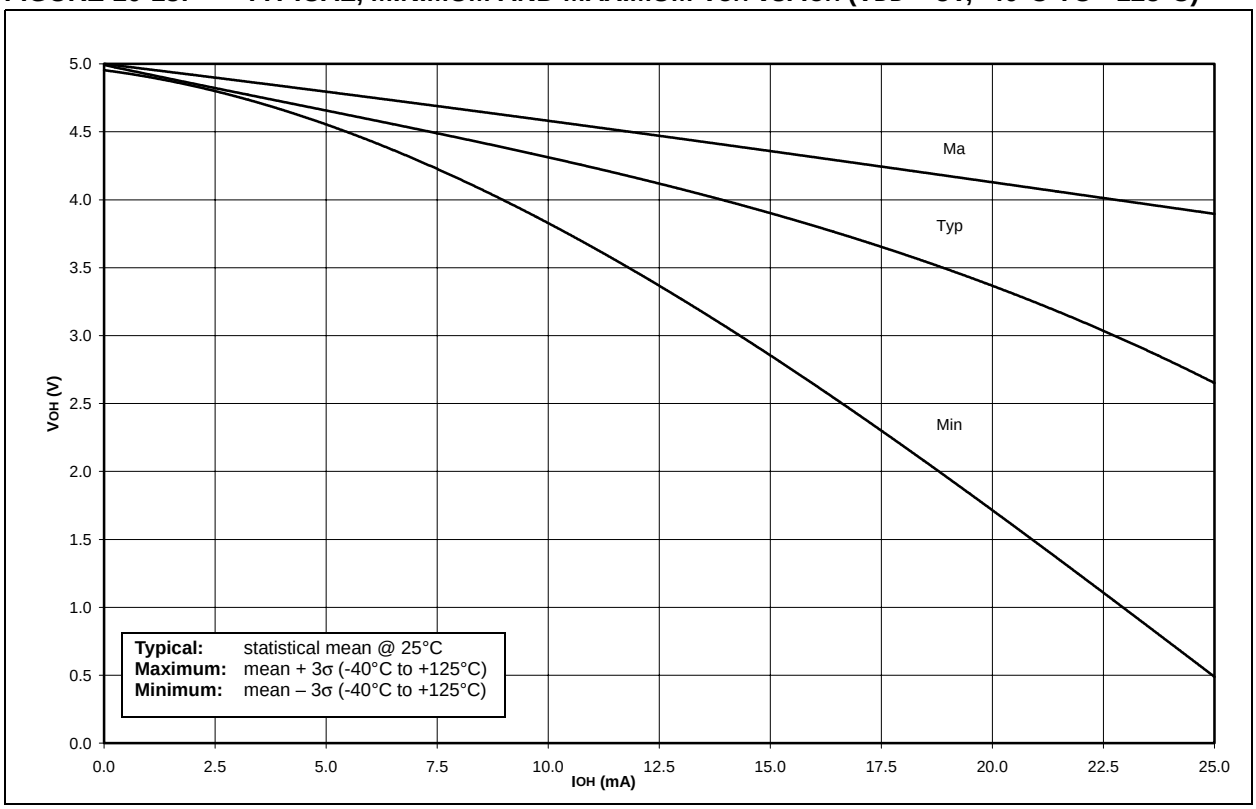


FIGURE 10-14: TYPICAL, MINIMUM AND MAXIMUM V_{OH} vs. I_{OH} (V_{DD} = 3V, -40°C TO +125°C)

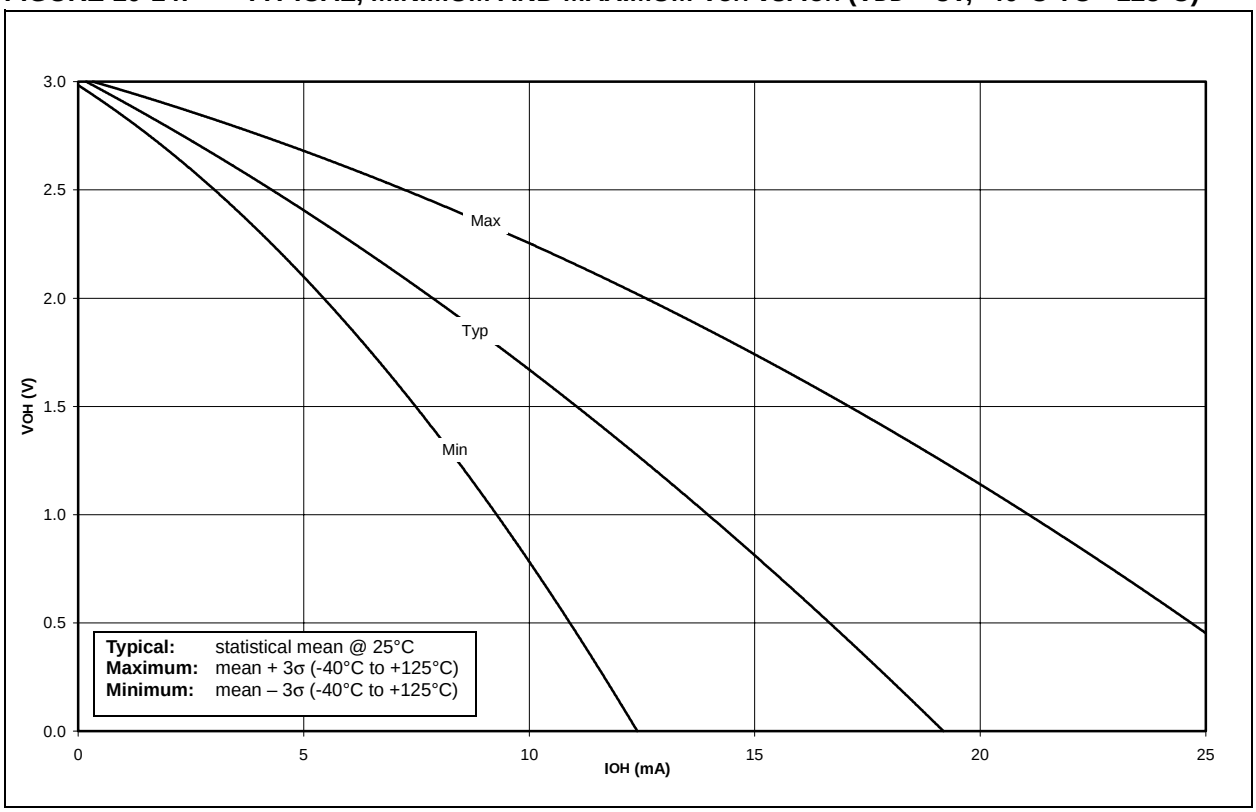


FIGURE 10-15: TYPICAL, MINIMUM AND MAXIMUM V_{OL} vs. I_{OL} (V_{DD} = 5V, -40°C TO +125°C)

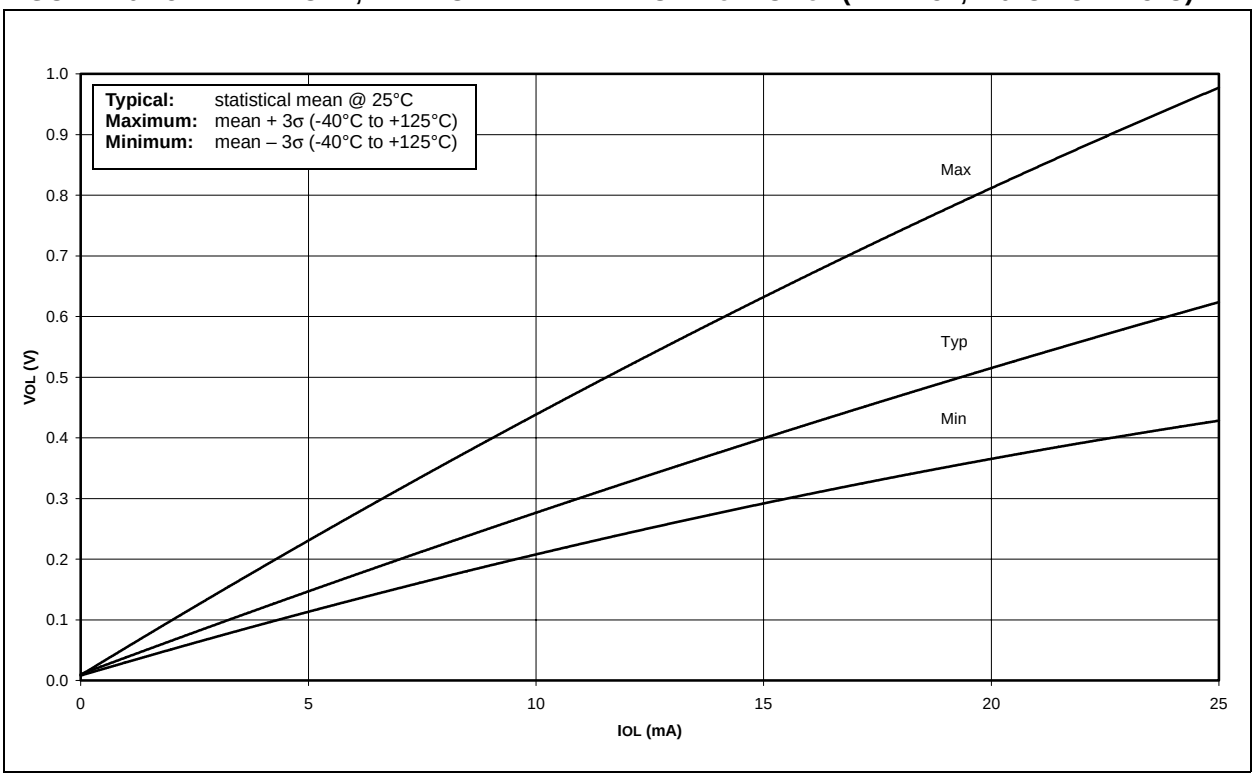


FIGURE 10-16: TYPICAL, MINIMUM AND MAXIMUM V_{OL} vs. I_{OL} (V_{DD} = 3V, -40°C TO +125°C)

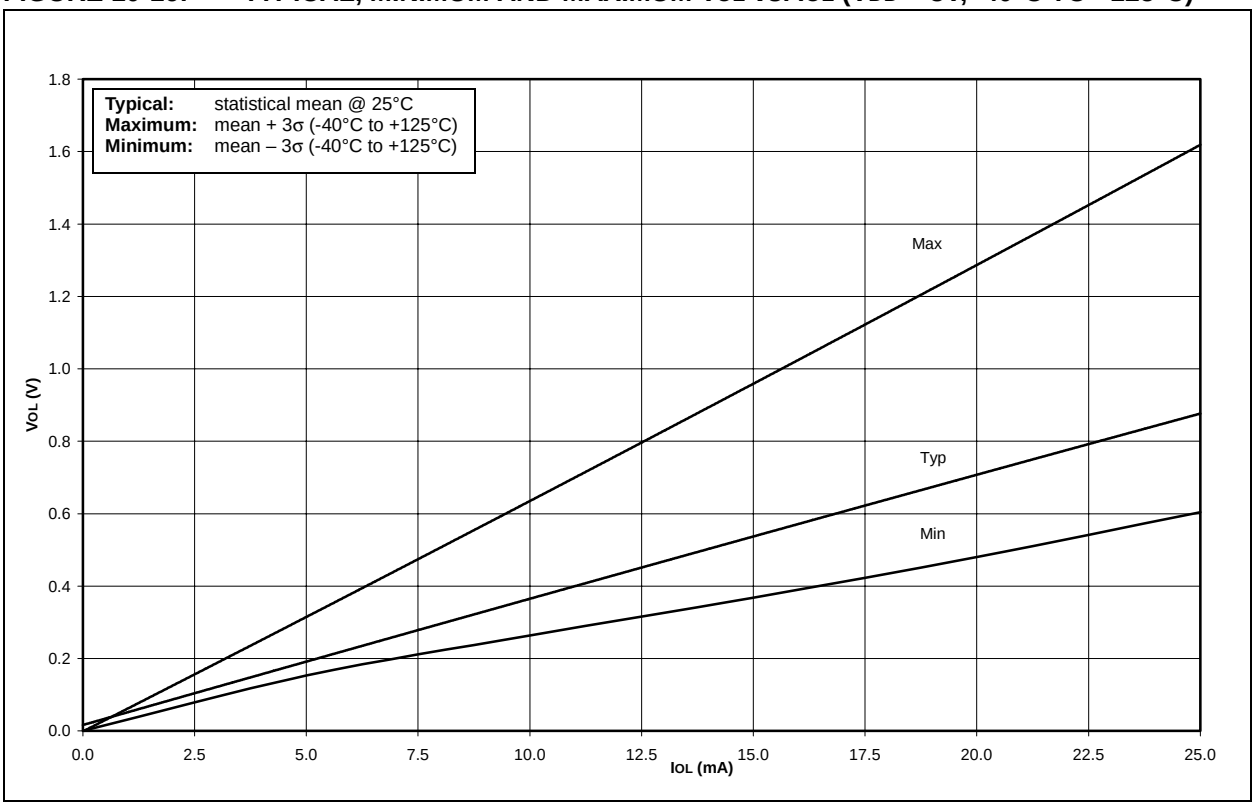


FIGURE 10-17: MINIMUM AND MAXIMUM VIN vs. VDD, (TTL INPUT, -40°C TO +125°C)

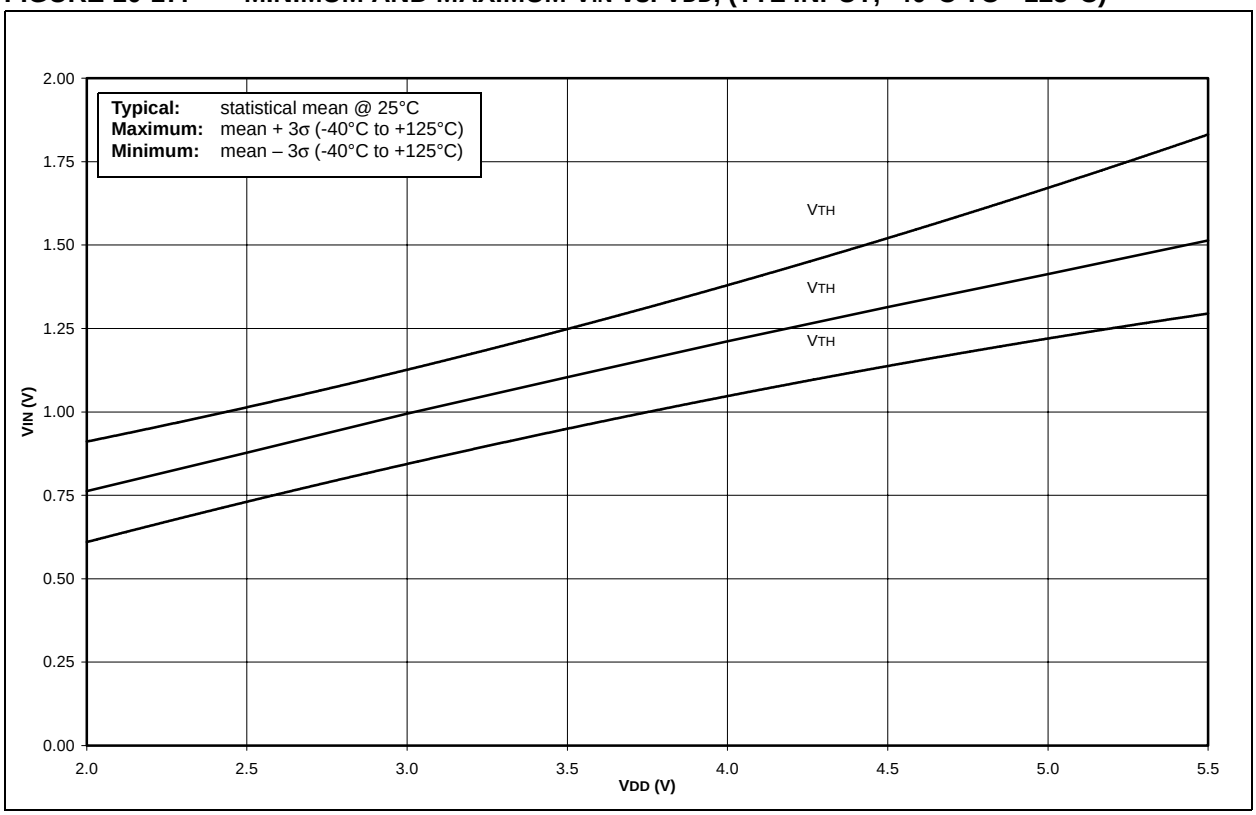
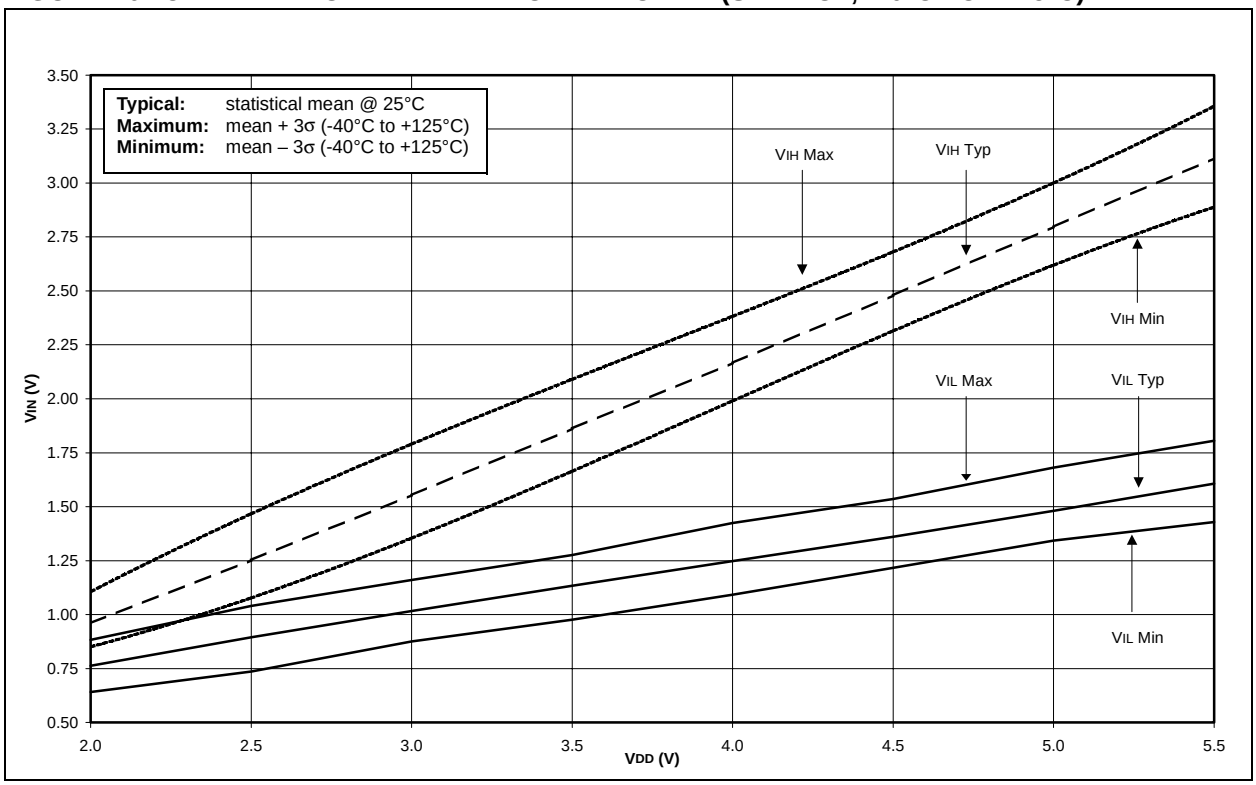


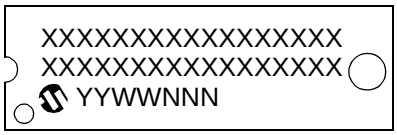
FIGURE 10-18: MINIMUM AND MAXIMUM VIN vs. VDD (ST INPUT, -40°C TO +125°C)



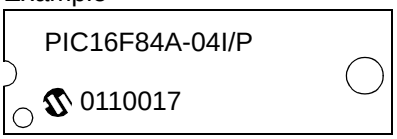
11.0 PACKAGING INFORMATION

11.1 Package Marking Information

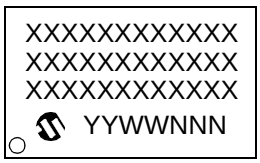
18-Lead PDIP



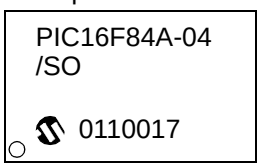
Example



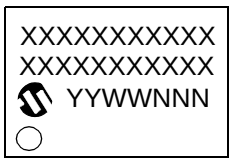
18-Lead SOIC



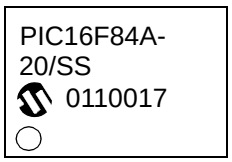
Example



20-Lead SSOP



Example

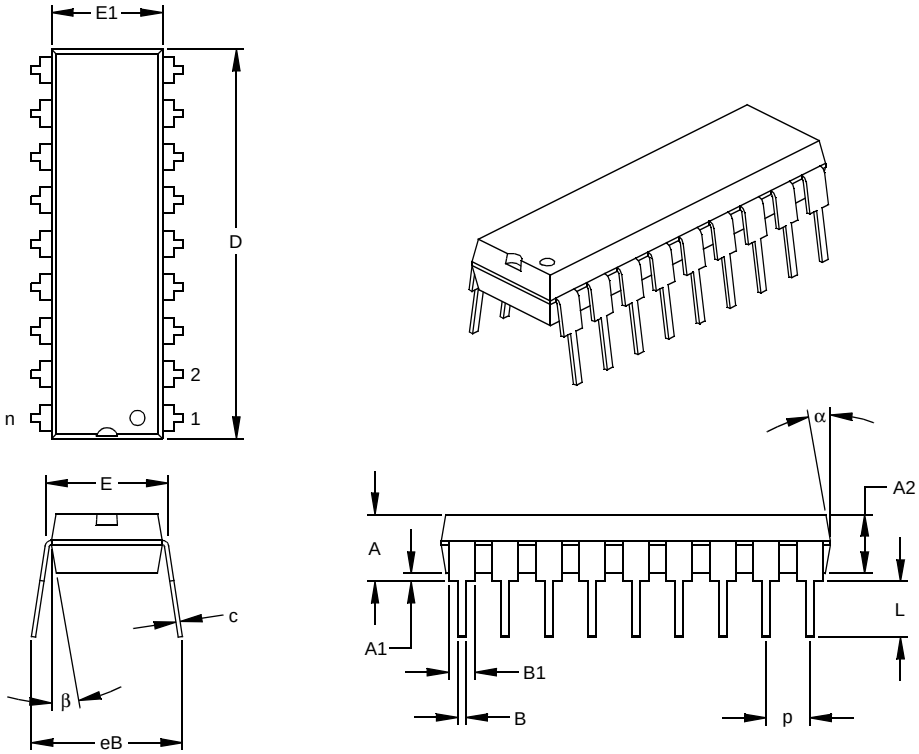


Legend:	XX...X	Customer specific information*
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

***** Standard PICmicro device marking consists of Microchip part number, year code, week code, and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip sales office. For QTP devices, any special marking adders are included in QTP price.

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

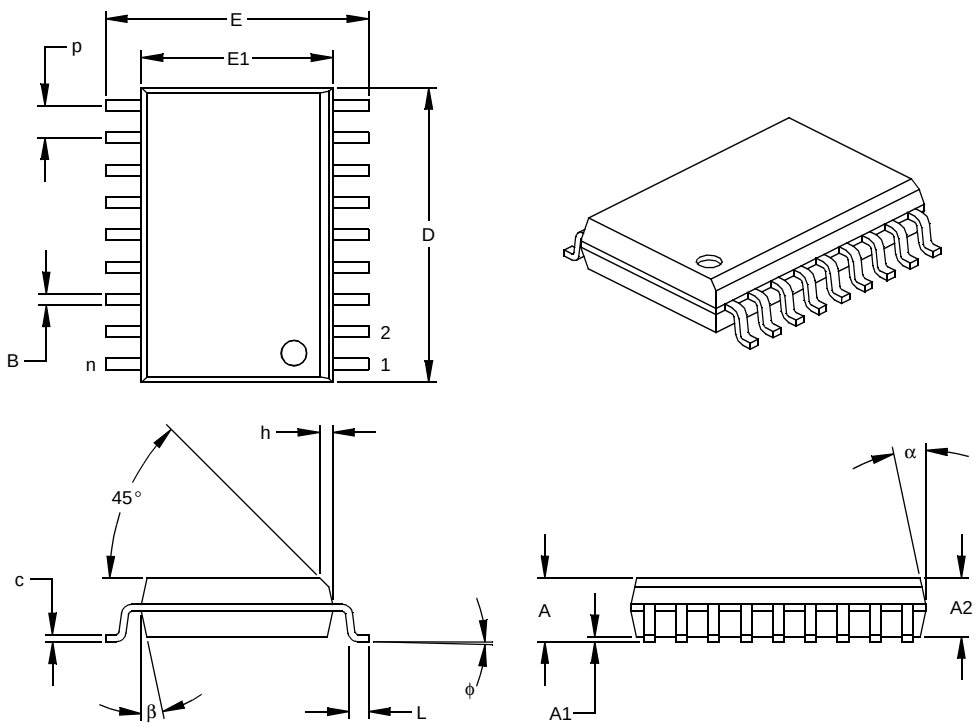


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-007

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

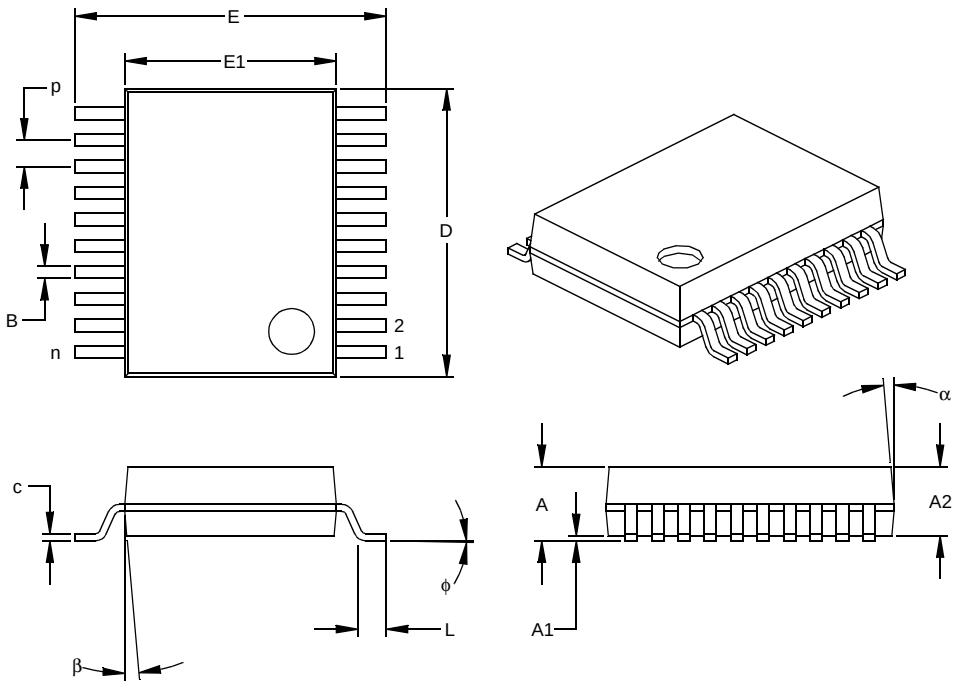


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	ϕ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-150
Drawing No. C04-072

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	9/98	This is a new data sheet. However, the devices described in this data sheet are the upgrades to the devices found in the *PIC16F8X Data Sheet*, DS30430.
B	8/01	Added DC and AC Characteristics Graphs and Tables to Section 10.

APPENDIX B: CONVERSION CONSIDERATIONS

Considerations for converting from one PIC16X8X device to another are listed in Table 1.

TABLE 1: CONVERSION CONSIDERATIONS - PIC16C84, PIC16F83/F84, PIC16CR83/CR84, PIC16F84A

Difference	PIC16C84	PIC16F83/F84	PIC16CR83/ CR84	PIC16F84A
Program Memory Size	1K x 14	512 x 14 / 1K x 14	512 x 14 / 1K x 14	1K x 14
Data Memory Size	36 x 8	36 x 8 / 68 x 8	36 x 8 / 68 x 8	68 x 8
Voltage Range	2.0V - 6.0V (-40°C to +85°C)	2.0V - 6.0V (-40°C to +85°C)	2.0V - 6.0V (-40°C to +85°C)	2.0V - 5.5V (-40°C to +125°C)
Maximum Operating Frequency	10 MHz	10 MHz	10 MHz	20 MHz
Supply Current (I_{DD}). See parameter # D014 in the electrical specs for more detail.	I_{DD} (typ) = 60 µA I_{DD} (max) = 400 µA (LP osc, F_{OSC} = 32 kHz, V_{DD} = 2.0V, WDT disabled)	I_{DD} (typ) = 15 µA I_{DD} (max) = 45 µA (LP osc, F_{OSC} = 32 kHz, V_{DD} = 2.0V, WDT disabled)	I_{DD} (typ) = 15 µA I_{DD} (max) = 45 µA (LP osc, F_{OSC} = 32 kHz, V_{DD} = 2.0V, WDT disabled)	I_{DD} (typ) = 15 µA I_{DD} (max) = 45 µA (LP osc, F_{OSC} = 32 kHz, V_{DD} = 2.0V, WDT disabled)
Power-down Current (I_{PD}). See parameters # D020, D021, and D021A in the electrical specs for more detail.	I_{PD} (typ) = 26 µA I_{PD} (max) = 100 µA (V_{DD} = 2.0V, WDT disabled, industrial)	I_{PD} (typ) = 0.4 µA I_{PD} (max) = 9 µA (V_{DD} = 2.0V, WDT disabled, industrial)	I_{PD} (typ) = 0.4 µA I_{PD} (max) = 6 µA (V_{DD} = 2.0V, WDT disabled, industrial)	I_{PD} (typ) = 0.4 µA I_{PD} (max) = 1 µA (V_{DD} = 2.0V, WDT disabled, industrial)
Input Low Voltage (V_{IL}). See parameters # D032 and D034 in the electrical specs for more detail.	V_{IL} (max) = 0.2V_{DD} (OSC1, RC mode)	V_{IL} (max) = 0.1V_{DD} (OSC1, RC mode)	V_{IL} (max) = 0.1V_{DD} (OSC1, RC mode)	V_{IL} (max) = 0.1V_{DD} (OSC1, RC mode)
Input High Voltage (V_{IH}). See parameter # D040 in the electrical specs for more detail.	V_{IH} (min) = 0.36V_{DD} (I/O Ports with TTL, 4.5V ≤ V_{DD} ≤ 5.5V)	V_{IH} (min) = 2.4V (I/O Ports with TTL, 4.5V ≤ V_{DD} ≤ 5.5V)	V_{IH} (min) = 2.4V (I/O Ports with TTL, 4.5V ≤ V_{DD} ≤ 5.5V)	V_{IH} (min) = 2.4V (I/O Ports with TTL, 4.5V ≤ V_{DD} ≤ 5.5V)
Data EEPROM Memory Erase/Write cycle time (T_{DEW}). See parameter # D122 in the electrical specs for more detail.	T_{DEW} (typ) = 10 ms T_{DEW} (max) = 20 ms	T_{DEW} (typ) = 10 ms T_{DEW} (max) = 20 ms	T_{DEW} (typ) = 10 ms T_{DEW} (max) = 20 ms	T_{DEW} (typ) = 4 ms T_{DEW} (max) = 8 ms
Port Output Rise/Fall time (TioR, TioF). See parameters #20, 20A, 21, and 21A in the electrical specs for more detail.	TioR, TioF (max) = 25 ns (C84) TioR, TioF (max) = 60 ns (LC84)	TioR, TioF (max) = 35 ns (C84) TioR, TioF (max) = 70 ns (LC84)	TioR, TioF (max) = 35 ns (C84) TioR, TioF (max) = 70 ns (LC84)	TioR, TioF (max) = 35 ns (C84) TioR, TioF (max) = 70 ns (LC84)
$\overline{MCLR}$ on-chip filter. See parameter #30 in the electrical specs for more detail.	No	Yes	Yes	Yes
PORTA and crystal oscillator values less than 500 kHz	For crystal oscillator configurations operating below 500 kHz, the device may generate a spurious internal Q-clock when PORTA<0> switches state.	N/A	N/A	N/A
RB0/INT pin	TTL	TTL/ST* (*Schmitt Trigger)	TTL/ST* (*Schmitt Trigger)	TTL/ST* (*Schmitt Trigger)

TABLE 1: CONVERSION CONSIDERATIONS - PIC16C84, PIC16F83/F84, PIC16CR83/CR84, PIC16F84A (CONTINUED)

Difference	PIC16C84	PIC16F83/F84	PIC16CR83/ CR84	PIC16F84A
EEADR<7:6> and IDD	It is recommended that the EEADR<7:6> bits be cleared. When either of these bits is set, the maximum IDD for the device is higher than when both are cleared.	N/A	N/A	N/A
The polarity of the $\overline{\text{PWRTE}}$ bit	PWRTE	$\overline{\text{PWRTE}}$	$\overline{\text{PWRTE}}$	$\overline{\text{PWRTE}}$
Recommended value of REXT for RC oscillator circuits	REXT = 3kΩ - 100kΩ	REXT = 5kΩ - 100kΩ	REXT = 5kΩ - 100kΩ	REXT = 3kΩ - 100kΩ
GIE bit unintentional enable	If an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the `RETFIE` instruction).	N/A	N/A	N/A
Packages	PDIP, SOIC	PDIP, SOIC	PDIP, SOIC	PDIP, SOIC, SSOP
Open Drain High Voltage (VOD)	14V	12V	12V	8.5V

APPENDIX C: MIGRATION FROM BASELINE TO MID-RANGE DEVICES

This section discusses how to migrate from a baseline device (i.e., PIC16C5X) to a mid-range device (i.e., PIC16CXXX).

The following is the list of feature improvements over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes, both in program memory (2K now as opposed to 512K before) and the register file (128 bytes now versus 32 bytes before).
2. A PC latch register (PCLATH) is added to handle program memory paging. PA2, PA1 and PA0 bits are removed from the STATUS register and placed in the OPTION register.
3. Data memory paging is redefined slightly. The STATUS register is modified.
4. Four new instructions have been added: `RETURN`, `RETFIE`, `ADDLW`, and `SUBLW`. Two instructions, `TRIS` and `OPTION`, are being phased out, although they are kept for compatibility with PIC16C5X.
5. OPTION and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to eight-deep.
8. RESET vector is changed to 0000h.
9. RESET of all registers is revisited. Five different RESET (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from SLEEP through interrupt is added.
11. Two separate timers, the Oscillator Start-up Timer (OST) and Power-up Timer (PWRT), are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt-on-change features.
13. T0CKI pin is also a port pin (RA4/T0CKI).
14. FSR is a full 8-bit register.
15. "In system programming" is made possible. The user can program PIC16CXX devices using only five pins: V_{DD}, V_{SS}, V_{PP}, RB6 (clock) and RB7 (data in/out).

To convert code written for PIC16C5X to PIC16F84A, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for `CALL`, `GOTO`.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables for reallocation.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change RESET vector to 0000h.

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PIC16F84A PRODUCT IDENTIFICATION SYSTEM

To order or obtain information (e.g., on pricing or delivery) refer to the factory or the listed sales office.

PART NO.	-XX	X	/XX	XXX
Device	Frequency Range	Temperature Range	Package	Pattern

Device	PIC16F84A(1), PIC16F84AT(2) PIC16LF84A(1), PIC16LF84AT(2)
Frequency Range	04 = 4 MHz 20 = 20 MHz
Temperature Range	- = 0°C to +70°C I = -40°C to +85°C
Package	P = PDIP SO = SOIC (Gull Wing, 300 mil body) SS = SSOP
Pattern	QTP, SQTP, ROM Code (factory specified) or Special Requirements . Blank for OTP and Windowed devices.

Examples:

a) PIC16F84A -04/P 301 = Commercial temp., PDIP package, 4 MHz, normal VDD limits, QTP pattern #301.

b) PIC16LF84A - 04I/SO = Industrial temp., SOIC package, 200 kHz, Extended VDD limits.

c) PIC16F84A - 20I/P = Industrial temp., PDIP package, 20 MHz, normal VDD limits.

Note 1: F = Standard VDD range
LF = Extended VDD range
2: T = in tape and reel - SOIC and SSOP packages only.

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08/01/01

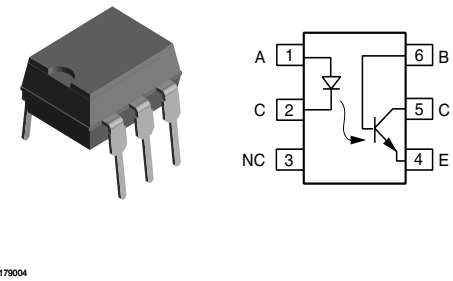
Optocoupler, Phototransistor Output, With Base Connection

Features

- Isolation Test Voltage 5300 V_{RMS}
- Interfaces with Common Logic Families
- Input-output Coupling Capacitance < 0.5 pF
- Industry Standard Dual-in-line 6-pin Package

Agency Approvals

- UL File #E52744 System Code H or J
- DIN EN 60747-5-2(VDE0884)
  DIN EN 60747-5-5 pending
  Available with Option 1



i179004

Applications

AC Mains Detection

Reed relay driving

Switch Mode Power Supply Feedback

Telephone Ring Detection

Logic Ground Isolation

Logic Coupling with High Frequency Noise Rejection

Description

The 4N25 family is an Industry Standard Single Channel Phototransistor Coupler.This family includes the 4N25/ 4N26/ 4N27/ 4N28. Each optocoupler consists of gallium arsenide infrared LED and a silicon NPN phototransistor.

These couplers are Underwriters Laboratories (UL) listed to comply with a 5300 V_{RMS} isolation test voltage. This isolation performance is accomplished through special Vishay manufacturing process.

Compliance to DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-5-5 pending partial discharge isolation specification is available by ordering option1.

These isolation processes and the Vishay ISO9001 quality program results in the highest isolation performance available for a commercial plastic phototransistor optocoupler.

The devices are also available in lead formed configuration suitable for surface mounting and are available either on tape and reel, or in standard tube shipping containers.

Note:

For additional design information see Application Note 45 Normalized Curves

Order Information

Part	Remarks
4N25	CTR > 20 %, DIP-6
4N26	CTR > 20 %, DIP-6
4N27	CTR > 10 %, DIP-6
4N28	CTR > 10 %, DIP-6
4N25-X006	CTR > 20 %, DIP-6 400 mil (option 6)
4N25-X007	CTR > 20 %, SMD-6 (option 7)
4N25-X009	CTR > 20 %, SMD-6 (option 9)
4N26-X006	CTR > 20 %, DIP-6 400 mil (option 6)
4N26-X007	CTR > 20 %, SMD-6 (option 7)
4N26-X009	CTR > 20 %, SMD-6 (option 9)
4N27-X007	CTR > 10 %, SMD-6 (option 7)
4N27-X009	CTR > 10 %, SMD-6 (option 9)
4N28-X009	CTR > 10 %, SMD-6 (option 9)

For additional information on the available options refer to Option Information.

Absolute Maximum Ratings

T_{amb} = 25 °C, unless otherwise specified

Stresses in excess of the absolute Maximum Ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute Maximum Rating for extended periods of the time can adversely affect reliability.

Input

Parameter	Test condition	Symbol	Value	Unit
Reverse voltage		V_R	6.0	V
Forward current		I_F	60	mA
Surge current	t < 10 µs	I_{FSM}	2.5	A
Power dissipation		P_{diss}	100	mW

Output

Parameter	Test condition	Symbol	Value	Unit
Collector-emitter breakdown voltage		V_{CEO}	70	V
Emitter-base breakdown voltage		V_{EBO}	7.0	V
Collector current		I_C	50	mA
Collector currrent	t < 1.0 ms	I_C	100	mA
Power dissipation		P_{diss}	150	mW

Coupler

Parameter	Test condition	Symbol	Value	Unit
Isolation test voltage		V_{ISO}	5300	V_{RMS}
Creepage			≥ 7.0	mm
Clearance			≥ 7.0	mm
Isolation thickness between emitter and detector			≥ 0.4	mm
Comparative tracking index	DIN IEC 112/VDE0303, part 1		175	
Isolation resistance	V_{IO} = 500 V, T_{amb} = 25 °C	R_{IO}	10^{12}	Ω
	V_{IO} = 500 V, T_{amb} = 100 °C	R_{IO}	10^{11}	Ω
Storage temperature		T_{stg}	- 55 to + 150	°C
Operating temperature		T_{amb}	- 55 to + 100	°C
Junction temperature		T_j	100	°C
Soldering temperature	max.10 s, dip soldering: distance to seating plane ≥ 1.5 mm	T_{sld}	260	°C

Electrical Characteristics

T_{amb} = 25 °C, unless otherwise specified
Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

Input

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward voltage[1)]	I_F = 50 mA	V_F		1.3	1.5	V
Reverse current[1)]	V_R = 3.0 V	I_R		0.1	100	µA
Capacitance	V_R = 0 V	C_O		25		pF

1) Indicates JEDEC registered values

Output

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
Collector-base breakdown voltage[1)]	I_C = 100 µA		BV_{CBO}	70			V
Collector-emitter breakdown voltage[1)]	I_C = 1.0 mA		BV_{CEO}	30			V
Emitter-collector breakdown voltage[1)]	I_E = 100 µA		BV_{ECO}	7.0			V
I_{CEO}(dark)[1)]	V_{CE} = 10 V, (base open)	4N25			5.0	50	nA
		4N26			5.0	50	nA
		4N27			5.0	50	nA
		4N28			10	100	nA
I_{CBO}(dark)[1)]	V_{CB} = 10 V, (emitter open)				2.0	20	nA
Collector-emitter capacitance	V_{CE} = 0		C_{CE}		6.0		pF

1) Indicates JEDEC registered values

Coupler

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
Isolation voltage[1)]	Peak, 60 Hz	4N25	V_{IO}	2500			V
		4N26	V_{IO}	1500			V
		4N27	V_{IO}	1500			V
		4N28	V_{IO}	500			V
Saturation voltage, collector-emitter	I_{CE} = 2.0 mA, I_F = 50 mA		$V_{CE(sat)}$			0.5	V
Resistance, input output[1)]	V_{IO} = 500 V		R_{IO}	100			GΩ
Capacitance (input-output)	f = 1.0 MHz		C_{IO}		0.5		pF

1) Indicates JEDEC registered values

Current Transfer Ratio

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
DC Current Transfer Ratio[1)]	V_{CE} = 10 V, I_F = 10 mA	4N25	CTR_{DC}	20	50		%
		4N26	CTR_{DC}	20	50		%
		4N27	CTR_{DC}	10	30		%
		4N28	CTR_{DC}	10	30		%

1) Indicates JEDEC registered value

Switching Characteristics

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Rise and fall times	V_{CE} = 10 V, I_F = 10 mA, R_L = 100 Ω	t_r, t_f		2.0		µs

Typical Characteristics (T_{amb} = 25 °C unless otherwise specified)

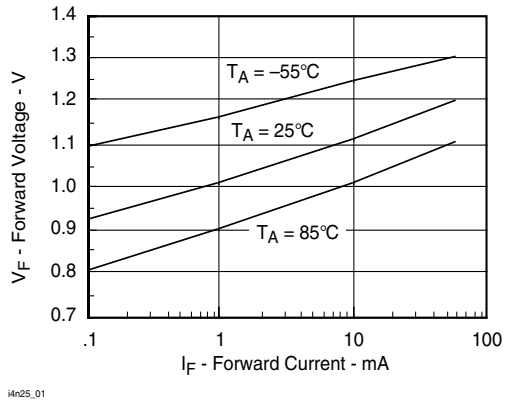


Fig. 1 Forward Voltage vs. Forward Current

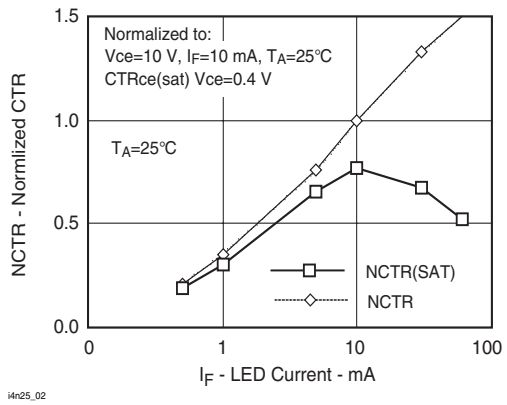


Fig. 2 Normalized Non-Saturated and Saturated CTR vs. LED Current

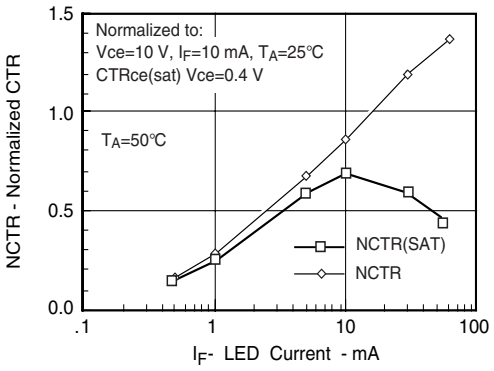


Fig. 3 Normalized Non-saturated and Saturated CTR vs. LED Current

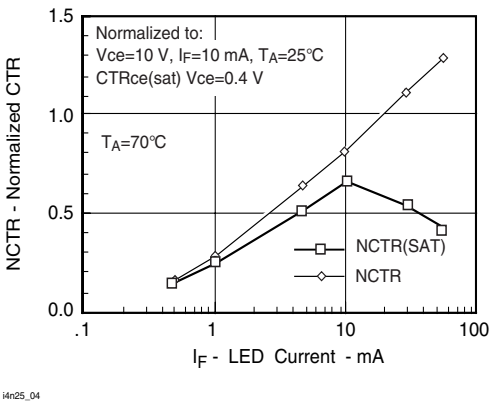


Fig. 4 Normalized Non-saturated and saturated CTR vs. LED Current

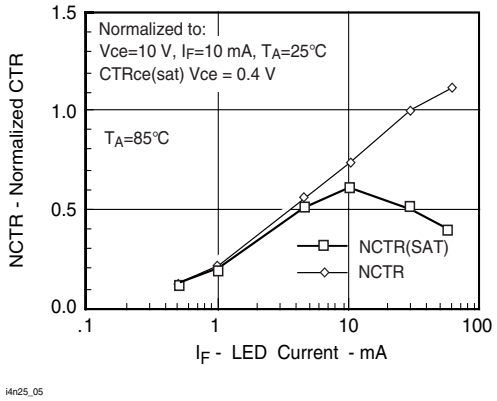


Fig. 5 Normalized Non-saturated and saturated CTR vs. LED Current

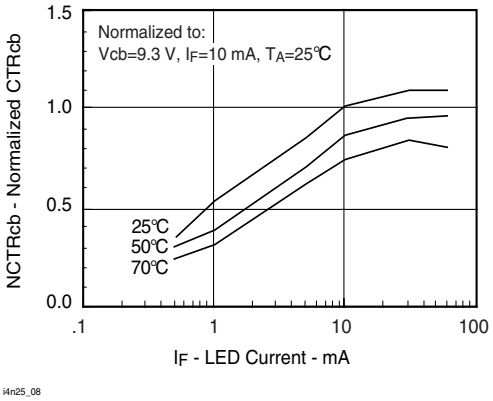


Fig. 8 Normalized CTRcb vs. LED Current and Temp.

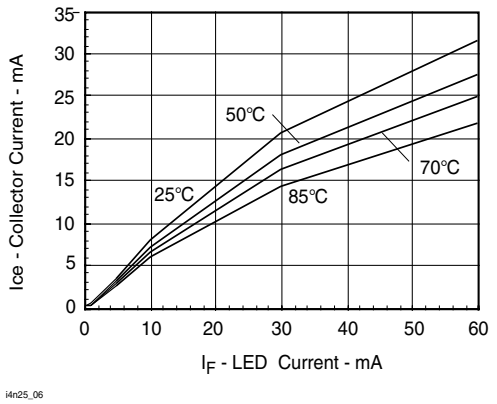


Fig. 6 Collector-Emitter Current vs. Temperature and LED Current

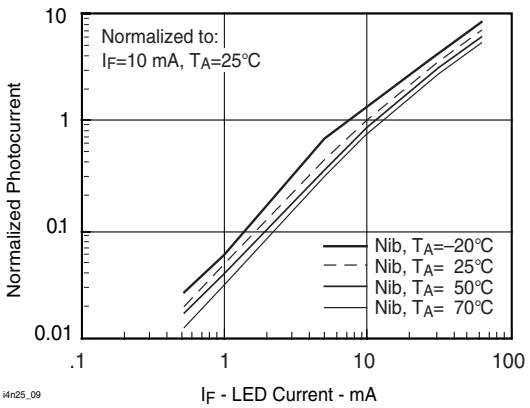


Fig. 9 Normalized Photocurrent vs. I_F and Temp.

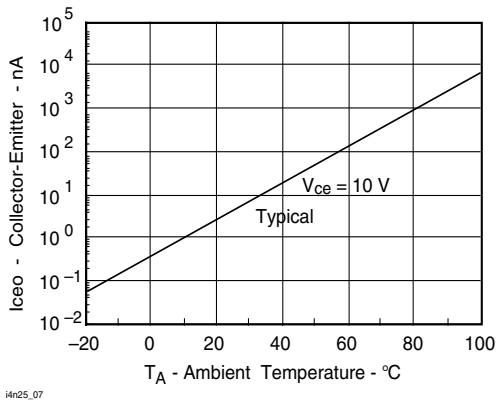


Fig. 7 Collector-Emitter Leakage Current vs.Temp.

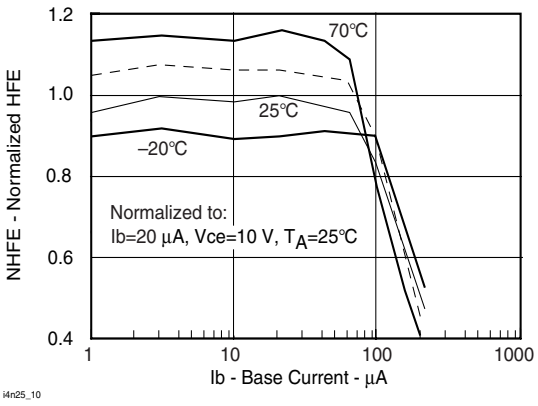


Fig. 10 Normalized Non-saturated HFE vs. Base Current and Temperature

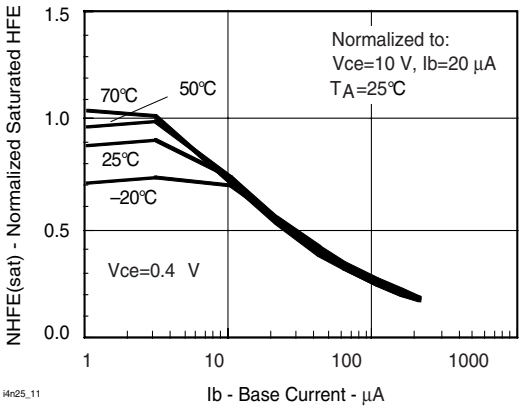


Fig. 11 Normalized HFE vs. Base Current and Temp.

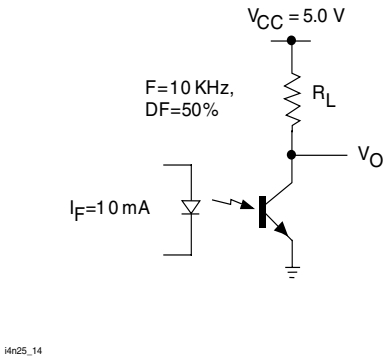


Fig. 14 Switching Schematic

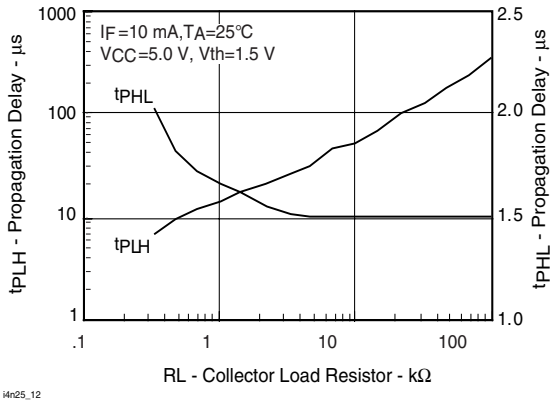


Fig. 12 Propagation Delay vs. Collector Load Resistor

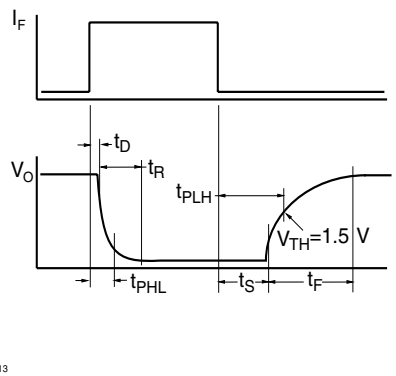
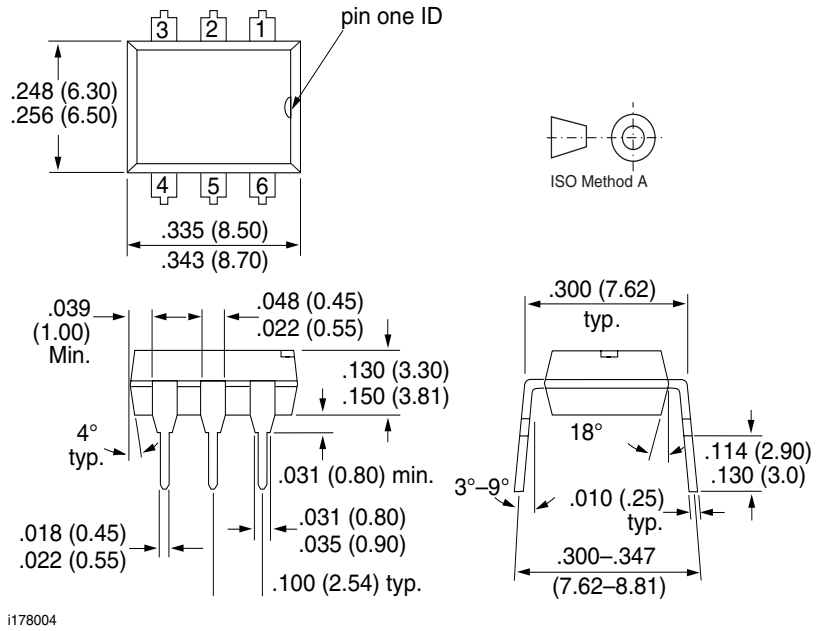
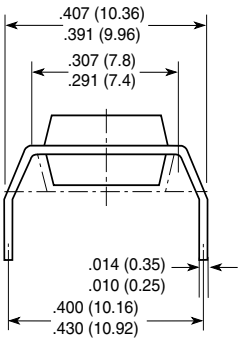


Fig. 13 Switching Timing

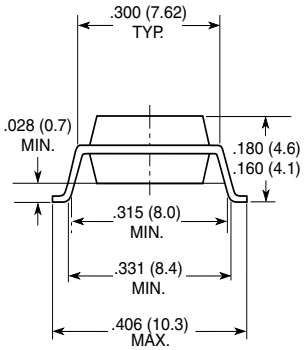
Package Dimensions in Inches (mm)



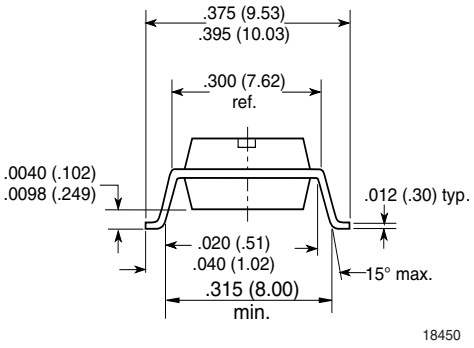
Option 6



Option 7



Option 9



Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operatingsystems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany
Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

Low Cost, Low Power Instrumentation Amplifier

AD620

FEATURES
EASY TO USE
Gain Set with One External Resistor
(Gain Range 1 to 1000)
Wide Power Supply Range (±2.3 V to ±18 V)
Higher Performance than Three Op Amp IA Designs
Available in 8-Lead DIP and SOIC Packaging
Low Power, 1.3 mA max Supply Current

EXCELLENT DC PERFORMANCE ("B GRADE")
50 μV max, Input Offset Voltage
0.6 μV/°C max, Input Offset Drift
1.0 nA max, Input Bias Current
100 dB min Common-Mode Rejection Ratio (G = 10)

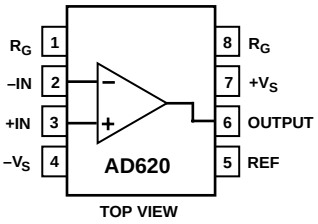
LOW NOISE
9 nV/√Hz, @ 1 kHz, Input Voltage Noise
0.28 μV p-p Noise (0.1 Hz to 10 Hz)

EXCELLENT AC SPECIFICATIONS
120 kHz Bandwidth (G = 100)
15 μs Settling Time to 0.01%

APPLICATIONS
Weigh Scales
ECG and Medical Instrumentation
Transducer Interface
Data Acquisition Systems
Industrial Process Controls
Battery Powered and Portable Equipment

CONNECTION DIAGRAM

8-Lead Plastic Mini-DIP (N), Cerdip (Q) and SOIC (R) Packages



TOP VIEW

PRODUCT DESCRIPTION

The AD620 is a low cost, high accuracy instrumentation amplifier that requires only one external resistor to set gains of 1 to 1000. Furthermore, the AD620 features 8-lead SOIC and DIP packaging that is smaller than discrete designs, and offers lower power (only 1.3 mA max supply current), making it a good fit for battery powered, portable (or remote) applications.

The AD620, with its high accuracy of 40 ppm maximum nonlinearity, low offset voltage of 50 μV max and offset drift of 0.6 μV/°C max, is ideal for use in precision data acquisition systems, such as weigh scales and transducer interfaces. Furthermore, the low noise, low input bias current, and low power of the AD620 make it well suited for medical applications such as ECG and noninvasive blood pressure monitors.

The low input bias current of 1.0 nA max is made possible with the use of Superβeta processing in the input stage. The AD620 works well as a preamplifier due to its low input voltage noise of 9 nV/√Hz at 1 kHz, 0.28 μV p-p in the 0.1 Hz to 10 Hz band, 0.1 pA/√Hz input current noise. Also, the AD620 is well suited for multiplexed applications with its settling time of 15 μs to 0.01% and its cost is low enough to enable designs with one in-amp per channel.

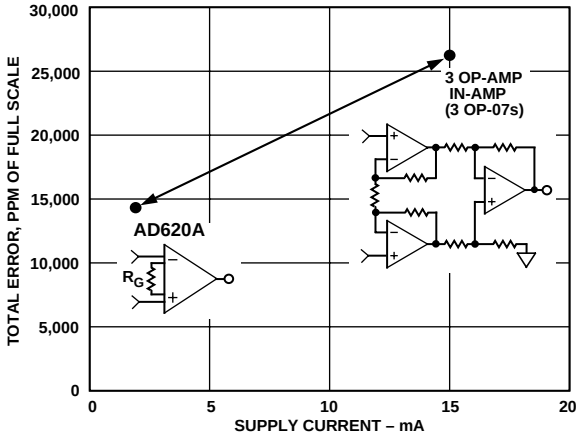


Figure 1. Three Op Amp IA Designs vs. AD620

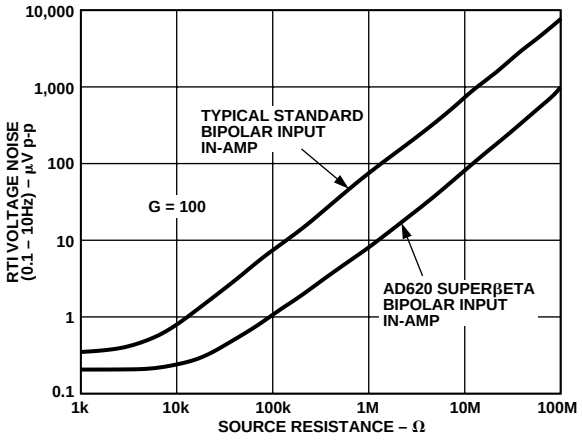


Figure 2. Total Voltage Noise vs. Source Resistance

REV. E

One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106, U.S.A.
Tel: 781/329-4700 World Wide Web Site: http://www.analog.com
Fax: 781/326-8703

AD620—SPECIFICATIONS (Typical @ +25°C, V_S = ±15 V, and R_L = 2 kΩ, unless otherwise noted)

Model	Conditions	AD620A Min	AD620A Typ	AD620A Max	AD620B Min	AD620B Typ	AD620B Max	AD620S[1] Min	AD620S[1] Typ	AD620S[1] Max	Units
GAIN	G = 1 + (49.4 k/R_G)										
Gain Range		1		10,000	1		10,000	1		10,000	
Gain Error[2]	V_{OUT} = ±10 V										
G = 1			0.03	0.10		0.01	0.02		0.03	0.10	%
G = 10			0.15	0.30		0.10	0.15		0.15	0.30	%
G = 100			0.15	0.30		0.10	0.15		0.15	0.30	%
G = 1000			0.40	0.70		0.35	0.50		0.40	0.70	%
Nonlinearity,	V_{OUT} = –10 V to +10 V,										
G = 1–1000	R_L = 10 kΩ		10	40		10	40		10	40	ppm
G = 1–100	R_L = 2 kΩ		10	95		10	95		10	95	ppm
Gain vs. Temperature											
	G =1			10			10			10	ppm/°C
	Gain >1[2]			–50			–50			–50	ppm/°C
VOLTAGE OFFSET	(Total RTI Error = V_{OSI} + V_{OSO}/G)										
Input Offset, V_{OSI}	V_S = ±5 V to ±15 V		30	125		15	50		30	125	µV
Over Temperature	V_S = ±5 V to ±15 V			185			85			225	µV
Average TC	V_S = ±5 V to ±15 V		0.3	1.0		0.1	0.6		0.3	1.0	µV/°C
Output Offset, V_{OSO}	V_S = ±15 V		400	1000		200	500		400	1000	µV
	V_S = ±5 V			1500			750			1500	µV
Over Temperature	V_S = ±5 V to ±15 V			2000			1000			2000	µV
Average TC	V_S = ±5 V to ±15 V		5.0	15		2.5	7.0		5.0	15	µV/°C
Offset Referred to the Input vs. Supply (PSR)	V_S = ±2.3 V to ±18 V										
G = 1		80	100		80	100		80	100		dB
G = 10		95	120		100	120		95	120		dB
G = 100		110	140		120	140		110	140		dB
G = 1000		110	140		120	140		110	140		dB
INPUT CURRENT											
Input Bias Current			0.5	2.0		0.5	1.0		0.5	2	nA
Over Temperature				2.5			1.5			4	nA
Average TC			3.0			3.0			8.0		pA/°C
Input Offset Current			0.3	1.0		0.3	0.5		0.3	1.0	nA
Over Temperature				1.5			0.75			2.0	nA
Average TC			1.5			1.5			8.0		pA/°C
INPUT											
Input Impedance											
Differential			10‖2			10‖2			10‖2		GΩ‖pF
Common-Mode			10‖2			10‖2			10‖2		GΩ‖pF
Input Voltage Range[3]	V_S = ±2.3 V to ±5 V	$–V_S$ + 1.9		$+V_S$ – 1.2	$–V_S$ + 1.9		$+V_S$ – 1.2	$–V_S$ + 1.9		$+V_S$ – 1.2	V
Over Temperature		$–V_S$ + 2.1		$+V_S$ – 1.3	$–V_S$ + 2.1		$+V_S$ – 1.3	$–V_S$ + 2.1		$+V_S$ – 1.3	V
	V_S = ±5 V to ±18 V	$–V_S$ + 1.9		$+V_S$ – 1.4	$–V_S$ + 1.9		$+V_S$ – 1.4	$–V_S$ + 1.9		$+V_S$ – 1.4	V
Over Temperature		$–V_S$ + 2.1		$+V_S$ – 1.4	$–V_S$ + 2.1		$+V_S$ – 1.4	$–V_S$ + 2.3		$+V_S$ – 1.4	V
Common-Mode Rejection Ratio DC to 60 Hz with I kΩ Source Imbalance	V_{CM} = 0 V to ±10 V										
G = 1		73	90		80	90		73	90		dB
G = 10		93	110		100	110		93	110		dB
G = 100		110	130		120	130		110	130		dB
G = 1000		110	130		120	130		110	130		dB
OUTPUT											
Output Swing	R_L = 10 kΩ,										
	V_S = ±2.3 V to ±5 V	$–V_S$ + 1.1		$+V_S$ – 1.2	$–V_S$ + 1.1		$+V_S$ – 1.2	$–V_S$ + 1.1		$+V_S$ – 1.2	V
Over Temperature		$–V_S$ + 1.4		$+V_S$ – 1.3	$–V_S$ + 1.4		$+V_S$ – 1.3	$–V_S$ + 1.6		$+V_S$ – 1.3	V
	V_S = ±5 V to ±18 V	$–V_S$ + 1.2		$+V_S$ – 1.4	$–V_S$ + 1.2		$+V_S$ – 1.4	$–V_S$ + 1.2		$+V_S$ – 1.4	V
Over Temperature		$–V_S$ + 1.6		$+V_S$ – 1.5	$–V_S$ + 1.6		$+V_S$ – 1.5	$–V_S$ + 2.3		$+V_S$ – 1.5	V
Short Current Circuit			±18			±18			±18		mA

Model	Conditions	AD620A Min	AD620A Typ	AD620A Max	AD620B Min	AD620B Typ	AD620B Max	AD620S[1] Min	AD620S[1] Typ	AD620S[1] Max	Units
DYNAMIC RESPONSE											
Small Signal –3 dB Bandwidth											
G = 1			1000			1000			1000		kHz
G = 10			800			800			800		kHz
G = 100			120			120			120		kHz
G = 1000			12			12			12		kHz
Slew Rate		0.75	1.2		0.75	1.2		0.75	1.2		V/μs
Settling Time to 0.01%	10 V Step										
G = 1–100			15			15			15		μs
G = 1000			150			150			150		μs
NOISE											
Voltage Noise, 1 kHz	$Total\ RTI\ Noise = \sqrt{(e^2_{ni}) + (e_{no}/G)^2}$										
Input, Voltage Noise, e_{ni}			9	13		9	13		9	13	nV/$\sqrt{Hz}$
Output, Voltage Noise, e_{no}			72	100		72	100		72	100	nV/$\sqrt{Hz}$
RTI, 0.1 Hz to 10 Hz											
G = 1			3.0			3.0	6.0		3.0	6.0	μV p-p
G = 10			0.55			0.55	0.8		0.55	0.8	μV p-p
G = 100–1000			0.28			0.28	0.4		0.28	0.4	μV p-p
Current Noise	f = 1 kHz		100			100			100		fA/$\sqrt{Hz}$
0.1 Hz to 10 Hz			10			10			10		pA p-p
REFERENCE INPUT											
R_{IN}			20			20			20		kΩ
I_{IN}	V_{IN+}, V_{REF} = 0		+50	+60		+50	+60		+50	+60	μA
Voltage Range		$-V_S$ + 1.6		$+V_S$ – 1.6	$-V_S$ + 1.6		$+V_S$ – 1.6	$-V_S$ + 1.6		$+V_S$ – 1.6	V
Gain to Output			1 ± 0.0001			1 ± 0.0001			1 ± 0.0001		
POWER SUPPLY											
Operating Range[4]		±2.3		±18	±2.3		±18	±2.3		±18	V
Quiescent Current	V_S = ±2.3 V to ±18 V		0.9	1.3		0.9	1.3		0.9	1.3	mA
Over Temperature			1.1	1.6		1.1	1.6		1.1	1.6	mA
TEMPERATURE RANGE											
For Specified Performance		–40 to +85			–40 to +85			–55 to +125			°C

NOTES
[1]See Analog Devices military data sheet for 883B tested specifications.
[2]Does not include effects of external resistor R_G.
[3]One input grounded. G = 1.
[4]This is defined as the same supply range which is used to specify PSR.

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS[1]

Supply Voltage . . . . . ±18 V
Internal Power Dissipation[2] . . . . . 650 mW
Input Voltage (Common Mode) . . . . . $\pm V_S$
Differential Input Voltage . . . . . ±25 V
Output Short Circuit Duration . . . . . Indefinite
Storage Temperature Range (Q) . . . . . –65°C to +150°C
Storage Temperature Range (N, R) . . . . . –65°C to +125°C
Operating Temperature Range
AD620 (A, B) . . . . . –40°C to +85°C
AD620 (S) . . . . . –55°C to +125°C
Lead Temperature Range
(Soldering 10 seconds) . . . . . +300°C

NOTES
[1]Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
[2]Specification is for device in free air:
8-Lead Plastic Package: θ_{JA} = 95°C/W
8-Lead Cerdip Package: θ_{JA} = 110°C/W
8-Lead SOIC Package: θ_{JA} = 155°C/W

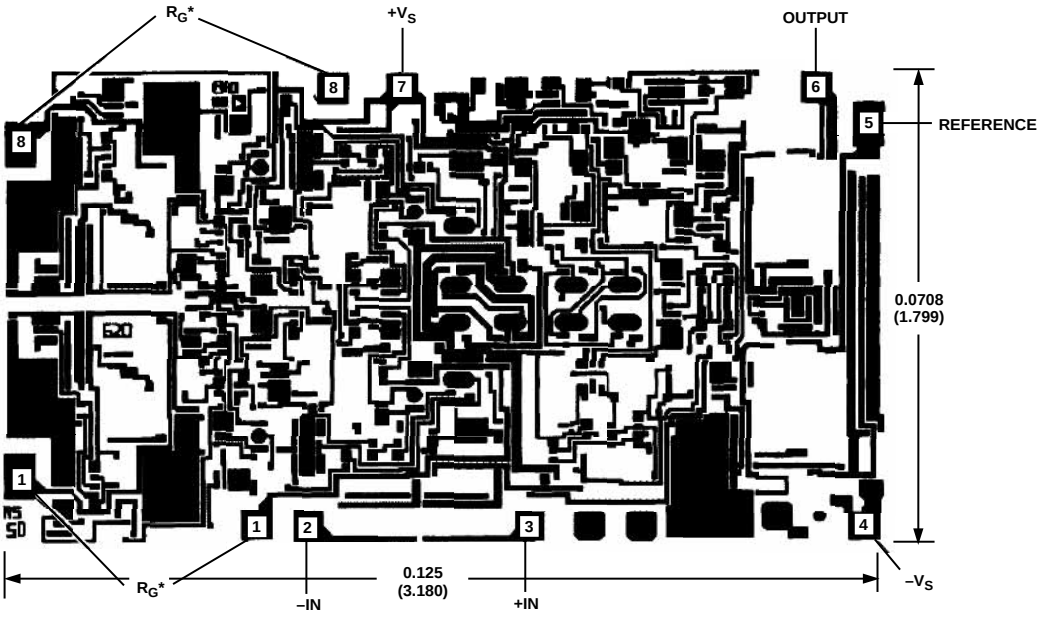
ORDERING GUIDE

Model	Temperature Ranges	Package Options*
AD620AN	–40°C to +85°C	N-8
AD620BN	–40°C to +85°C	N-8
AD620AR	–40°C to +85°C	SO-8
AD620AR-REEL	–40°C to +85°C	13" REEL
AD620AR-REEL7	–40°C to +85°C	7" REEL
AD620BR	–40°C to +85°C	SO-8
AD620BR-REEL	–40°C to +85°C	13" REEL
AD620BR-REEL7	–40°C to +85°C	7" REEL
AD620ACHIPS	–40°C to +85°C	Die Form
AD620SQ/883B	–55°C to +125°C	Q-8

*N = Plastic DIP; Q = Cerdip; SO = Small Outline.

METALIZATION PHOTOGRAPH

Dimensions shown in inches and (mm).
Contact factory for latest dimensions.



*FOR CHIP APPLICATIONS: THE PADS $1R_G$ AND $8R_G$ MUST BE CONNECTED IN PARALLEL TO THE EXTERNAL GAIN REGISTER R_G. DO NOT CONNECT THEM IN SERIES TO R_G. FOR UNITY GAIN APPLICATIONS WHERE R_G IS NOT REQUIRED, THE PADS $1R_G$ MAY SIMPLY BE BONDED TOGETHER, AS WELL AS THE PADS $8R_G$.

CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD620 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

Typical Characteristics (@ +25°C, V_S = ±15 V, R_L = 2 kΩ, unless otherwise noted)

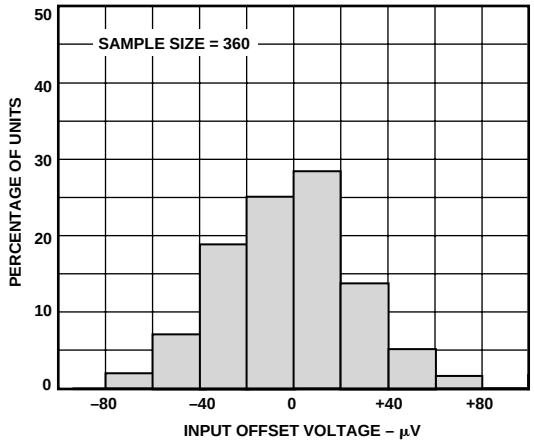


Figure 3. Typical Distribution of Input Offset Voltage

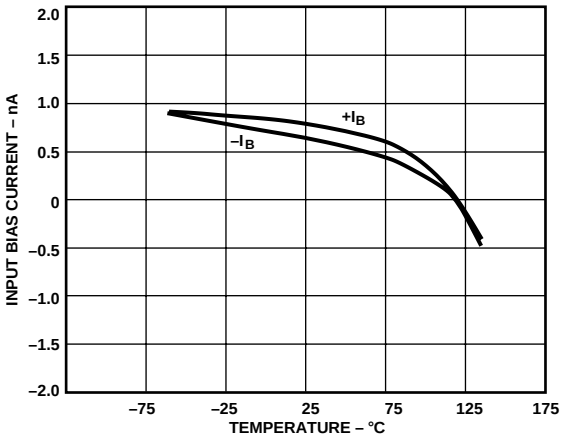


Figure 6. Input Bias Current vs. Temperature

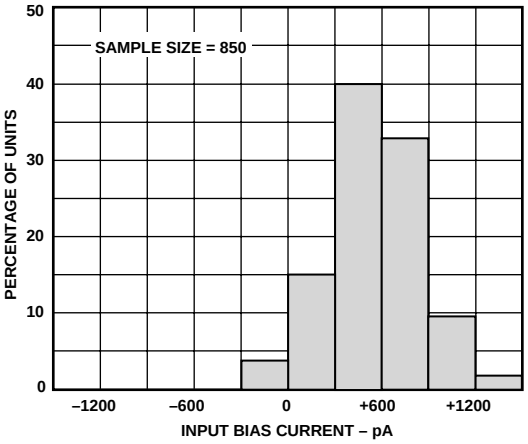


Figure 4. Typical Distribution of Input Bias Current

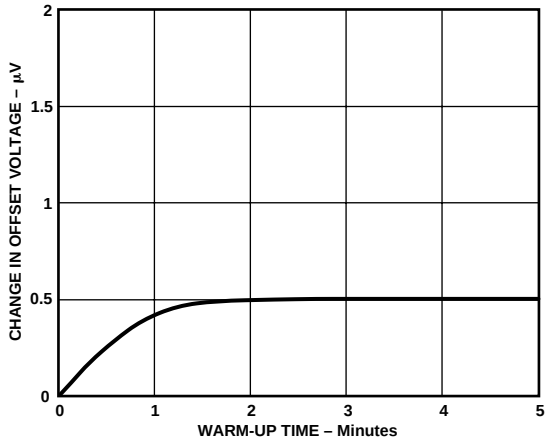


Figure 7. Change in Input Offset Voltage vs. Warm-Up Time

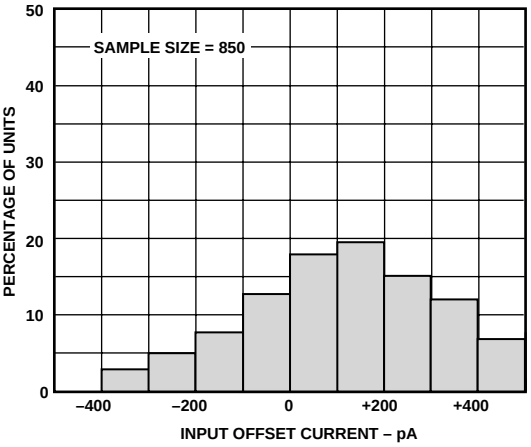


Figure 5. Typical Distribution of Input Offset Current

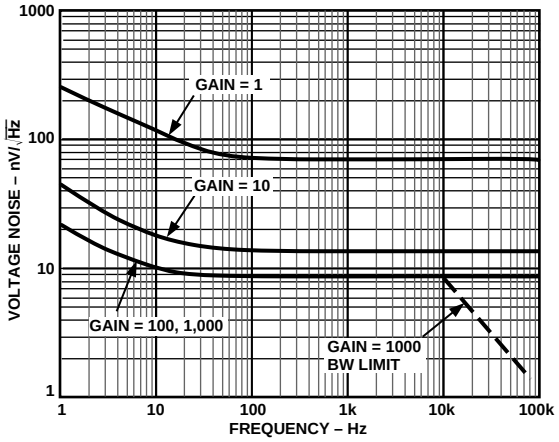


Figure 8. Voltage Noise Spectral Density vs. Frequency, (G = 1–1000)

AD620–Typical Characteristics

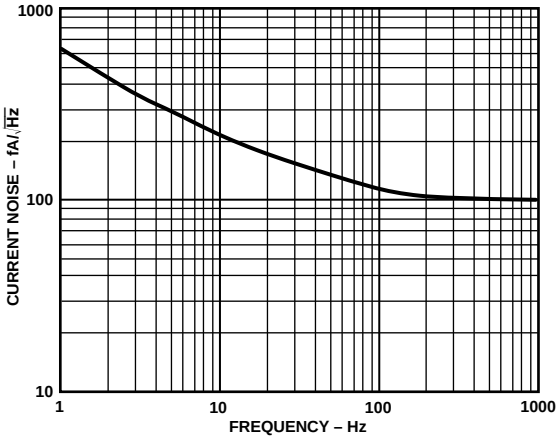


Figure 9. Current Noise Spectral Density vs. Frequency

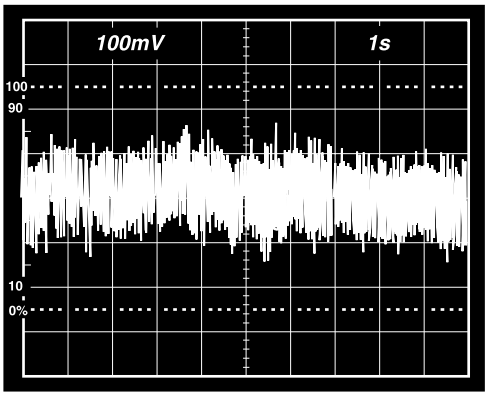


Figure 11. 0.1 Hz to 10 Hz Current Noise, 5 pA/Div

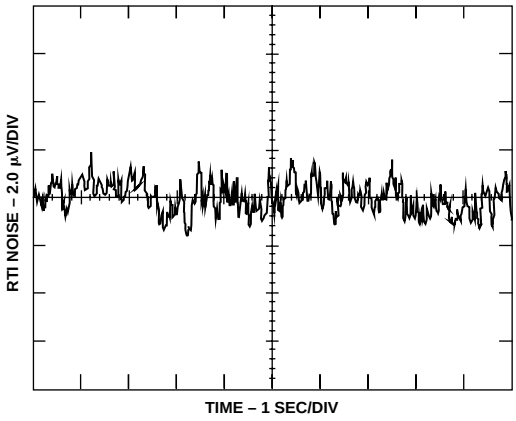


Figure 10a. 0.1 Hz to 10 Hz RTI Voltage Noise (G = 1)

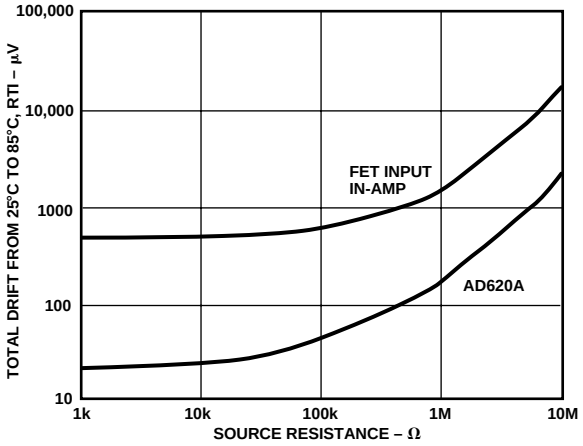


Figure 12. Total Drift vs. Source Resistance

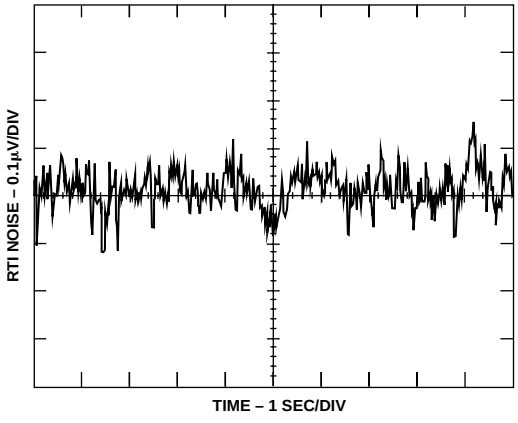


Figure 10b. 0.1 Hz to 10 Hz RTI Voltage Noise (G = 1000)

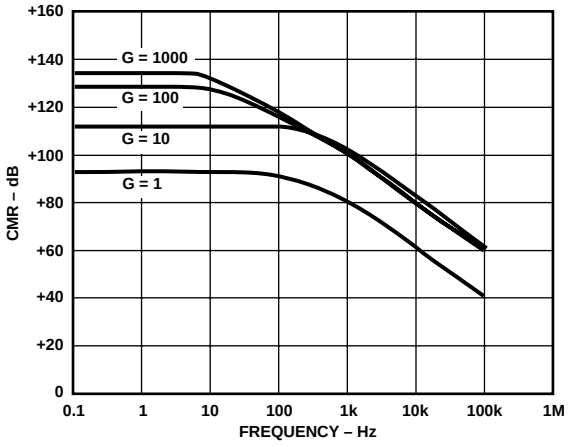


Figure 13. CMR vs. Frequency, RTI, Zero to 1 kΩ Source Imbalance

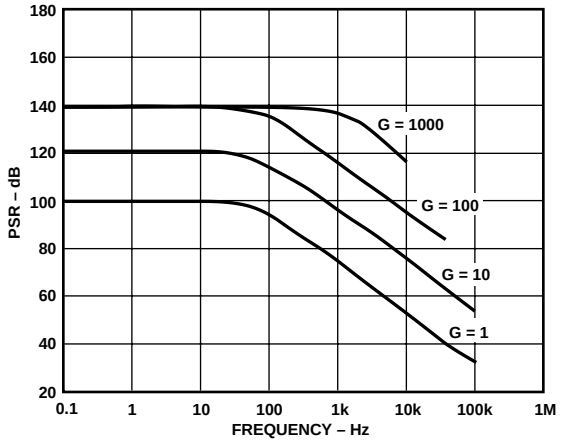


Figure 14. Positive PSR vs. Frequency, RTI (G = 1–1000)

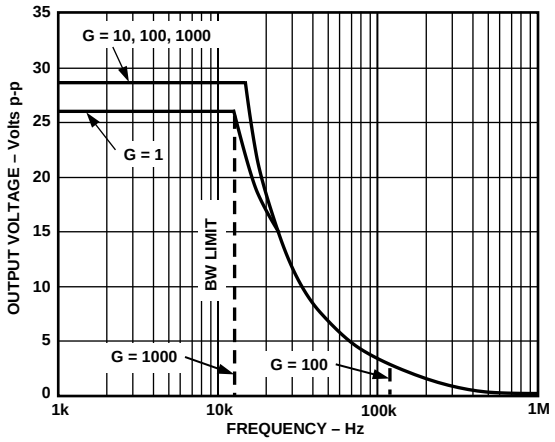


Figure 17. Large Signal Frequency Response

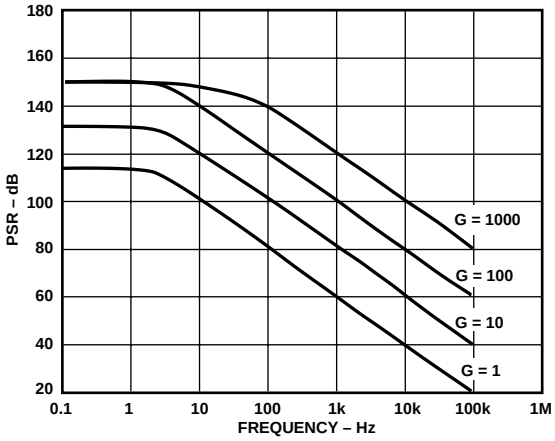


Figure 15. Negative PSR vs. Frequency, RTI (G = 1–1000)

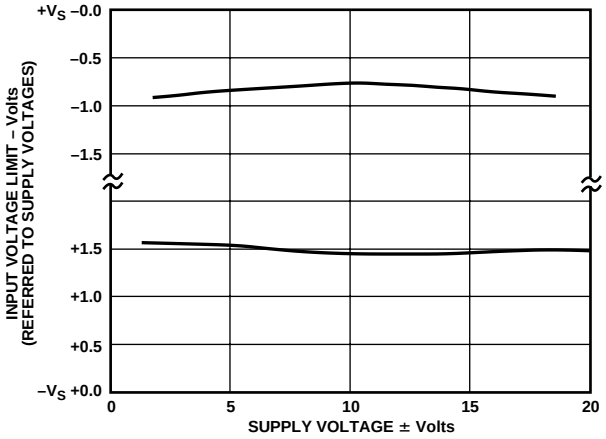


Figure 18. Input Voltage Range vs. Supply Voltage, G = 1

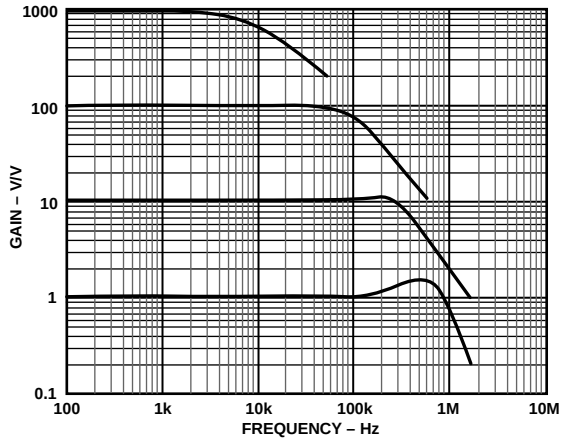


Figure 16. Gain vs. Frequency

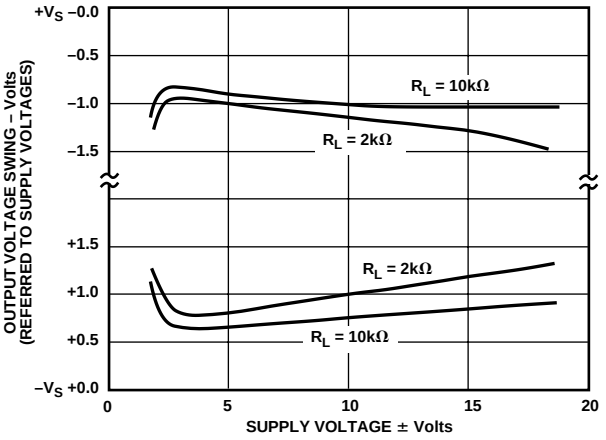


Figure 19. Output Voltage Swing vs. Supply Voltage, G = 10

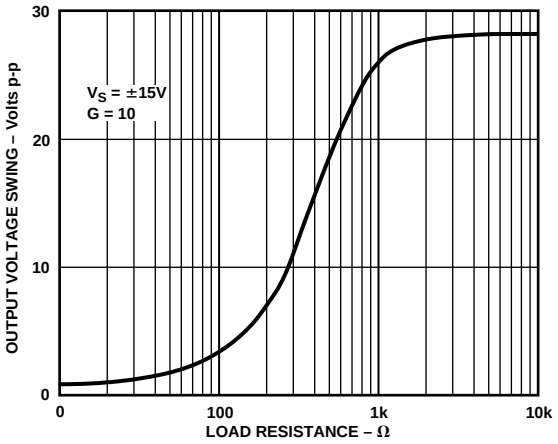


Figure 20. Output Voltage Swing vs. Load Resistance

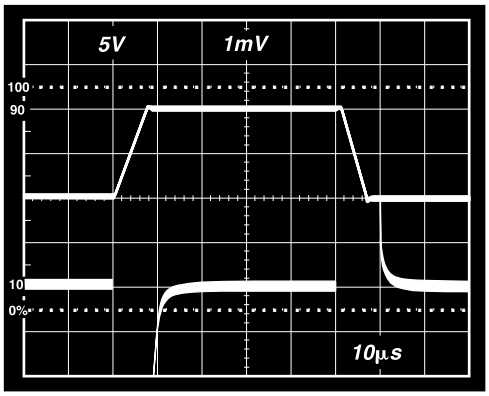


Figure 23. Large Signal Response and Settling Time, G = 10 (0.5 mV = 001%)

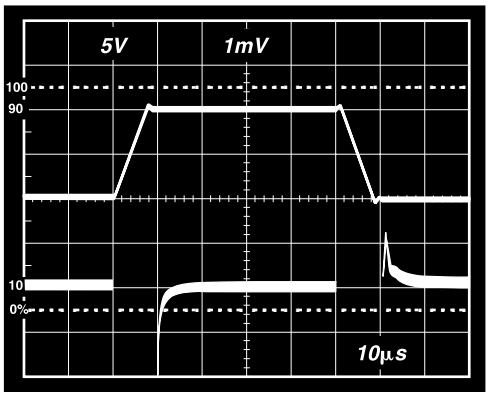


Figure 21. Large Signal Pulse Response and Settling Time G = 1 (0.5 mV = 0.01%)

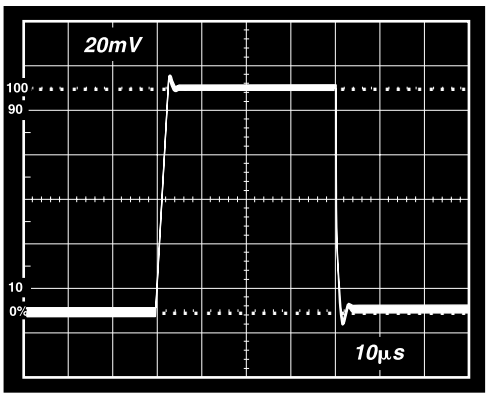


Figure 24. Small Signal Response, G = 10, R_L = 2 kΩ, C_L = 100 pF

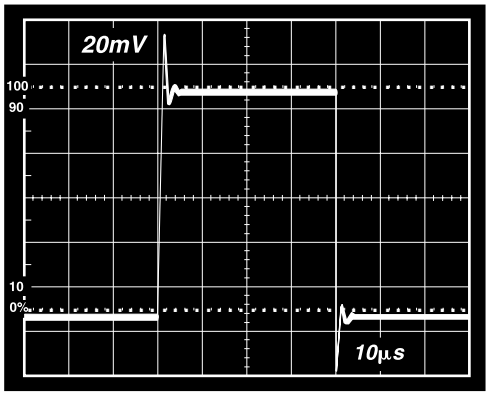


Figure 22. Small Signal Response, G = 1, R_L = 2 kΩ, C_L = 100 pF

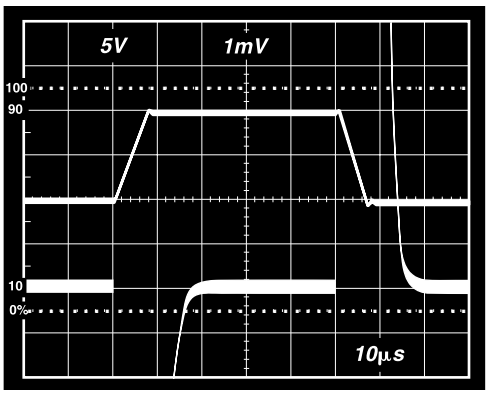


Figure 25. Large Signal Response and Settling Time, G = 100 (0.5 mV = 0.01%)

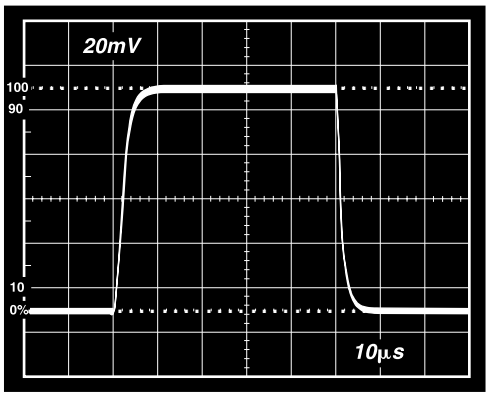


Figure 26. Small Signal Pulse Response, G = 100, R_L = 2 kΩ, C_L = 100 pF

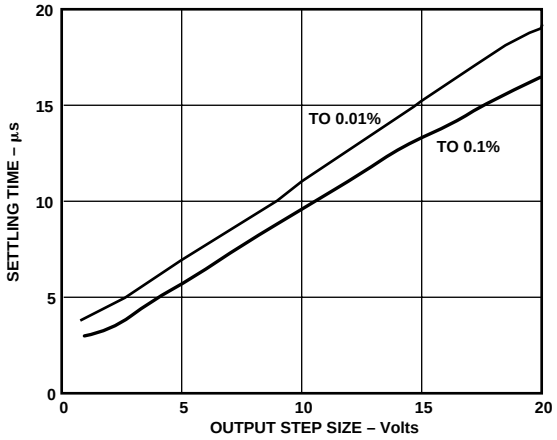


Figure 29. Settling Time vs. Step Size (G = 1)

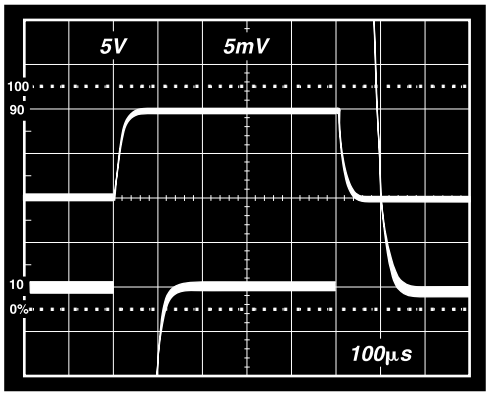


Figure 27. Large Signal Response and Settling Time, G = 1000 (0.5 mV = 0.01%)

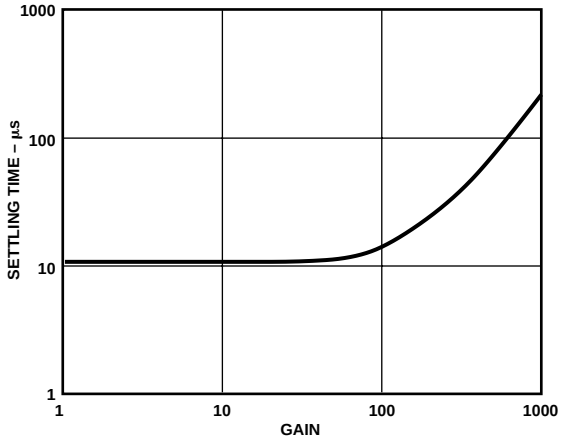


Figure 30. Settling Time to 0.01% vs. Gain, for a 10 V Step

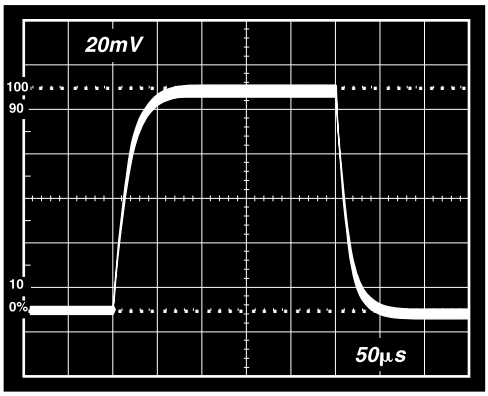


Figure 28. Small Signal Pulse Response, G = 1000, R_L = 2 kΩ, C_L = 100 pF

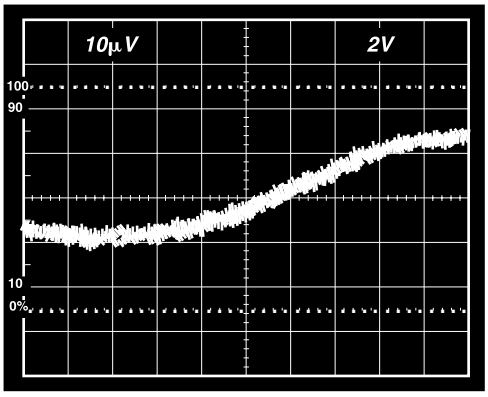


Figure 31a. Gain Nonlinearity, G = 1, R_L = 10 kΩ (10 μV = 1 ppm)

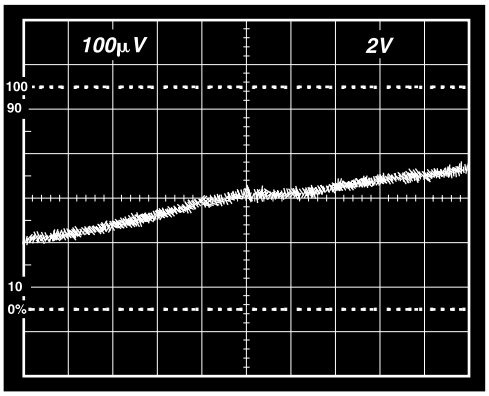


Figure 31b. Gain Nonlinearity, G = 100, R_L = 10 kΩ (100 µV = 10 ppm)

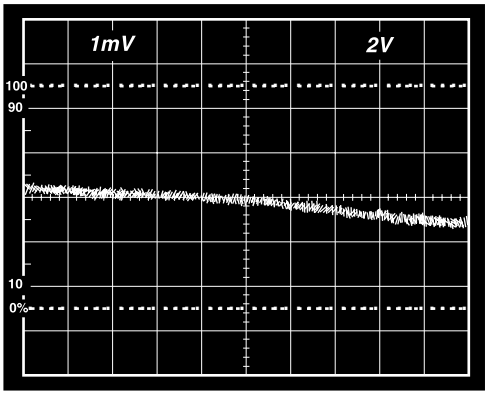


Figure 31c. Gain Nonlinearity, G = 1000, R_L = 10 kΩ (1 mV = 100 ppm)

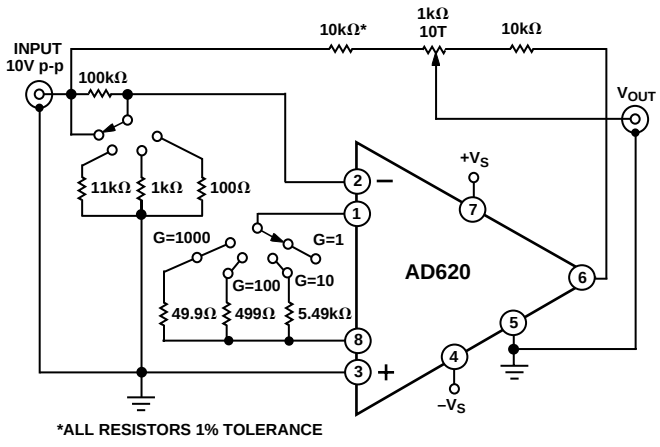


Figure 32. Settling Time Test Circuit

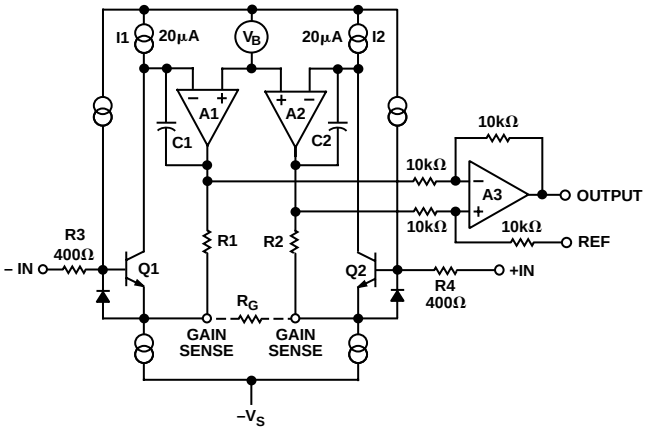


Figure 33. Simplified Schematic of AD620

THEORY OF OPERATION

The AD620 is a monolithic instrumentation amplifier based on a modification of the classic three op amp approach. Absolute value trimming allows the user to program gain *accurately* (to 0.15% at G = 100) with only one resistor. Monolithic construction and laser wafer trimming allow the tight matching and tracking of circuit components, thus ensuring the high level of performance inherent in this circuit.

The input transistors Q1 and Q2 provide a single differential-pair bipolar input for high precision (Figure 33), yet offer 10× lower Input Bias Current thanks to Superβeta processing. Feedback through the Q1-A1-R1 loop and the Q2-A2-R2 loop maintains constant collector current of the input devices Q1, Q2 thereby impressing the input voltage across the external gain setting resistor R_G. This creates a differential gain from the inputs to the A1/A2 outputs given by G = (R1 + R2)/R_G + 1. The unity-gain subtracter A3 removes any common-mode signal, yielding a single-ended output referred to the REF pin potential.

The value of R_G also determines the transconductance of the preamp stage. As R_G is reduced for larger gains, the transconductance increases asymptotically to that of the input transistors. This has three important advantages: (a) Open-loop gain is boosted for increasing programmed gain, thus reducing gain-related errors. (b) The gain-bandwidth product (determined by C1, C2 and the preamp transconductance) increases with programmed gain, thus optimizing frequency response. (c) The input voltage noise is reduced to a value of 9 nV/$\sqrt{\text{Hz}}$, determined mainly by the collector current and base resistance of the input devices.

The internal gain resistors, R1 and R2, are trimmed to an absolute value of 24.7 kΩ, allowing the gain to be programmed accurately with a single external resistor.

The gain equation is then

$$G = \frac{49.4\ k\Omega}{R_G} + 1$$

so that

$$R_G = \frac{49.4\ k\Omega}{G - 1}$$

Make vs. Buy: A Typical Bridge Application Error Budget
The AD620 offers improved performance over "homebrew" three op amp IA designs, along with smaller size, fewer components and 10× lower supply current. In the typical application, shown in Figure 34, a gain of 100 is required to amplify a bridge output of 20 mV full scale over the industrial temperature range of –40°C to +85°C. The error budget table below shows how to calculate the effect various error sources have on circuit accuracy.

Regardless of the system in which it is being used, the AD620 provides greater accuracy, and at low power and price. In simple systems, absolute accuracy and drift errors are by far the most significant contributors to error. In more complex systems with an intelligent processor, an autogain/autozero cycle will remove all absolute accuracy and drift errors leaving only the resolution errors of gain nonlinearity and noise, thus allowing full 14-bit accuracy.

Note that for the homebrew circuit, the OP07 specifications for input voltage offset and noise have been multiplied by $\sqrt{2}$. This is because a three op amp type in-amp has two op amps at its inputs, both contributing to the overall input error.

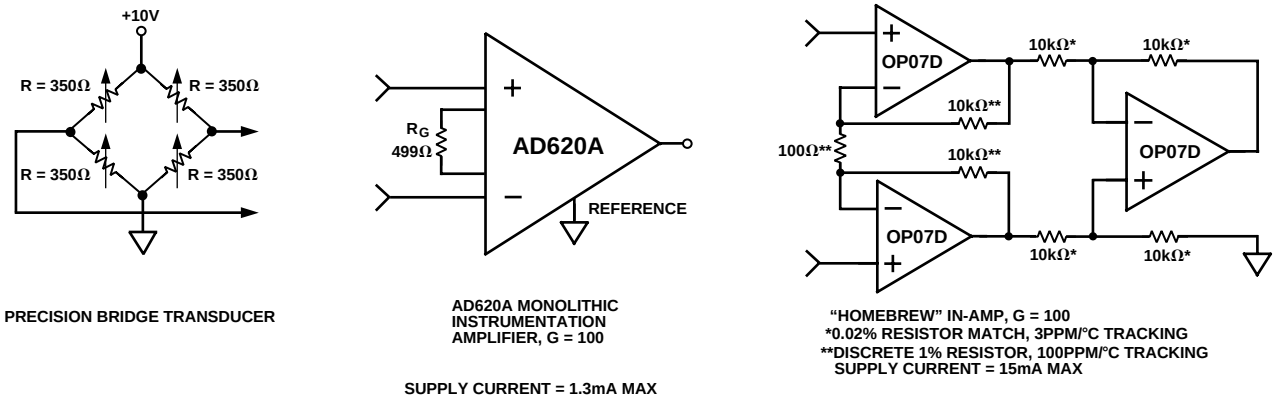


Figure 34. Make vs. Buy

Table I. Make vs. Buy Error Budget

Error Source	AD620 Circuit Calculation	"Homebrew" Circuit Calculation	Error, ppm of Full Scale AD620	Homebrew
ABSOLUTE ACCURACY at T_A = +25°C				
Input Offset Voltage, µV	125 µV/20 mV	(150 µV × $\sqrt{2}$)/20 mV	6,250	10,607
Output Offset Voltage, µV	1000 µV/100/20 mV	((150 µV × 2)/100)/20 mV	500	150
Input Offset Current, nA	2 nA × 350 Ω/20 mV	(6 nA × 350 Ω)/20 mV	18	53
CMR, dB	110 dB→3.16 ppm, × 5 V/20 mV	(0.02% Match × 5 V)/20 mV/100	791	500
		Total Absolute Error	7,558	11,310
DRIFT TO +85°C				
Gain Drift, ppm/°C	(50 ppm + 10 ppm) × 60°C	100 ppm/°C Track × 60°C	3,600	6,000
Input Offset Voltage Drift, µV/°C	1 µV/°C × 60°C/20 mV	(2.5 µV/°C × $\sqrt{2}$ × 60°C)/20 mV	3,000	10,607
Output Offset Voltage Drift, µV/°C	15 µV/°C × 60°C/100/20 mV	(2.5 µV/°C × 2 × 60°C)/100/20 mV	450	150
		Total Drift Error	7,050	16,757
RESOLUTION				
Gain Nonlinearity, ppm of Full Scale	40 ppm	40 ppm	40	40
Typ 0.1 Hz–10 Hz Voltage Noise, µV p-p	0.28 µV p-p/20 mV	(0.38 µV p-p × $\sqrt{2}$)/20 mV	14	27
		Total Resolution Error	54	67
		Grand Total Error	14,662	28,134

G = 100, V_S = ±15 V.

(All errors are min/max and referred to input.)

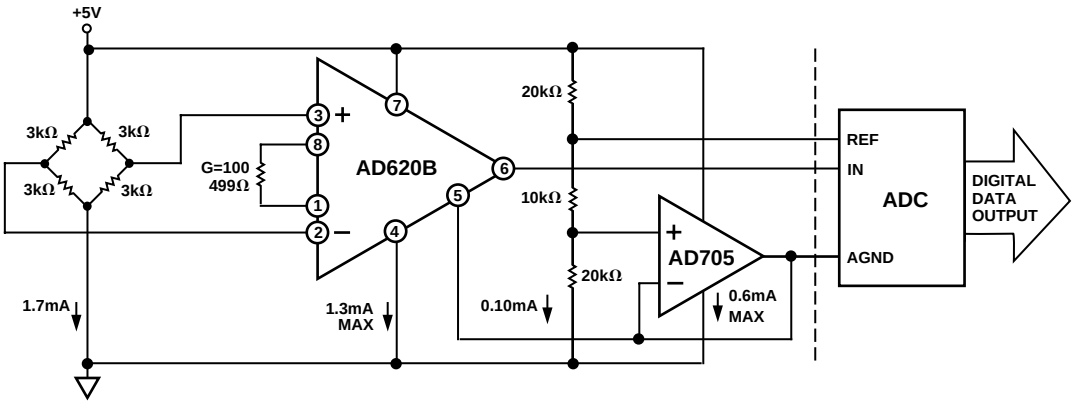


Figure 35. A Pressure Monitor Circuit which Operates on a +5 V Single Supply

Pressure Measurement

Although useful in many bridge applications such as weigh scales, the AD620 is especially suitable for higher resistance pressure sensors powered at lower voltages where small size and low power become more significant.

Figure 35 shows a 3 kΩ pressure transducer bridge powered from +5 V. In such a circuit, the bridge consumes only 1.7 mA. Adding the AD620 and a buffered voltage divider allows the signal to be conditioned for only 3.8 mA of total supply current.

Small size and low cost make the AD620 especially attractive for voltage output pressure transducers. Since it delivers low noise and drift, it will also serve applications such as diagnostic non-invasive blood pressure measurement.

Medical ECG

The low current noise of the AD620 allows its use in ECG monitors (Figure 36) where high source resistances of 1 MΩ or higher are not uncommon. The AD620's low power, low supply voltage requirements, and space-saving 8-lead mini-DIP and SOIC package offerings make it an excellent choice for battery powered data recorders.

Furthermore, the low bias currents and low current noise coupled with the low voltage noise of the AD620 improve the dynamic range for better performance.

The value of capacitor C1 is chosen to maintain stability of the right leg drive loop. Proper safeguards, such as isolation, must be added to this circuit to protect the patient from possible harm.

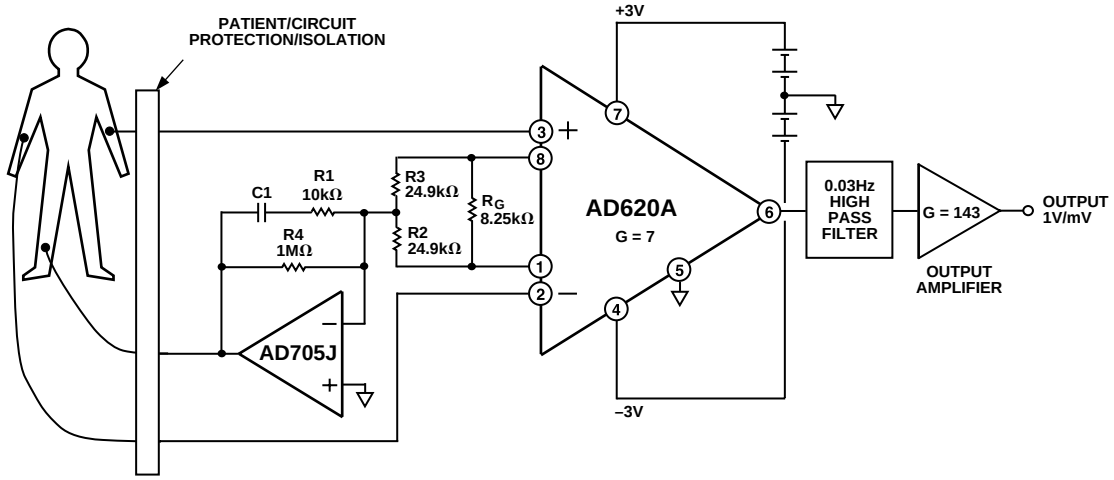


Figure 36. A Medical ECG Monitor Circuit

Precision V-I Converter

The AD620, along with another op amp and two resistors, makes a precision current source (Figure 37). The op amp buffers the reference terminal to maintain good CMR. The output voltage V_X of the AD620 appears across R1, which converts it to a current. This current less only, the input bias current of the op amp, then flows out to the load.

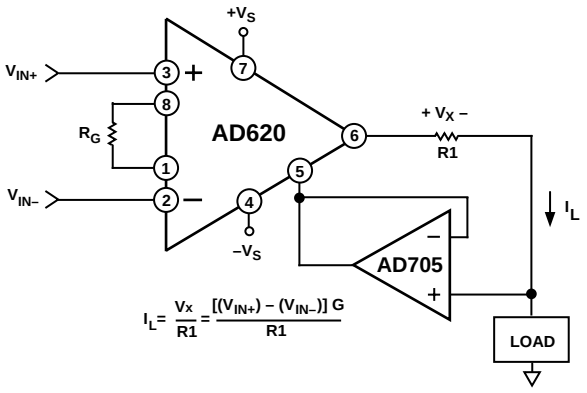


Figure 37. Precision Voltage-to-Current Converter (Operates on 1.8 mA, ±3 V)

GAIN SELECTION

The AD620's gain is resistor programmed by R_G, or more precisely, by whatever impedance appears between Pins 1 and 8. The AD620 is designed to offer accurate gains using 0.1%–1% resistors. Table II shows required values of R_G for various gains. Note that for G = 1, the R_G pins are unconnected ($R_G = \infty$). For any arbitrary gain R_G can be calculated by using the formula:

$$R_G = \frac{49.4\ k\Omega}{G-1}$$

To minimize gain error, avoid high parasitic resistance in series with R_G; to minimize gain drift, R_G should have a low TC—less than 10 ppm/°C—for the best performance.

Table II. Required Values of Gain Resistors

1% Std Table Value of R_G, Ω	Calculated Gain	0.1% Std Table Value of R_G, Ω	Calculated Gain
49.9 k	1.990	49.3 k	2.002
12.4 k	4.984	12.4 k	4.984
5.49 k	9.998	5.49 k	9.998
2.61 k	19.93	2.61 k	19.93
1.00 k	50.40	1.01 k	49.91
499	100.0	499	100.0
249	199.4	249	199.4
100	495.0	98.8	501.0
49.9	991.0	49.3	1,003

INPUT AND OUTPUT OFFSET VOLTAGE

The low errors of the AD620 are attributed to two sources, input and output errors. The output error is divided by G when referred to the input. In practice, the input errors dominate at high gains and the output errors dominate at low gains. The total V_{OS} for a given gain is calculated as:

Total Error RTI = input error + (output error/G)

Total Error RTO = (input error × G) + output error

REFERENCE TERMINAL

The reference terminal potential defines the zero output voltage, and is especially useful when the load does not share a precise ground with the rest of the system. It provides a direct means of injecting a precise offset to the output, with an allowable range of 2 V within the supply voltages. Parasitic resistance should be kept to a minimum for optimum CMR.

INPUT PROTECTION

The AD620 features 400 Ω of series thin film resistance at its inputs, and will safely withstand input overloads of up to ±15 V or ±60 mA for several hours. This is true for all gains, and power on and off, which is particularly important since the signal source and amplifier may be powered separately. For longer time periods, the current should not exceed 6 mA ($I_{IN} \le V_{IN}/400\ \Omega$). For input overloads beyond the supplies, clamping the inputs to the supplies (using a low leakage diode such as an FD333) will reduce the required resistance, yielding lower noise.

RF INTERFERENCE

All instrumentation amplifiers can rectify out of band signals, and when amplifying small signals, these rectified voltages act as small dc offset errors. The AD620 allows direct access to the input transistor bases and emitters enabling the user to apply some first order filtering to unwanted RF signals (Figure 38), where RC ≈ 1/(2 πf) and where f ≥ the bandwidth of the AD620; C ≤ 150 pF. Matching the extraneous capacitance at Pins 1 and 8 and Pins 2 and 3 helps to maintain high CMR.

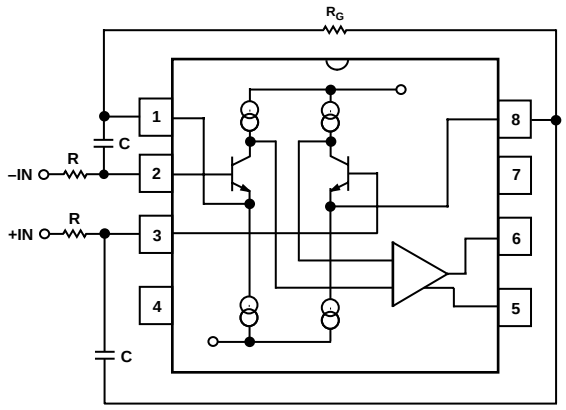


Figure 38. Circuit to Attenuate RF Interference

COMMON-MODE REJECTION

Instrumentation amplifiers like the AD620 offer high CMR, which is a measure of the change in output voltage when both inputs are changed by equal amounts. These specifications are usually given for a full-range input voltage change and a specified source imbalance.

For optimal CMR the reference terminal should be tied to a low impedance point, and differences in capacitance and resistance should be kept to a minimum between the two inputs. In many applications shielded cables are used to minimize noise, and for best CMR over frequency the shield should be properly driven. Figures 39 and 40 show active data guards that are configured to improve ac common-mode rejections by "bootstrapping" the capacitances of input cable shields, thus minimizing the capacitance mismatch between the inputs.

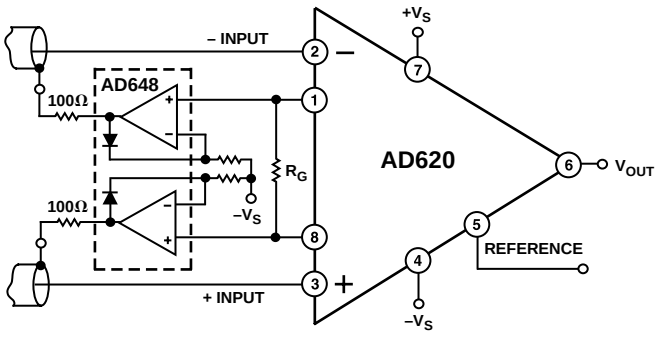


Figure 39. Differential Shield Driver

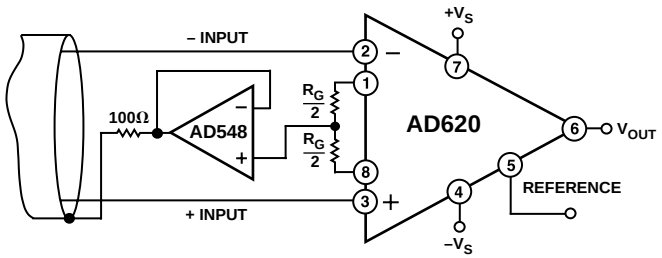


Figure 40. Common-Mode Shield Driver

GROUNDING

Since the AD620 output voltage is developed with respect to the potential on the reference terminal, it can solve many grounding problems by simply tying the REF pin to the appropriate "local ground."

In order to isolate low level analog signals from a noisy digital environment, many data-acquisition components have separate analog and digital ground pins (Figure 41). It would be convenient to use a single ground line; however, current through ground wires and PC runs of the circuit card can cause hundreds of millivolts of error. Therefore, separate ground returns should be provided to minimize the current flow from the sensitive points to the system ground. These ground returns must be tied together at some point, usually best at the ADC package as shown.

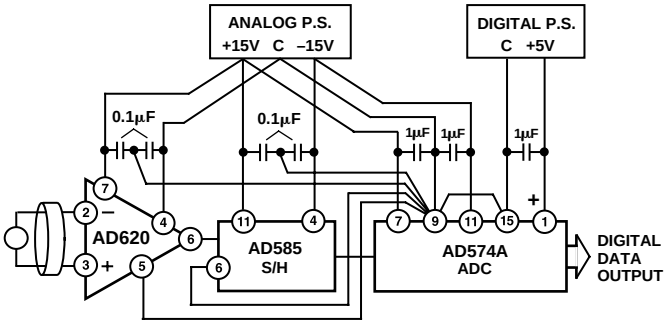


Figure 41. Basic Grounding Practice

GROUND RETURNS FOR INPUT BIAS CURRENTS

Input bias currents are those currents necessary to bias the input transistors of an amplifier. There must be a direct return path for these currents; therefore, when amplifying "floating" input sources such as transformers, or ac-coupled sources, there must be a dc path from each input to ground as shown in Figure 42. Refer to the *Instrumentation Amplifier Application Guide* (free from Analog Devices) for more information regarding in amp applications.

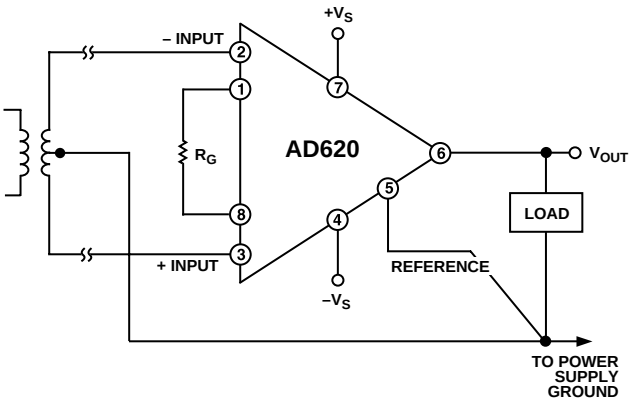


Figure 42a. Ground Returns for Bias Currents with Transformer Coupled Inputs

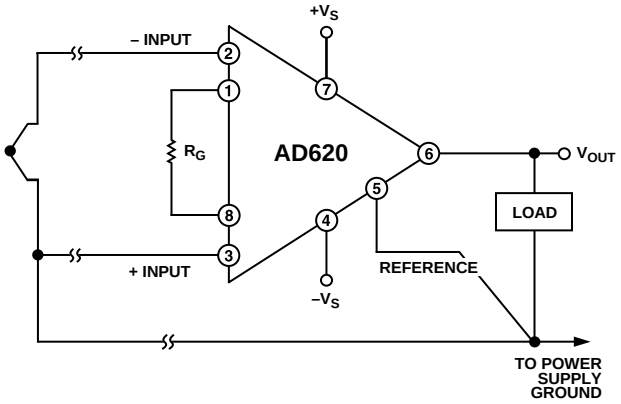


Figure 42b. Ground Returns for Bias Currents with Thermocouple Inputs

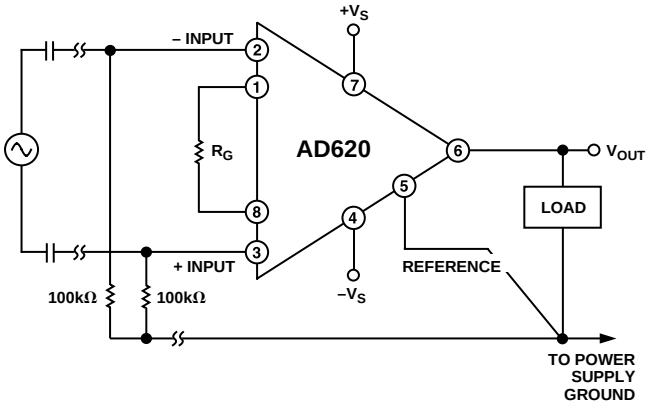
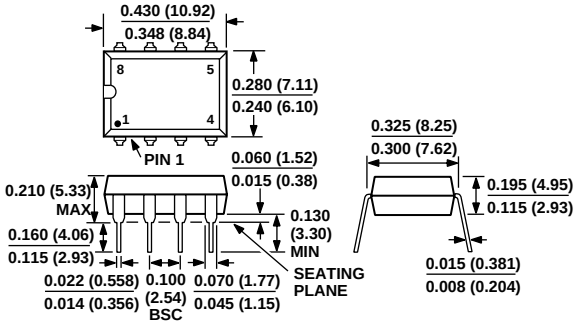


Figure 42c. Ground Returns for Bias Currents with AC Coupled Inputs

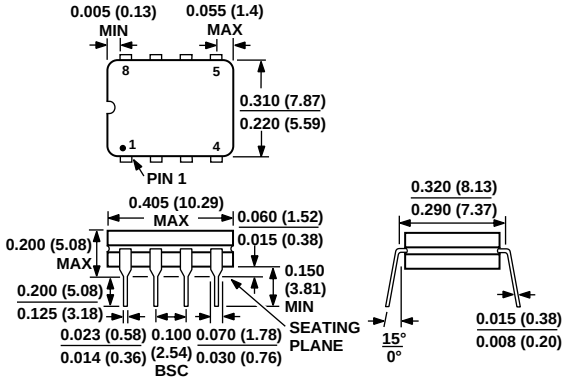
OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

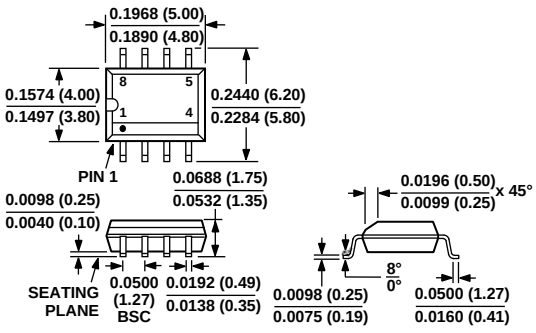
Plastic DIP (N-8) Package



Cerdip (Q-8) Package



SOIC (SO-8) Package



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NEC

BIPOLAR ANALOG INTEGRATED CIRCUIT

μPC358

LOW POWER DUAL OPERATIONAL AMPLIFIERS

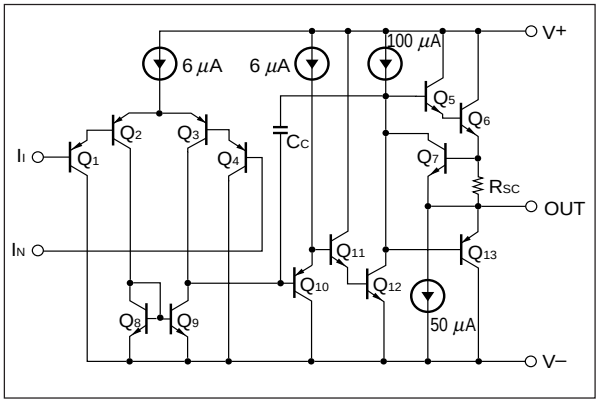
DESCRIPTION

The μPC358 is a dual operational amplifier which is designed to operate from a single power supply over a wide range of voltages. Operation from split power supplies is also possible and the power supply current drain is very low. Further advantage, the input common-mode voltage range includes ground in the linear mode.

FEATURES

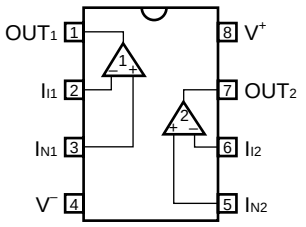
- Internally frequency compensation
- Wide output voltage swing V^- to V^+ –1.5 V
- Common mode input voltage range includes V^-
- Wide supply voltage range
  3 V to 30 V (Single)
  ±1.5 V to ±15 V (Split)
- Output short circuit protection

EQUIVALENT CIRCUIT (1/2 Circuit)

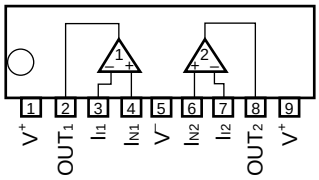


PIN CONFIGURATION (Marking Side)

μPC358C, 358G2



μPC358HA



ORDERING INFORMATION

Part Number	Package
μPC358C	8-pin plastic DIP (300 mil)
μPC358G2	8-pin plastic SOP (225 mil)
μPC358HA	9-pin slim SIP

The information in this document is subject to change without notice.

Document No. G11765EJ4V0DS00 (4th edition)
(Previous No. IC-1284)
Date Published May 1997 N
Printed in Japan

The mark ★ shows major revised points.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C)

Parameter			Symbol	Ratings	Unit
Voltage between V^+ and V^-		**Note 1**	$V^+ - V^-$	–0.3 to +32	V
Differential Input Voltage			V_{ID}	±32	V
Input Voltage		**Note 2**	V_I	V^-–0.3 to V^-+32	V
Output Voltage		**Note 3**	V_O	V^-–0.3 to V^++0.3	V
Power Dissipation	C Package	**Note 4**	P_T	350	mW
	G2 Package	**Note 5**		440	mW
	HA Package	**Note 4**		350	mW
Output Short Circuit Duration		**Note 6**		Indefinite	s
Operating Ambient Temperature			T_A	–20 to +80	°C
Storage Temperature			T_{stg}	–55 to +125	°C

Notes 1. Reverse connection of supply voltage can cause destruction.

2. The input voltage should be allowed to input without damage or destruction independent of the magnitude of V^+. Either input signal should not be allowed to go negative by more than 0.3 V. The normal operation will establish when the both inputs are within the Common Mode Input Voltage Range of electrical characteristics.

3. This specification is the voltage which should be allowed to supply to the output terminal from external without damage or destructive. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The output voltage of normal operation will be the Output Voltage Swing of electrical characteristics.

4. Thermal derating factor is –5.0 mW/°C when operating ambient temperature is higher than 55 °C.

5. Thermal derating factor is –4.4 mW/°C when operating ambient temperature is higher than 25 °C.

6. Pay careful attention to the total power dissipation not to exceed the absolute maximum ratings, Note 4 and Note 5.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage (Split)	$V^{\pm}$	±1.5		±15	V
Supply Voltage (V^- = GND)	V^+	+3		+30	V

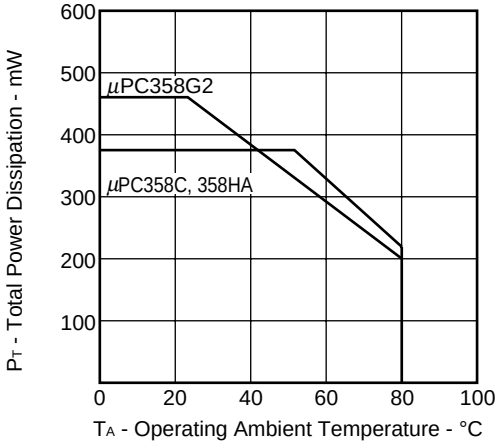
ELECTRICAL CHARACTERISTICS (T_A = 25 °C, V^+ = +5 V, V^- = GND)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input Offset Voltage	V_{IO}	R_S = 0 Ω		±2	±7	mV
Input Offset Current	I_{IO}			±5	±50	nA
Input Bias Current **Note 7**	I_B			45	250	nA
Large Signal Voltage Gain	A_V	$R_L \geq$ 2 kΩ	25	100		V/mA
Supply Current	I_{CC}	$R_L = \infty$, I_O = 0 A, Both Amplifiers		0.7	1.2	mA
Common Mode Rejection Ratio	CMR		65	70		dB
Supply Voltage Rejection Ratio	SVR		65	100		dB
Output Voltage Swing	V_O	R_L = 2 kΩ (Connect to GND)	0		V^+ –1.5	V
Common Mode Input Voltage Range	V_{ICM}		0		V^+ –1.5	V
Output Current (SOURCE)	$I_{O\ SOURCE}$	V_{IN}^+ = +1 V, V_{IN}^- = 0 V	20	40		mA
Output Current (SINK)	$I_{O\ SINK}$	V_{IN}^- = +1 V, V_{IN}^+ = 0 V	10	20		mA
		V_{IN}^- = +1 V, V_{IN}^+ = 0 V, V_O = 200 mV	12	50		μA
Channel Separation		f = 1 kHz to 20 kHz		120		dB

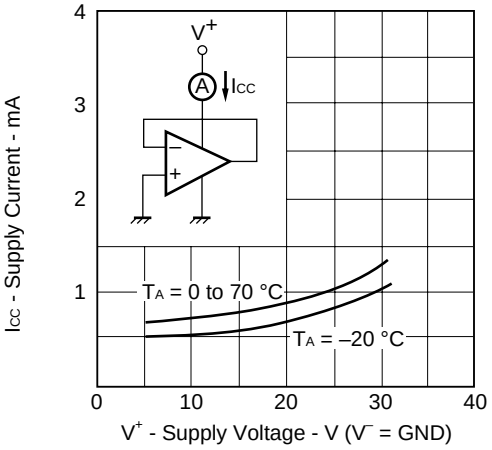
Note 7. Input bias currents flow out from IC. Because each currents are base current of PNP-transistor on input stage.

TYPICAL PERFORMANCE CHARACTERISTICS (T_A = 25 °C, TYP.)

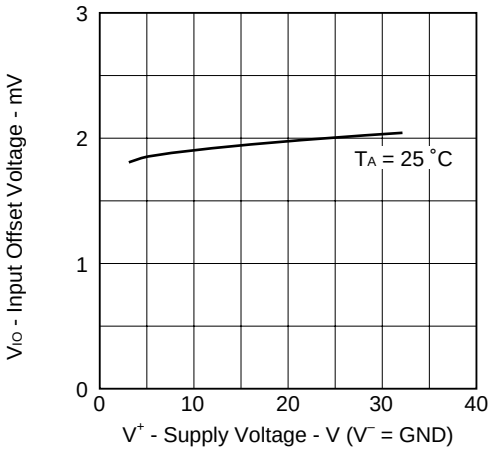
POWER DISSIPATION



SUPPLY CURRENT



★ INPUT OFFSET VOLTAGE



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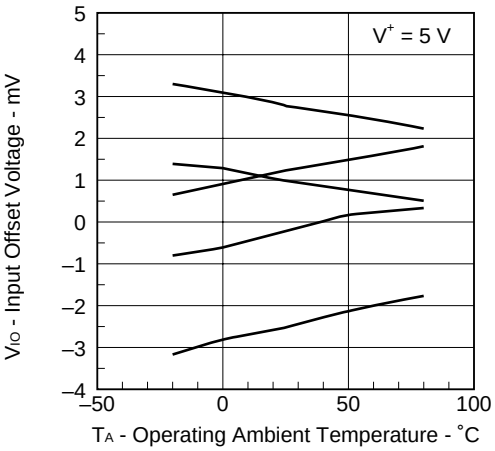
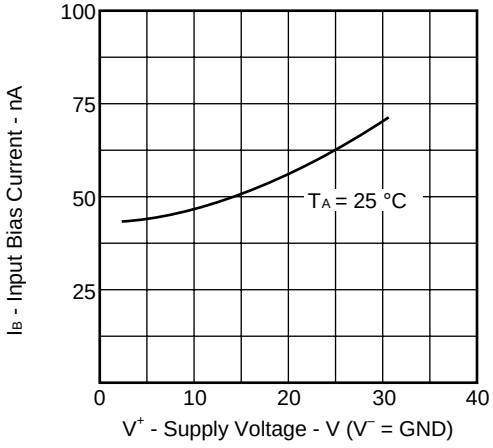
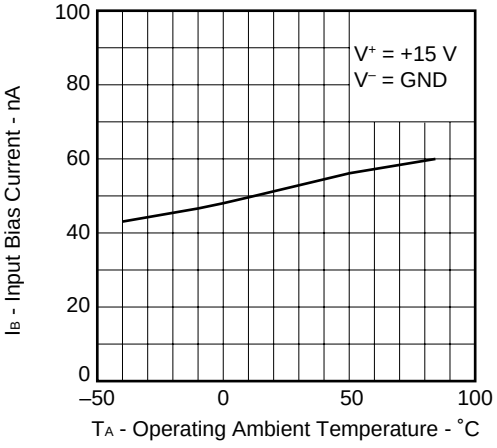


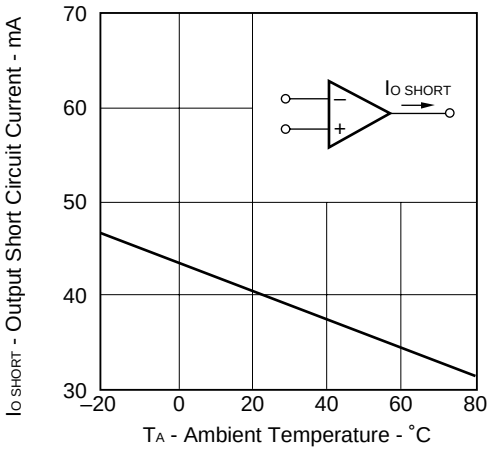
★ INPUT BIAS CURRENT



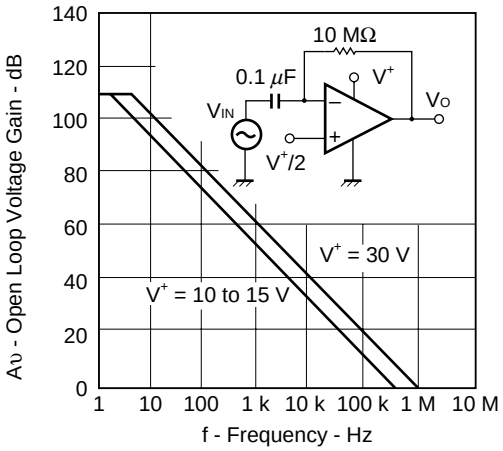
★ INPUT BIAS CURRENT



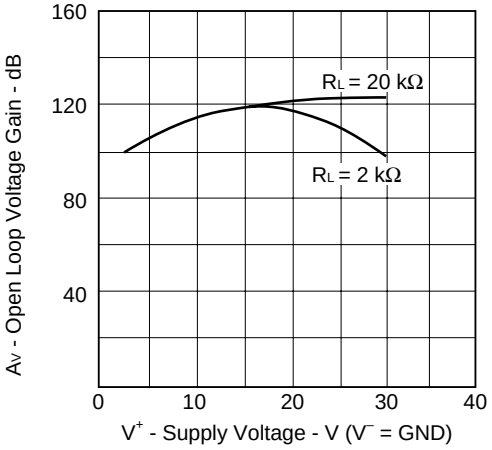
OUTPUT SHORT CIRCUIT CURRENT



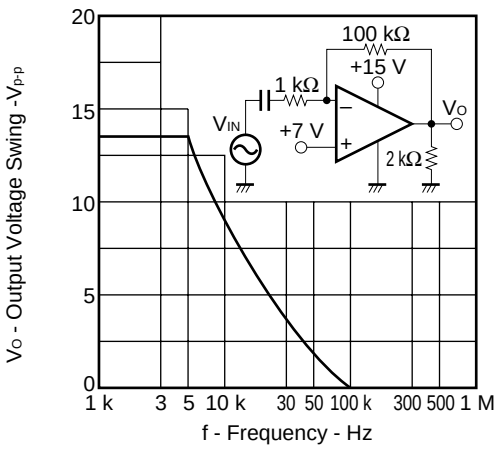
OPEN LOOP FREQUENCY RESPONSE



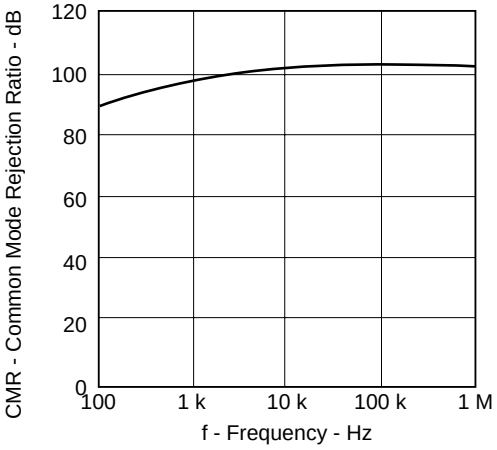
OPEN LOOP VOLTAGE GAIN



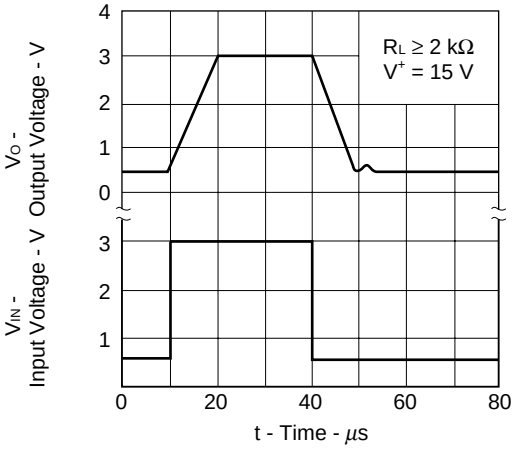
★ **LARGE SIGNAL FREQUENCY RESPONSE**



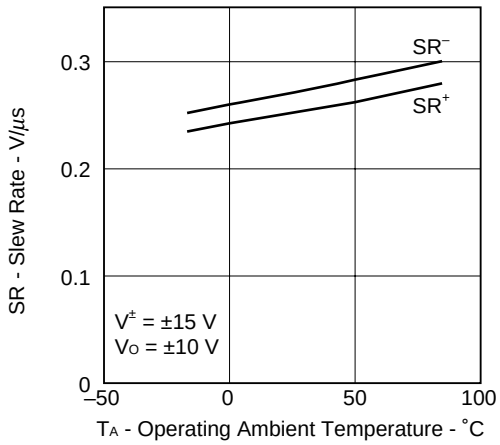
COMMON MODE REJECTION RATIO



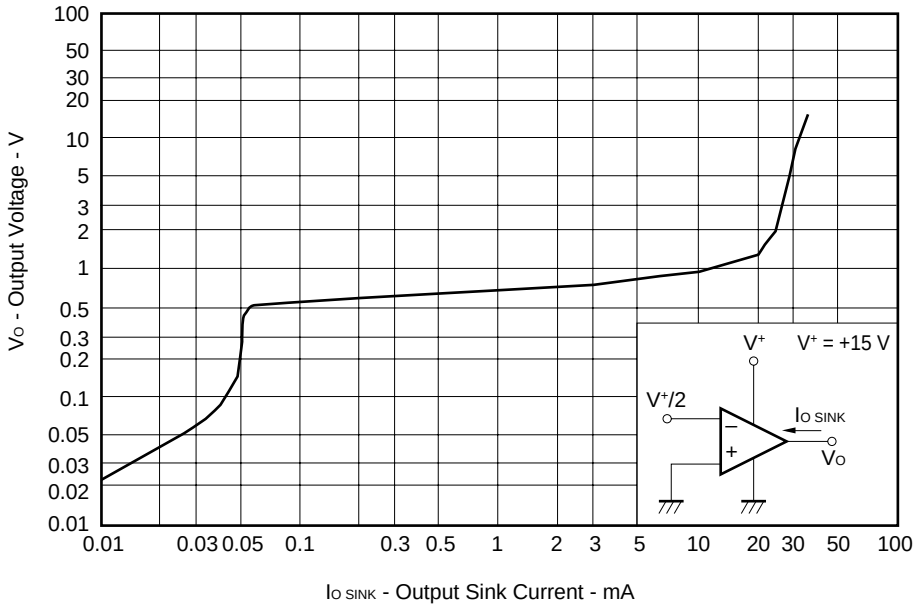
VOLTAGE FOLLOWER PULSE RESPONSE



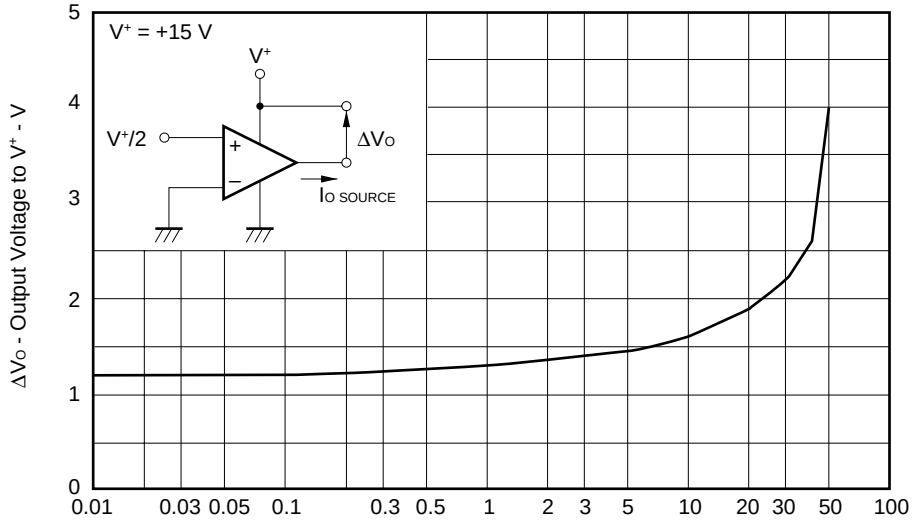
★ **SLEW RATE**



★ **OUTPUT SINK CURRENT LIMIT**

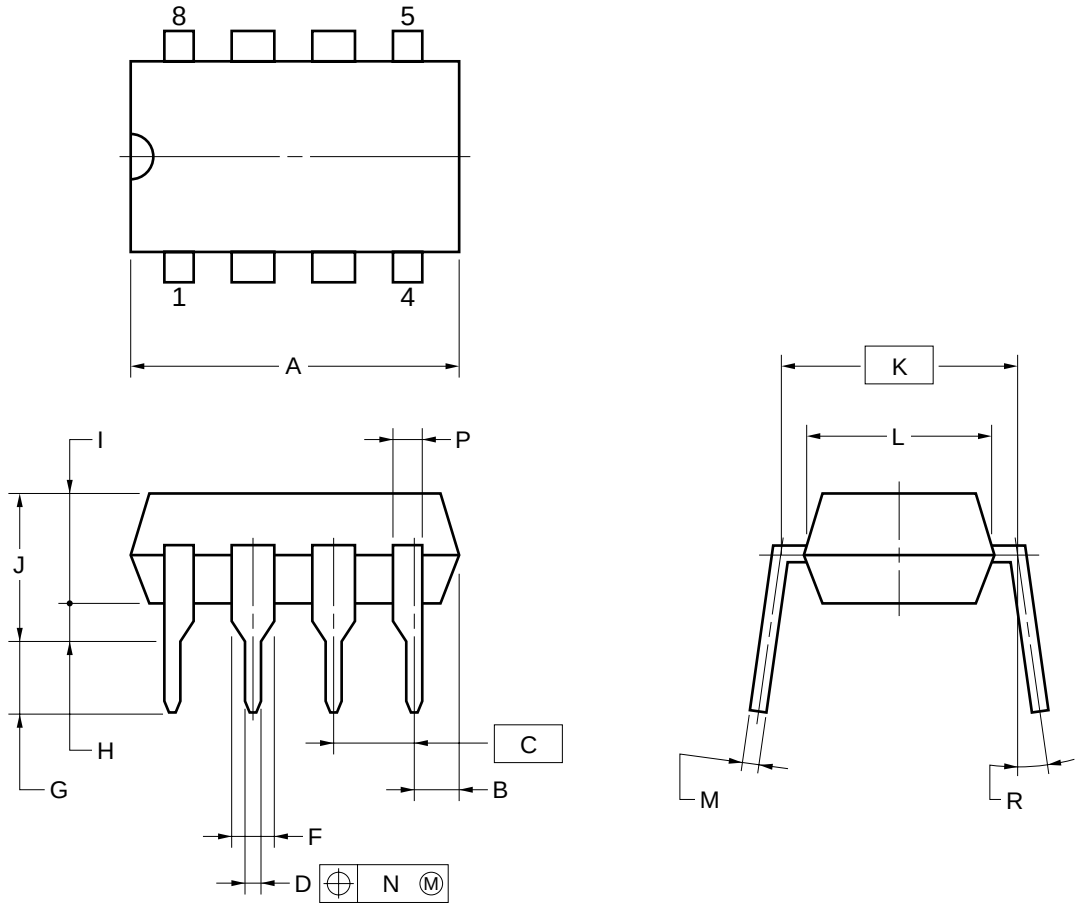


★ **OUTPUT SOURCE CURRENT LIMIT**



PACKAGE DRAWINGS

8 PIN PLASTIC DIP (300 mil)



NOTES

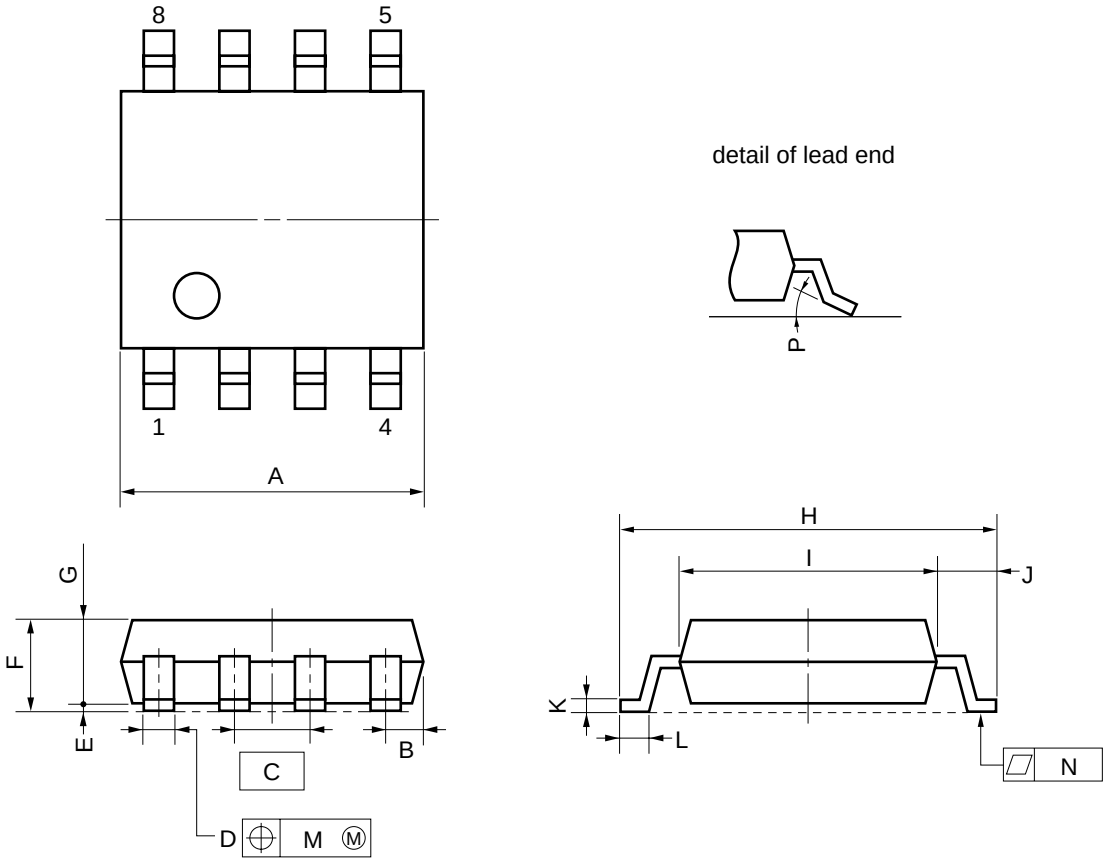
1) Each lead centerline is located within 0.25 mm (0.01 inch) of its true position (T.P.) at maximum material condition.

2) Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS	INCHES
A	10.16 MAX.	0.400 MAX.
B	1.27 MAX.	0.050 MAX.
C	2.54 (T.P.)	0.100 (T.P.)
D	0.50 ± 0.10	$0.020^{+0.004}_{-0.005}$
F	1.4 MIN.	0.055 MIN.
G	3.2 ± 0.3	0.126 ± 0.012
H	0.51 MIN.	0.020 MIN.
I	4.31 MAX.	0.170 MAX.
J	5.08 MAX.	0.200 MAX.
K	7.62 (T.P.)	0.300 (T.P.)
L	6.4	0.252
M	$0.25^{+0.10}_{-0.05}$	$0.010^{+0.004}_{-0.003}$
N	0.25	0.01
P	0.9 MIN.	0.035 MIN.
R	0~15°	0~15°

P8C-100-300B,C-1

8 PIN PLASTIC SOP (225 mil)



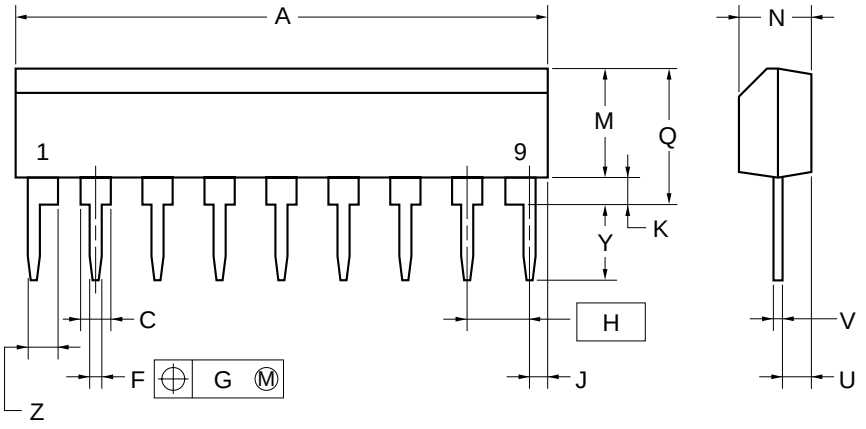
NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	5.37 MAX.	0.212 MAX.
B	0.78 MAX.	0.031 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.40^{+0.10}_{-0.05}$	$0.016^{+0.004}_{-0.003}$
E	0.1±0.1	0.004±0.004
F	1.8 MAX.	0.071 MAX.
G	1.49	0.059
H	6.5±0.3	0.256±0.012
I	4.4	0.173
J	1.1	0.043
K	$0.15^{+0.10}_{-0.05}$	$0.006^{+0.004}_{-0.002}$
L	0.6±0.2	$0.024^{+0.008}_{-0.009}$
M	0.12	0.005
N	0.10	0.004
P	$3^{\circ}{}^{+7^{\circ}}_{-3^{\circ}}$	$3^{\circ}{}^{+7^{\circ}}_{-3^{\circ}}$

S8GM-50-225B-4

9 PIN PLASTIC SLIM SIP



NOTE

Each lead centerline is located within 0.25 mm (0.01 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	22.86 MAX.	0.900 MAX.
C	1.1 MIN.	0.043 MIN.
F	0.5±0.1	$0.02^{+0.004}_{-0.005}$
G	0.25	0.010
H	2.54	0.100
J	1.27 MAX.	0.050 MAX.
K	0.51 MIN.	0.020 MIN.
M	5.08 MAX.	0.200 MAX.
N	2.8±0.2	$0.11^{+0.009}_{-0.008}$
Q	5.75 MAX.	0.227 MAX.
U	1.5 MAX.	0.059 MAX.
V	$0.25^{+0.10}_{-0.05}$	$0.01^{+0.004}_{-0.003}$
Y	3.2±0.5	0.126±0.02
Z	1.1 MIN.	0.043 MIN.

P9HA-254B-1

RECOMMENDED SOLDERING CONDITIONS

When soldering these products, it is highly recommended to observe the conditions as shown below. If other soldering processes are used, or if the soldering is performed under different conditions, please make sure to consult with our sales offices.

For more details, refer to our document "**SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL**" **(C10535E)**.

Type of Surface Mount Device

μPC358G2: 8-pin plastic SOP (225 mil)

Process	Conditions	Symbol
Infrared ray reflow	Peak temperature: 230 °C or below (Package surface temperature), Reflow time: 30 seconds or less (at 210 °C or higher), Maximum number of reflow processes: 1 time.	IR30-00-1
Vapor phase soldering	Peak temperature: 215 °C or below (Package surface temperature), Reflow time: 40 seconds or less (at 200 °C or higher), Maximum number of reflow processes: 1 time.	VP15-00-1
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or less, Maximum number of flow processes: 1 time, Pre-heating temperature: 120 °C or below (Package surface temperature).	WS60-00-1
Partial heating method	Pin temperature: 300 °C or below, Heat time: 3 seconds or less (Per each side of the device).	–

Caution Apply only one kind of soldering condition to a device, except for "partial heating method", or the device will be damaged by heat stress.

Types of Through-hole Device

μPC358C: 8-pin plastic DIP (300 mil)
μPC358HA: 9-pin slim SIP

Process	Conditions
Wave soldering (only to leads)	Solder temperature: 260 °C or below, Flow time: 10 seconds or less.
★ Partial heating method	Pin temperature: 300 °C or below, Heat time: 3 seconds or less (per each lead).

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

REFERENCE DOCUMENTS

QUALITY GRADES ON NEC SEMICONDUCTOR DEVICES	C11531E
SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL	C10535E
IC PACKAGE MANUAL	C10943X
GUIDE TO QUALITY ASSUARANCE FOR SEMICONDUCTOR DEVICES	MEI-1202
SEMICONDUCTORS SELECTION GUIDE	X10679E
NEC SEMICONDUCTOR DEVICE RELIABILITY/ QUALITY CONTROL SYSTEM - STANDARD LINEAR IC	IEI-1212

[MEMO]

[MEMO]

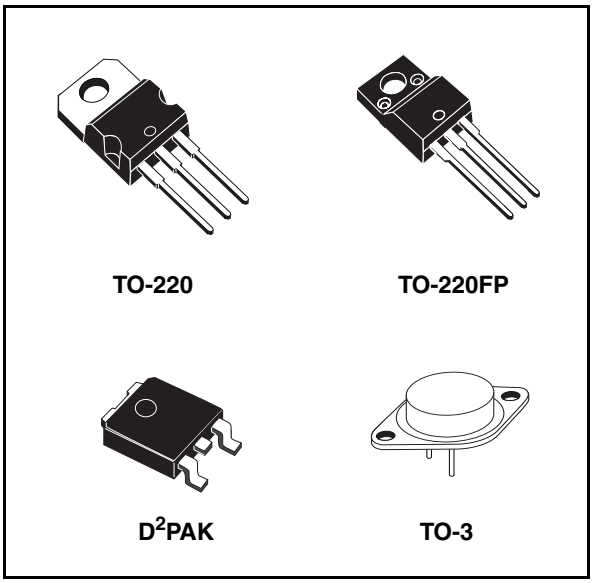
M4 96.5

L7800 series

Positive voltage regulators

Features

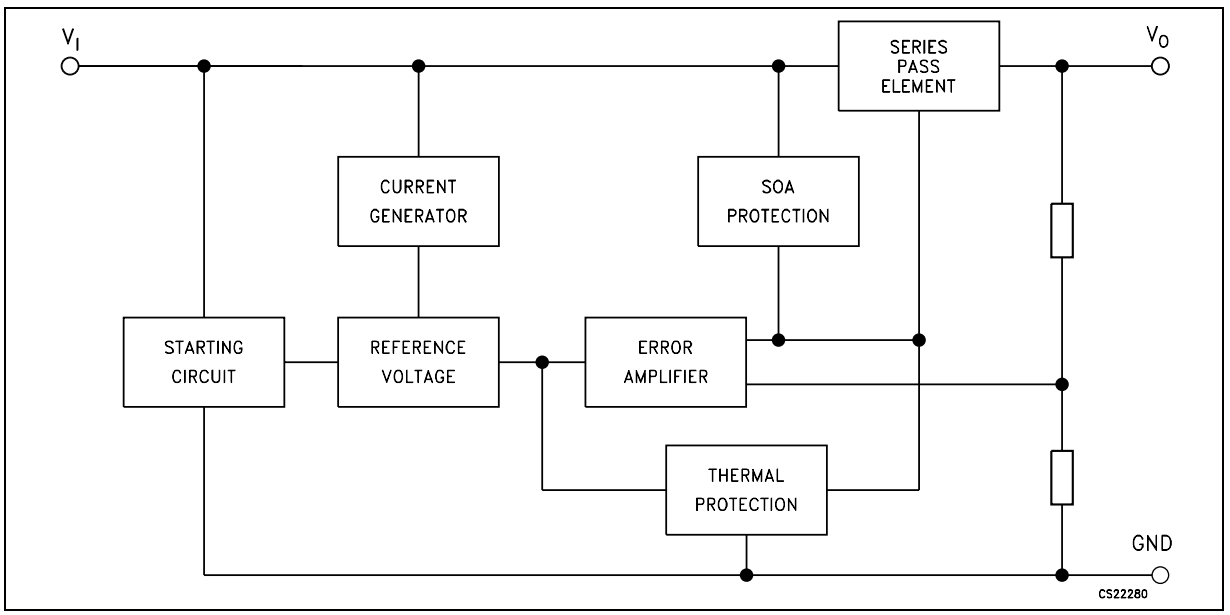
- Output current to 1.5A
- Output voltages of 5; 5.2; 6; 8; 8.5; 9; 10; 12; 15; 18; 20; 24V
- Thermal overload protection
- Short circuit protection
- Output transition SOA protection



Description

The L7800 series of three-terminal positive regulators is available in TO-220, TO-220FP, TO-3 and D^2PAK packages and several fixed output voltages, making it useful in a wide range of applications. These regulators can provide local on-card regulation, eliminating the distribution problems associated with single point regulation. Each type employs internal current limiting, thermal shut-down and safe area protection, making it essentially indestructible. If adequate heat sinking is provided, they can deliver over 1A output current. Although designed primarily as fixed voltage regulators, these devices can be used with external components to obtain adjustable voltage and currents.

Schematic diagram



Contents

1 Pin configuration

Figure 1. Pin connections (top view)

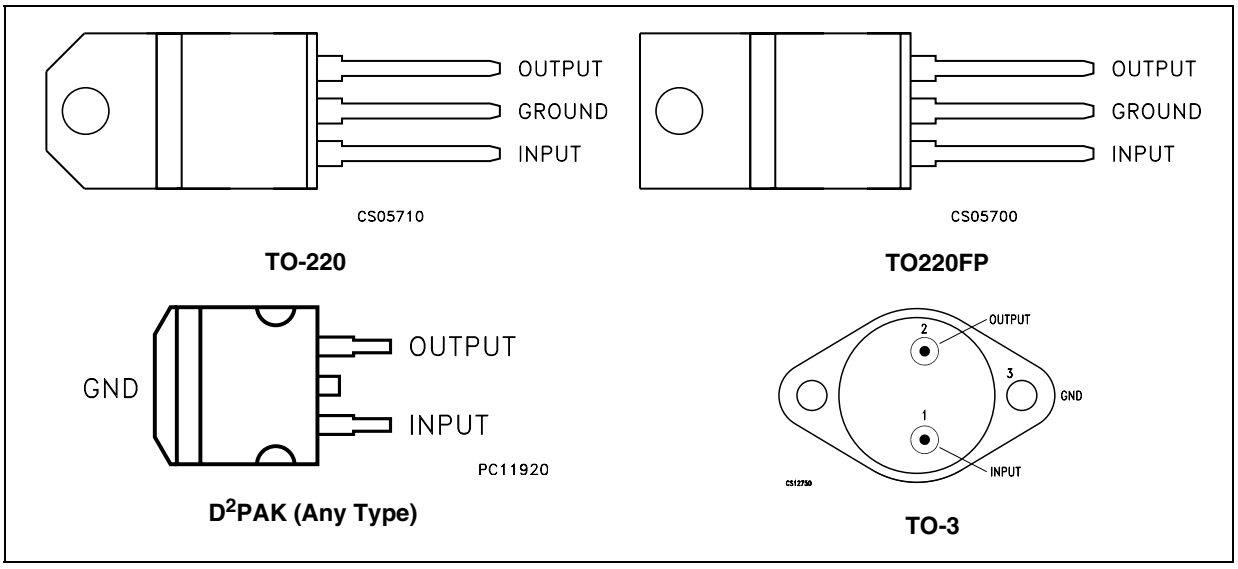
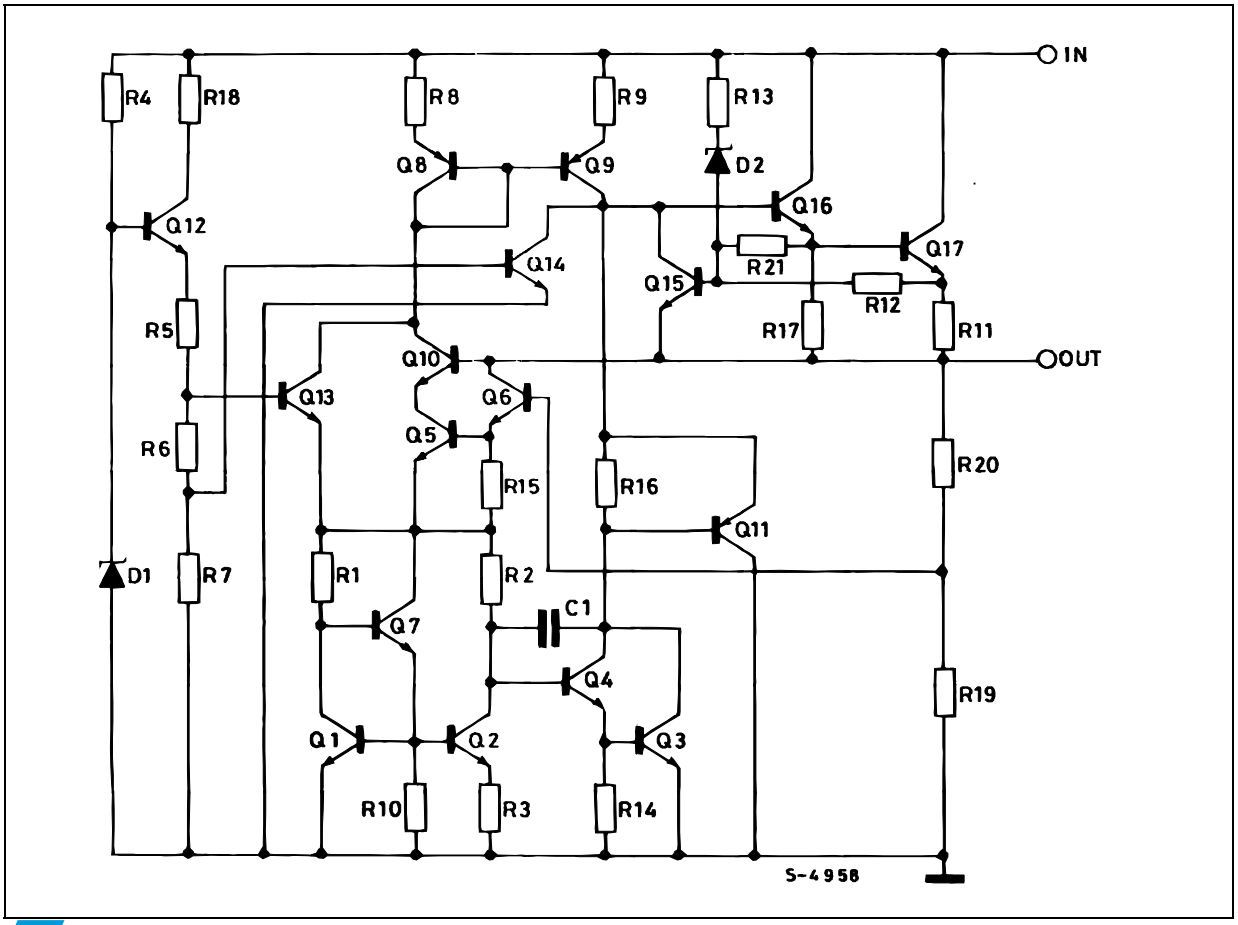


Figure 2. Schematic diagram



2 Maximum ratings

Table 1. Absolute maximum ratings

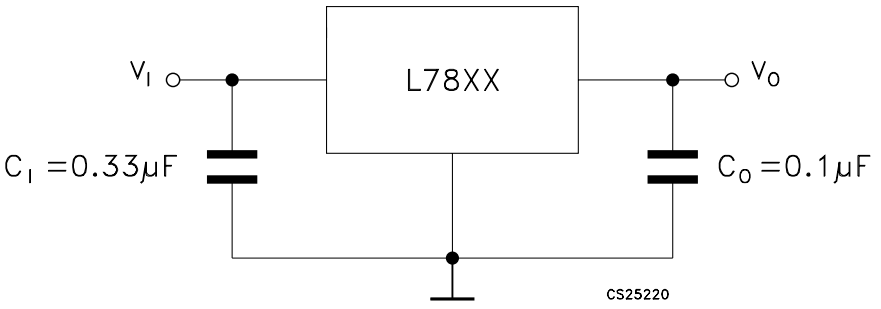
Symbol	Parameter		Value	Unit
V_I	DC Input voltage	for V_O= 5 to 18V	35	V
		for V_O= 20, 24V	40	
I_O	Output current		Internally Limited	
P_D	Power dissipation		Internally Limited	
T_{STG}	Storage temperature range		-65 to 150	°C
T_{OP}	Operating junction temperature range	for L7800	-55 to 150	°C
		for L7800C	0 to 150	

Note: Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied

Table 2. Thermal Data

Symbol	Parameter	D^2PAK	TO-220	TO-220FP	TO-3	Unit
R_{thJC}	Thermal resistance junction-case	3	5	5	4	°C/W
R_{thJA}	Thermal resistance junction-ambient	62.5	50	60	35	°C/W

Figure 3. Application circuits



3 Test circuits

Figure 4. DC Parameter

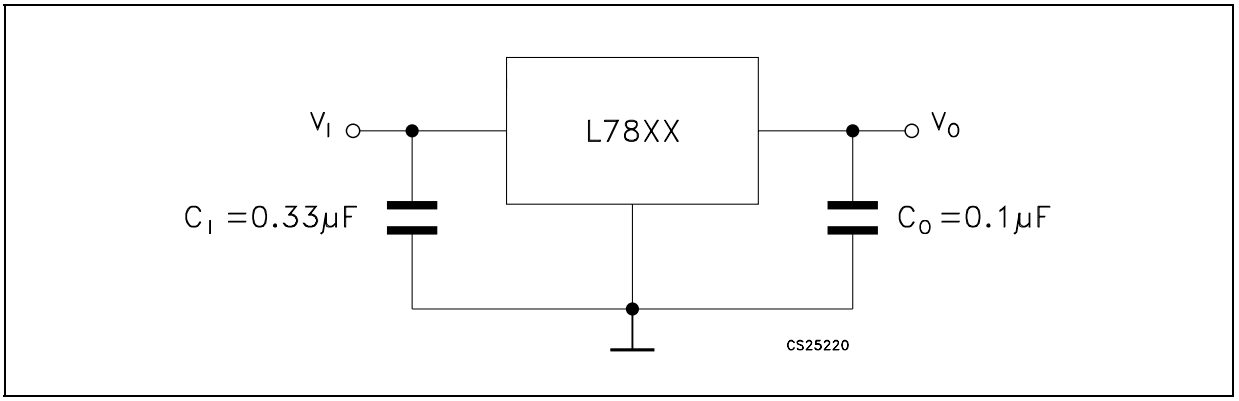


Figure 5. Load regulation

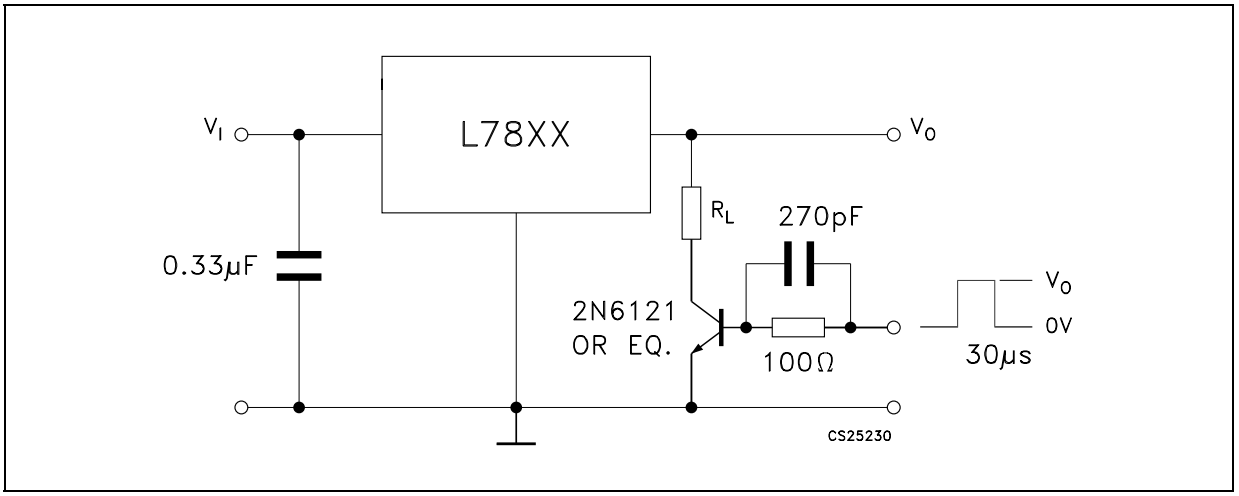
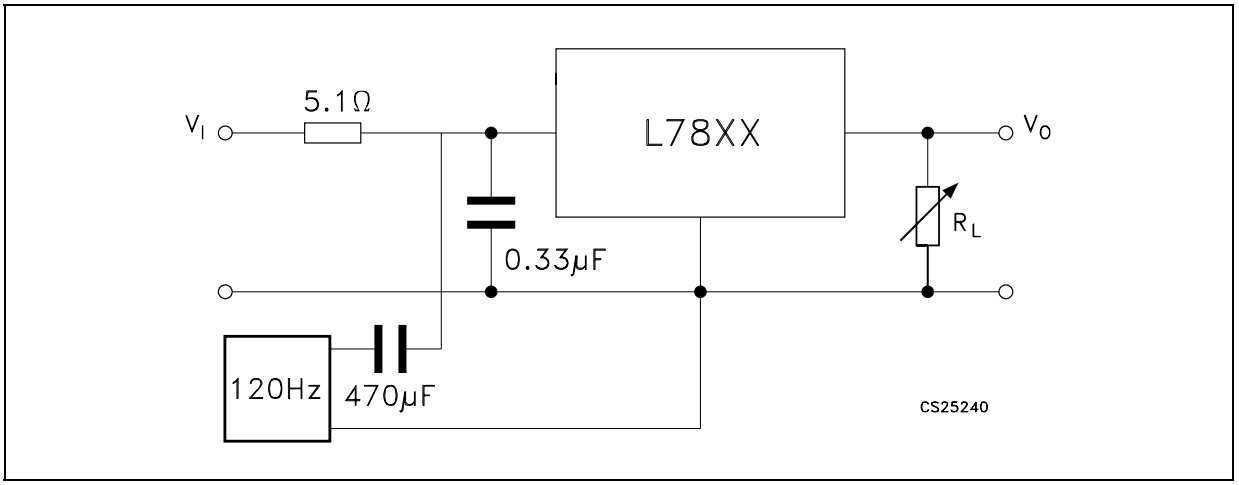


Figure 6. Ripple rejection



4 Electrical characteristics

Table 3. Electrical characteristics of L7805 (refer to the test circuits, T_J = -55 to 150°C, V_I = 10V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	4.8	5	5.2	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 8 to 20V	4.65	5	5.35	V
ΔV_O(1)	Line regulation	V_I = 7 to 25V, T_J = 25°C		3	50	mV
		V_I = 8 to 12V, T_J = 25°C		1	25	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			100	mV
		I_O = 250 to 750mA, T_J = 25°C			25	
I_d	Quiescent current	T_J = 25°C			6	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 8 to 25 V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		0.6		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C			40	µV/V_O
SVR	Supply voltage rejection	V_I = 8 to 18V, f = 120Hz	68			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2	2.5	V
R_O	Output resistance	f = 1 KHz		17		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75	1.2	A
I_{scp}	Short circuit peak current	T_J = 25°C	1.3	2.2	3.3	A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 4. Electrical characteristics of L7806 (refer to the test circuits, T_J = -55 to 150°C, V_I = 11V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	5.75	6	6.25	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 9 to 21V	5.65	6	6.35	V
ΔV_O(1)	Line regulation	V_I = 8 to 25V, T_J = 25°C			60	mV
		V_I = 9 to 13V, T_J = 25°C			30	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			100	mV
		I_O = 250 to 750mA, T_J = 25°C			30	
I_d	Quiescent current	T_J = 25°C			6	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 9 to 25V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		0.7		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C			40	µV/V_O
SVR	Supply voltage rejection	V_I = 9 to 19V, f = 120Hz	65			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2	2.5	V
R_O	Output resistance	f = 1 KHz		19		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75	1.2	A
I_{scp}	Short circuit peak current	T_J = 25°C	1.3	2.2	3.3	A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 5. Electrical characteristics of L7808 (refer to the test circuits, T_J = -55 to 150°C, V_I = 14V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	7.7	8	8.3	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 11.5 to 23V	7.6	8	8.4	V
ΔV_O(1)	Line regulation	V_I = 10.5 to 25V, T_J = 25°C			80	mV
		V_I = 11 to 17V, T_J = 25°C			40	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			100	mV
		I_O = 250 to 750mA, T_J = 25°C			40	
I_d	Quiescent current	T_J = 25°C			6	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 11.5 to 25V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C			40	µV/V_O
SVR	Supply voltage rejection	V_I = 11.5 to 21.5V, f = 120Hz	62			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2	2.5	V
R_O	Output resistance	f = 1 KHz		16		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75	1.2	A
I_{scp}	Short circuit peak current	T_J = 25°C	1.3	2.2	3.3	A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 6. Electrical characteristics of L7812 (refer to the test circuits, T_J = -55 to 150°C, V_I = 19V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	11.5	12	12.5	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 15.5 to 27V	11.4	12	12.6	V
ΔV_O(1)	Line regulation	V_I = 14.5 to 30V, T_J = 25°C			120	mV
		V_I = 16 to 22V, T_J = 25°C			60	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			100	mV
		I_O = 250 to 750mA, T_J = 25°C			60	
I_d	Quiescent current	T_J = 25°C			6	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 15 to 30V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		1.5		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C			40	µV/V_O
SVR	Supply voltage rejection	V_I = 15 to 25V, f = 120Hz	61			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2	2.5	V
R_O	Output resistance	f = 1 KHz		18		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75	1.2	A
I_{scp}	Short circuit peak current	T_J = 25°C	1.3	2.2	3.3	A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 7. Electrical characteristics of L7815 (refer to the test circuits, T_J = -55 to 150°C, V_I = 23V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	14.4	15	15.6	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 18.5 to 30V	14.25	15	15.75	V
ΔV_O(1)	Line regulation	V_I = 17.5 to 30V, T_J = 25°C			150	mV
		V_I = 20 to 26V, T_J = 25°C			75	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			150	mV
		I_O = 250 to 750mA, T_J = 25°C			75	
I_d	Quiescent current	T_J = 25°C			6	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 18.5 to 30V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		1.8		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C			40	µV/V_O
SVR	Supply voltage rejection	V_I = 18.5 to 28.5V, f = 120Hz	60			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2	2.5	V
R_O	Output resistance	f = 1 KHz		19		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75	1.2	A
I_{scp}	Short circuit peak current	T_J = 25°C	1.3	2.2	3.3	A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 8. Electrical characteristics of L7818 (refer to the test circuits, T_J = -55 to 150°C, V_I = 26V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	17.3	18	18.7	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 22 to 33V	17.1	18	18.9	V
ΔV_O(1)	Line regulation	V_I = 21 to 33V, T_J = 25°C			180	mV
		V_I = 24 to 30V, T_J = 25°C			90	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			180	mV
		I_O = 250 to 750mA, T_J = 25°C			90	
I_d	Quiescent current	T_J = 25°C			6	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 22 to 33V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		2.3		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C			40	µV/V_O
SVR	Supply voltage rejection	V_I = 22 to 32V, f = 120Hz	59			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2	2.5	V
R_O	Output resistance	f = 1 KHz		22		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75	1.2	A
I_{scp}	Short circuit peak current	T_J = 25°C	1.3	2.2	3.3	A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 9. Electrical characteristics of L7820 (refer to the test circuits, T_J = -55 to 150°C, V_I = 28V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	19.2	20	20.8	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 24 to 35V	19	20	21	V
ΔV_O(1)	Line regulation	V_I = 22.5 to 35V, T_J = 25°C			200	mV
		V_I = 26 to 32V, T_J = 25°C			100	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			200	mV
		I_O = 250 to 750mA, T_J = 25°C			100	
I_d	Quiescent current	T_J = 25°C			6	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 24 to 35V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		2.5		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C			40	µV/V_O
SVR	Supply voltage rejection	V_I = 24 to 35V, f = 120Hz	58			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2	2.5	V
R_O	Output resistance	f = 1 KHz		24		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75	1.2	A
I_{scp}	Short circuit peak current	T_J = 25°C	1.3	2.2	3.3	A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 10. Electrical characteristics of L7824 (refer to the test circuits, T_J = -55 to 150°C, V_I = 33V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	23	24	25	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 28 to 38V	22.8	24	25.2	V
ΔV_O(1)	Line regulation	V_I = 27 to 38V, T_J = 25°C			240	mV
		V_I = 30 to 36V, T_J = 25°C			120	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			240	mV
		I_O = 250 to 750mA, T_J = 25°C			120	
I_d	Quiescent current	T_J = 25°C			6	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 28 to 38V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		3		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C			40	µV/V_O
SVR	Supply voltage rejection	V_I = 28 to 38V, f = 120Hz	56			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2	2.5	V
R_O	Output resistance	f = 1 KHz		28		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75	1.2	A
I_{scp}	Short circuit peak current	T_J = 25°C	1.3	2.2	3.3	A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 11. Electrical characteristics of L7805C (refer to the test circuits, T_J = -55 to 150°C, V_I = 10V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	4.8	5	5.2	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 7 to 20V	4.75	5	5.25	V
ΔV_O(1)	Line regulation	V_I = 7 to 25V, T_J = 25°C		3	100	mV
		V_I = 8 to 12V, T_J = 25°C		1	50	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			100	mV
		I_O = 250 to 750mA, T_J = 25°C			50	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 7 to 25 V			0.8	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1.1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		40		µV/V_O
SVR	Supply voltage rejection	V_I = 8 to 18V, f = 120Hz	62			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		17		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 12. Electrical characteristics of L7852C (refer to the test circuits, T_J = -55 to 150°C, V_I = 10V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	5.0	5.2	5.4	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 8 to 20V	4.95	5.2	5.45	V
ΔV_O(1)	Line regulation	V_I = 7 to 25V, T_J = 25°C		3	105	mV
		V_I = 8 to 12V, T_J = 25°C		1	52	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			105	mV
		I_O = 250 to 750mA, T_J = 25°C			52	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 7 to 25 V			1.3	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		42		µV/V_O
SVR	Supply voltage rejection	V_I = 8 to 18V, f = 120Hz	61			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		17		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.75		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 13. Electrical characteristics of L7806C (refer to the test circuits, T_J = -55 to 150°C, V_I = 11V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	5.75	6	6.25	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 8 to 21V	5.7	6	6.3	V
ΔV_O(1)	Line regulation	V_I = 8 to 25V, T_J = 25°C			120	mV
		V_I = 9 to 13V, T_J = 25°C			60	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			120	mV
		I_O = 250 to 750mA, T_J = 25°C			60	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 8 to 25V			1.3	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-0.8		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		45		µV/V_O
SVR	Supply voltage rejection	V_I = 9 to 19V, f = 120Hz	59			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		19		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.55		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 14. Electrical characteristics of L7808C (refer to the test circuits, T_J = -55 to 150°C, V_I = 14V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	7.7	8	8.3	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 10.5 to 25V	7.6	8	8.4	V
ΔV_O(1)	Line regulation	V_I = 10.5 to 25V, T_J = 25°C			160	mV
		V_I = 11 to 17V, T_J = 25°C			80	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			160	mV
		I_O = 250 to 750mA, T_J = 25°C			80	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 10.5 to 25V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-0.8		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		52		µV/V_O
SVR	Supply voltage rejection	V_I = 11.5 to 21.5V, f = 120Hz	56			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		16		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.45		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 15. Electrical characteristics of L7885C (refer to the test circuits, T_J = -55 to 150°C, V_I = 14.5V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	8.2	8.5	8.8	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 11 to 26V	8.1	8.5	8.9	V
ΔV_O(1)	Line regulation	V_I = 11 to 27V, T_J = 25°C			160	mV
		V_I = 11.5 to 17.5V, T_J = 25°C			80	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			160	mV
		I_O = 250 to 750mA, T_J = 25°C			80	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 11 to 27V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-0.8		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		55		µV/V_O
SVR	Supply voltage rejection	V_I = 12 to 22V, f = 120Hz	56			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		16		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.45		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 16. Electrical characteristics of L7809C (refer to the test circuits, T_J = -55 to 150°C, V_I = 15V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	8.64	9	9.36	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 11.5 to 26V	8.55	9	9.45	V
ΔV_O(1)	Line regulation	V_I = 11.5 to 26V, T_J = 25°C			180	mV
		V_I = 12 to 18V, T_J = 25°C			90	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			180	mV
		I_O = 250 to 750mA, T_J = 25°C			90	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 11.5 to 26V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		70		µV/V_O
SVR	Supply voltage rejection	V_I = 12 to 23V, f = 120Hz	55			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		17		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.40		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 17. Electrical characteristics of L7810C (refer to the test circuits, T_J = -55 to 150°C, V_I = 15V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	9.6	10	10.4	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 12.5 to 26V	9.5	10	10.5	V
ΔV_O(1)	Line regulation	V_I = 12.5 to 26V, T_J = 25°C			200	mV
		V_I = 13.5 to 19V, T_J = 25°C			100	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			200	mV
		I_O = 250 to 750mA, T_J = 25°C			100	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 12.5 to 26V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		70		µV/V_O
SVR	Supply voltage rejection	V_I = 13 to 23V, f = 120Hz	55			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		17		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.40		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 18. Electrical characteristics of L7812C (refer to the test circuits, T_J = -55 to 150°C, V_I = 19V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	11.5	12	12.5	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 14.5 to 27V	11.4	12	12.6	V
ΔV_O(1)	Line regulation	V_I = 14.5 to 30V, T_J = 25°C			240	mV
		V_I = 16 to 22V, T_J = 25°C			120	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			240	mV
		I_O = 250 to 750mA, T_J = 25°C			120	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 14.5 to 30V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		75		µV/V_O
SVR	Supply voltage rejection	V_I = 15 to 25V, f = 120Hz	55			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		18		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.35		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 19. Electrical characteristics of L7815C (refer to the test circuits, T_J = -55 to 150°C, V_I = 23V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	14.5	15	15.6	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 17.5 to 30V	14.25	15	15.75	V
ΔV_O(1)	Line regulation	V_I = 17.5 to 30V, T_J = 25°C			300	mV
		V_I = 20 to 26V, T_J = 25°C			150	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			300	mV
		I_O = 250 to 750mA, T_J = 25°C			150	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 17.5 to 30V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		90		µV/V_O
SVR	Supply voltage rejection	V_I = 18.5 to 28.5V, f = 120Hz	54			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		19		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.23		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.2		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 20. Electrical characteristics of L7818C (refer to the test circuits, T_J = -55 to 150°C, V_I = 26V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	17.3	18	18.7	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 21 to 33V	17.1	18	18.9	V
ΔV_O(1)	Line regulation	V_I = 21 to 33V, T_J = 25°C			360	mV
		V_I = 24 to 30V, T_J = 25°C			180	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			360	mV
		I_O = 250 to 750mA, T_J = 25°C			180	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 21 to 33V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		110		µV/V_O
SVR	Supply voltage rejection	V_I = 22 to 32V, f = 120Hz	53			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		22		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.20		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.1		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 21. Electrical characteristics of L7820C (refer to the test circuits, T_J = -55 to 150°C, V_I = 28V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	19.2	20	20.8	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 23 to 35V	19	20	21	V
ΔV_O(1)	Line regulation	V_I = 22.5 to 35V, T_J = 25°C			400	mV
		V_I = 26 to 32V, T_J = 25°C			200	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			400	mV
		I_O = 250 to 750mA, T_J = 25°C			200	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 23 to 35V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		150		µV/V_O
SVR	Supply voltage rejection	V_I = 24 to 35V, f = 120Hz	52			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		24		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.18		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.1		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 22. Electrical characteristics of L7824C (refer to the test circuits, T_J = -55 to 150°C, V_I = 33V, I_O = 500 mA, C_I = 0.33 µF, C_O = 0.1 µF unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_O	Output voltage	T_J = 25°C	23	24	25	V
V_O	Output voltage	I_O = 5mA to 1A, $P_O \leq$15W V_I = 27 to 38V	22.8	24	25.2	V
ΔV_O(1)	Line regulation	V_I = 27 to 38V, T_J = 25°C			480	mV
		V_I = 30 to 36V, T_J = 25°C			240	
ΔV_O(1)	Load regulation	I_O = 5 mA to 1.5A, T_J = 25°C			480	mV
		I_O = 250 to 750mA, T_J = 25°C			240	
I_d	Quiescent current	T_J = 25°C			8	mA
ΔI_d	Quiescent current change	I_O = 5mA to 1A			0.5	mA
		V_I = 27 to 38V			1	
$\Delta V_O/\Delta T$	Output voltage drift	I_O = 5mA		-1.5		mV/°C
eN	Output noise voltage	B =10Hz to 100KHz, T_J = 25°C		170		µV/V_O
SVR	Supply voltage rejection	V_I = 28 to 38V, f = 120Hz	50			dB
V_d	Dropout voltage	I_O = 1A, T_J = 25°C		2		V
R_O	Output resistance	f = 1 KHz		28		mΩ
I_{sc}	Short circuit current	V_I = 35V, T_J = 25°C		0.15		A
I_{scp}	Short circuit peak current	T_J = 25°C		2.1		A

1. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

5 Typical performance

Figure 7. Dropout voltage vs junction temperature

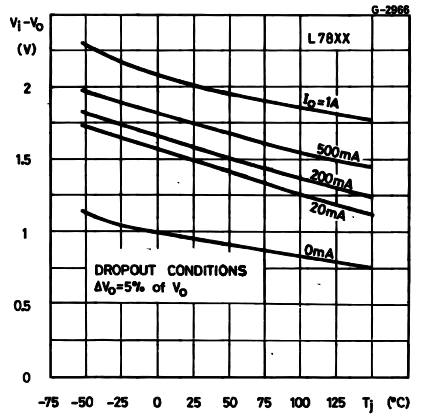


Figure 8. Peak output current vs input/output differential voltage

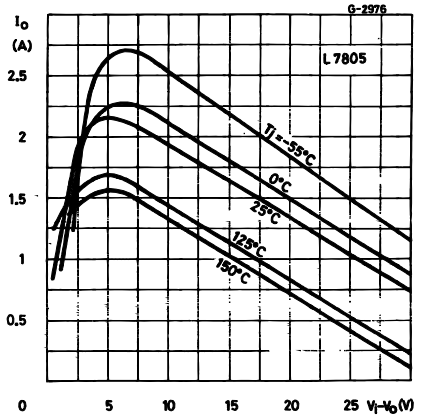


Figure 9. Supply voltage rejection vs frequency

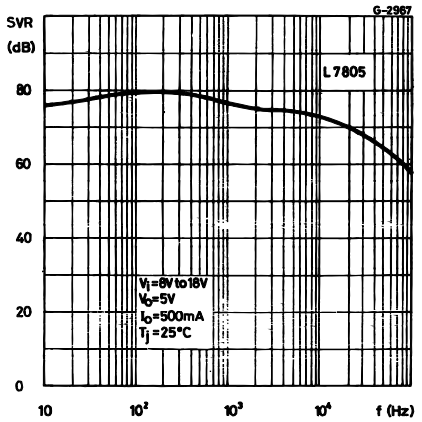


Figure 10. Output voltage vs junction temperature

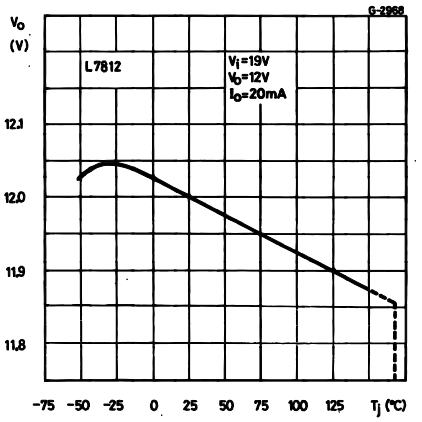


Figure 11. Output impedance vs frequency

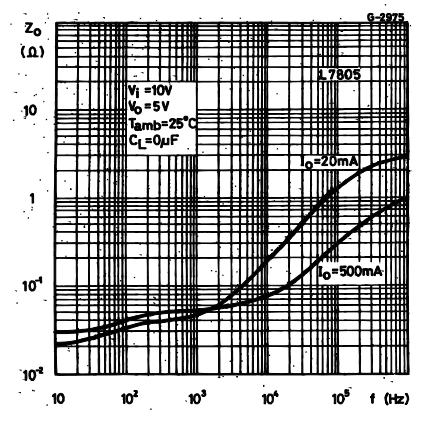


Figure 12. Quiescent current vs junction temp.

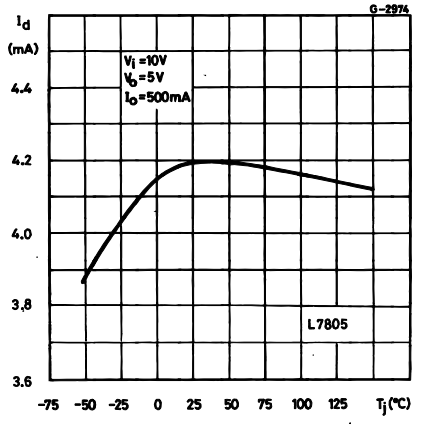


Figure 13. Load transient response

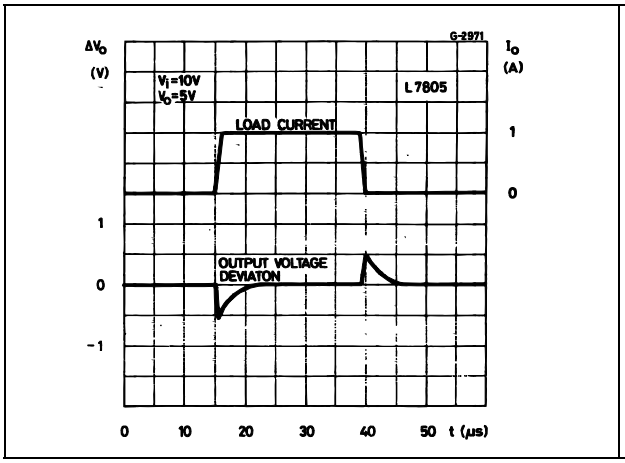


Figure 14. Line transient response

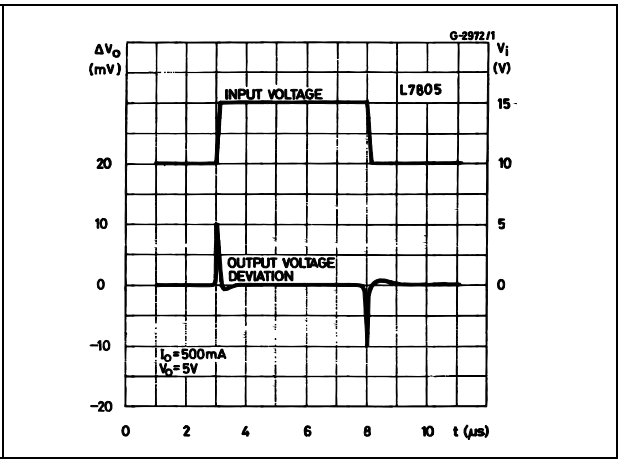


Figure 15. Quiescent current vs input voltage

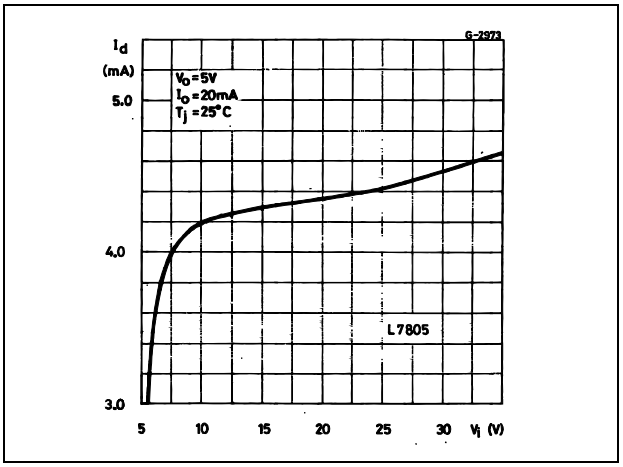
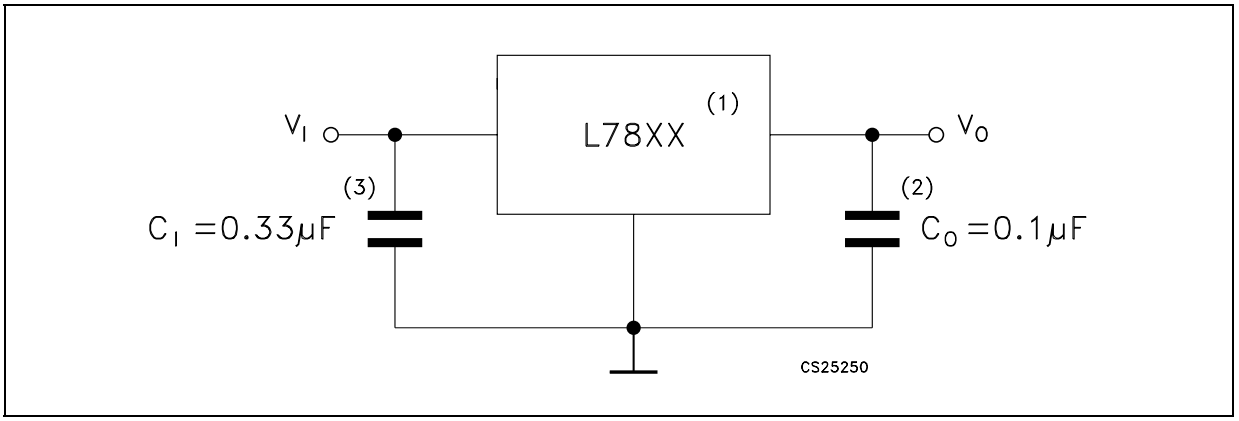


Figure 16. Fixed output regulator



1. To specify an output voltage, substitute voltage value for "XX".
2. Although no output capacitor is need for stability, it does improve transient response.
3. Required if regulator is locate an appreciable distance from power supply filter.

Figure 17. Current regulator

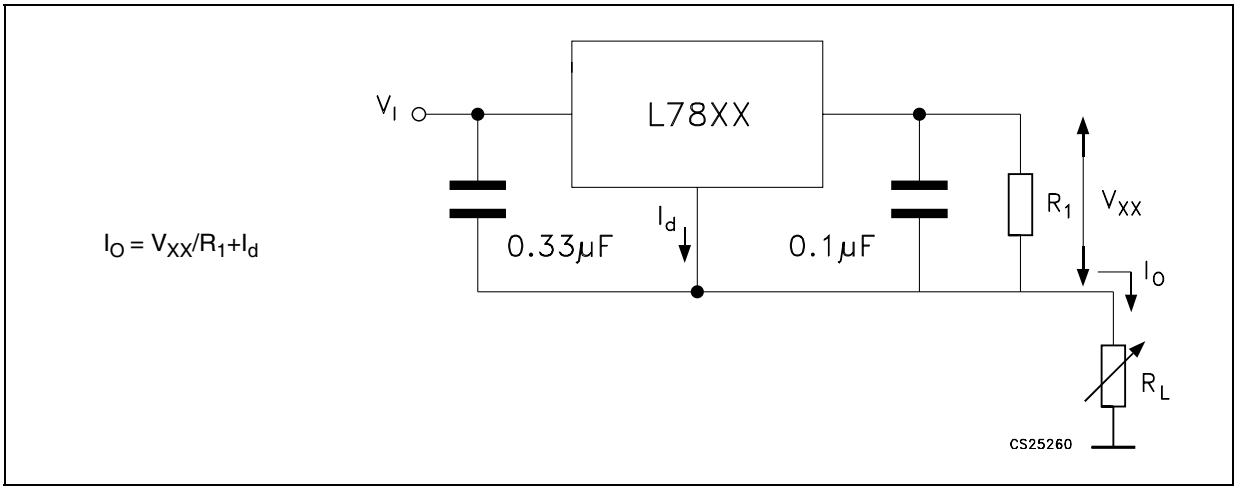


Figure 18. Circuit for increasing output voltage

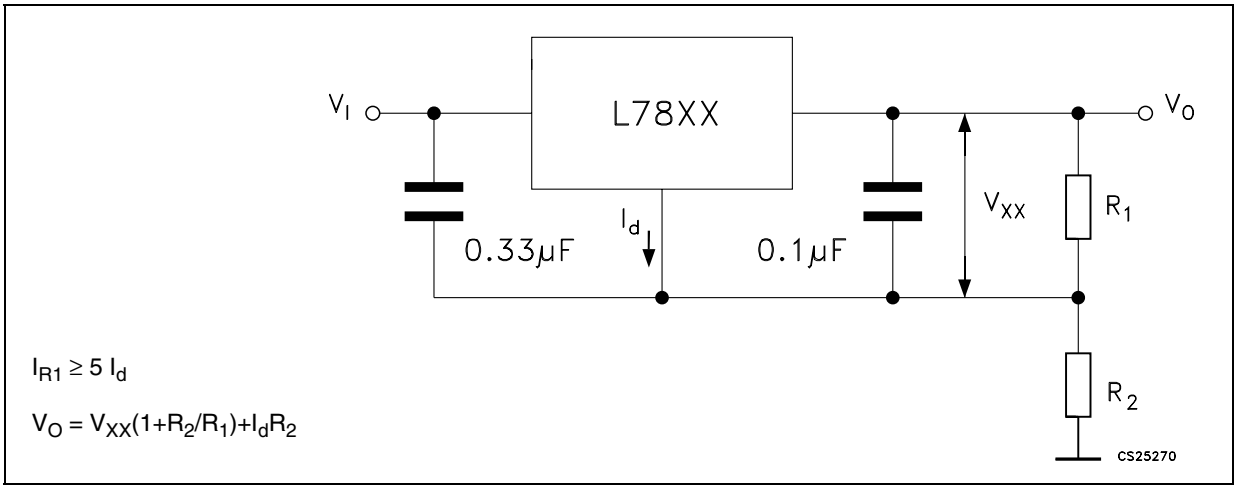


Figure 19. Adjustable output regulator (7 to 30V)

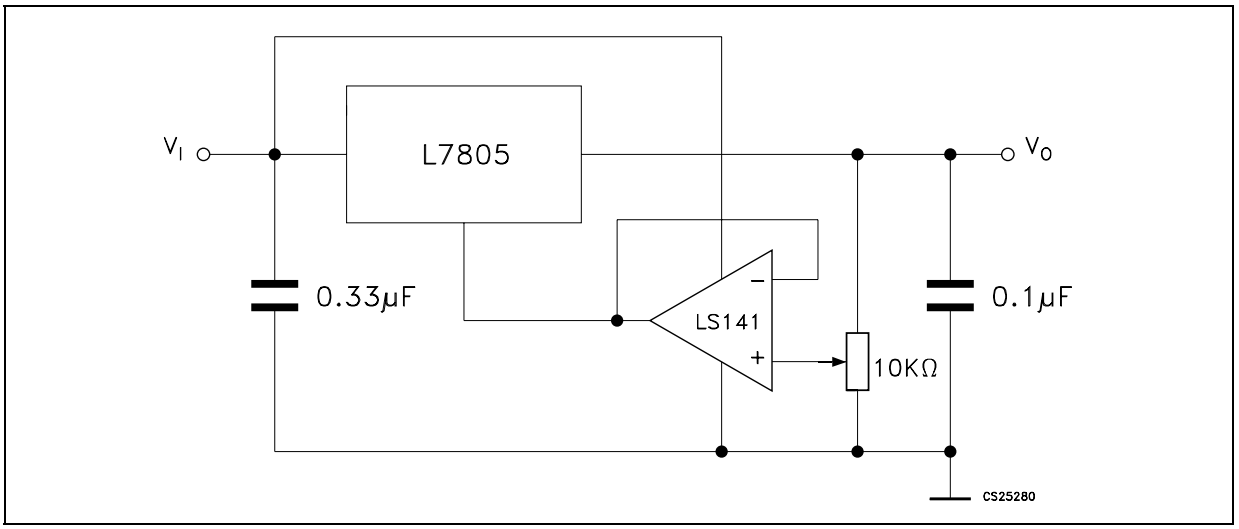


Figure 20. 0.5 to 10V Regulator

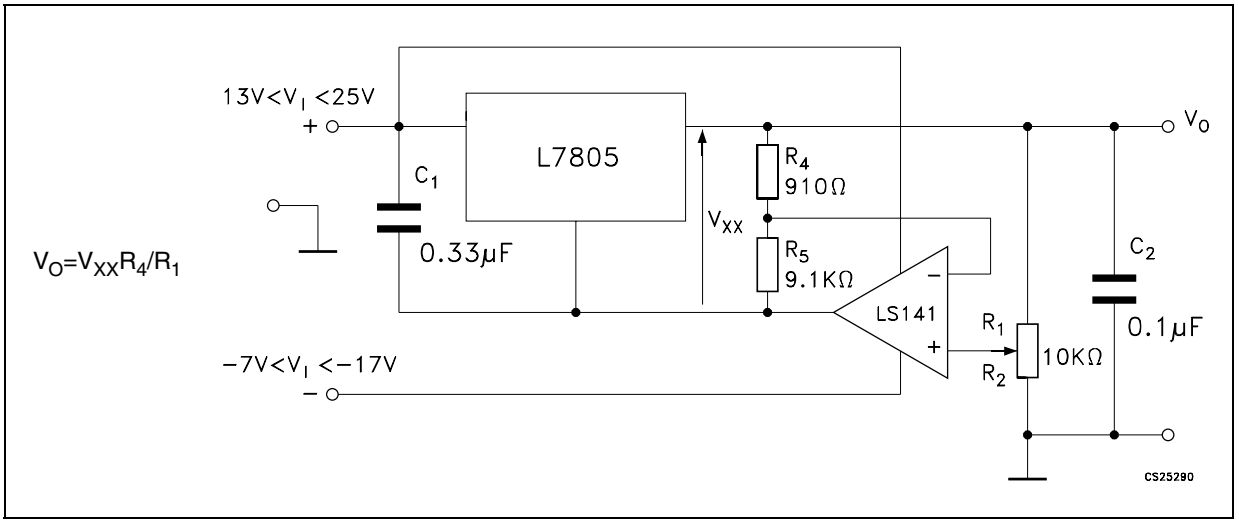


Figure 21. High current voltage regulator

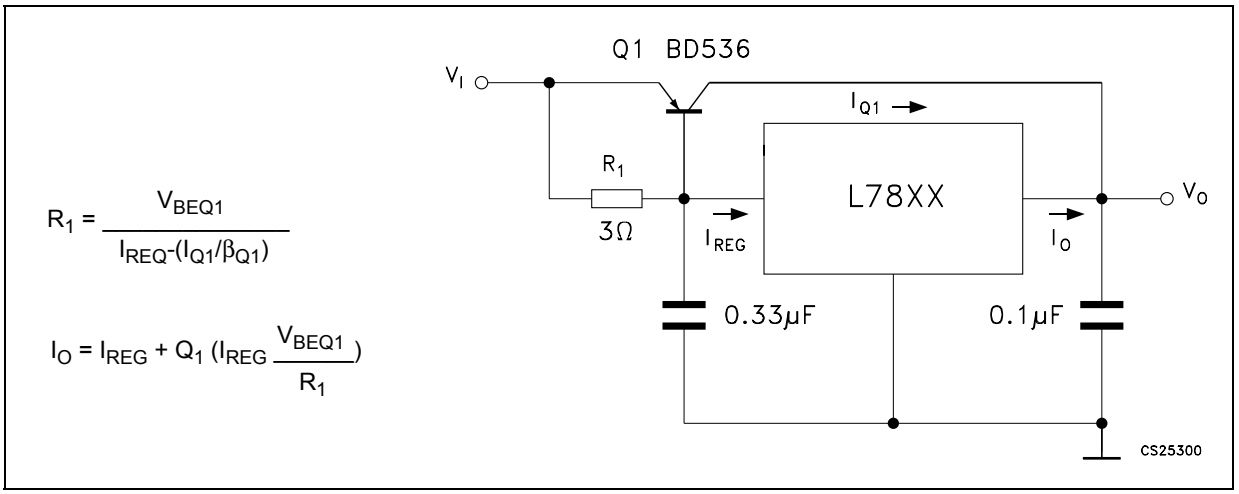


Figure 22. High output current with short circuit protection

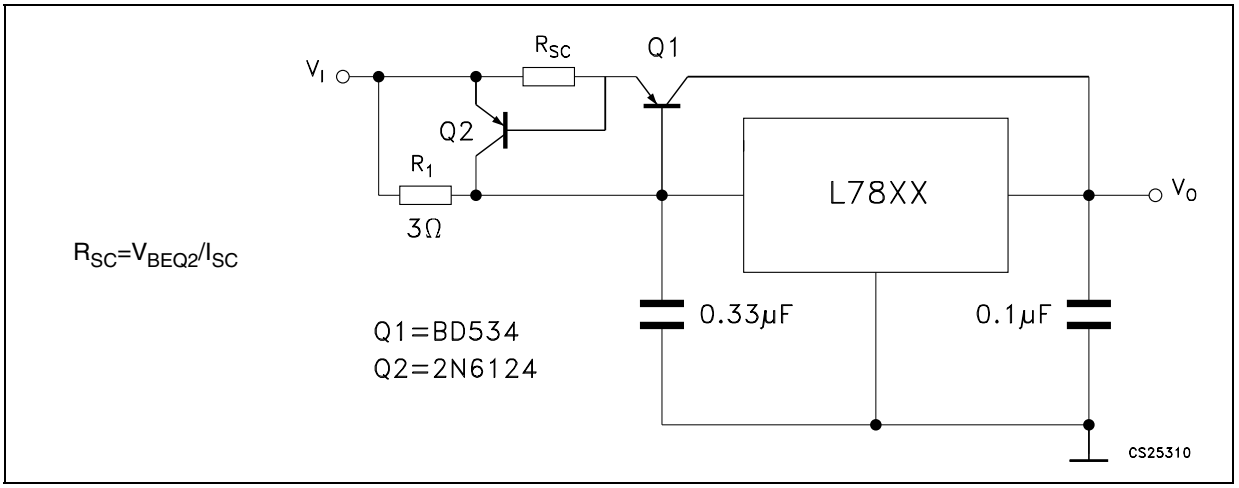


Figure 23. Tracking voltage regulator

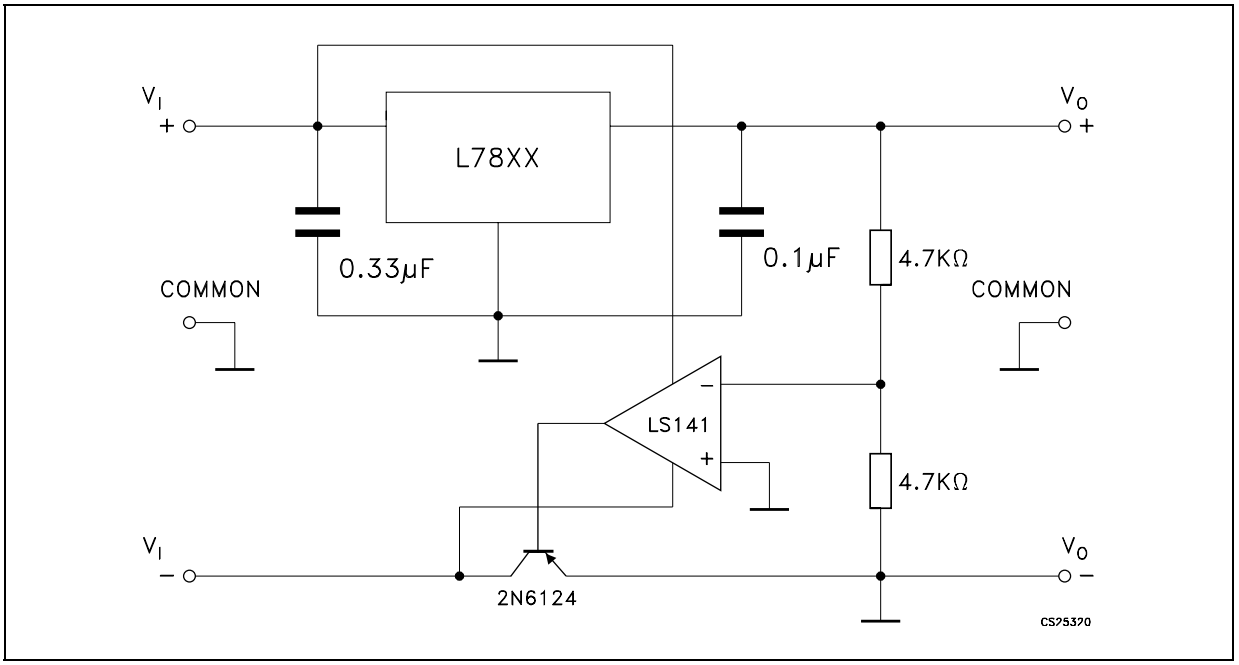
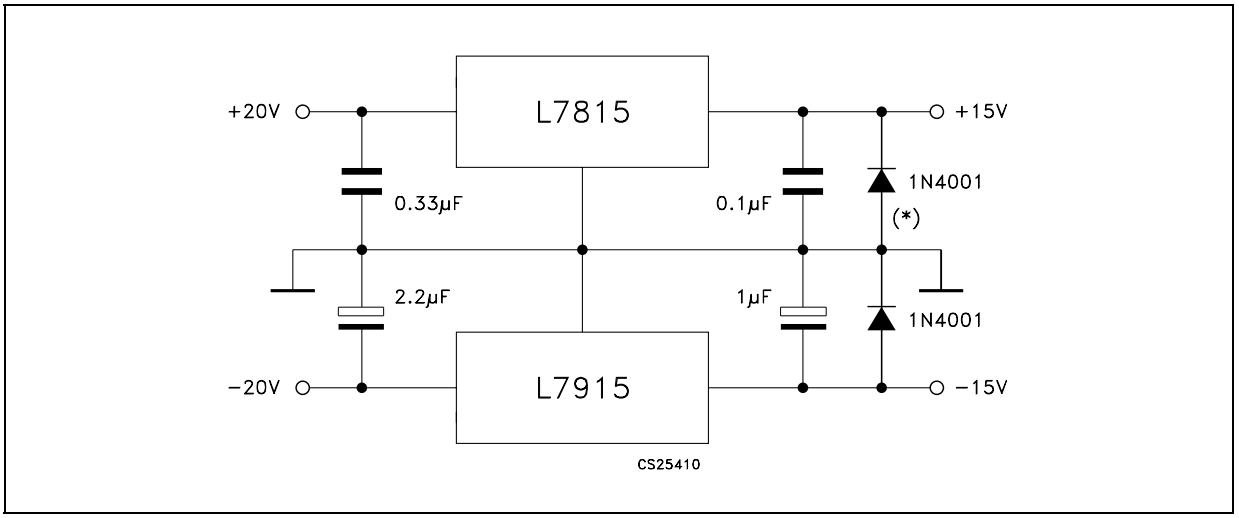


Figure 24. Split power supply (± 15V - 1 A)



* Against potential latch-up problems.

Figure 25. Negative output voltage circuit

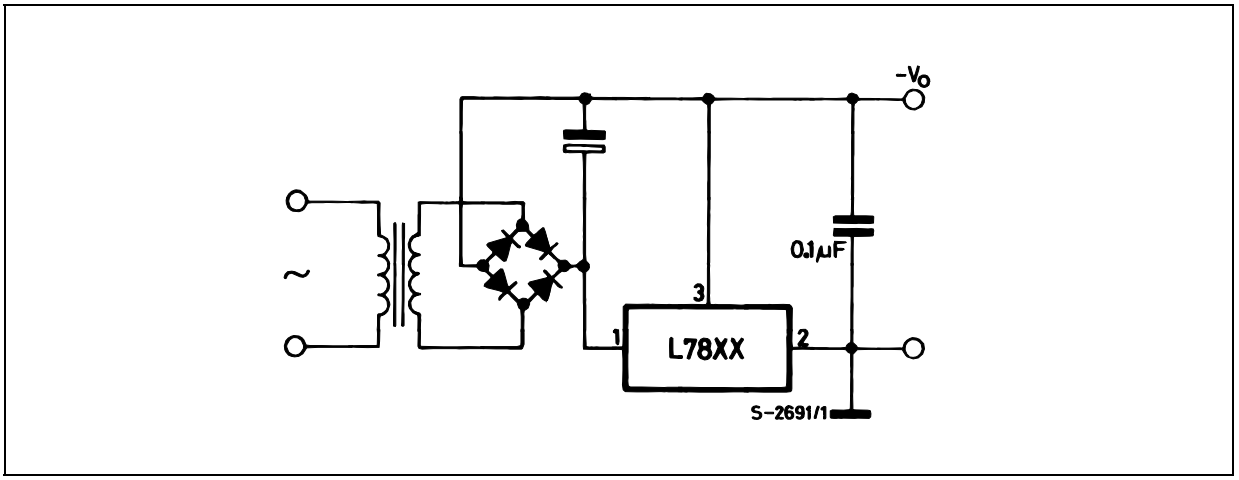


Figure 26. Switching regulator

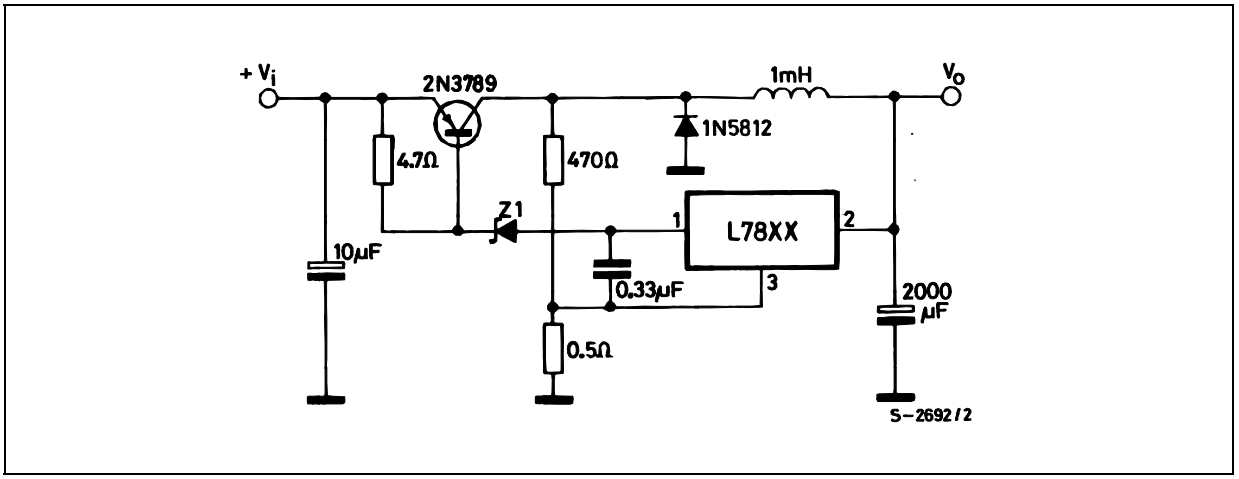


Figure 27. High input voltage circuit

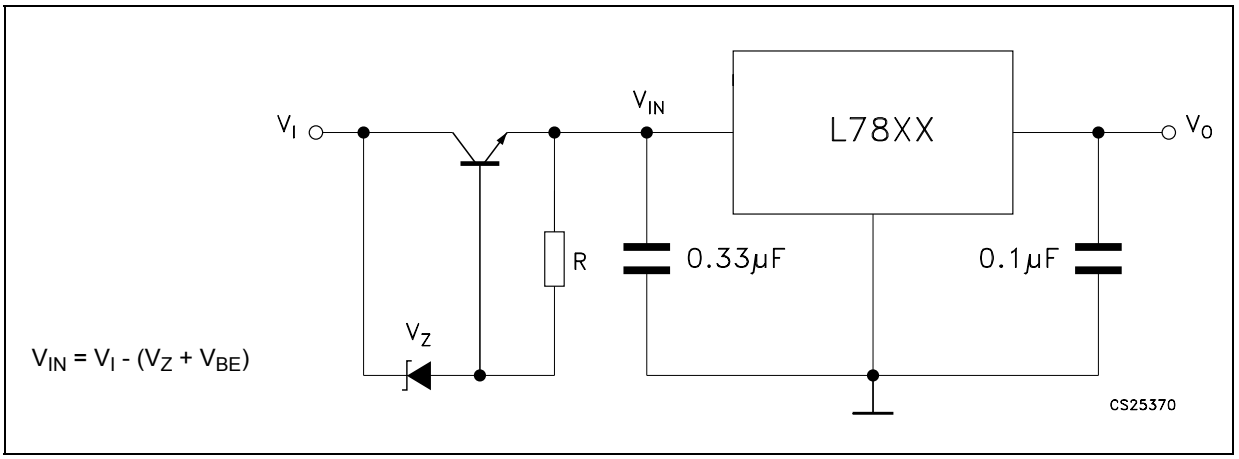


Figure 28. High input voltage circuit

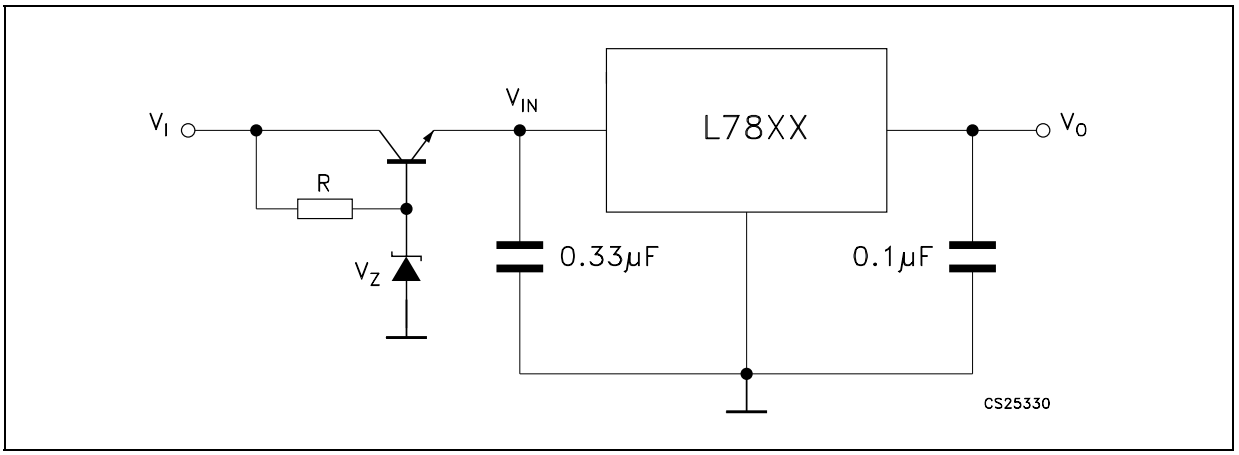


Figure 29. High output voltage regulator

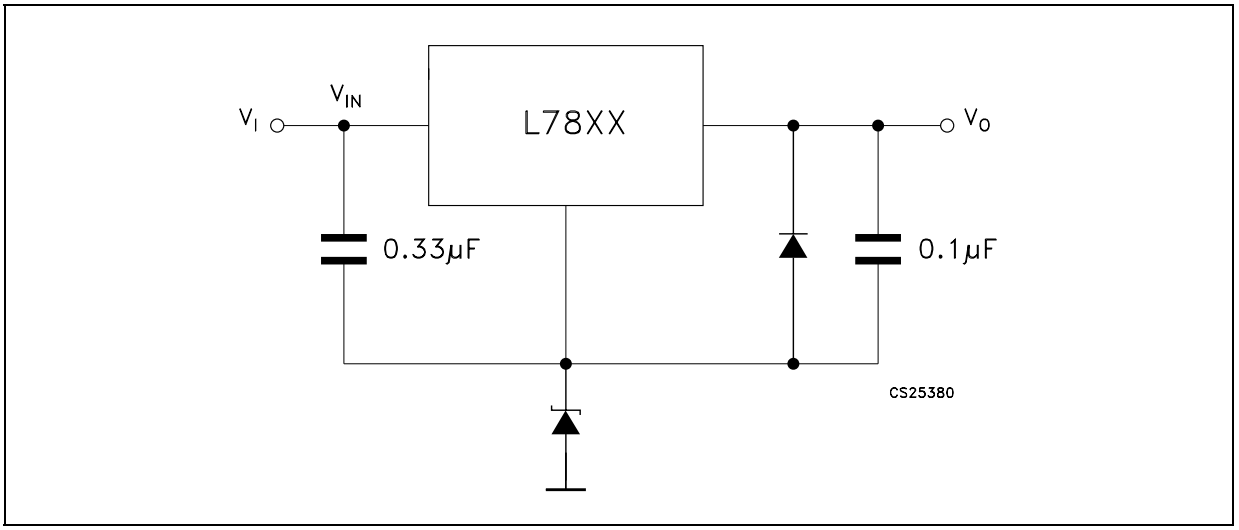


Figure 30. High input and output voltage

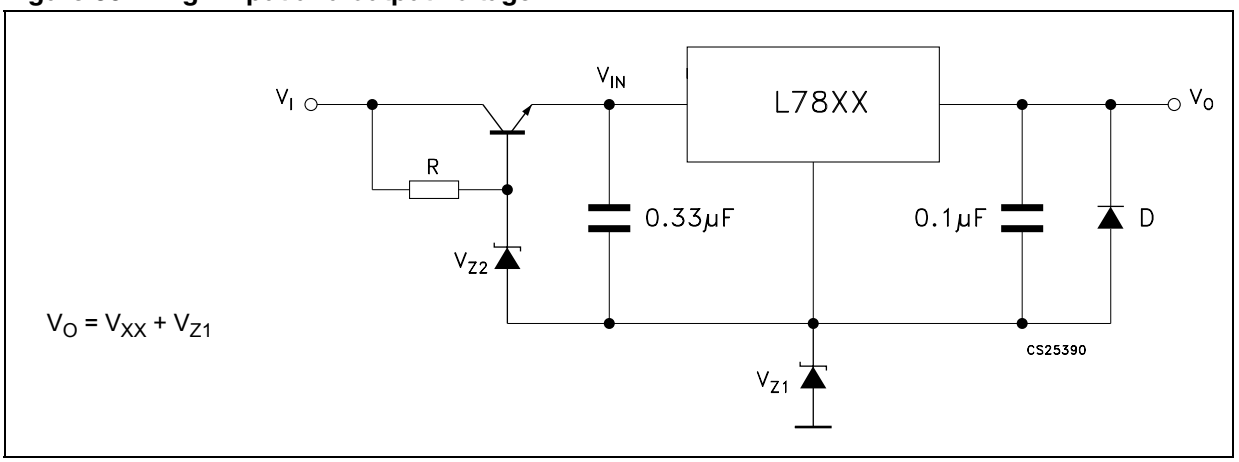


Figure 31. Reducing power dissipation with dropping resistor

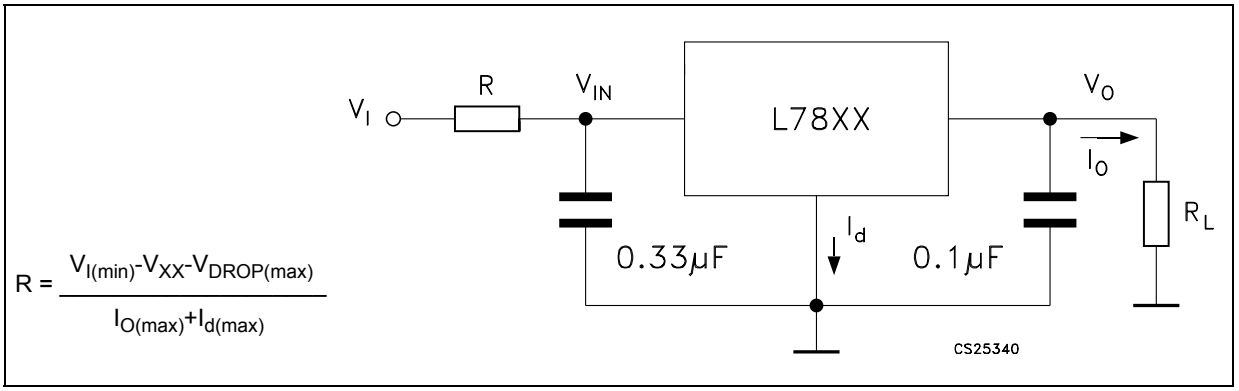


Figure 32. Remote shutdown

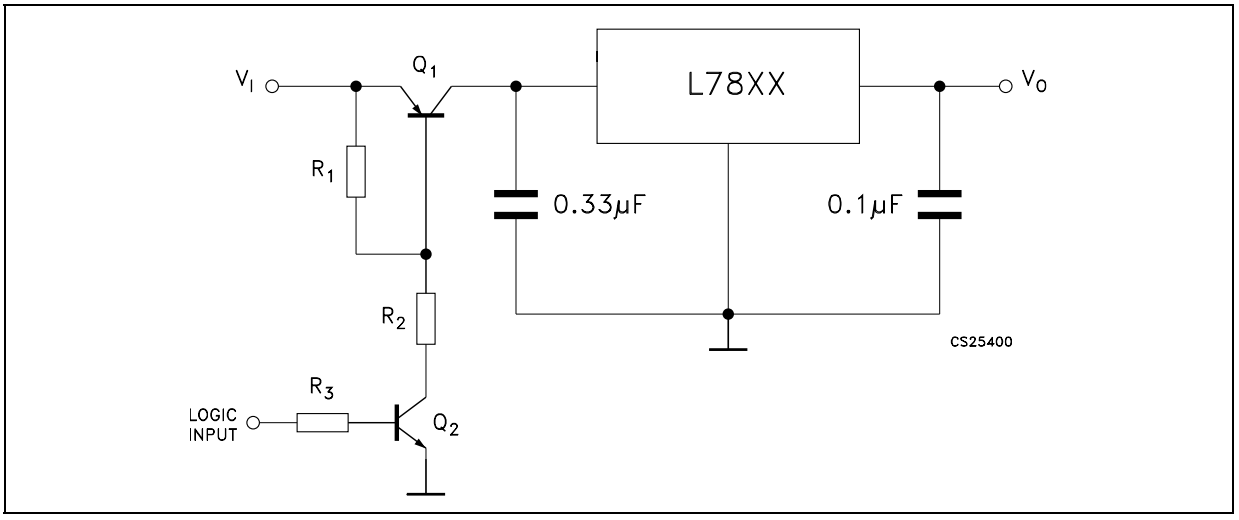
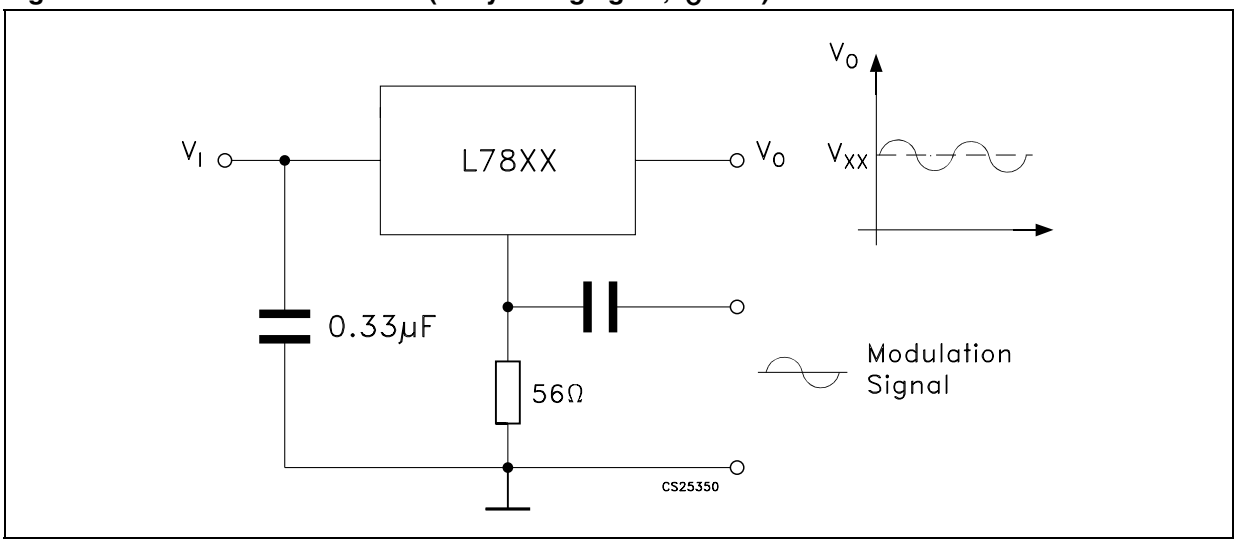
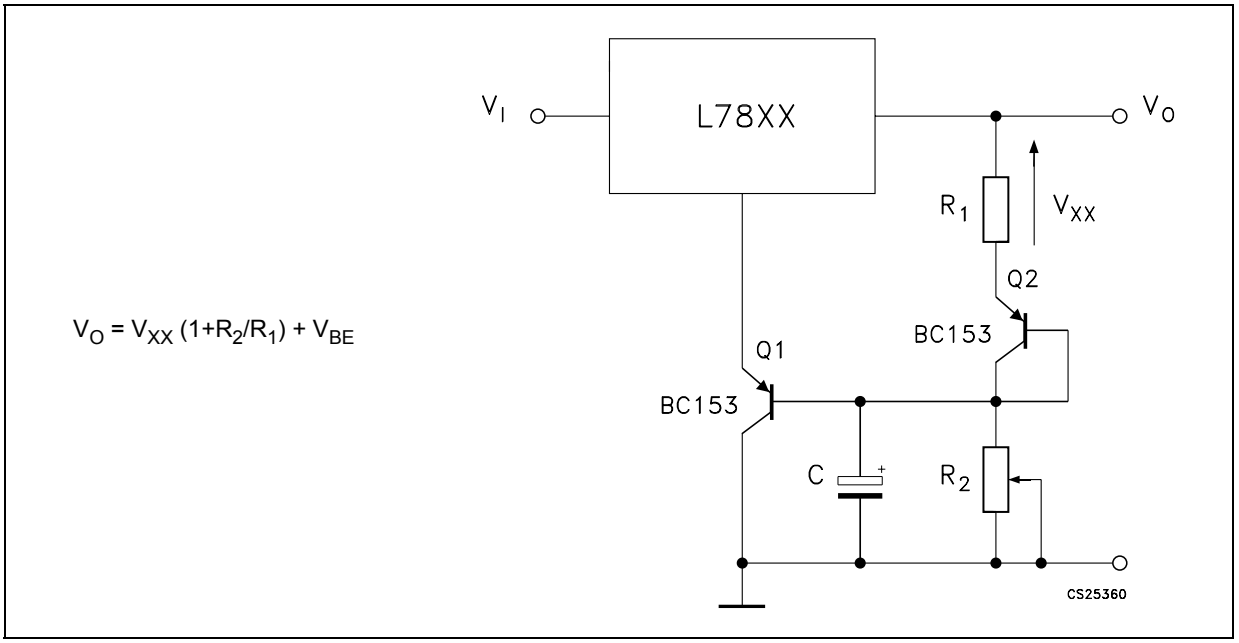


Figure 33. Power AM modulator (unity voltage gain, $I_O \leq 0.5$)



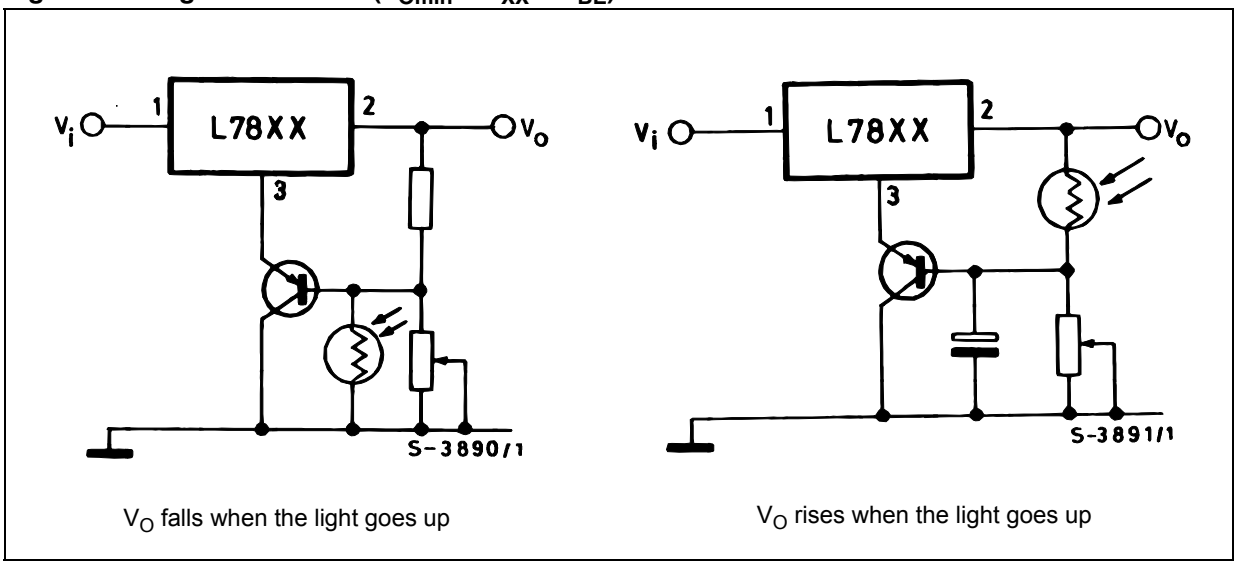
Note: The circuit performs well up to 100 KHz.

Figure 34. Adjustable output voltage with temperature compensation



Note: Q_2 is connected as a diode in order to compensate the variation of the Q_1 V_{BE} with the temperature. C allows a slow rise time of the V_O.

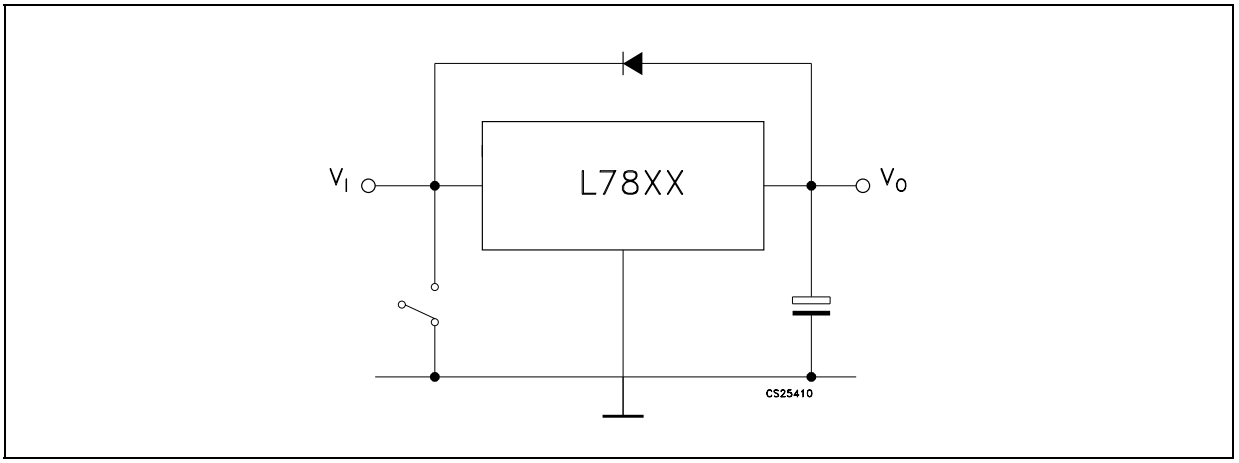
Figure 35. Light controllers ($V_{Omin} = V_{XX} + V_{BE}$)



V_O falls when the light goes up

V_O rises when the light goes up

Figure 36. Protection against input short-circuit with high capacitance loads



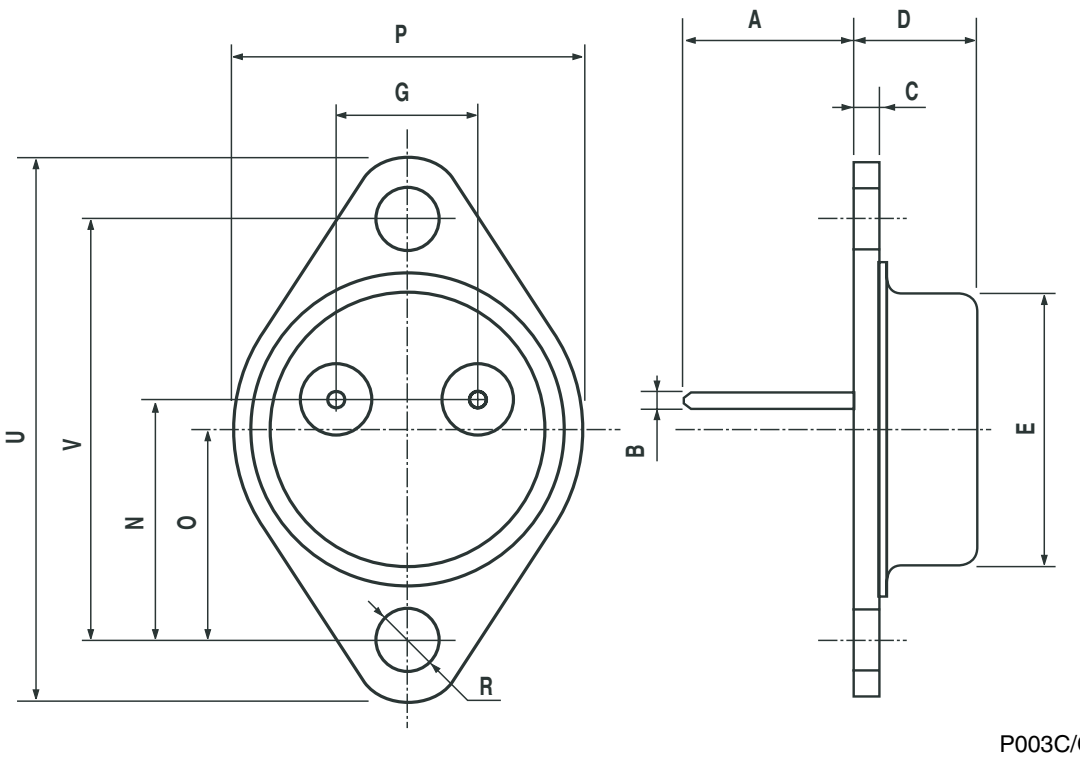
1. Application with high capacitance loads and an output voltage greater than 6 volts need an external diode (see fig. 32) to protect the device against input short circuit. In this case the input voltage falls rapidly while the output voltage decrease slowly. The capacitance discharges by means of the Base-Emitter junction of the series pass transistor in the regulator. If the energy is sufficiently high, the transistor may be destroyed. The external diode by-passes the current from the IC to ground.

6 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

TO-3 MECHANICAL DATA

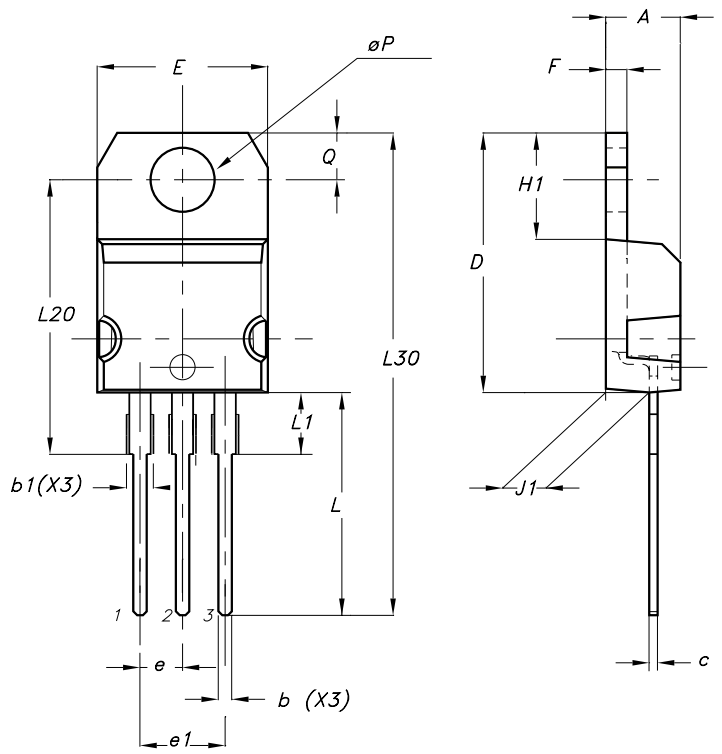
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A		11.85			0.466	
B	0.96	1.05	1.10	0.037	0.041	0.043
C			1.70			0.066
D			8.7			0.342
E			20.0			0.787
G		10.9			0.429	
N		16.9			0.665	
P			26.2			1.031
R	3.88		4.09	0.152		0.161
U			39.5			1.555
V		30.10			1.185	



P003C/C

TO-220 (A TYPE) MECHANICAL DATA

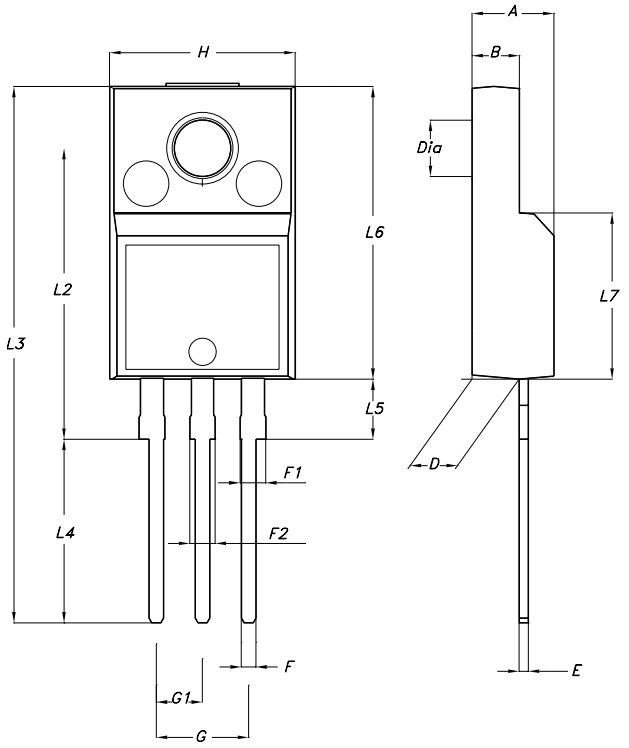
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.067
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.600		0.620
E	10.0		10.40	0.393		0.409
e	2.4		2.7	0.094		0.106
e1	4.95		5.15	0.194		0.203
F	1.23		1.32	0.048		0.051
H1	6.2		6.6	0.244		0.260
J1	2.40		2.72	0.094		0.107
L	13.0		14.0	0.511		0.551
L1	3.5		3.93	0.137		0.154
L20		16.4			0.645	
L30		28.9			1.138	
ϕP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



0015988/N

TO-220FP MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.70	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.50	0.045		0.059
F2	1.15		1.50	0.045		0.059
G	4.95		5.2	0.194		0.204
G1	2.4		2.7	0.094		0.106
H	10.0		10.40	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L5	2.9		3.6	0.114		0.142
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
DIA.	3		3.2	0.118		0.126



7012510A-H

Figure 37. DRAWING DIMENSION D²PAK (TYPE STD-ST)

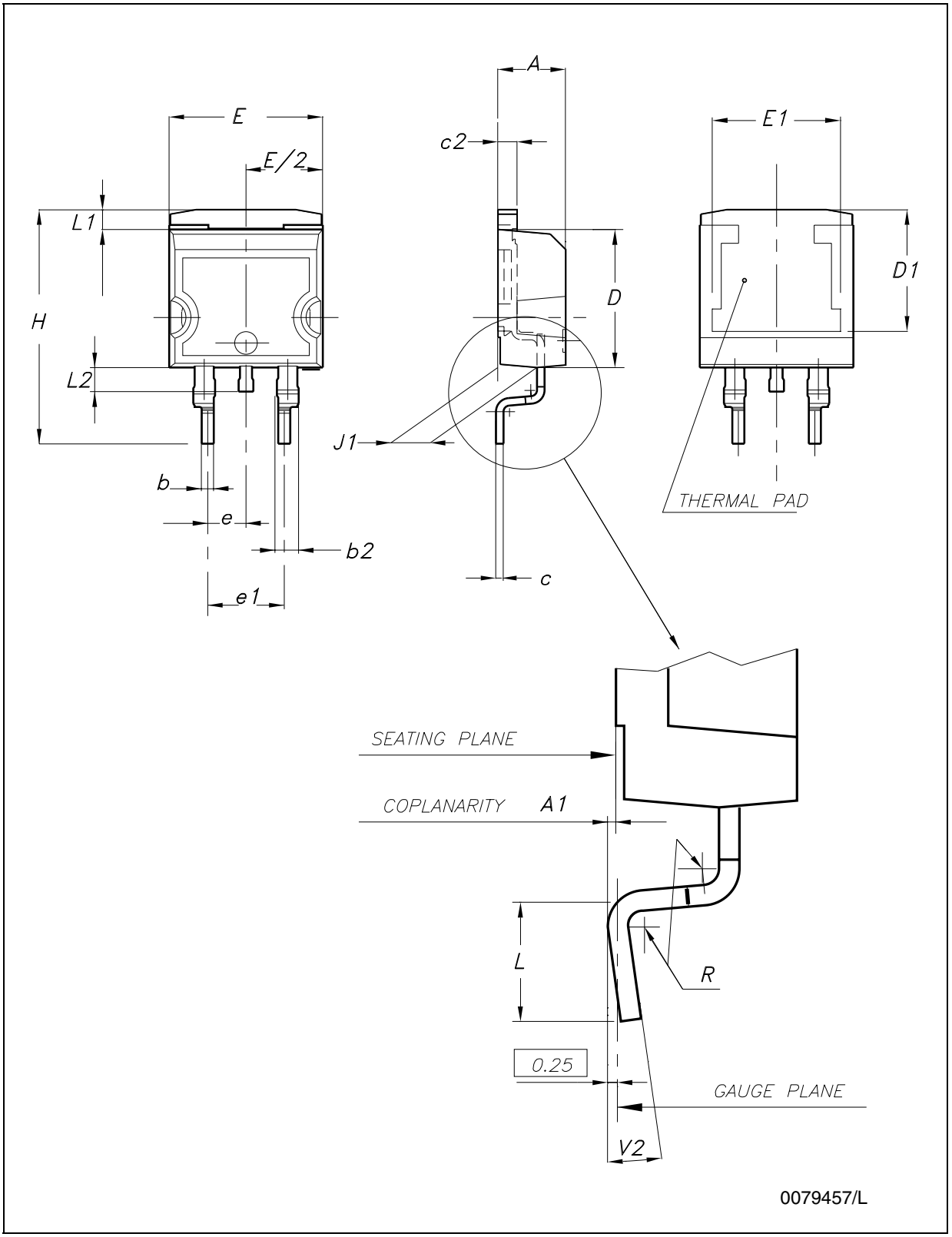


Figure 38. DRAWING DIMENSION D²PAK (TYPE WOOSEOK-SUBCON.)

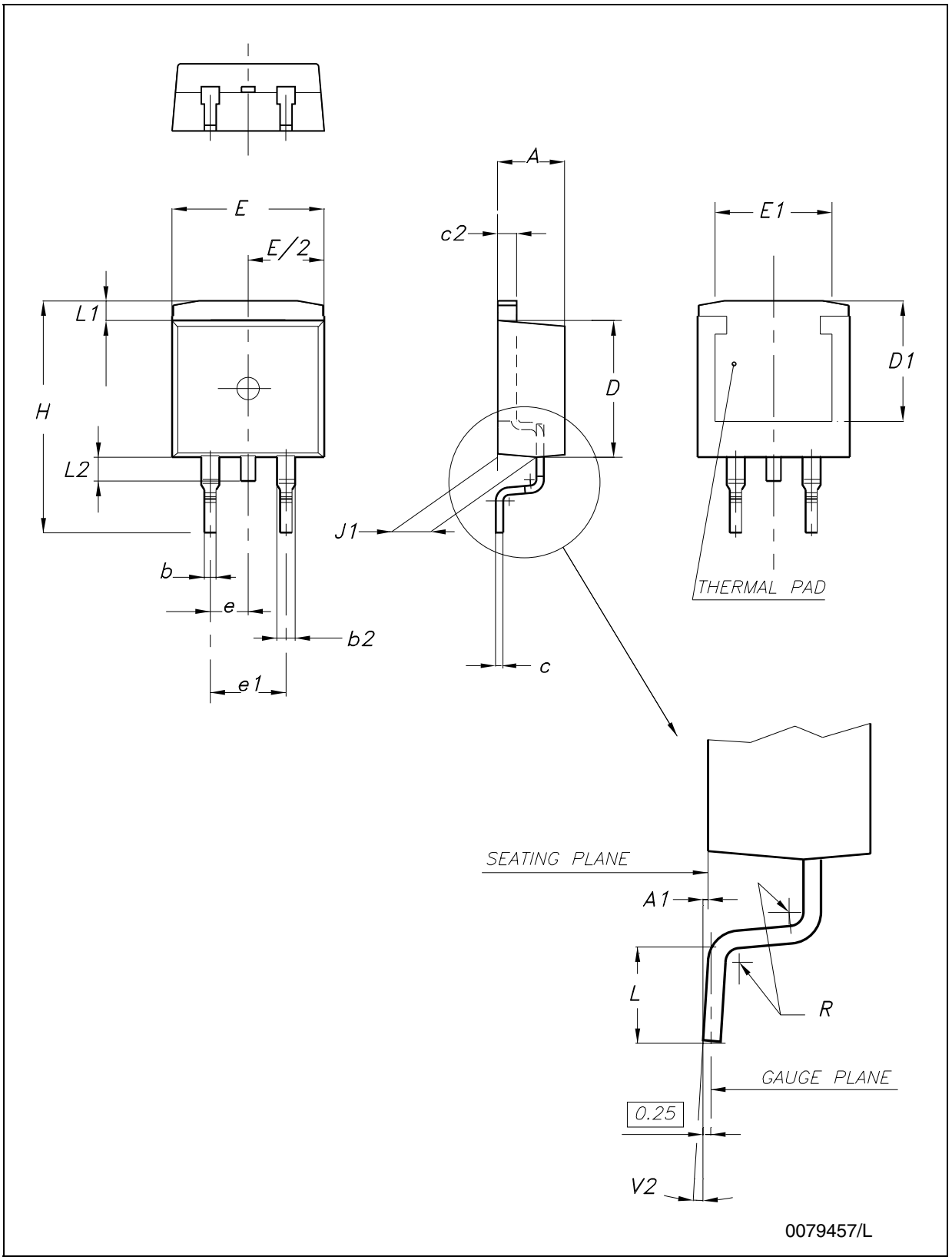


Table 23. D²PAK MECHANICAL DATA

DIM.	TYPE STD-ST			TYPE WOOSEOK-SUBCON.		
	mm.			mm.		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	4.30		4.70
A1	0.03		0.23	0		0.20
b	0.70		0.93	0.70		0.90
b2	1.14		1.70	1.17		1.37
c	0.45		0.60	0.45	0.50	0.60
c2	1.23		1.36	1.25	1.30	1.40
D	8.95		9.35	9	9.20	9.40
D1	7.50			7.50		
E	10		10.40	9.80		10.20
E1	8.50			7.50		
e		2.54			2.54	
e1	4.88		5.28		5.08	
H	15		15.85	15	15.30	15.60
J1	2.49		2.69	2.20		2.60
L	2.29		2.79	1.79		2.79
L1	1.27		1.40	1		1.40
L2	1.30		1.75	1.20		1.60
R		0.4			0.30	
V2	0°		8°	0°		3°

Note: The D²PAK package coming from the subcontractor Wooseok is fully compatible with the ST's package suggested footprint.

Figure 39. D²PAK FOOTPRINT RECOMMENDED DATA

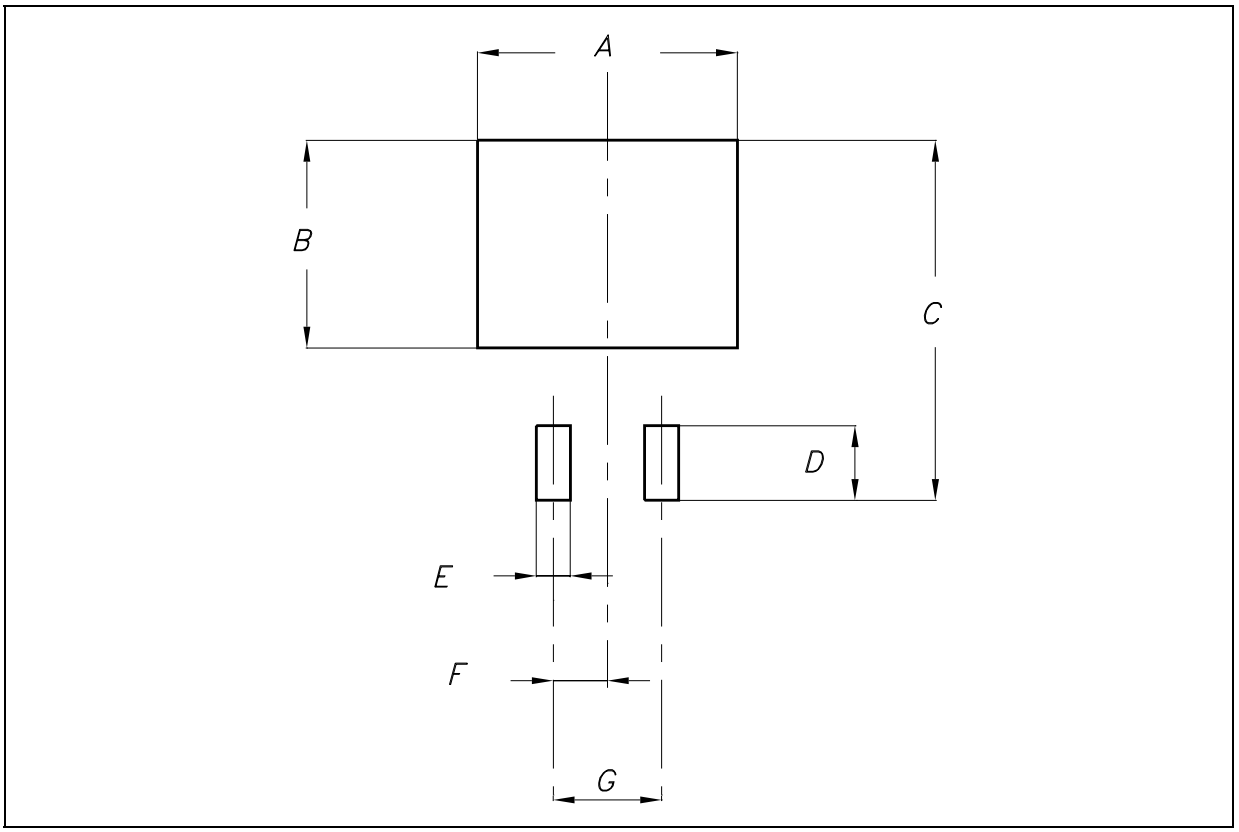
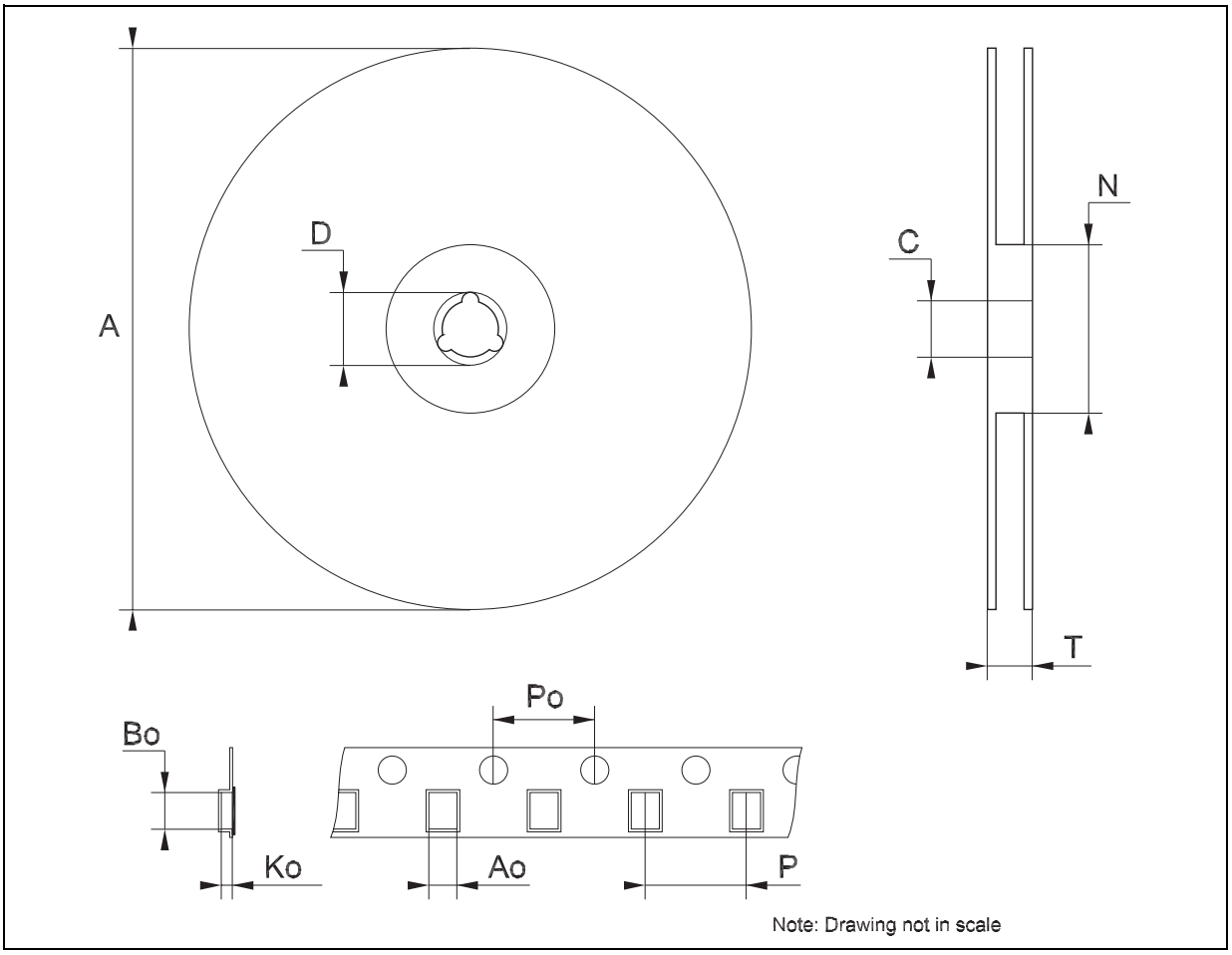


Table 24. FOOTPRINT DATA

VALUES		
	mm.	**inch.**
A	12.20	0.480
B	9.75	0.384
C	16.90	0.665
D	3.50	0.138
E	1.60	0.063
F	2.54	0.100
G	5.08	0.200

Tape & Reel D²PAK-P²PAK-D²PAK/A-P²PAK/A MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			180			7.086
C	12.8	13.0	13.2	0.504	0.512	0.519
D	20.2			0.795		
N	60			2.362		
T			14.4			0.567
Ao	10.50	10.6	10.70	0.413	0.417	0.421
Bo	15.70	15.80	15.90	0.618	0.622	0.626
Ko	4.80	4.90	5.00	0.189	0.193	0.197
Po	3.9	4.0	4.1	0.153	0.157	0.161
P	11.9	12.0	12.1	0.468	0.472	0.476



Note: Drawing not in scale

7 Order code

Table 25. Order code

Part numbers	Packaging			
	TO-220 (A Type)	D^2PAK	TO-220FP	TO-3
L7805				L7805T
L7805C	L7805CV	L7805CD2T-TR	L7805CP	L7805CT
L7852C	L7852CV	L7852CD2T-TR(1)	L7852CP(1)	L7852CT(1)
L7806C	L7806CV	L7806CD2T-TR		L7806CT
L7808C	L7808CV	L7808CD2T-TR	L7808CP	L7808CT
L7885C	L7885CV	L7885CD2T-TR(1)	L7885CP(1)	L7885CT(1)
L7809C	L7809CV	L7809CD2T-TR	L7809CP	L7809CT
L7810C	L7810CV	L7810CD2T-TR(1)		
L7812C	L7812CV	L7812CD2T-TR	L7812CP	L7812CT
L7815C	L7815CV	L7815CD2T-TR	L7815CP	L7815CT
L7818C	L7818CV	L7818CD2T-TR(1)		L7818CT
L7820C	L7820CV	L7820CD2T-TR(1)	L7820CP(1)	L7820CT(1)
L7824C	L7824CV	L7824CD2T-TR	L7824CP	L7824CT

1. Available on request.

8 Revision history

Table 26. Revision history

Date	Revision	Changes
21-Jun-2004	12	Document updating.
03-Aug-2006	13	Order codes has been updated and new template.
19-Jan-2007	14	D^2PAK mechanical data has been updated and add footprint data.
31-May-2007	15	Order codes has been updated.

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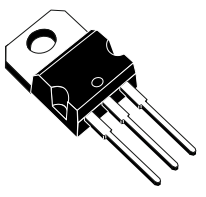
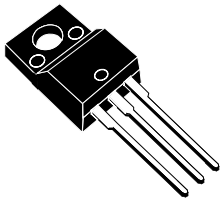
L7900 SERIES

NEGATIVE VOLTAGE REGULATORS

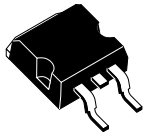
- OUTPUT CURRENT UP TO 1.5A
- OUTPUT VOLTAGES OF -5; -6; -8; -12; -15; -18; -20; -24V
- THERMAL OVERLOAD PROTECTION
- SHORT CIRCUIT PROTECTION
- OUTPUT TRANSITION SOA PROTECTION



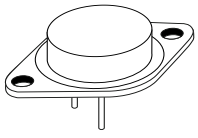
TO-220



TO-220FP



D^{2}PAK



TO-3

DESCRIPTION

The L7900 series of three-terminal negative regulators is available in TO-220, TO-220FP, TO-3 and D^{2}PAK packages and several fixed output voltages, making it useful in a wide range of applications. These regulators can provide local on-card regulation, eliminating the distribution problems associated with single point regulation; furthermore, having the same voltage option as the L7800 positive standard series, they are particularly suited for split power supplies. If adequate heat sinking is provided, they can deliver over 1.5A output current.

Although designed primarily as fixed voltage regulators, these devices can be used with external components to obtain adjustable voltages and currents.

SCHEMATIC DIAGRAM

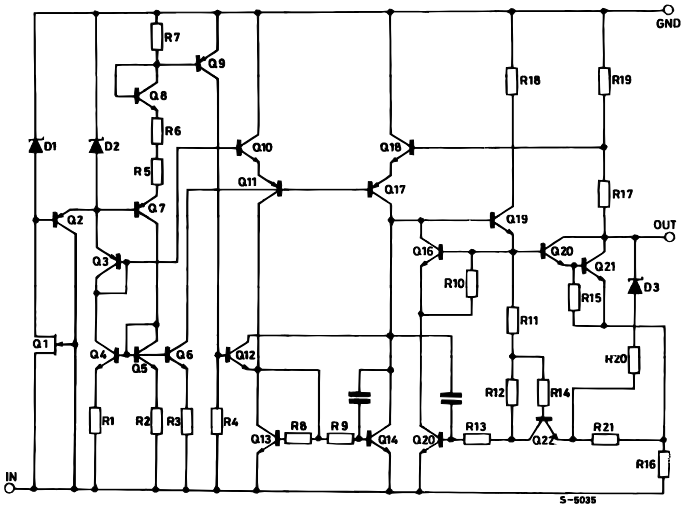


Table 1: Absolute Maximum Ratings

Symbol	Parameter		Value	Unit
V_I	DC Input Voltage	for V_O = 5 to 18V	-35	V
		for V_O = 20, 24V	-40	
I_O	Output Current		Internally Limited	
P_{tot}	Power Dissipation		Internally Limited	
T_{stg}	Storage Temperature Range		-65 to 150	°C
T_{op}	Operating Junction Temperature Range		0 to 150	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied.

Table 2: Thermal Data

Symbol	Parameter		D^2PAK	TO-220	TO-220FP	TO-3	Unit
$R_{thj\text{-}case}$	Thermal Resistance Junction-case	Max	3	3	5	4	°C/W
$R_{thj\text{-}amb}$	Thermal Resistance Junction-ambient	Max	62.5	50	60	35	°C/W

Figure 1: Connection Diagram (top view)

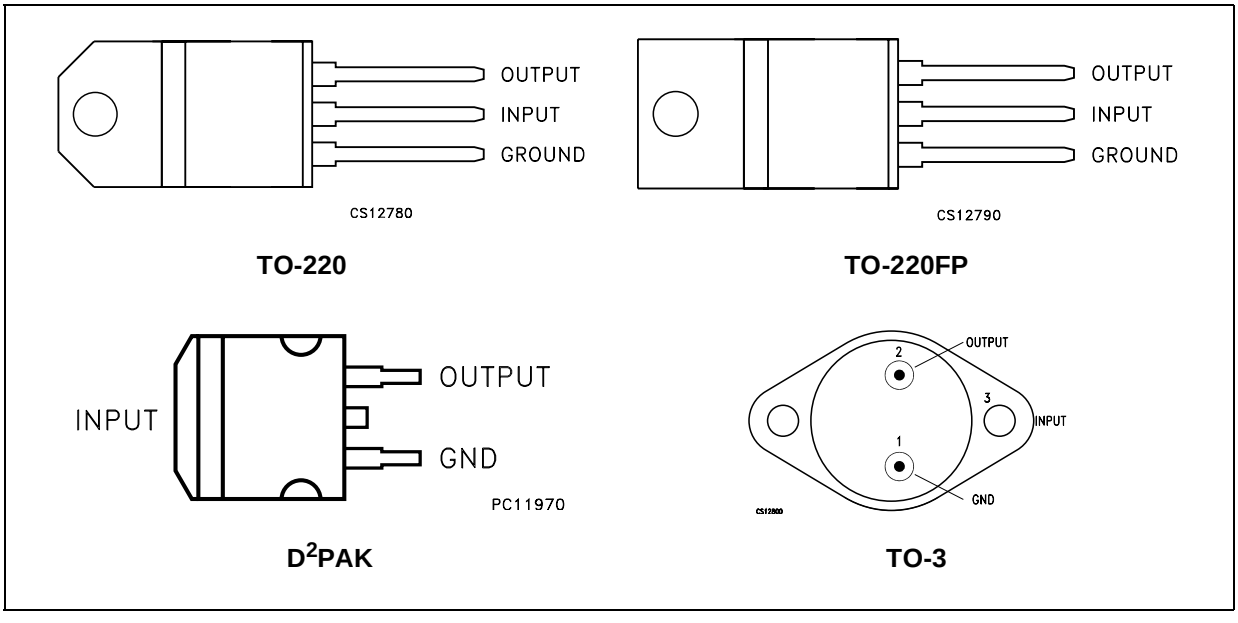


Table 3: Ordering Codes

TYPE	TO-220 (A Type)	TO-220 (C Type)	D^2PAK (A Type) (#)	D^2PAK (C Type) (T & R)	TO-220FP	TO-3	OUTPUT VOLTAGE
L7905C	L7905CV	L7905C-V	L7905CD2T	L7905C-D2TR	L7905CP	L7905CT (*)	-5 V
L7906C	L7906CV		L7906CD2T		L7906CP (*)	L7906CT (*)	-6 V
L7908C	L7908CV		L7908CD2T		L7908CP (*)	L7908CT (*)	-8 V
L7912C	L7912CV	L7912C-V	L7912CD2T		L7912CP	L7912CT (*)	-12 V
L7915C	L7915CV		L7915CD2T		L7915CP	L7915CT	-15 V
L7918C	L7918CV		L7918CD2T(*)		L7918CP (*)	L7918CT (*)	-18 V
L7920C	L7920CV		L7920CD2T(*)		L7920CP (*)	L7920CT (*)	-20 V
L7924C	L7924CV		L7924CD2T(*)		L7924CP (*)	L7924CT	-24 V

(#) Available in Tape & Reel with the suffix "-TR".
(*) Available on Request.

Figure 2: Test Circuit

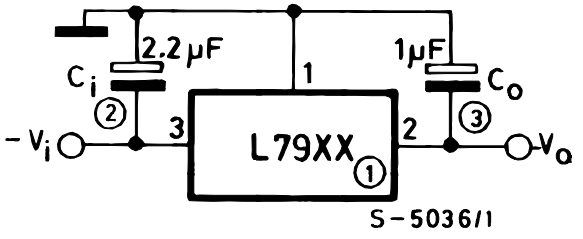


Table 4: Electrical Characteristics Of L7905C (refer to the test circuits, T_J = 0 to 125°C, V_I = -10V, I_O = 500 mA, C_I = 2.2 µF, C_O = 1 µF unless otherwise specified).

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_O	Output Voltage	T_J = 25°C	-4.8	-5	-5.2	V
V_O	Output Voltage	I_O = -5 mA to -1 A $P_O \leq$ 15 W V_I = 8 to 20 V	-4.75	-5	-5.25	V
ΔV_O(*)	Line Regulation	V_I = -7 to -25 V T_J = 25°C			100	mV
		V_I = -8 to -12 V T_J = 25°C			50	
ΔV_O(*)	Load Regulation	I_O = 5 mA to 1.5 A T_J = 25°C			100	mV
		I_O = 250 to 750 mA T_J = 25°C			50	
I_d	Quiescent Current	T_J = 25°C			3	mA
ΔI_d	Quiescent Current Change	I_O = 5 mA to 1 A			0.5	mA
		V_I = -8 to -25 V			1.3	
$\Delta V_O/\Delta T$	Output Voltage Drift	I_O = 5 mA		-0.4		mV/°C
eN	Output Noise Voltage	B = 10Hz to 100KHz T_J = 25°C		100		µV
SVR	Supply Voltage Rejection	ΔV_I = 10 V f = 120Hz	54	60		dB
V_d	Dropout Voltage	I_O = 1 A T_J = 25°C ΔV_O = 100 mV		1.4		V
I_{sc}	Short Circuit Current			2.1		A

(*) Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 5: Electrical Characteristics Of L7906C (refer to the test circuits, T_J = 0 to 125°C, V_I = -11V, I_O = 500 mA, C_I = 2.2 µF, C_O = 1 µF unless otherwise specified).

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_O	Output Voltage	T_J = 25°C	-5.75	-6	-6.25	V
V_O	Output Voltage	I_O = -5 mA to -1 A $P_O \leq$ 15 W V_I = -9.5 to -21.5 V	-5.7	-6	-6.3	V
ΔV_O(*)	Line Regulation	V_I = -8.5 to -25 V T_J = 25°C			120	mV
		V_I = -9 to -15 V T_J = 25°C			60	
ΔV_O(*)	Load Regulation	I_O = 5 mA to 1.5 A T_J = 25°C			120	mV
		I_O = 250 to 750 mA T_J = 25°C			60	
I_d	Quiescent Current	T_J = 25°C			3	mA
ΔI_d	Quiescent Current Change	I_O = 5 mA to 1 A			0.5	mA
		V_I = -9.5 to -25 V			1.3	
$\Delta V_O/\Delta T$	Output Voltage Drift	I_O = 5 mA		-0.6		mV/°C
eN	Output Noise Voltage	B = 10Hz to 100KHz T_J = 25°C		144		µV
SVR	Supply Voltage Rejection	ΔV_I = 10 V f = 120Hz	54	60		dB
V_d	Dropout Voltage	I_O = 1 A T_J = 25°C ΔV_O = 100 mV		1.4		V
I_{sc}	Short Circuit Current			2		A

(*) Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 6: Electrical Characteristics Of L7908C (refer to the test circuits, T_J = 0 to 125°C, V_I = -14V, I_O = 500 mA, C_I = 2.2 µF, C_O = 1 µF unless otherwise specified).

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_O	Output Voltage	T_J = 25°C	-7.7	-8	-8.3	V
V_O	Output Voltage	I_O = -5 mA to -1 A $P_O \leq$ 15 W V_I = -11.5 to -23 V	-7.6	-8	-8.4	V
ΔV_O(*)	Line Regulation	V_I = -10.5 to -25 V T_J = 25°C			160	mV
		V_I = -11 to -17 V T_J = 25°C			80	
ΔV_O(*)	Load Regulation	I_O = 5 mA to 1.5 A T_J = 25°C			160	mV
		I_O = 250 to 750 mA T_J = 25°C			80	
I_d	Quiescent Current	T_J = 25°C			3	mA
ΔI_d	Quiescent Current Change	I_O = 5 mA to 1 A			0.5	mA
		V_I = -11.5 to -25 V			1	
$\Delta V_O/\Delta T$	Output Voltage Drift	I_O = 5 mA		-0.6		mV/°C
eN	Output Noise Voltage	B = 10Hz to 100KHz T_J = 25°C		175		µV
SVR	Supply Voltage Rejection	ΔV_I = 10 V f = 120Hz	54	60		dB
V_d	Dropout Voltage	I_O = 1 A T_J = 25°C ΔV_O = 100 mV		1.1		V
I_{sc}	Short Circuit Current			1.5		A

(*) Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 7: Electrical Characteristics Of L7912C (refer to the test circuits, T_J = 0 to 125°C, V_I = -19V, I_O = 500 mA, C_I = 2.2 µF, C_O = 1 µF unless otherwise specified).

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_O	Output Voltage	T_J = 25°C	-11.5	-12	-12.5	V
V_O	Output Voltage	I_O = -5 mA to -1 A $P_O \leq$ 15 W V_I = -15.5 to -27 V	-11.4	-12	-12.6	V
ΔV_O(*)	Line Regulation	V_I = -14.5 to -30 V T_J = 25°C			240	mV
		V_I = -16 to -22 V T_J = 25°C			120	
ΔV_O(*)	Load Regulation	I_O = 5 mA to 1.5 A T_J = 25°C			240	mV
		I_O = 250 to 750 mA T_J = 25°C			120	
I_d	Quiescent Current	T_J = 25°C			3	mA
ΔI_d	Quiescent Current Change	I_O = 5 mA to 1 A			0.5	mA
		V_I = -15 to -30 V			1	
$\Delta V_O/\Delta T$	Output Voltage Drift	I_O = 5 mA		-0.8		mV/°C
eN	Output Noise Voltage	B = 10Hz to 100KHz T_J = 25°C		200		µV
SVR	Supply Voltage Rejection	ΔV_I = 10 V f = 120Hz	54	60		dB
V_d	Dropout Voltage	I_O = 1 A T_J = 25°C ΔV_O = 100 mV		1.1		V
I_{sc}	Short Circuit Current			1.5		A

(*) Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 8: Electrical Characteristics Of L7915C (refer to the test circuits, T_J = 0 to 125°C, V_I = -23V, I_O = 500 mA, C_I = 2.2 µF, C_O = 1 µF unless otherwise specified).

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_O	Output Voltage	T_J = 25°C	-14.4	-15	-15.6	V
V_O	Output Voltage	I_O = -5 mA to -1 A $P_O \leq$ 15 W V_I = -18.5 to -30 V	-14.3	-15	-15.7	V
ΔV_O(*)	Line Regulation	V_I = -17.5 to -30 V T_J = 25°C			300	mV
		V_I = -20 to -26 V T_J = 25°C			150	
ΔV_O(*)	Load Regulation	I_O = 5 mA to 1.5 A T_J = 25°C			300	mV
		I_O = 250 to 750 mA T_J = 25°C			150	
I_d	Quiescent Current	T_J = 25°C			3	mA
ΔI_d	Quiescent Current Change	I_O = 5 mA to 1 A			0.5	mA
		V_I = -18.5 to -30 V			1	
$\Delta V_O/\Delta T$	Output Voltage Drift	I_O = 5 mA		-0.9		mV/°C
eN	Output Noise Voltage	B = 10Hz to 100KHz T_J = 25°C		250		µV
SVR	Supply Voltage Rejection	ΔV_I = 10 V f = 120Hz	54	60		dB
V_d	Dropout Voltage	I_O = 1 A T_J = 25°C ΔV_O = 100 mV		1.1		V
I_{sc}	Short Circuit Current			1.3		A

(*) Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 9: Electrical Characteristics Of L7918C (refer to the test circuits, T_J = 0 to 125°C, V_I = -27V, I_O = 500 mA, C_I = 2.2 µF, C_O = 1 µF unless otherwise specified).

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_O	Output Voltage	T_J = 25°C	-17.3	-18	-18.7	V
V_O	Output Voltage	I_O = -5 mA to -1 A $P_O \leq$ 15 W V_I = -22 to -33 V	-17.1	-18	-18.9	V
ΔV_O(*)	Line Regulation	V_I = -21 to -33 V T_J = 25°C			360	mV
		V_I = -24 to -30 V T_J = 25°C			180	
ΔV_O(*)	Load Regulation	I_O = 5 mA to 1.5 A T_J = 25°C			360	mV
		I_O = 250 to 750 mA T_J = 25°C			180	
I_d	Quiescent Current	T_J = 25°C			3	mA
ΔI_d	Quiescent Current Change	I_O = 5 mA to 1 A			0.5	mA
		V_I = -22 to -33 V			1	
$\Delta V_O/\Delta T$	Output Voltage Drift	I_O = 5 mA		-1		mV/°C
eN	Output Noise Voltage	B = 10Hz to 100KHz T_J = 25°C		300		µV
SVR	Supply Voltage Rejection	ΔV_I = 10 V f = 120Hz	54	60		dB
V_d	Dropout Voltage	I_O = 1 A T_J = 25°C ΔV_O = 100 mV		1.1		V
I_{sc}	Short Circuit Current			1.1		A

(*) Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

Table 10: Electrical Characteristics Of L7920C (refer to the test circuits, T_J = 0 to 125°C, V_I = -29V, I_O = 500 mA, C_I = 2.2 µF, C_O = 1 µF unless otherwise specified).

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_O	Output Voltage	T_J = 25°C	-19.2	-20	-20.8	V
V_O	Output Voltage	I_O = -5 mA to -1 A $P_O \leq$ 15 W V_I = -24 to -35 V	-19	-20	-21	V
ΔV_O(*)	Line Regulation	V_I = -23 to -35 V T_J = 25°C			400	mV
		V_I = -26 to -32 V T_J = 25°C			200	
ΔV_O(*)	Load Regulation	I_O = 5 mA to 1.5 A T_J = 25°C			400	mV
		I_O = 250 to 750 mA T_J = 25°C			200	
I_d	Quiescent Current	T_J = 25°C			3	mA
ΔI_d	Quiescent Current Change	I_O = 5 mA to 1 A			0.5	mA
		V_I = -24 to -35 V			1	
$\Delta V_O/\Delta T$	Output Voltage Drift	I_O = 5 mA		-1.1		mV/°C
eN	Output Noise Voltage	B = 10Hz to 100KHz T_J = 25°C		350		µV
SVR	Supply Voltage Rejection	ΔV_I = 10 V f = 120Hz	54	60		dB
V_d	Dropout Voltage	I_O = 1 A T_J = 25°C ΔV_O = 100 mV		1.1		V
I_{sc}	Short Circuit Current			0.9		A

(*) Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

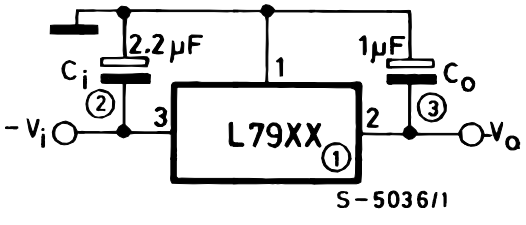
Table 11: Electrical Characteristics Of L7924C (refer to the test circuits, T_J = 0 to 125°C, V_I = -33V, I_O = 500 mA, C_I = 2.2 µF, C_O = 1 µF unless otherwise specified).

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_O	Output Voltage	T_J = 25°C	-23	-24	-24.5	V
V_O	Output Voltage	I_O = -5 mA to -1 A $P_O \leq$ 15 W V_I = -27 to -38 V	-22.8	-24	-25.2	V
ΔV_O(*)	Line Regulation	V_I = -27 to -38 V T_J = 25°C			480	mV
		V_I = -30 to -36 V T_J = 25°C			240	
ΔV_O(*)	Load Regulation	I_O = 5 mA to 1.5 A T_J = 25°C			480	mV
		I_O = 250 to 750 mA T_J = 25°C			240	
I_d	Quiescent Current	T_J = 25°C			3	mA
ΔI_d	Quiescent Current Change	I_O = 5 mA to 1 A			0.5	mA
		V_I = -27 to -38 V			1	
$\Delta V_O/\Delta T$	Output Voltage Drift	I_O = 5 mA		-1		mV/°C
eN	Output Noise Voltage	B = 10Hz to 100KHz T_J = 25°C		400		µV
SVR	Supply Voltage Rejection	ΔV_I = 10 V f = 120Hz	54	60		dB
V_d	Dropout Voltage	I_O = 1 A T_J = 25°C ΔV_O = 100 mV		1.1		V
I_{sc}	Short Circuit Current			1.1		A

(*) Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

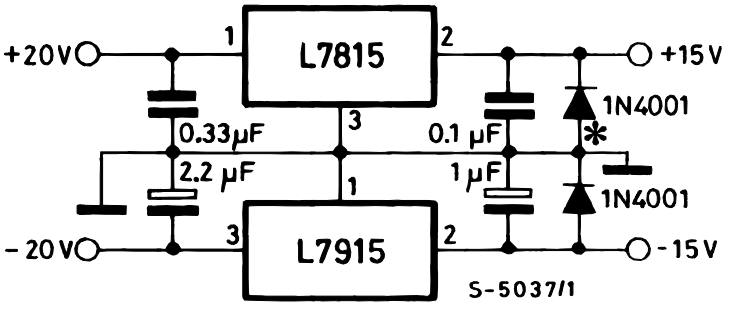
APPLICATIONS INFORMATION

Figure 3: Fixed Output Regulator



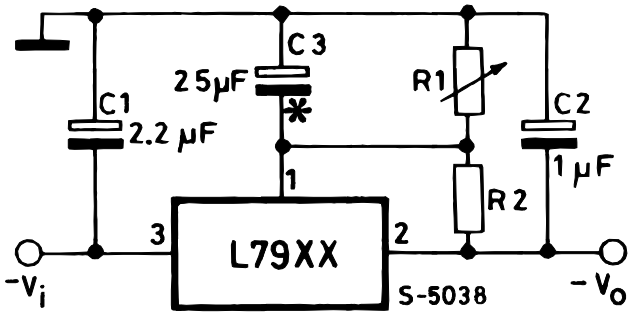
NOTE:
1. To specify an output voltage, substitute voltage value for "XX".
2. Required for stability. For value given, capacitor must be solid tantalum. If aluminium electrolytics are used, at least ten times value should be selected. C1 is required if regulator is located an appreciable distance from power supply filter.
3. To improve transient response. If large capacitors are used, a high current diode from input to output (1N4001 or similar) should be introduced to protect the device from momentary input short circuit.

Figure 4: Split Power Supply (± 15V/1A)



Against potential latch-up problems.

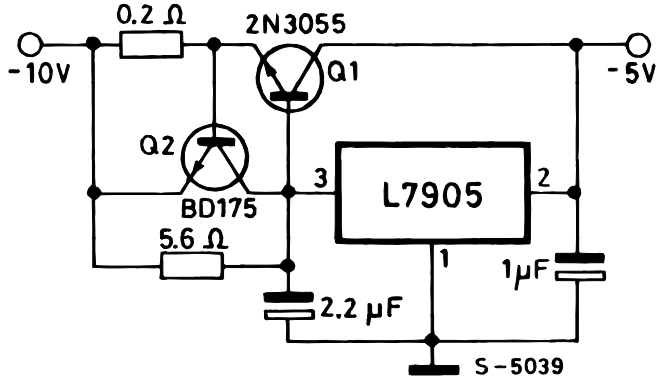
Figure 5: Circuit for Increasing Output Voltage



$$V_O = V_{xx}\frac{R_1 + R_2}{R_2} \qquad \frac{V_{xx}}{R_2} > 3I_d$$

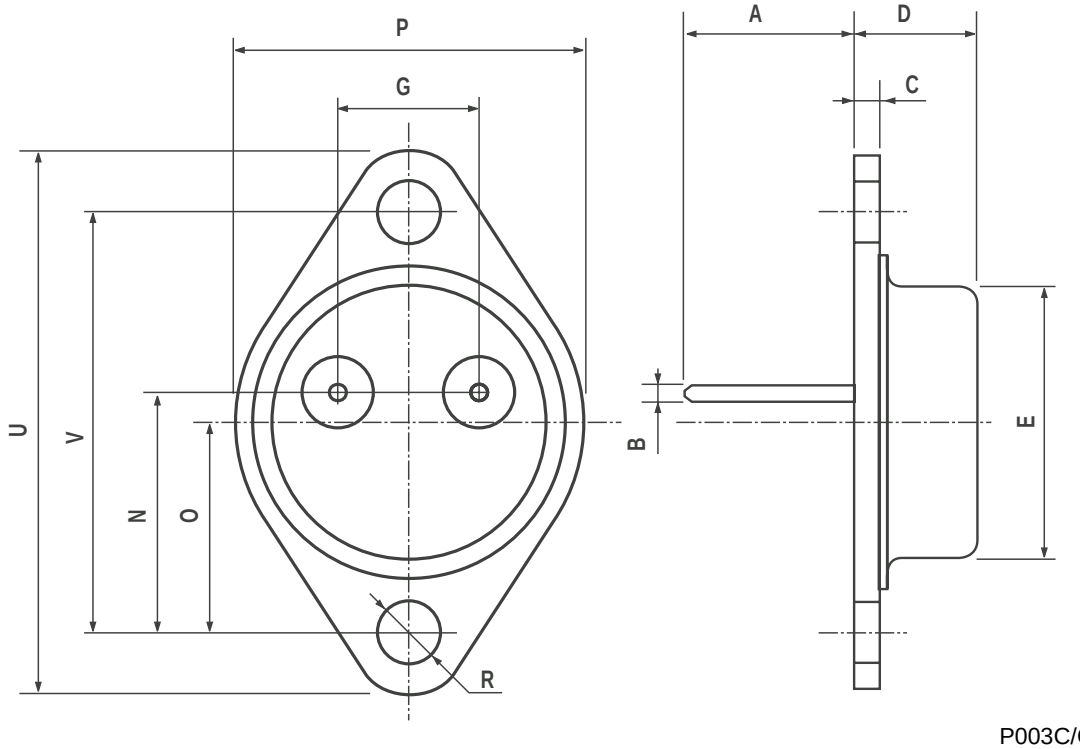
C3 Optional for improved transient response and ripple rejection.

Figure 6: High Current Negative Regulator (-5V/4A with 5A current limiting)



TO-3 MECHANICAL DATA

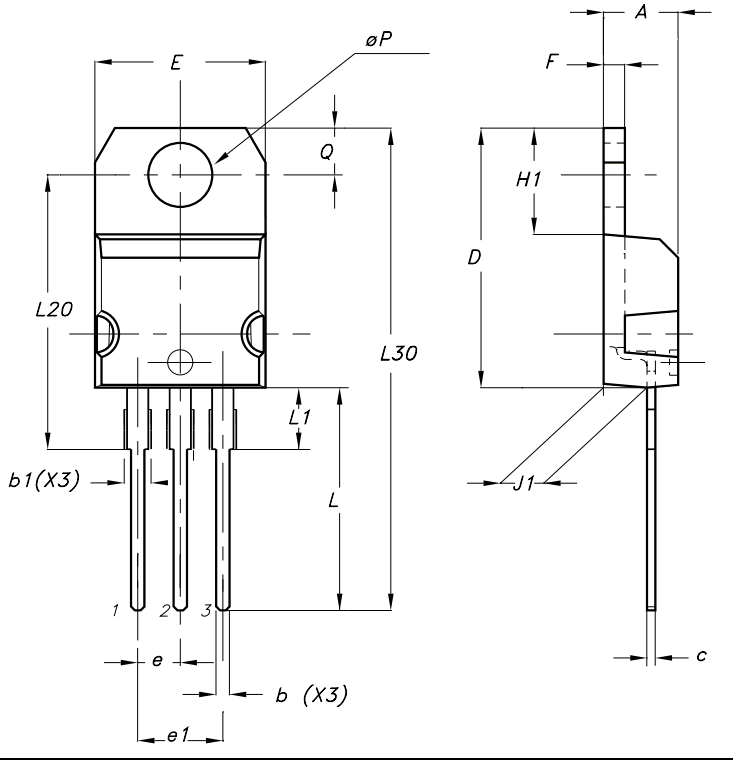
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A		11.85			0.466	
B	0.96	1.05	1.10	0.037	0.041	0.043
C			1.70			0.066
D			8.7			0.342
E			20.0			0.787
G		10.9			0.429	
N		16.9			0.665	
P			26.2			1.031
R	3.88		4.09	0.152		0.161
U			39.5			1.555
V		30.10			1.185	



P003C/C

TO-220 (A TYPE) MECHANICAL DATA

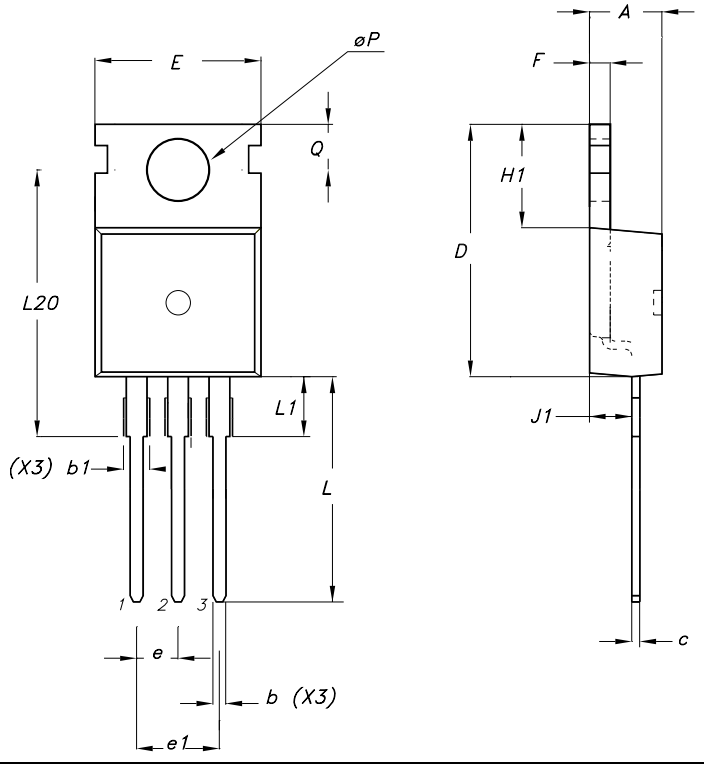
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.067
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.600		0.620
E	10.0		10.40	0.393		0.409
e	2.4		2.7	0.094		0.106
e1	4.95		5.15	0.194		0.203
F	1.23		1.32	0.048		0.051
H1	6.2		6.6	0.244		0.260
J1	2.40		2.72	0.094		0.107
L	13.0		14.0	0.511		0.551
L1	3.5		3.93	0.137		0.154
L20		16.4			0.645	
L30		28.9			1.138	
ϕP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



0015988/N

TO-220 (C TYPE) MECHANICAL DATA

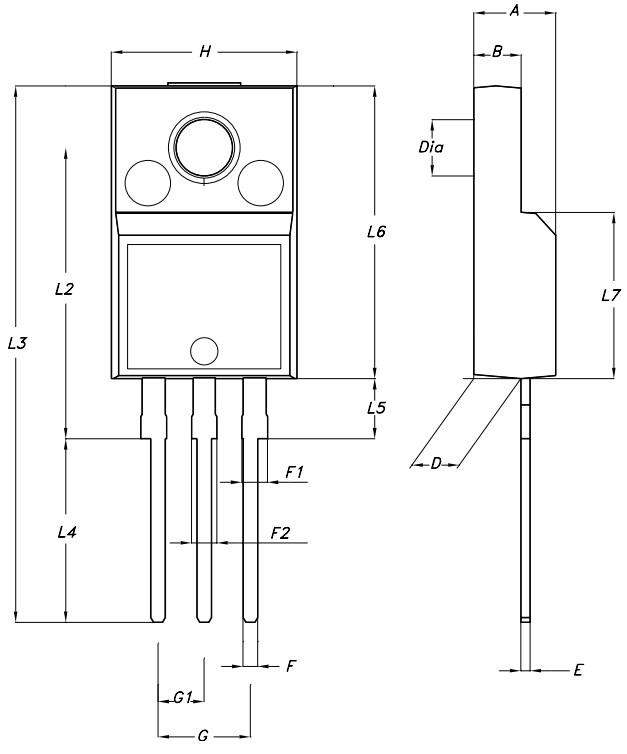
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.30		4.70	0.169		0.185
b	0.70		0.90	0.028		0.035
b1	1.42		1.62	0.056		0.064
c	0.45		0.60	0.018		0.024
D		15.70			0.618	
E	9.80		10.20	0.386		0.402
e		2.54			0.100	
e1		5.08			0.200	
F	1.25		1.39	0.049		0.055
H1		6.5			0.256	
J1	2.20		2.60	0.087		0.202
L	12.88		13.28	0.507		0.523
L1		3			0.118	
L20	15.70		16.1	0.618		0.634
L30		28.9			1.138	
ϕP	3.50		3.70	0.138		0.146
Q	2.70		2.90	0.106		0.114



0015988/N

TO-220FP MECHANICAL DATA

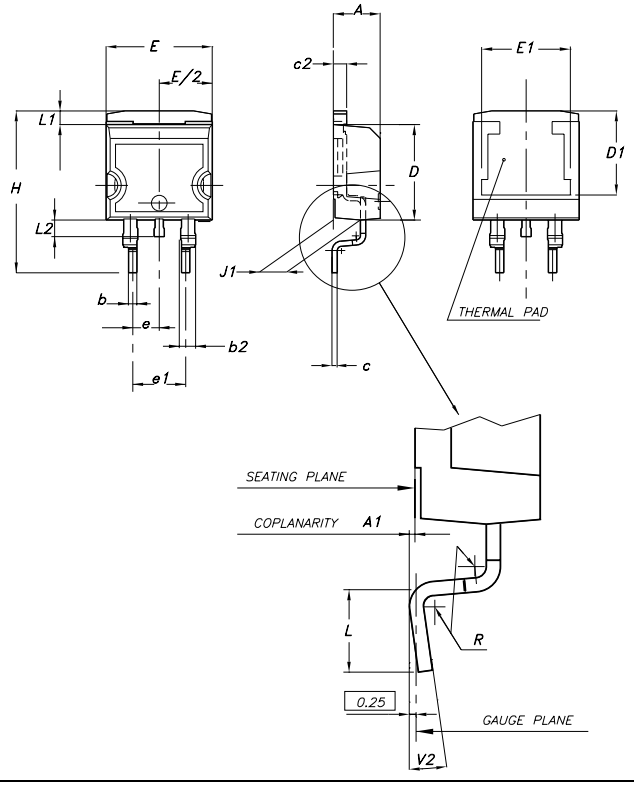
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.70	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.50	0.045		0.059
F2	1.15		1.50	0.045		0.059
G	4.95		5.2	0.194		0.204
G1	2.4		2.7	0.094		0.106
H	10.0		10.40	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L5	2.9		3.6	0.114		0.142
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
DIA.	3		3.2	0.118		0.126



7012510A-H

D²PAK (A TYPE) MECHANICAL DATA

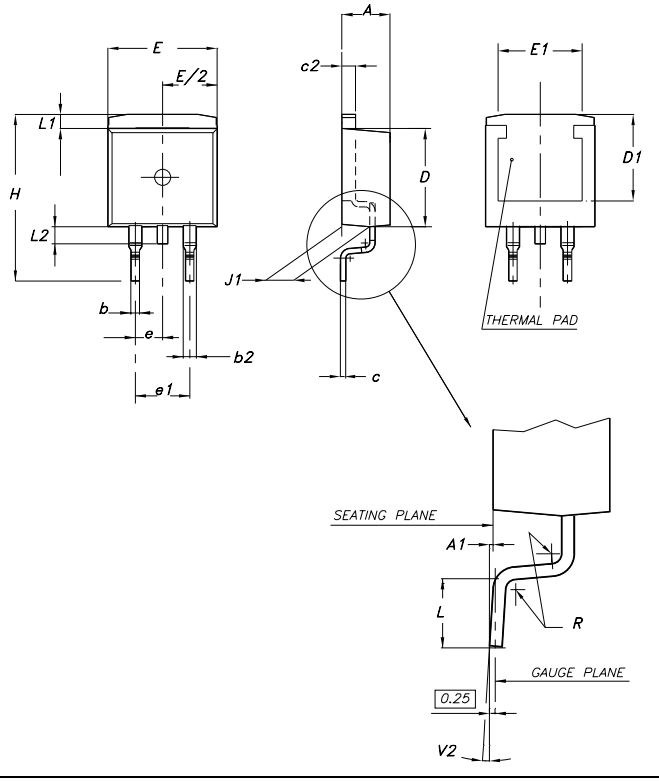
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.7		0.93	0.027		0.036
b2	1.14		1.7	0.044		0.067
c	0.45		0.6	0.017		0.023
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	8			0.315		
E	10		10.4	0.393		0.409
E1	8.5			0.335		
e		2.54			0.100	
e1	4.88		5.28	0.192		0.208
H	15		15.85	0.590		0.624
J1	2.49		2.69	0.098		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.4	0.050		0.055
L2	1.3		1.75	0.051		0.069
R		0.4			0.016	
V2	0°		8°	0°		8°



0079457/J

D²PAK (C TYPE) MECHANICAL DATA

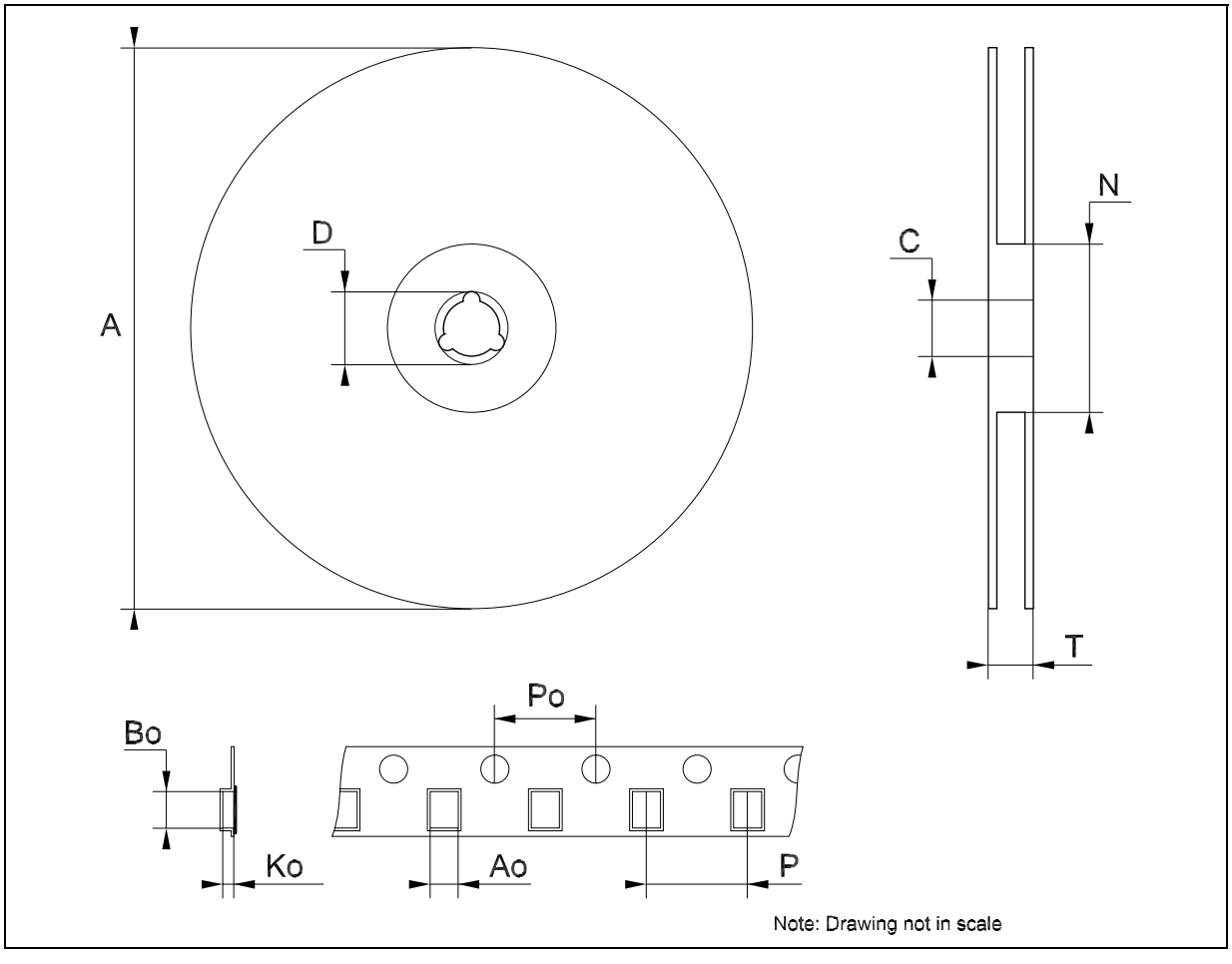
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.3		4.7	0.169		0.185
A1	0		0.20	0.000		0.008
b	0.70		0.90	0.028		0.035
b2	1.17		1.37	0.046		0.054
c	0.45	0.50	0.6	0.018	0.020	0.024
c2	1.25	1.30	1.40	0.049	0.051	0.055
D	9.0	9.2	9.4	0.354	0.362	0.370
D1	7.5			0.295		
E	9.8		10.2	0.386		0.402
E1	7.5			0.295		
e		2.54			0.100	
e1		5.08			0.200	
H	15	15.30	15.60	0.591	0.602	0.614
J1	2.20		2.60	0.087		0.102
L	1.79		2.79	0.070		0.110
L1	1.0		1.4	0.039		0.055
L2	1.2		1.6	0.047		0.063
R		0.3			0.012	
V2	0°		3°	0°		3°



0079457/J

Tape & Reel D²PAK-P²PAK-D²PAK/A-P²PAK/A MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			180			7.086
C	12.8	13.0	13.2	0.504	0.512	0.519
D	20.2			0.795		
N	60			2.362		
T			14.4			0.567
Ao	10.50	10.6	10.70	0.413	0.417	0.421
Bo	15.70	15.80	15.90	0.618	0.622	0.626
Ko	4.80	4.90	5.00	0.189	0.193	0.197
Po	3.9	4.0	4.1	0.153	0.157	0.161
P	11.9	12.0	12.1	0.468	0.472	0.476



Note: Drawing not in scale

Table 12: Revision History

Date	Revision	Description of Changes
22-Jun-2004	9	Ordering Codes updated Table 3, pag. 3.

LM2904,LM358/LM358A,LM258/LM258A

Dual Operational Amplifier

Features

- Internally Frequency Compensated for Unity Gain
- Large DC Voltage Gain: 100dB
- Wide Power Supply Range:
  LM258/LM258A, LM358/LM358A: 3V~32V (or ±1.5V ~ 16V)
  LM2904 : 3V~26V (or ±1.5V ~ 13V)
- Input Common Mode Voltage Range Includes Ground
- Large Output Voltage Swing: 0V DC to Vcc -1.5V DC
- Power Drain Suitable for Battery Operation.

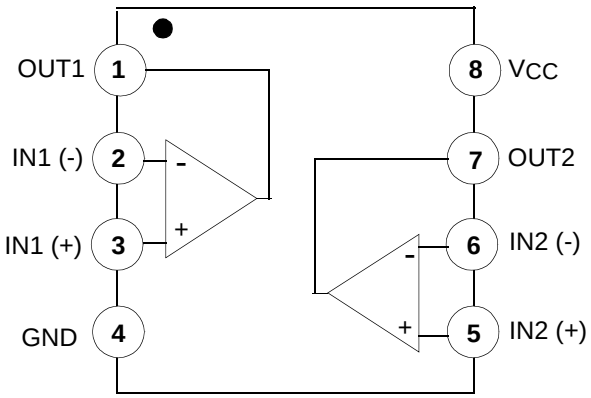
Description

The LM2904,LM358/LM358A, LM258/LM258A consist of two independent, high gain, internally frequency compensated operational amplifiers which were designed specifically to operate from a single power supply over a wide range of voltage. Operation from split power supplies is also possible and the low power supply current drain is independent of the magnitude of the power supply voltage. Application areas include transducer amplifier, DC gain blocks and all the conventional OP-AMP circuits which now can be easily implemented in single power supply systems.

8-DIP

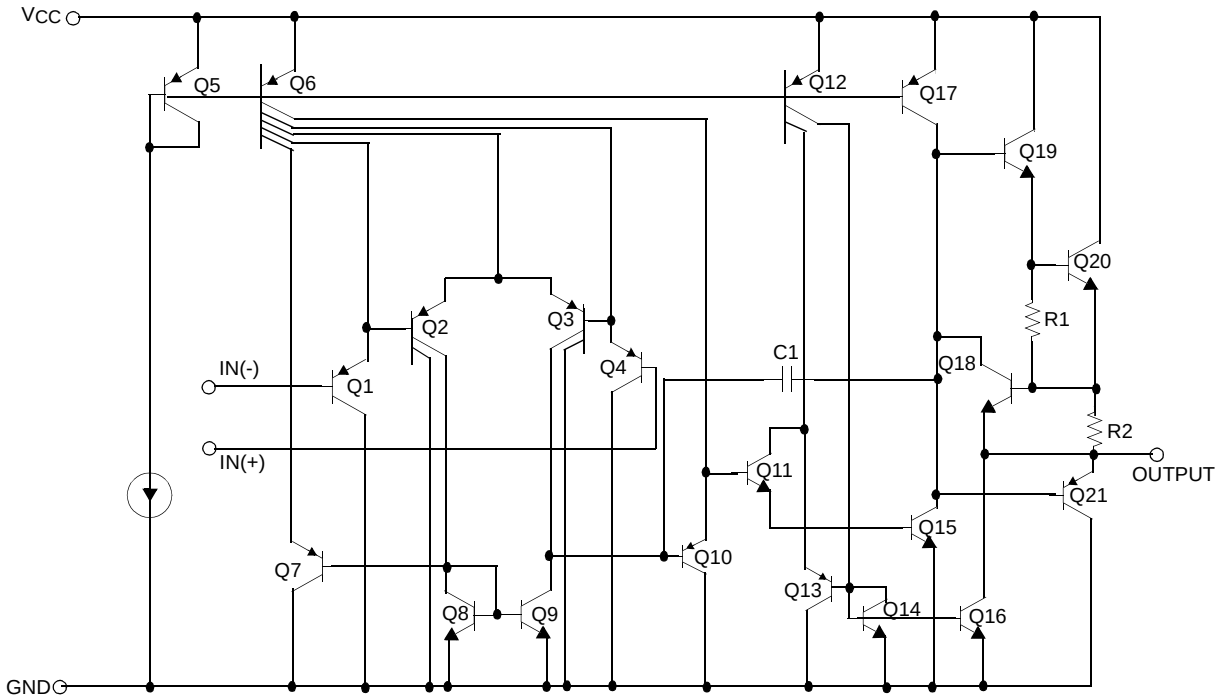
8-SOP

Internal Block Diagram



Schematic Diagram

(One section only)



Absolute Maximum Ratings

Parameter	Symbol	LM258/LM258A	LM358/LM358A	LM2904	Unit
Supply Voltage	V_{CC}	±16 or 32	±16 or 32	±13 or 26	V
Differential Input Voltage	$V_{I(DIFF)}$	32	32	26	V
Input Voltage	V_I	-0.3 to +32	-0.3 to +32	-0.3 to +26	V
Output Short Circuit to GND V_{CC}≤15V, T_A = 25°C(One Amp)	-	Continuous	Continuous	Continuous	-
Operating Temperature Range	T_{OPR}	-25 ~ +85	0 ~ +70	-40 ~ +85	°C
Storage Temperature Range	T_{STG}	-65 ~ +150	-65 ~ +150	-65 ~ +150	°C

Electrical Characteristics

(Vcc = 5.0V, V_{EE} = GND, T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Conditions	LM258			LM358			LM2904			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
Input Offset Voltage	V_{IO}	V_{CM} = 0V to V_{CC} -1.5V $V_{O(P)}$ = 1.4V, R_S = 0Ω	-	2.9	5.0	-	2.9	7.0	-	2.9	7.0	mV
Input Offset Current	I_{IO}	-	-	3	30	-	5	50	-	5	50	nA
Input Bias Current	I_{BIAS}	-	-	45	150	-	45	250	-	45	250	nA
Input Voltage Range	$V_{I(R)}$	V_{CC} = 30V (LM2904, V_{CC}=26V)	0	-	Vcc -1.5	0	-	Vcc -1.5	0	-	Vcc -1.5	V
Supply Current	I_{CC}	R_L = ∞, V_{CC} = 30V (LM2904, V_{CC}=26V)	-	0.8	2.0	-	0.8	2.0	-	0.8	2.0	mA
		R_L = ∞, V_{CC} = 5V	-	0.5	1.2	-	0.5	1.2	-	0.5	1.2	mA
Large Signal Voltage Gain	G_V	V_{CC} = 15V, R_L= 2kΩ $V_{O(P)}$ = 1V to 11V	50	100	-	25	100	-	25	100	-	V/mV
Output Voltage Swing	$V_{O(H)}$	V_{CC}=30V (V_{CC} =26V for LM2904), R_L = 2kΩ	26	-	-	26	-	-	22	-	-	V
		V_{CC}=30V (V_{CC} =26V for LM2904), R_L= 10kΩ	27	28	-	27	28	-	23	24	-	V
	$V_{O(L)}$	V_{CC} = 5V, R_L= 10kΩ	-	5	20	-	5	20	-	5	20	mV
Common-Mode Rejection Ratio	CMRR	-	70	85	-	65	80	-	50	80	-	dB
Power Supply Rejection Ratio	PSRR	-	65	100	-	65	100	-	50	100	-	dB
Channel Separation	CS	f = 1kHz to 20kHz (Note1)	-	120	-	-	120	-	-	120	-	dB
Short Circuit to GND	I_{SC}	-	-	40	60	-	40	60	-	40	60	mA
Output Current	I_{SOURCE}	$V_{I(+)}$ = 1V, $V_{I(-)}$ = 0V V_{CC} = 15V, $V_{O(P)}$ = 2V	20	30	-	20	30	-	20	30	-	mA
	I_{SINK}	$V_{I(+)}$ = 0V, $V_{I(-)}$ = 1V, V_{CC} = 15V, $V_{O(P)}$ = 2V	10	15	-	10	15	-	10	15	-	mA
		$V_{I(+)}$ = 0V,$V_{I(-)}$ =1V , V_{CC} = 15V, $V_{O(P)}$ = 200mV	12	100	-	12	100	-	-	-	-	µA
Differential Input Voltage	$V_{I(DIFF)}$	-	-	-	V_{CC}	-	-	V_{CC}	-	-	V_{CC}	V

Note:

1. This parameter, although guaranteed, is not 100% tested in production.

Electrical Characteristics (Continued)

(V_{CC}= 5.0V, V_{EE} = GND, unless otherwise specified)
The following specification apply over the range of -25°C ≤ T_A ≤ +85°C for the LM258; and the 0°C ≤ T_A ≤ +70°C for the LM358; and the -40°C ≤ T_A ≤ +85°C for the LM2904

Parameter	Symbol	Conditions	LM258			LM358			LM2904			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
Input Offset Voltage	V_{IO}	V_{CM} = 0V to V_{CC} -1.5V $V_{O(P)}$ = 1.4V, R_S = 0Ω	-	-	7.0	-	-	9.0	-	-	10.0	mV
Input Offset Voltage Drift	$\Delta V_{IO}/\Delta T$	R_S = 0Ω	-	7.0	-	-	7.0	-	-	7.0	-	µV/°C
Input Offset Current	I_{IO}	-	-	-	100	-	-	150	-	45	200	nA
Input Offset Current Drift	$\Delta I_{IO}/\Delta T$	-	-	10	-	-	10	-	-	10	-	pA/°C
Input Bias Current	I_{BIAS}	-	-	40	300	-	40	500	-	40	500	nA
Input Voltage Range	$V_{I(R)}$	V_{CC} = 30V (LM2904 , V_{CC} = 26V)	0	-	Vcc -2.0	0	-	Vcc -2.0	0	-	Vcc -2.0	V
Large Signal Voltage Gain	G_V	V_{CC} = 15V, R_L =2.0kΩ $V_{O(P)}$ = 1V to 11V	25	-	-	15	-	-	15	-	-	V/mV
Output Voltage Swing	$V_{O(H)}$	V_{CC}=30V (V_{CC} = 26V for LM2904) R_L = 2kΩ	26	-	-	26	-	-	22	-	-	V
		R_L=10kΩ	27	28	-	27	28	-	23	24	-	V
	$V_{O(L)}$	V_{CC} = 5V, R_L=10kΩ	-	5	20	-	5	20	-	5	20	mV
Output Current	I_{SOURCE}	$V_{I(+)}$ = 1V, $V_{I(-)}$ = 0V V_{CC} = 15V, $V_{O(P)}$ = 2V	10	30	-	10	30	-	10	30	-	mA
	I_{SINK}	$V_{I(+)}$ = 0V, $V_{I(-)}$ = 1V V_{CC} = 15V, $V_{O(P)}$ = 2V	5	8	-	5	9	-	5	9	-	mA
Differential Input Voltage	$V_{I(DIFF)}$	-	-	-	V_{CC}	-	-	V_{CC}	-	-	V_{CC}	V

Electrical Characteristics (Continued)

(V_{CC} = 5.0V, V_{EE} = GND, T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Conditions	LM258A			LM358A			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Input Offset Voltage	V_{IO}	V_{CM} = 0V to V_{CC} -1.5V $V_{O(P)}$ = 1.4V, R_S = 0Ω	-	1.0	3.0	-	2.0	3.0	mV
Input Offset Current	I_{IO}	-	-	2	15	-	5	30	nA
Input Bias Current	I_{BIAS}	-	-	40	80	-	45	100	nA
Input Voltage Range	$V_{I(R)}$	V_{CC} = 30V	0	-	V_{CC} -1.5	0	-	V_{CC} -1.5	V
Supply Current	I_{CC}	R_L = ∞,V_{CC} = 30V	-	0.8	2.0	-	0.8	2.0	mA
		RL = ∞, V_{CC} = 5V	-	0.5	1.2	-	0.5	1.2	mA
Large Signal Voltage Gain	G_V	V_{CC} = 15V, R_L= 2kΩ V_O = 1V to 11V	50	100	-	25	100	-	V/mV
Output Voltage Swing	V_{OH}	V_{CC} = 30V, R_L = 2kΩ	26	-	-	26	-	-	V
		V_{CC} = 30V, R_L =10kΩ	27	28	-	27	28	-	V
	$V_{O(L)}$	V_{CC} = 5V, R_L=10kΩ	-	5	20	-	5	20	mV
Common-Mode Rejection Ratio	CMRR	-	70	85	-	65	85	-	dB
Power Supply Rejection Ratio	PSRR	-	65	100	-	65	100	-	dB
Channel Separation	CS	f = 1kHz to 20kHz (Note1)	-	120	-	-	120	-	dB
Short Circuit to GND	I_{SC}	-	-	40	60	-	40	60	mA
Output Current	I_{SOURCE}	$V_{I(+)}$ = 1V, $V_{I(-)}$ = 0V V_{CC} = 15V, $V_{O(P)}$ = 2V	20	30	-	20	30	-	mA
	I_{SINK}	$V_{I(+)}$ = 1V, $V_{I(-)}$ = 0V V_{CC} = 15V, $V_{O(P)}$ = 2V	10	15	-	10	15	-	mA
		V_{in+} = 0V, $V_{in(-)}$ = 1V $V_{O(P)}$ = 200mV	12	100	-	12	100	-	µA
Differential Input Voltage	$V_{I(DIFF)}$	-	-	-	V_{CC}	-	-	V_{CC}	V

Note:

1. This parameter, although guaranteed, is not 100% tested in production.

Electrical Characteristics (Continued)

(V_{CC} = 5.0V, V_{EE} = GND, unless otherwise specified)
The following specification apply over the range of -25°C ≤ T_A ≤ +85°C for the LM258A; and the 0°C ≤ T_A ≤ +70°C for the LM358A

Parameter	Symbol	Conditions		LM258A			LM358A			Unit
				Min.	Typ.	Max.	Min.	Typ.	Max.	
Input Offset Voltage	V_{IO}	V_{CM} = 0V to V_{CC} -1.5V $V_{O(P)}$ = 1.4V, R_S = 0Ω		-	-	4.0	-	-	5.0	mV
Input Offset Voltage Drift	$\Delta V_{IO}/\Delta T$	-		-	7.0	15	-	7.0	20	µV/°C
Input Offset Current	I_{IO}	-		-	-	30	-	-	75	nA
Input Offset Current Drift	$\Delta I_{IO}/\Delta T$	-		-	10	200	-	10	300	pA/°C
Input Bias Current	I_{BIAS}	-		-	40	100	-	40	200	nA
Input Common-Mode Voltage Range	$V_{I(R)}$	V_{CC} = 30V		0	-	Vcc -2.0	0	-	Vcc -2.0	V
Output Voltage Swing	$V_{O(H)}$	V_{CC} = 30V	R_L = 2kΩ	26	-	-	26	-	-	V
			R_L = 10kΩ	27	28	-	27	28	-	V
	$V_{O(L)}$	V_{CC} = 5V, R_L=10kΩ		-	5	20	-	5	20	mV
Large Signal Voltage Gain	G_V	V_{CC} = 15V, R_L=2.0kΩ $V_{O(P)}$ = 1V to 11V		25	-	-	15	-	-	V/mV
Output Current	I_{SOURCE}	$V_{I(+)}$ = 1V, $V_{I(-)}$ = 0V V_{CC} = 15V, $V_{O(P)}$ = 2V		10	30	-	10	30	-	mA
	I_{SINK}	$V_{I(+)}$ = 1V, $V_{I(-)}$ = 0V V_{CC} = 15V, $V_{O(P)}$ = 2V		5	9	-	5	9	-	mA
Differential Input Voltage	$V_{I(DIFF)}$	-		-	-	V_{CC}	-	-	V_{CC}	V

Typical Performance Characteristics

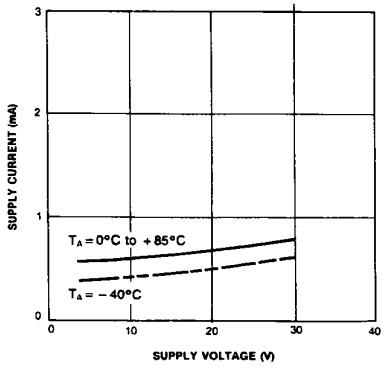


Figure 1. Supply Current vs Supply Voltage

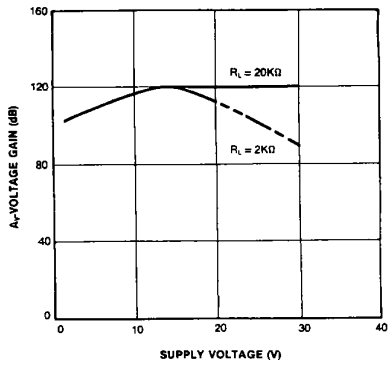


Figure 2. Voltage Gain vs Supply Voltage

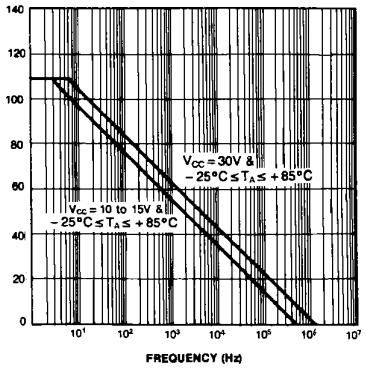


Figure 3. Open Loop Frequency Response

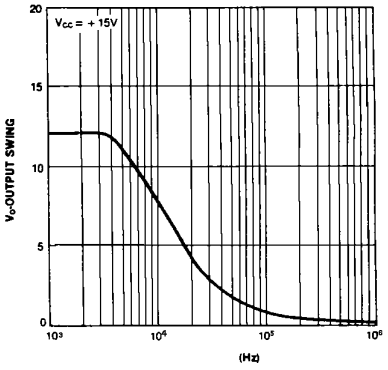


Figure 4. Large Signal Output Swing vs Frequency

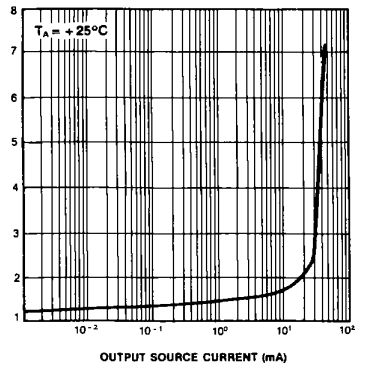


Figure 5. Output Characteristics vs Current Sourcing

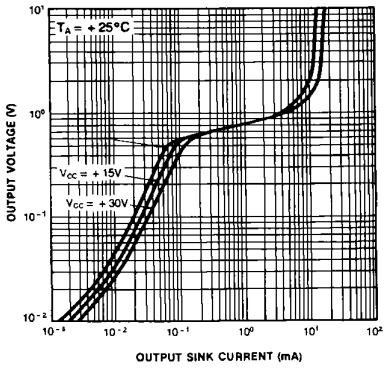


Figure 6. Output Characteristics vs Current Sinking

Typical Performance Characteristics (Continued)

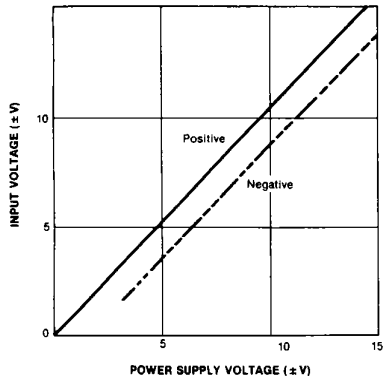


Figure 7. Input Voltage Range vs Supply Voltage

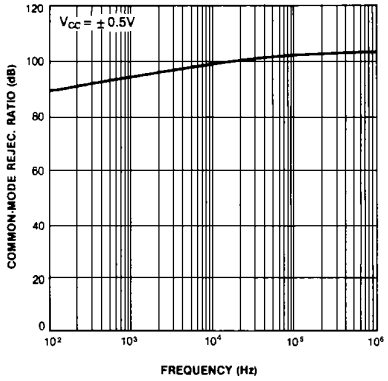


Figure 8. Common-Mode Rejection Ratio

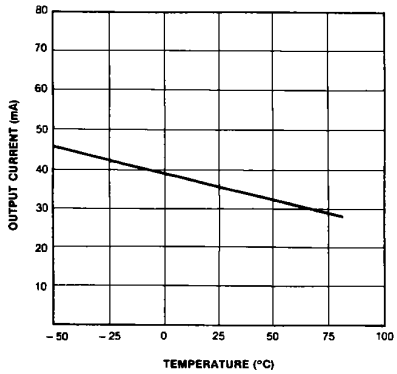


Figure 9. Output Current vs Temperature (Current Limiting)

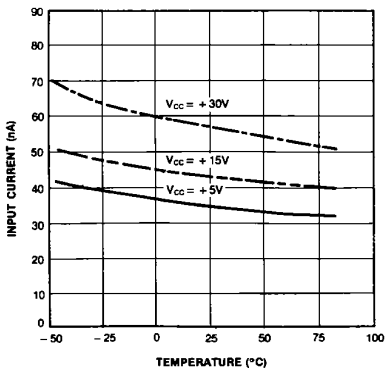


Figure 10. Input Current vs Temperature

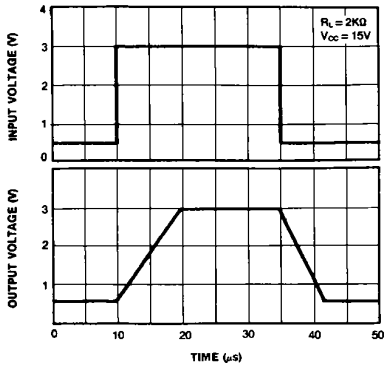


Figure 11. Voltage Follower Pulse Response

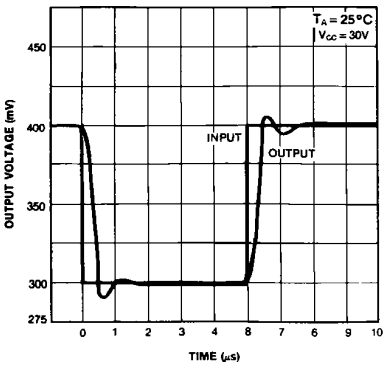


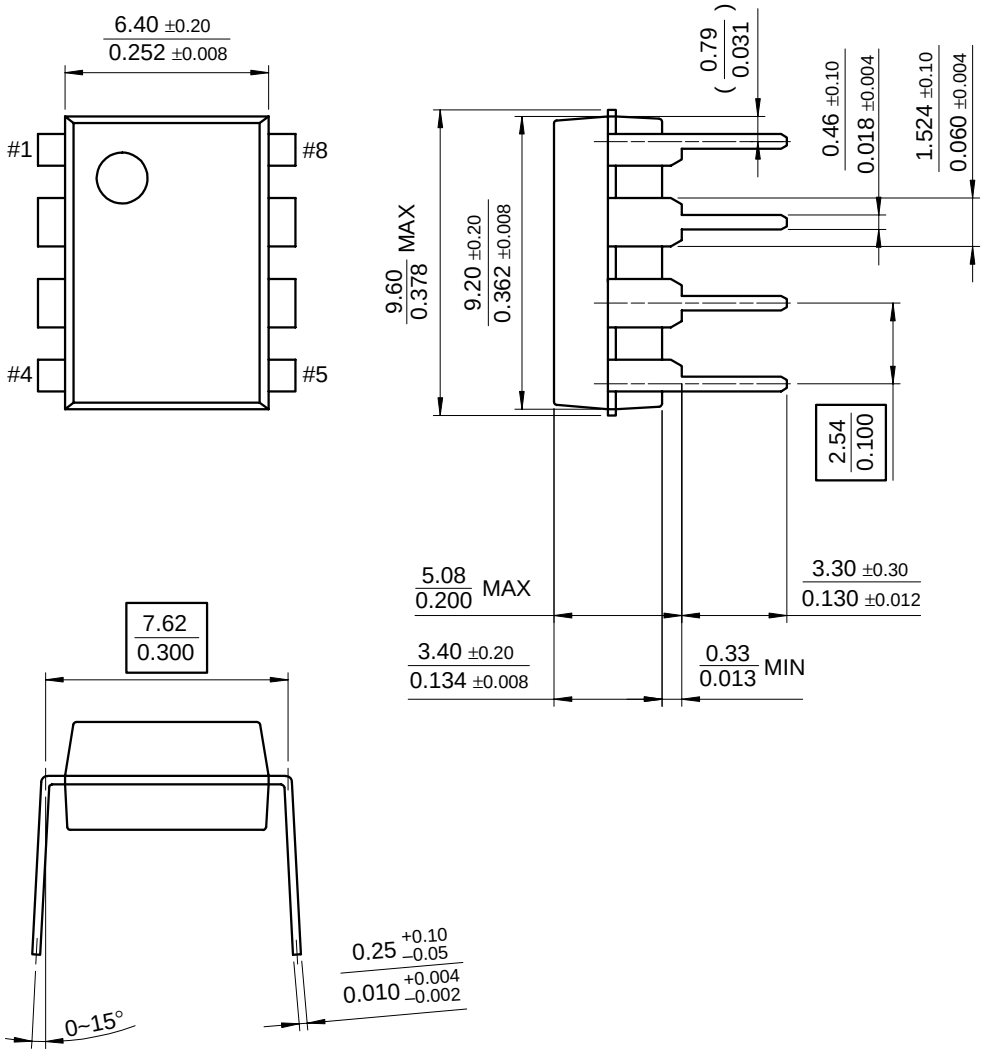
Figure 12. Voltage Follower Pulse Response (Small Signal)

Mechanical Dimensions

Package

Dimensions in millimeters

8-DIP

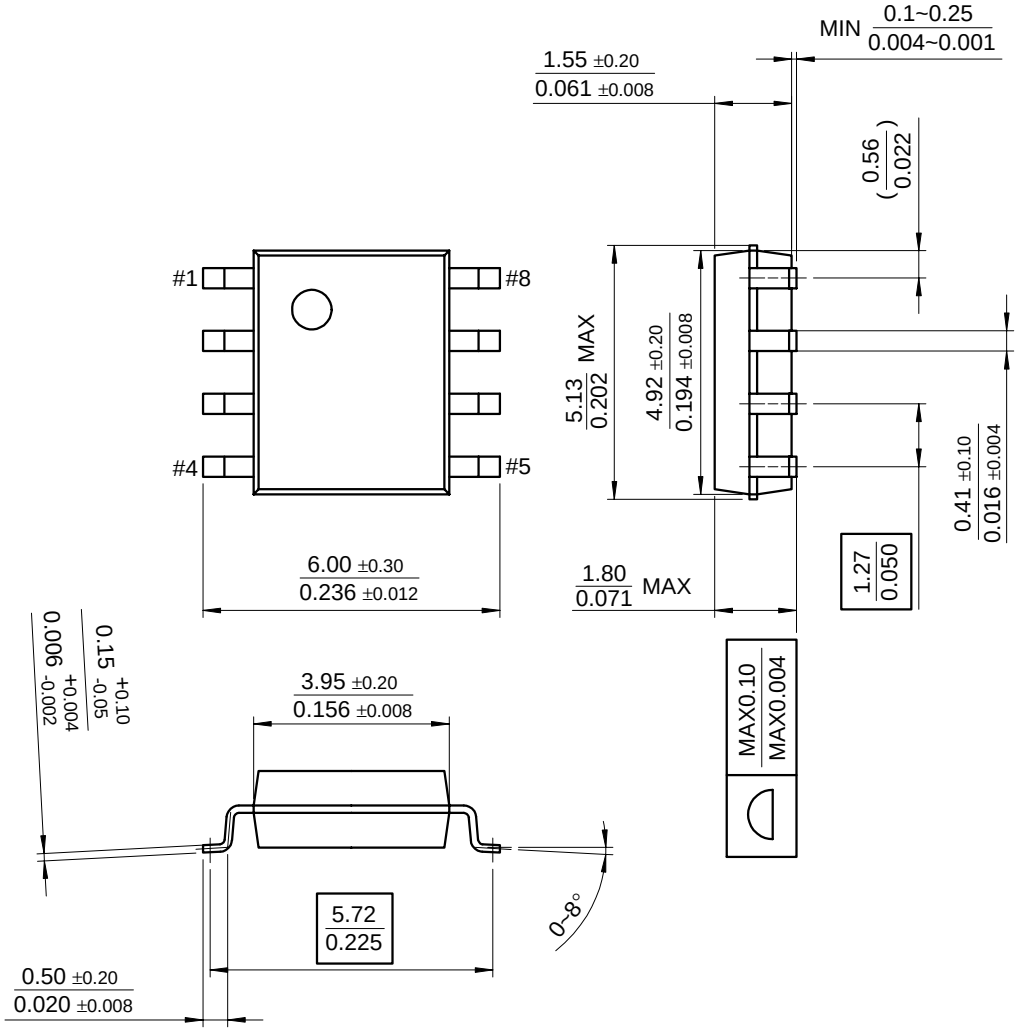


Mechanical Dimensions (Continued)

Package

Dimensions in millimeters

8-SOP



Ordering Information

Product Number	Package	Operating Temperature
LM358N	8-DIP	0 ~ +70°C
LM358AN		
LM358M	8-SOP	
LM358AM		
LM2904N	8-DIP	-40 ~ +85°C
LM2904M	8-SOP	
LM258N	8-DIP	-25 ~ +85°C
LM258AN		
LM258M	8-SOP	
LM258AM		

BC546B, BC547A, B, C, BC548B, C

Amplifier Transistors

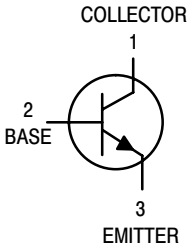
NPN Silicon

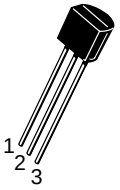
ON Semiconductor®

http://onsemi.com

Features

- Pb−Free Packages are Available*





TO−92
CASE 29
STYLE 17

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage BC546 BC547 BC548	V_{CEO}	 65 45 30	Vdc
Collector - Base Voltage BC546 BC547 BC548	V_{CBO}	 80 50 30	Vdc
Emitter - Base Voltage	V_{EBO}	6.0	Vdc
Collector Current − Continuous	I_C	100	mAdc
Total Device Dissipation @ T_A = 25°C Derate above 25°C	P_D	625 5.0	mW mW/°C
Total Device Dissipation @ T_C = 25°C Derate above 25°C	P_D	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−55 to +150	°C

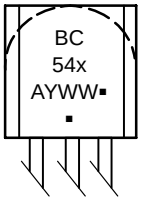
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	83.3	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MARKING DIAGRAM



BC54x = Device Code
x = 6, 7, or 8
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Collector − Emitter Breakdown Voltage (I_C = 1.0 mA, I_B = 0)	BC546	$V_{(BR)CEO}$	65	−	−	V
	BC547		45	−	−	
	BC548		30	−	−	
Collector − Base Breakdown Voltage (I_C = 100 μAdc)	BC546	$V_{(BR)CBO}$	80	−	−	V
	BC547		50	−	−	
	BC548		30	−	−	
Emitter − Base Breakdown Voltage (I_E = 10 μA, I_C = 0)	BC546	$V_{(BR)EBO}$	6.0	−	−	V
	BC547		6.0	−	−	
	BC548		6.0	−	−	
Collector Cutoff Current		I_{CES}				
(V_{CE} = 70 V, V_{BE} = 0)	BC546		−	0.2	15	nA
(V_{CE} = 50 V, V_{BE} = 0)	BC547		−	0.2	15	
(V_{CE} = 35 V, V_{BE} = 0)	BC548		−	0.2	15	
(V_{CE} = 30 V, T_A = 125°C)	BC546/547/548		−	−	4.0	μA
ON CHARACTERISTICS						
DC Current Gain		h_{FE}				−
(I_C = 10 μA, V_{CE} = 5.0 V)	BC547A		−	90	−	
	BC546B/547B/548B		−	150	−	
	BC548C		−	270	−	
(I_C = 2.0 mA, V_{CE} = 5.0 V)	BC546		110	−	450	
	BC547		110	−	800	
	BC548		110	−	800	
	BC547A		110	180	220	
	BC546B/547B/548B		200	290	450	
	BC547C/BC548C		420	520	800	
(I_C = 100 mA, V_{CE} = 5.0 V)	BC547A/548A		−	120	−	
	BC546B/547B/548B		−	180	−	
	BC548C		−	300	−	
Collector − Emitter Saturation Voltage		$V_{CE(sat)}$				V
(I_C = 10 mA, I_B = 0.5 mA)			−	0.09	0.25	
(I_C = 100 mA, I_B = 5.0 mA)			−	0.2	0.6	
(I_C = 10 mA, I_B = See Note 1)			−	0.3	0.6	
Base − Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.5 mA)		$V_{BE(sat)}$	−	0.7	−	V
Base − Emitter On Voltage		$V_{BE(on)}$				V
(I_C = 2.0 mA, V_{CE} = 5.0 V)			0.55	−	0.7	
(I_C = 10 mA, V_{CE} = 5.0 V)			−	−	0.77	
SMALL−SIGNAL CHARACTERISTICS						
Current − Gain − Bandwidth Product		f_T				MHz
(I_C = 10 mA, V_{CE} = 5.0 V, f = 100 MHz)	BC546		150	300	−	
	BC547		150	300	−	
	BC548		150	300	−	
Output Capacitance (V_{CB} = 10 V, I_C = 0, f = 1.0 MHz)		C_{obo}	−	1.7	4.5	pF
Input Capacitance (V_{EB} = 0.5 V, I_C = 0, f = 1.0 MHz)		C_{ibo}	−	10	−	pF
Small − Signal Current Gain		h_{fe}				−
(I_C = 2.0 mA, V_{CE} = 5.0 V, f = 1.0 kHz)	BC546		125	−	500	
	BC547/548		125	−	900	
	BC547A		125	220	260	
	BC546B/547B/548B		240	330	500	
	BC547C/548C		450	600	900	
Noise Figure		NF				dB
(I_C = 0.2 mA, V_{CE} = 5.0 V, R_S = 2 kΩ,	BC546		−	2.0	10	
f = 1.0 kHz, Δf = 200 Hz)	BC547		−	2.0	10	
	BC548		−	2.0	10	

1. I_B is value for which I_C = 11 mA at V_{CE} = 1.0 V.

BC547/BC548

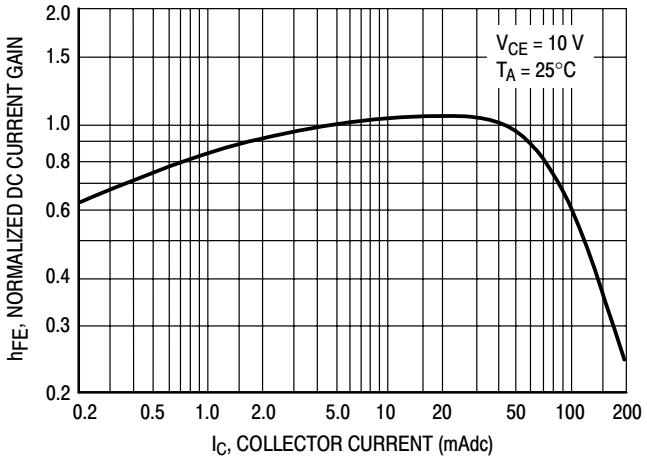


Figure 1. Normalized DC Current Gain

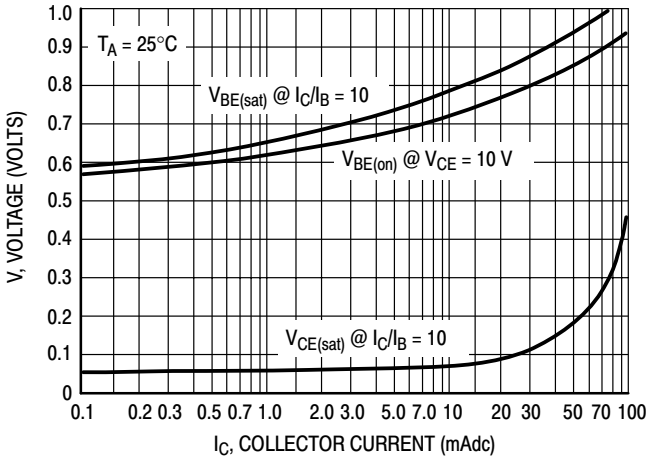


Figure 2. "Saturation" and "On" Voltages

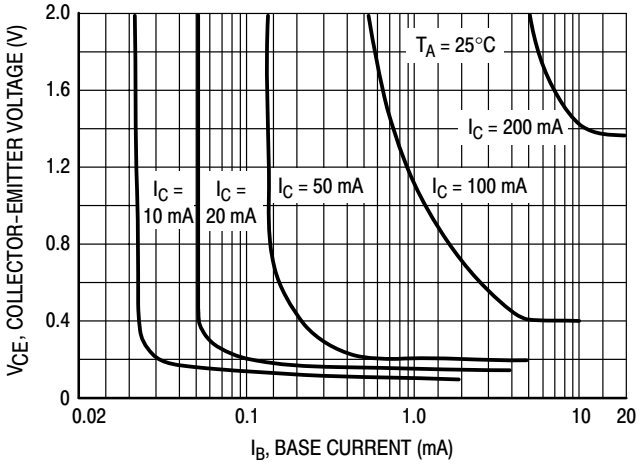


Figure 3. Collector Saturation Region

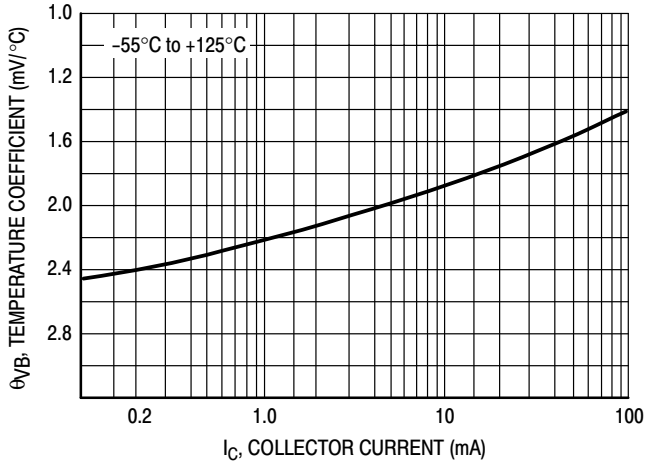


Figure 4. Base−Emitter Temperature Coefficient

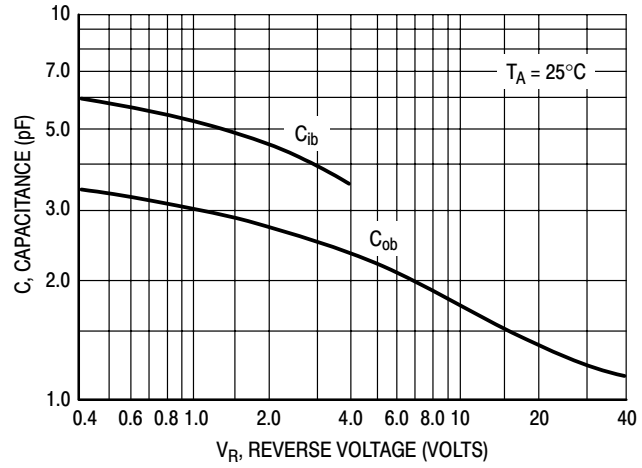


Figure 5. Capacitances

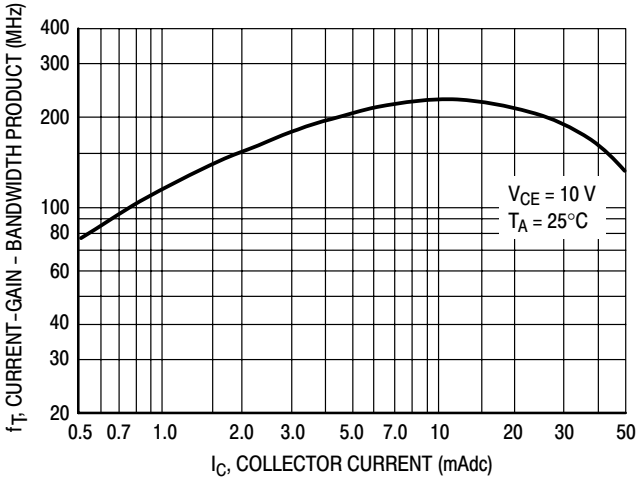


Figure 6. Current−Gain − Bandwidth Product

BC546

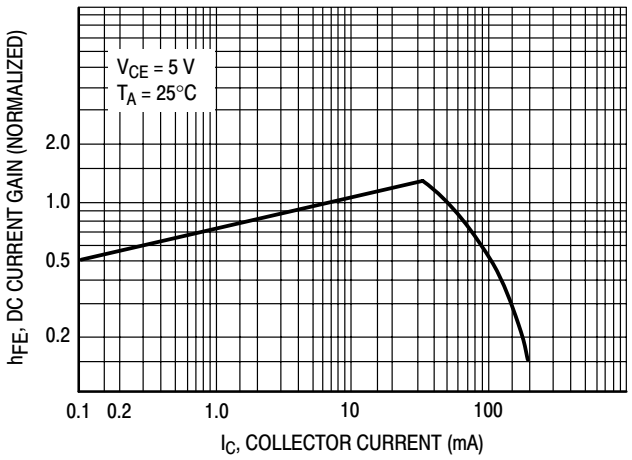


Figure 7. DC Current Gain

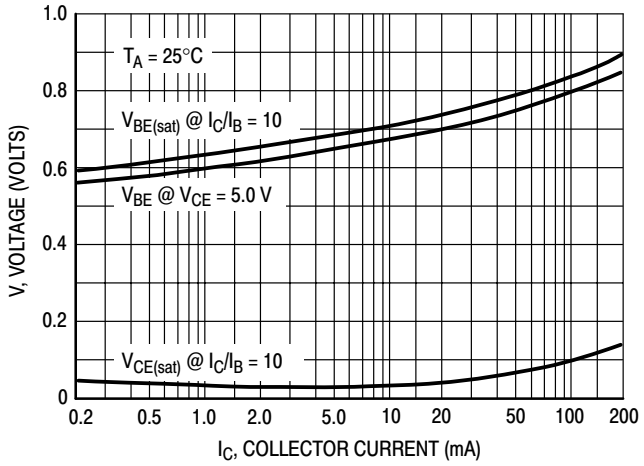


Figure 8. “On” Voltage

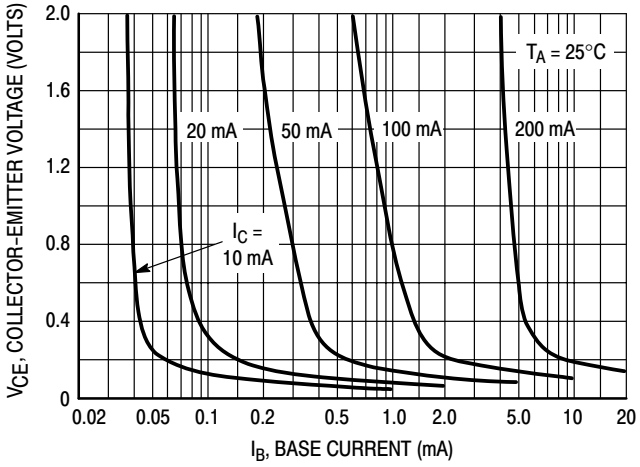


Figure 9. Collector Saturation Region

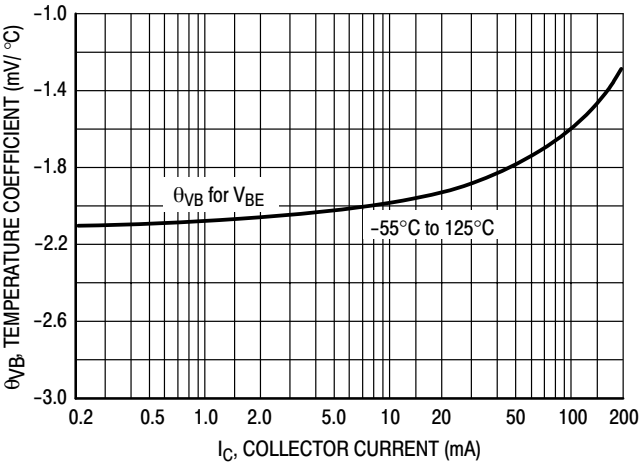


Figure 10. Base−Emitter Temperature Coefficient

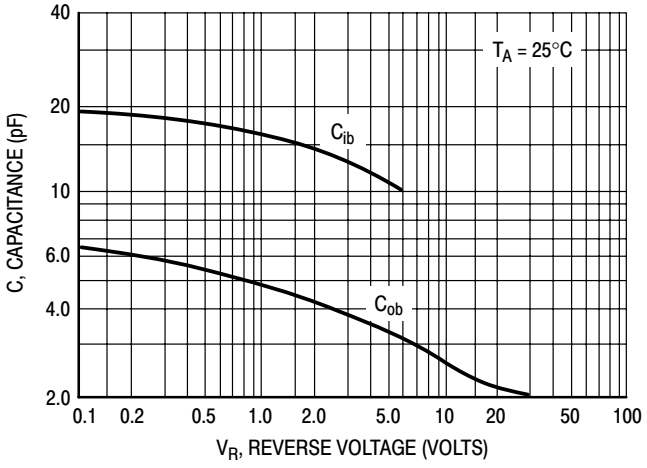


Figure 11. Capacitance

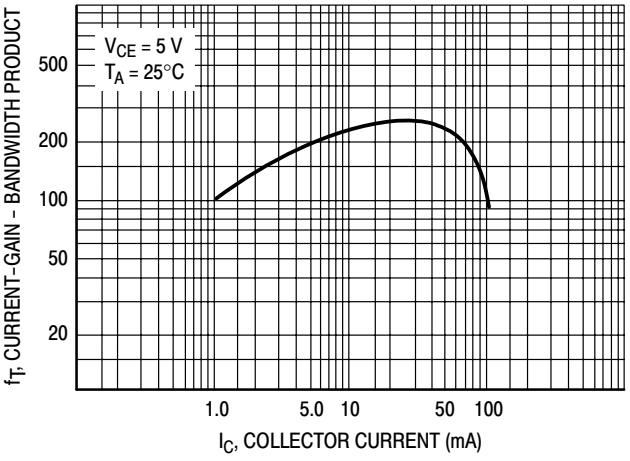


Figure 12. Current−Gain − Bandwidth Product

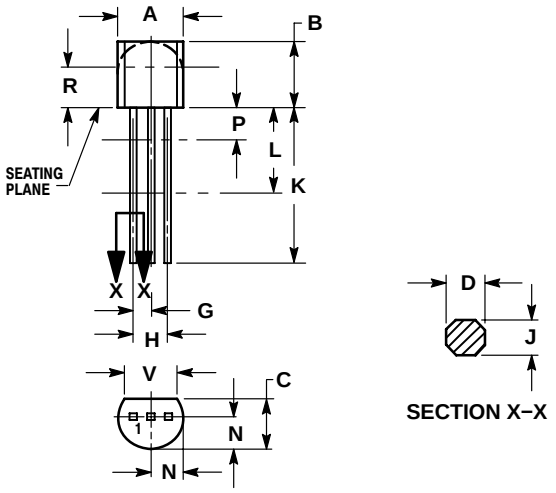
DEVICE ORDERING INFORMATION

Device	Package	Shipping†
BC546B	TO−92	5000 Units / Bulk
BC546BG	TO−92 (Pb−Free)	5000 Units / Bulk
BC546BRL1	TO−92	2000 / Tape & Reel
BC546BRL1G	TO−92 (Pb−Free)	2000 / Tape & Reel
BC546BZL1	TO−92	2000 / Ammo Box
BC546BZL1G	TO−92 (Pb−Free)	2000 / Ammo Box
BC547ARL	TO−92	2000 / Tape & Reel
BC547ARLG	TO−92 (Pb−Free)	2000 / Tape & Reel
BC547ARL1	TO−92	2000 / Tape & Reel
BC547ARL1G	TO−92 (Pb−Free)	2000 / Tape & Reel
BC547AZL1	TO−92	2000 / Ammo Box
BC547AZL1G	TO−92 (Pb−Free)	2000 / Ammo Box
BC547B	TO−92	5000 Units / Bulk
BC547BG	TO−92 (Pb−Free)	5000 Units / Bulk
BC547BRL1	TO−92	2000 / Tape & Reel
BC547BRL1G	TO−92 (Pb−Free)	2000 / Tape & Reel
BC547BZL1	TO−92	2000 / Ammo Box
BC547BZL1G	TO−92 (Pb−Free)	2000 / Ammo Box
BC547C	TO−92	5000 Units / Bulk
BC547CG	TO−92 (Pb−Free)	5000 Units / Bulk
BC547CZL1	TO−92	2000 / Ammo Box
BC547CZL1G	TO−92 (Pb−Free)	2000 / Ammo Box
BC548B	TO−92	5000 Units / Bulk
BC548BG	TO−92 (Pb−Free)	5000 Units / Bulk
BC548BRL1	TO−92	2000 / Tape & Reel
BC548BRL1G	TO−92 (Pb−Free)	2000 / Tape & Reel
BC548BZL1	TO−92	2000 / Ammo Box
BC548BZL1G	TO−92 (Pb−Free)	2000 / Ammo Box
BC548C	TO−92	5000 Units / Bulk
BC548CG	TO−92 (Pb−Free)	5000 Units / Bulk
BC548CZL1	TO−92	2000 / Ammo Box
BC548CZL1G	TO−92 (Pb−Free)	2000 / Ammo Box

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TO−92 (TO−226)
CASE 29−11
ISSUE AL



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

STYLE 17:
PIN 1. COLLECTOR
2. BASE
3. EMITTER

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PIC16F84A
Data Sheet

18-pin Enhanced FLASH/EEPROM
8-bit Microcontroller

Note the following details of the code protection feature on PICmicro® MCUs.

- The PICmicro family meets the specifications contained in the Microchip Data Sheet.
- Microchip believes that its family of PICmicro microcontrollers is one of the most secure products of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the PICmicro microcontroller in a manner outside the operating specifications contained in the data sheet. The person doing so may be engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable”.
- Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our product.

If you have any further questions about this matter, please contact the local sales office nearest to you.

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Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999. The Company’s quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs and microperipheral products. In addition, Microchip’s quality system for the design and manufacture of development systems is ISO 9001 certified.

PIC16F84A

18-pin *Enhanced* FLASH/EEPROM 8-Bit Microcontroller

High Performance RISC CPU Features:

- Only 35 single word instructions to learn
- All instructions single-cycle except for program branches which are two-cycle
- Operating speed: DC - 20 MHz clock input
  DC - 200 ns instruction cycle
- 1024 words of program memory
- 68 bytes of Data RAM
- 64 bytes of Data EEPROM
- 14-bit wide instruction words
- 8-bit wide data bytes
- 15 Special Function Hardware registers
- Eight-level deep hardware stack
- Direct, indirect and relative addressing modes
- Four interrupt sources:
  - External RB0/INT pin
  - TMR0 timer overflow
  - PORTB<7:4> interrupt-on-change
  - Data EEPROM write complete

Peripheral Features:

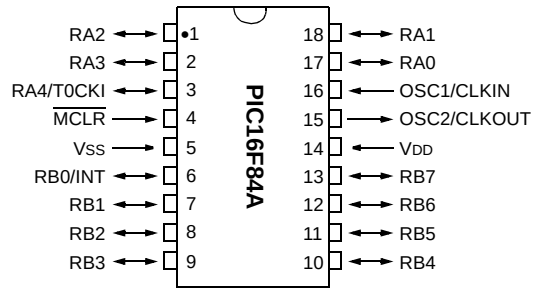
- 13 I/O pins with individual direction control
- High current sink/source for direct LED drive
  - 25 mA sink max. per pin
  - 25 mA source max. per pin
- TMR0: 8-bit timer/counter with 8-bit programmable prescaler

Special Microcontroller Features:

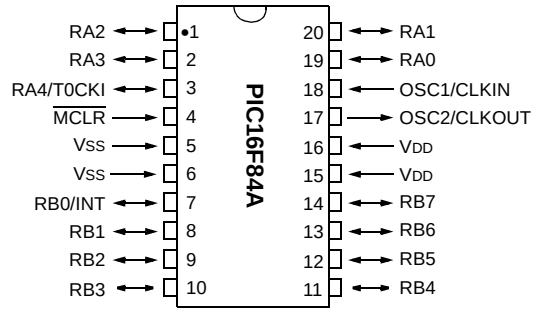
- 10,000 erase/write cycles *Enhanced* FLASH Program memory typical
- 10,000,000 typical erase/write cycles EEPROM Data memory typical
- EEPROM Data Retention > 40 years
- In-Circuit Serial Programming™ (ICSP™) - via two pins
- Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own On-Chip RC Oscillator for reliable operation
- Code protection
- Power saving SLEEP mode
- Selectable oscillator options

Pin Diagrams

PDIP, SOIC



SSOP



CMOS Enhanced FLASH/EEPROM Technology:

- Low power, high speed technology
- Fully static design
- Wide operating voltage range:
  - Commercial: 2.0V to 5.5V
  - Industrial: 2.0V to 5.5V
- Low power consumption:
  - < 2 mA typical @ 5V, 4 MHz
  - 15 μA typical @ 2V, 32 kHz
  - < 0.5 μA typical standby current @ 2V

Table of Contents

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1.0 DEVICE OVERVIEW

This document contains device specific information for the operation of the PIC16F84A device. Additional information may be found in the PICmicro™ Mid-Range Reference Manual, (DS33023), which may be downloaded from the Microchip website. The Reference Manual should be considered a complementary document to this data sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

The PIC16F84A belongs to the mid-range family of the PICmicro® microcontroller devices. A block diagram of the device is shown in Figure 1-1.

The program memory contains 1K words, which translates to 1024 instructions, since each 14-bit program memory word is the same width as each device instruction. The data memory (RAM) contains 68 bytes. Data EEPROM is 64 bytes.

There are also 13 I/O pins that are user-configured on a pin-to-pin basis. Some pins are multiplexed with other device functions. These functions include:

- External interrupt
- Change on PORTB interrupt
- Timer0 clock input

Table 1-1 details the pinout of the device with descriptions and details for each pin.

FIGURE 1-1: PIC16F84A BLOCK DIAGRAM

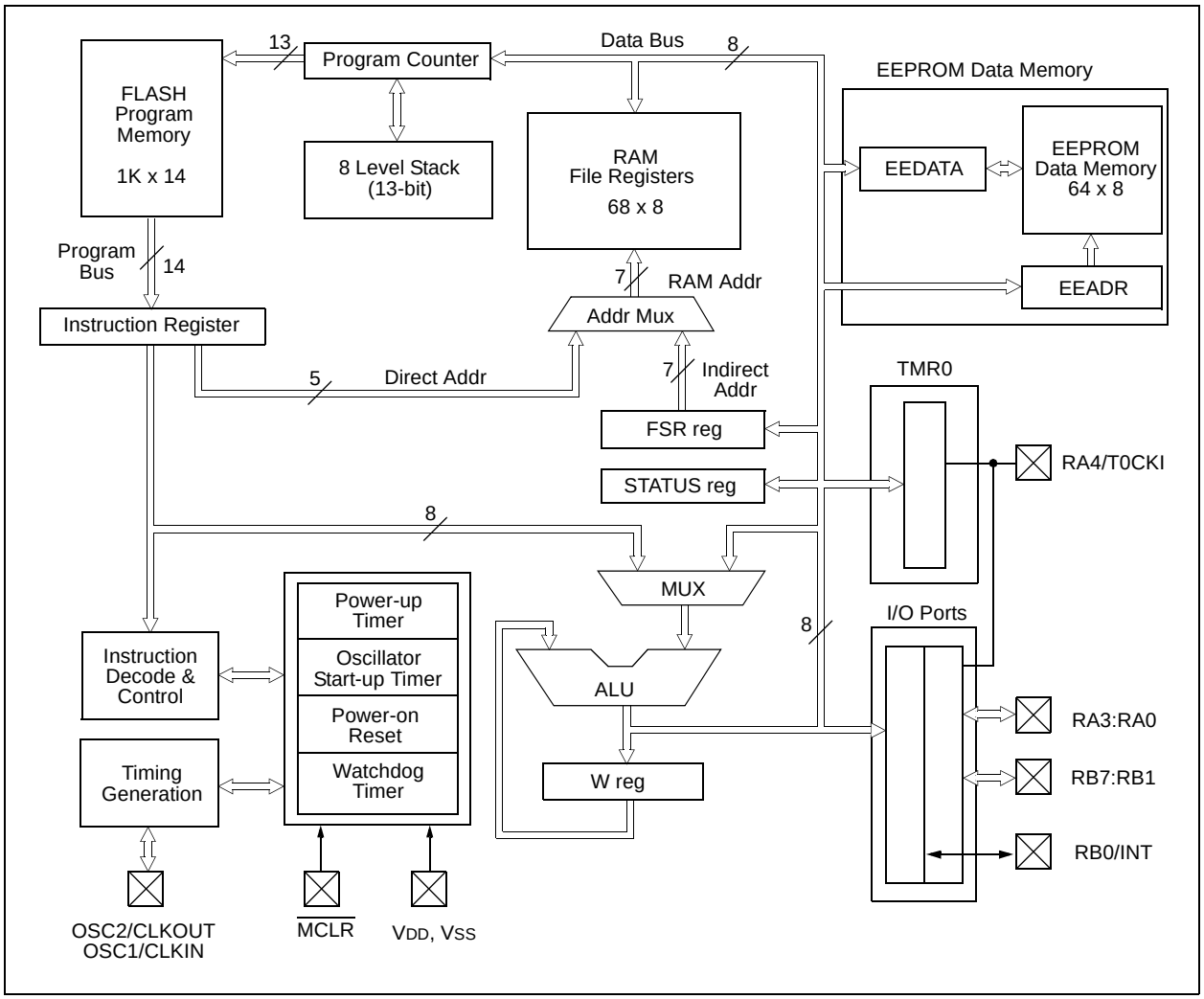


TABLE 1-1: PIC16F84A PINOUT DESCRIPTION

Pin Name	PDIP No.	SOIC No.	SSOP No.	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	16	16	18	I	ST/CMOS(3)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	19	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
$\overline{MCLR}$	4	4	4	I/P	ST	Master Clear (Reset) input/programming voltage input. This pin is an active low RESET to the device.
						PORTA is a bi-directional I/O port.
RA0	17	17	19	I/O	TTL	
RA1	18	18	20	I/O	TTL	
RA2	1	1	1	I/O	TTL	
RA3	2	2	2	I/O	TTL	
RA4/T0CKI	3	3	3	I/O	ST	Can also be selected to be the clock input to the TMR0 timer/counter. Output is open drain type.
						PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	6	6	7	I/O	TTL/ST(1)	RB0/INT can also be selected as an external interrupt pin.
RB1	7	7	8	I/O	TTL	
RB2	8	8	9	I/O	TTL	
RB3	9	9	10	I/O	TTL	
RB4	10	10	11	I/O	TTL	Interrupt-on-change pin.
RB5	11	11	12	I/O	TTL	Interrupt-on-change pin.
RB6	12	12	13	I/O	TTL/ST(2)	Interrupt-on-change pin. Serial programming clock.
RB7	13	13	14	I/O	TTL/ST(2)	Interrupt-on-change pin. Serial programming data.
VSS	5	5	5,6	P	—	Ground reference for logic and I/O pins.
VDD	14	14	15,16	P	—	Positive supply for logic and I/O pins.

Legend: I= input O = Output I/O = Input/Output P = Power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

2.0 MEMORY ORGANIZATION

There are two memory blocks in the PIC16F84A. These are the program memory and the data memory. Each block has its own bus, so that access to each block can occur during the same oscillator cycle.

The data memory can further be broken down into the general purpose RAM and the Special Function Registers (SFRs). The operation of the SFRs that control the “core” are described here. The SFRs used to control the peripheral modules are described in the section discussing each individual peripheral module.

The data memory area also contains the data EEPROM memory. This memory is not directly mapped into the data memory, but is indirectly mapped. That is, an indirect address pointer specifies the address of the data EEPROM memory to read/write. The 64 bytes of data EEPROM memory have the address range 0h-3Fh. More details on the EEPROM memory can be found in Section 3.0.

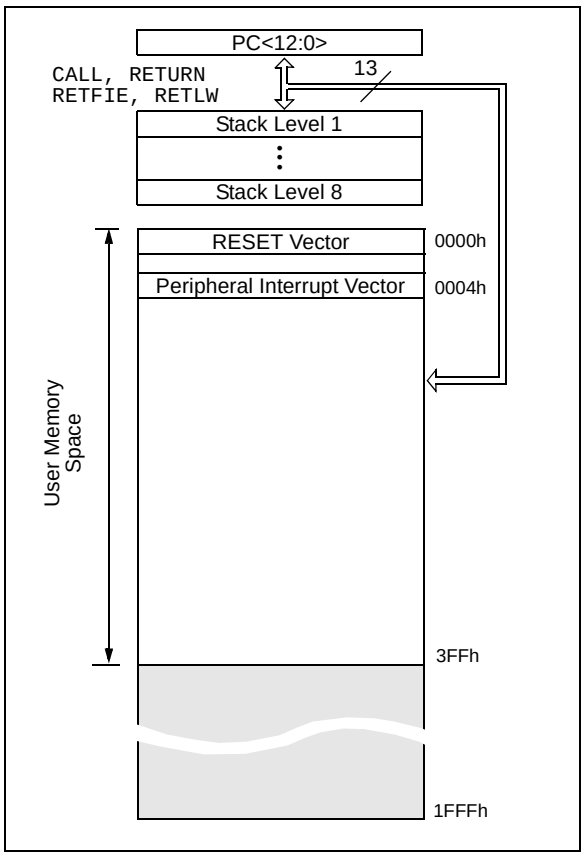
Additional information on device memory may be found in the PICmicro™ Mid-Range Reference Manual, (DS33023).

2.1 Program Memory Organization

The PIC16FXX has a 13-bit program counter capable of addressing an 8K x 14 program memory space. For the PIC16F84A, the first 1K x 14 (0000h-03FFh) are physically implemented (Figure 2-1). Accessing a location above the physically implemented address will cause a wraparound. For example, for locations 20h, 420h, 820h, C20h, 1020h, 1420h, 1820h, and 1C20h, the instruction will be the same.

The RESET vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK - PIC16F84A



2.2 Data Memory Organization

The data memory is partitioned into two areas. The first is the Special Function Registers (SFR) area, while the second is the General Purpose Registers (GPR) area. The SFRs control the operation of the device.

Portions of data memory are banked. This is for both the SFR area and the GPR area. The GPR area is banked to allow greater than 116 bytes of general purpose RAM. The banked areas of the SFR are for the registers that control the peripheral functions. Banking requires the use of control bits for bank selection. These control bits are located in the STATUS Register. Figure 2-2 shows the data memory map organization.

Instructions MOVWF and MOVF can move values from the W register to any location in the register file ("F"), and vice-versa.

The entire data memory can be accessed either directly using the absolute address of each register file or indirectly through the File Select Register (FSR) (Section 2.5). Indirect addressing uses the present value of the RP0 bit for access into the banked areas of data memory.

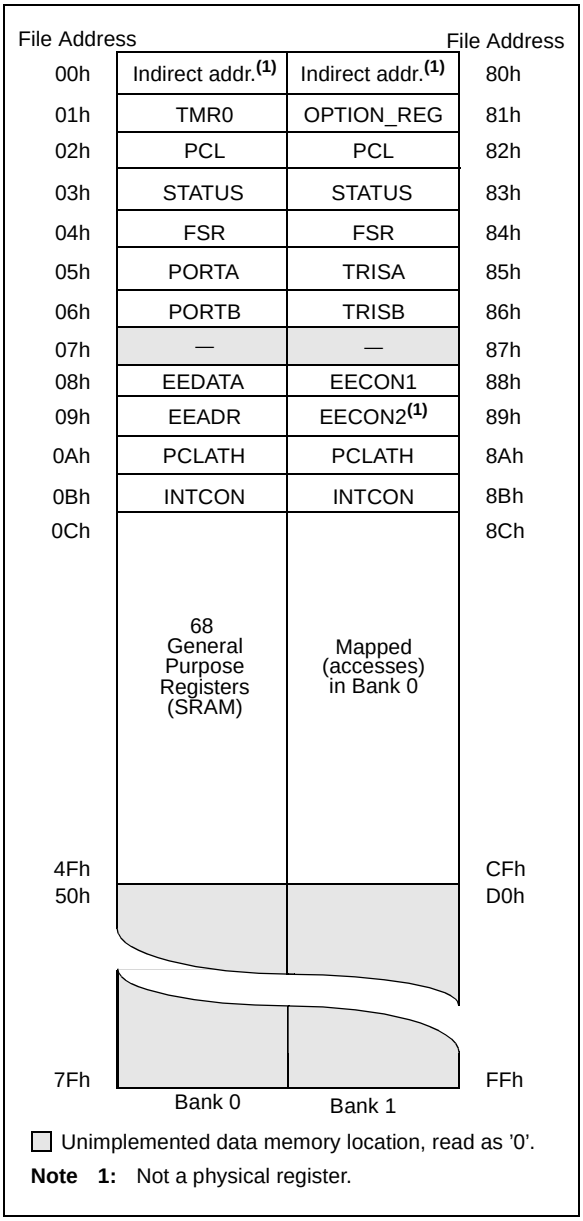
Data memory is partitioned into two banks which contain the general purpose registers and the special function registers. Bank 0 is selected by clearing the RP0 bit (STATUS<5>). Setting the RP0 bit selects Bank 1. Each Bank extends up to 7Fh (128 bytes). The first twelve locations of each Bank are reserved for the Special Function Registers. The remainder are General Purpose Registers, implemented as static RAM.

2.2.1 GENERAL PURPOSE REGISTER FILE

Each General Purpose Register (GPR) is 8-bits wide and is accessed either directly or indirectly through the FSR (Section 2.5).

The GPR addresses in Bank 1 are mapped to addresses in Bank 0. As an example, addressing location 0Ch or 8Ch will access the same GPR.

FIGURE 2-2: REGISTER FILE MAP - PIC16F84A



2.3 Special Function Registers

The Special Function Registers (Figure 2-2 and Table 2-1) are used by the CPU and Peripheral functions to control the device operation. These registers are static RAM.

The special function registers can be classified into two sets, core and peripheral. Those associated with the core functions are described in this section. Those related to the operation of the peripheral features are described in the section for that specific feature.

TABLE 2-1: SPECIAL FUNCTION REGISTER FILE SUMMARY

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on RESET	Details on page
Bank 0											
00h	INDF	Uses contents of FSR to address Data Memory (not a physical register)								---- ----	11
01h	TMR0	8-bit Real-Time Clock/Counter								xxxx xxxx	20
02h	PCL	Low Order 8 bits of the Program Counter (PC)								0000 0000	11
03h	STATUS(2)	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	8
04h	FSR	Indirect Data Memory Address Pointer 0								xxxx xxxx	11
05h	PORTA(4)	—	—	—	RA4/T0CKI	RA3	RA2	RA1	RA0	---x xxxx	16
06h	PORTB(5)	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0/INT	xxxx xxxx	18
07h	—	Unimplemented location, read as '0'								—	—
08h	EEDATA	EEPROM Data Register								xxxx xxxx	13,14
09h	EEADR	EEPROM Address Register								xxxx xxxx	13,14
0Ah	PCLATH	—	—	—	Write Buffer for upper 5 bits of the PC(1)					---0 0000	11
0Bh	INTCON	GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	10
Bank 1											
80h	INDF	Uses Contents of FSR to address Data Memory (not a physical register)								---- ----	11
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	9
82h	PCL	Low order 8 bits of Program Counter (PC)								0000 0000	11
83h	STATUS (2)	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	8
84h	FSR	Indirect data memory address pointer 0								xxxx xxxx	11
85h	TRISA	—	—	—	PORTA Data Direction Register					---1 1111	16
86h	TRISB	PORTB Data Direction Register								1111 1111	18
87h	—	Unimplemented location, read as '0'								—	—
88h	EECON1	—	—	—	EEIF	WRERR	WREN	WR	RD	---0 x000	13
89h	EECON2	EEPROM Control Register 2 (not a physical register)								---- ----	14
0Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of the PC(1)					---0 0000	11
0Bh	INTCON	GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	10

Legend: x = unknown, u = unchanged. - = unimplemented, read as '0', q = value depends on condition

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a slave register for PC<12:8>. The contents of PCLATH can be transferred to the upper byte of the program counter, but the contents of PC<12:8> are never transferred to PCLATH.

2: The $\overline{TO}$ and $\overline{PD}$ status bits in the STATUS register are not affected by a $\overline{MCLR}$ Reset.

3: Other (non power-up) RESETS include: external RESET through $\overline{MCLR}$ and the Watchdog Timer Reset.

4: On any device RESET, these pins are configured as inputs.

5: This is the value that will be in the port output latch.

2.3.1 STATUS REGISTER

The STATUS register contains the arithmetic status of the ALU, the RESET status and the bank select bit for data memory.

As with any register, the STATUS register can be the destination for any instruction. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where u = unchanged).

Only the `BCF, BSF, SWAPF` and `MOVWF` instructions should be used to alter the STATUS register (Table 7-2), because these instructions do not affect any status bit.

Note 1: The IRP and RP1 bits (STATUS<7:6>) are not used by the PIC16F84A and should be programmed as cleared. Use of these bits as general purpose R/W bits is NOT recommended, since this may affect upward compatibility with future products.

2: The C and DC bits operate as a $\overline{borrow}$ and digit borrow out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

3: When the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. The specified bit(s) will be updated according to device logic

REGISTER 2-1: STATUS REGISTER (ADDRESS 03h, 83h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

bit 7-6 **Unimplemented:** Maintain as '0'

bit 5 **RP0**: Register Bank Select bits (used for direct addressing)
01 = Bank 1 (80h - FFh)
00 = Bank 0 (00h - 7Fh)

bit 4 **$\overline{TO}$**: Time-out bit
1 = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
0 = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-down bit
1 = After power-up or by the `CLRWDT` instruction
0 = By execution of the `SLEEP` instruction

bit 2 **Z**: Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for $\overline{borrow}$, the polarity is reversed)
1 = A carry-out from the 4th low order bit of the result occurred
0 = No carry-out from the 4th low order bit of the result

bit 0 **C**: Carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for $\overline{borrow}$, the polarity is reversed)
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note: A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.3.2 OPTION REGISTER

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external INT interrupt, TMR0, and the weak pull-ups on PORTB.

Note:	When the prescaler is assigned to the WDT (PSA = '1'), TMR0 has a 1:1 prescaler assignment.

REGISTER 2-2: OPTION REGISTER (ADDRESS 81h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

bit 7 **$\overline{\text{RBPU}}$:** PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6 **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5 **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4 **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3 **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.3.3 INTCON REGISTER

The INTCON register is a readable and writable register that contains the various enable bits for all interrupt sources.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

REGISTER 2-3: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF
bit 7							bit 0

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6 **EEIE**: EE Write Complete Interrupt Enable bit
1 = Enables the EE Write Complete interrupts
0 = Disables the EE Write Complete interrupt

bit 5 **T0IE**: TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 interrupt
0 = Disables the TMR0 interrupt

bit 4 **INTE**: RB0/INT External Interrupt Enable bit
1 = Enables the RB0/INT external interrupt
0 = Disables the RB0/INT external interrupt

bit 3 **RBIE**: RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2 **T0IF**: TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INTF**: RB0/INT External Interrupt Flag bit
1 = The RB0/INT external interrupt occurred (must be cleared in software)
0 = The RB0/INT external interrupt did not occur

bit 0 **RBIF**: RB Port Change Interrupt Flag bit
1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)
0 = None of the RB7:RB4 pins have changed state

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.4 PCL and PCLATH

The program counter (PC) specifies the address of the instruction to fetch for execution. The PC is 13 bits wide. The low byte is called the PCL register. This register is readable and writable. The high byte is called the PCH register. This register contains the PC<12:8> bits and is not directly readable or writable. If the program counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP. All updates to the PCH register go through the PCLATH register.

2.4.1 STACK

The stack allows a combination of up to 8 program calls and interrupts to occur. The stack contains the return address from this branch in program execution.

Mid-range devices have an 8 level deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not modified when the stack is PUSHed or POPed.

After the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

2.5 Indirect Addressing; INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 2-1: INDIRECT ADDRESSING

- Register file 05 contains the value 10h
- Register file 06 contains the value 0Ah
- Load the value 05 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 06)
- A read of the INDF register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected).

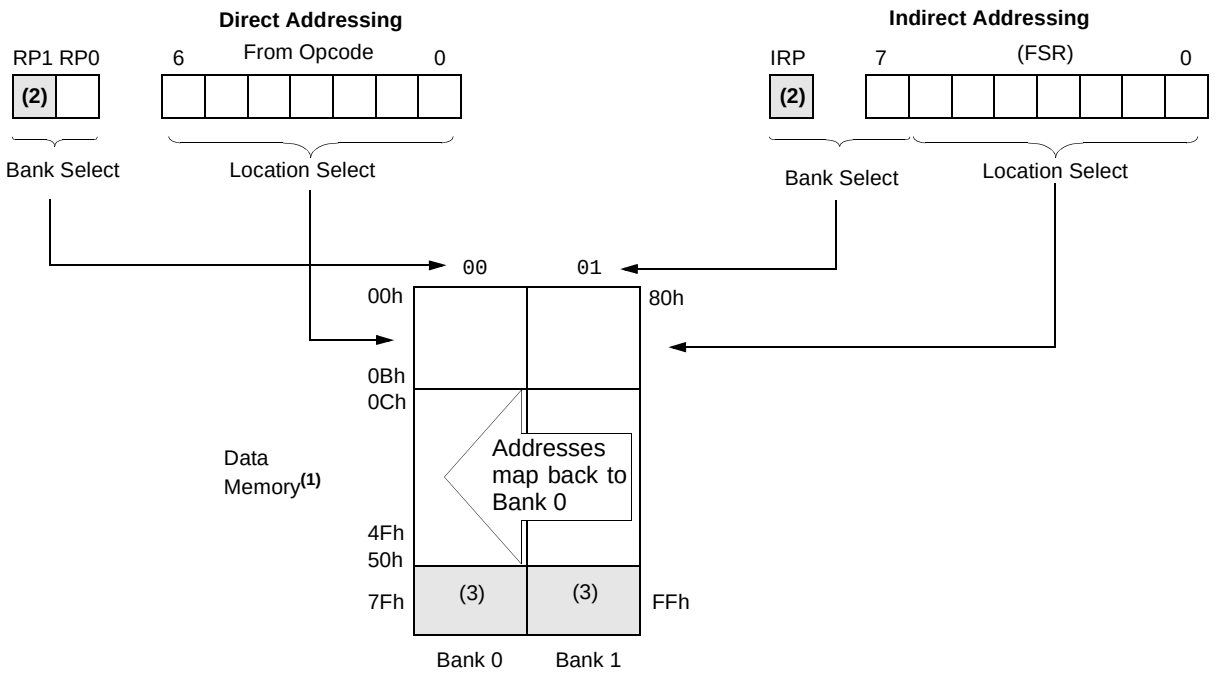
A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 2-2.

EXAMPLE 2-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

```
        movlw   0x20    ;initialize pointer
        movwf   FSR     ;to RAM
NEXT    clrf    INDF    ;clear INDF register
        incf    FSR     ;inc pointer
        btfss   FSR,4   ;all done?
        goto    NEXT    ;NO, clear next
CONTINUE
         :              ;YES, continue
```

An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 2-3. However, IRP is not used in the PIC16F84A.

FIGURE 2-3: DIRECT/INDIRECT ADDRESSING



Note 1: For memory map detail, see Figure 2-2.

2: Maintain as clear for upward compatibility with future products.

3: Not implemented.

3.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full V_{DD} range). This memory is not directly mapped in the register file space. Instead it is indirectly addressed through the Special Function Registers. There are four SFRs used to read and write this memory. These registers are:

- EECON1
- EECON2 (not a physically implemented register)
- EEDATA
- EEADR

EEDATA holds the 8-bit data for read/write, and EEADR holds the address of the EEPROM location being accessed. PIC16F84A devices have 64 bytes of data EEPROM with an address range from 0h to 3Fh.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write-time will vary with voltage and temperature as well as from chip to chip. Please refer to AC specifications for exact limits.

When the device is code protected, the CPU may continue to read and write the data EEPROM memory. The device programmer can no longer access this memory.

Additional information on the Data EEPROM is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

REGISTER 3-1: EECON1 REGISTER (ADDRESS 88h)

U-0	U-0	U-0	R/W-0	R/W-x	R/W-0	R/S-0	R/S-0
—	—	—	EEIF	WRERR	WREN	WR	RD
bit 7							bit 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **EEIF:** EEPROM Write Operation Interrupt Flag bit
1 = The write operation completed (must be cleared in software)
0 = The write operation is not complete or has not been started

bit 3 **WRERR:** EEPROM Error Flag bit
1 = A write operation is prematurely terminated
(any $\overline{\text{MCLR}}$ Reset or any WDT Reset during normal operation)
0 = The write operation completed

bit 2 **WREN:** EEPROM Write Enable bit
1 = Allows write cycles
0 = Inhibits write to the EEPROM

bit 1 **WR:** Write Control bit
1 = Initiates a write cycle. The bit is cleared by hardware once write is complete. The WR bit can only be set (not cleared) in software.
0 = Write cycle to the EEPROM is complete

bit 0 **RD:** Read Control bit
1 = Initiates an EEPROM read RD is cleared in hardware. The RD bit can only be set (not cleared) in software.
0 = Does not initiate an EEPROM read

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

3.1 Reading the EEPROM Data Memory

To read a data memory location, the user must write the address to the EEADR register and then set control bit RD (EECON1<0>). The data is available, in the very next cycle, in the EEDATA register; therefore, it can be read in the next instruction. EEDATA will hold this value until another read or until it is written to by the user (during a write operation).

EXAMPLE 3-1: DATA EEPROM READ

```
BCF     STATUS, RP0  ; Bank 0
MOVLW   CONFIG_ADDR  ;
MOVWF   EEADR        ; Address to read
BSF     STATUS, RP0  ; Bank 1
BSF     EECON1, RD   ; EE Read
BCF     STATUS, RP0  ; Bank 0
MOVF    EEDATA, W    ; W = EEDATA
```

3.2 Writing to the EEPROM Data Memory

To write an EEPROM data location, the user must first write the address to the EEADR register and the data to the EEDATA register. Then the user must follow a specific sequence to initiate the write for each byte.

EXAMPLE 3-2: DATA EEPROM WRITE

```
        BSF     STATUS, RP0  ; Bank 1
        BCF     INTCON, GIE  ; Disable INTs.
        BSF     EECON1, WREN ; Enable Write
        MOVLW   55h          ;
Required
Sequence
        MOVWF   EECON2       ; Write 55h
        MOVLW   AAh          ;
        MOVWF   EECON2       ; Write AAh
        BSF     EECON1,WR    ; Set WR bit
                             ;   begin write
        BSF     INTCON, GIE  ; Enable INTs.
```

The write will not initiate if the above sequence is not exactly followed (write 55h to EECON2, write AAh to EECON2, then set WR bit) for each byte. We strongly recommend that interrupts be disabled during this code segment.

Additionally, the WREN bit in EECON1 must be set to enable write. This mechanism prevents accidental writes to data EEPROM due to errant (unexpected) code execution (i.e., lost programs). The user should keep the WREN bit clear at all times, except when updating EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, clearing the WREN bit will not affect this write cycle. The WR bit will be inhibited from being set unless the WREN bit is set.

At the completion of the write cycle, the WR bit is cleared in hardware and the EE Write Complete Interrupt Flag bit (EEIF) is set. The user can either enable this interrupt or poll this bit. EEIF must be cleared by software.

3.3 Write Verify

Depending on the application, good programming practice may dictate that the value written to the Data EEPROM should be verified (Example 3-3) to the desired value to be written. This should be used in applications where an EEPROM bit will be stressed near the specification limit.

Generally, the EEPROM write failure will be a bit which was written as a '0', but reads back as a '1' (due to leakage off the bit).

EXAMPLE 3-3: WRITE VERIFY

```
      BCF   STATUS,RP0 ; Bank 0
      :                ; Any code
      :                ; can go here
      MOVF  EEDATA,W   ; Must be in Bank 0
      BSF   STATUS,RP0 ; Bank 1
READ
      BSF   EECON1, RD ; YES, Read the
                       ; value written
      BCF   STATUS, RP0 ; Bank 0
                       ;
                       ; Is the value written
                       ; (in W reg) and
                       ; read (in EEDATA)
                       ; the same?
                       ;
      SUBWF EEDATA, W  ;
      BTFSS STATUS, Z  ; Is difference 0?
      GOTO  WRITE_ERR  ; NO, Write error
```

TABLE 3-1: REGISTERS/BITS ASSOCIATED WITH DATA EEPROM

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other RESETS
08h	EEDATA	EEPROM Data Register								xxxx xxxx	uuuu uuuu
09h	EEADR	EEPROM Address Register								xxxx xxxx	uuuu uuuu
88h	EECON1	—	—	—	EEIF	WRERR	WREN	WR	RD	---0 x000	---0 q000
89h	EECON2	EEPROM Control Register 2								---- ----	---- ----

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0', q = value depends upon condition.
Shaded cells are not used by data EEPROM.

4.0 I/O PORTS

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

Additional information on I/O ports may be found in the PICmicro™ Mid-Range Reference Manual (DS33023).

4.1 PORTA and TRISA Registers

PORTA is a 5-bit wide, bi-directional port. The corresponding data direction register is TRISA. Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output (i.e., put the contents of the output latch on the selected pin).

Note:	On a Power-on Reset, these pins are configured as inputs and read as '0'.

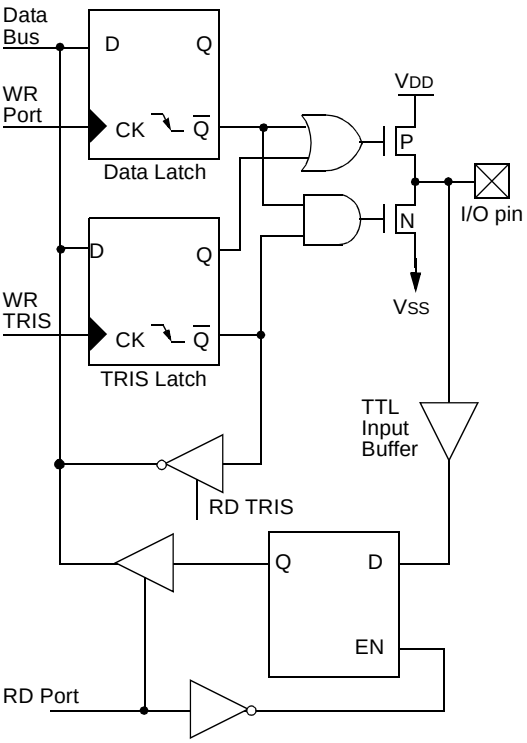
Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read. This value is modified and then written to the port data latch.

Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin. The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers.

EXAMPLE 4-1: INITIALIZING PORTA

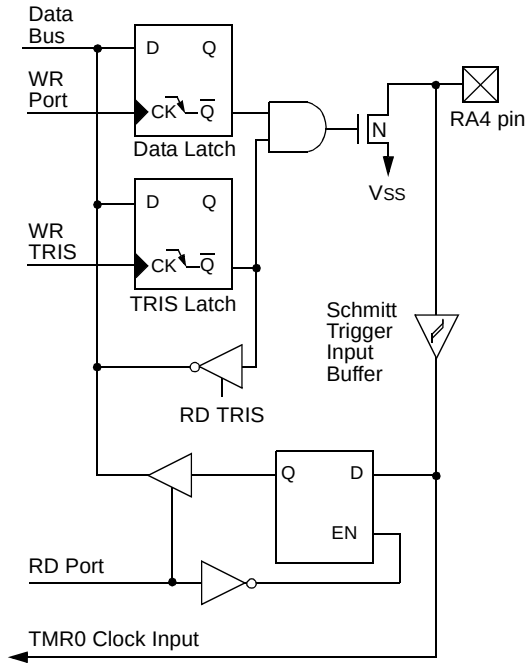
```
BCF     STATUS, RP0 ;
CLRF    PORTA       ; Initialize PORTA by
                    ; clearing output
                    ; data latches
BSF     STATUS, RP0 ; Select Bank 1
MOVLW   0x0F        ; Value used to
                    ; initialize data
                    ; direction
MOVWF   TRISA       ; Set RA<3:0> as inputs
                    ; RA4 as output
                    ; TRISA<7:5> are always
                    ; read as '0'.
```

FIGURE 4-1: BLOCK DIAGRAM OF PINS RA3:RA0



Note: I/O pins have protection diodes to VDD and VSS.

FIGURE 4-2: BLOCK DIAGRAM OF PIN RA4



Note: I/O pins have protection diodes to VDD and VSS.

TABLE 4-1: PORTA FUNCTIONS

Name	Bit0	Buffer Type	Function
RA0	bit0	TTL	Input/output
RA1	bit1	TTL	Input/output
RA2	bit2	TTL	Input/output
RA3	bit3	TTL	Input/output
RA4/T0CKI	bit4	ST	Input/output or external clock input for TMR0. Output is open drain type.

Legend: TTL = TTL input, ST = Schmitt Trigger input

TABLE 4-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other RESETS
05h	PORTA	—	—	—	RA4/T0CKI	RA3	RA2	RA1	RA0	---x xxxx	---u uuuu
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are unimplemented, read as '0'.

4.2 PORTB and TRISB Registers

PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., put the contents of the output latch on the selected pin).

EXAMPLE 4-2: INITIALIZING PORTB

```
BCF     STATUS, RP0 ;
CLRF    PORTB       ; Initialize PORTB by
                    ; clearing output
                    ; data latches
BSF     STATUS, RP0 ; Select Bank 1
MOVLW   0xCF        ; Value used to
                    ; initialize data
                    ; direction
MOVWF   TRISB       ; Set RB<3:0> as inputs
                    ; RB<5:4> as outputs
                    ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{RBPU}$ (OPTION<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

Four of PORTB's pins, RB7:RB4, have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt-on-change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

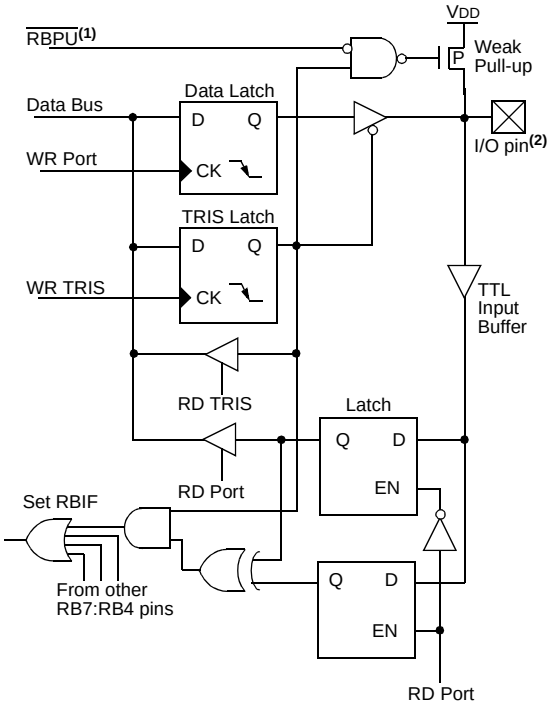
a) Any read or write of PORTB. This will end the mismatch condition.

b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

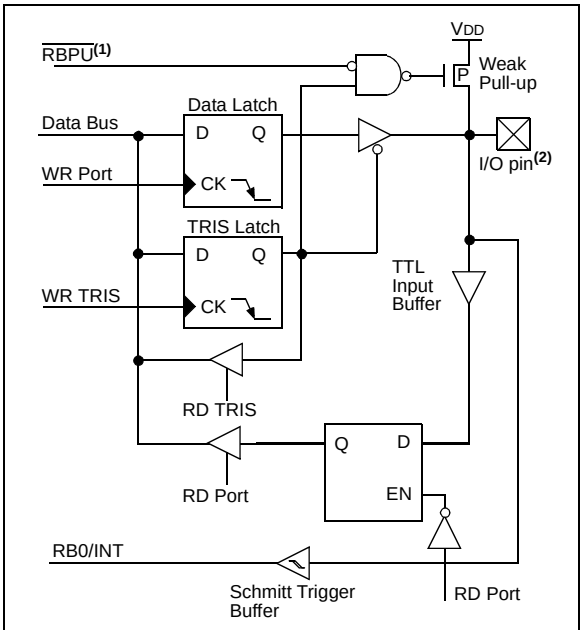
FIGURE 4-3: BLOCK DIAGRAM OF PINS RB7:RB4



Note 1: TRISB = '1' enables weak pull-up (if $\overline{RBPU}$ = '0' in the OPTION_REG register).

2: I/O pins have diode protection to VDD and VSS.

FIGURE 4-4: BLOCK DIAGRAM OF PINS RB3:RB0



Note 1: TRISB = '1' enables weak pull-up (if $\overline{RBPU}$ = '0' in the OPTION_REG register).

2: I/O pins have diode protection to VDD and VSS.

TABLE 4-3: PORTB FUNCTIONS

Name	Bit	Buffer Type	I/O Consistency Function
RB0/INT	bit0	TTL/ST(1)	Input/output pin or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	TTL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3	bit3	TTL	Input/output pin. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST(2)	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming clock.
RB7	bit7	TTL/ST(2)	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming data.

Legend: TTL = TTL input, ST = Schmitt Trigger.

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

TABLE 4-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other RESETS
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0/INT	xxxx xxxx	uuuu uuuu
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
0Bh,8Bh	INTCON	GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u

Legend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.

5.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- Internal or external clock select
- Edge select for external clock
- 8-bit software programmable prescaler
- Interrupt-on-overflow from FFh to 00h

Figure 5-1 is a simplified block diagram of the Timer0 module.

Additional information on timer modules is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

5.1 Timer0 Operation

Timer0 can operate as a timer or as a counter.

Timer mode is selected by clearing bit T0CS (OPTION_REG<5>). In Timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If the TMR0 register is written, the increment is inhibited for the following two instruction cycles. The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting bit T0CS (OPTION_REG<5>). In Counter mode, Timer0 will increment, either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the Timer0 Source Edge Select bit, T0SE (OPTION_REG<4>). Clearing bit T0SE selects the rising edge. Restrictions on the external clock input are discussed below.

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (TOSC). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

Additional information on external clock requirements is available in the PICmicro™ Mid-Range Reference Manual, (DS33023).

5.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer, respectively (Figure 5-2). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that there is only one prescaler available which is mutually exclusively shared between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer, and vice-versa.

The prescaler is not readable or writable.

The PSA and PS2:PS0 bits (OPTION_REG<3:0>) determine the prescaler assignment and prescale ratio.

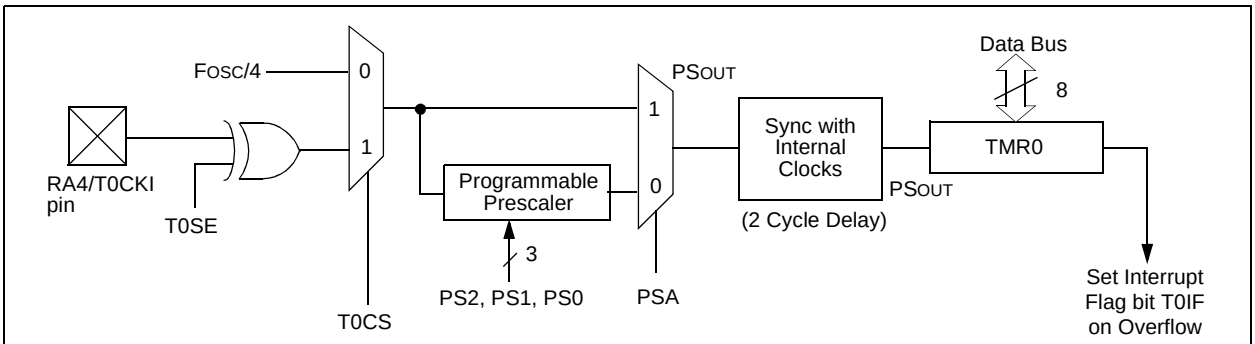
Clearing bit PSA will assign the prescaler to the Timer0 module. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4, ..., 1:256 are selectable.

Setting bit PSA will assign the prescaler to the Watchdog Timer (WDT). When the prescaler is assigned to the WDT, prescale values of 1:1, 1:2, ..., 1:128 are selectable.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., `CLRF 1, MOVWF 1, BSF 1,` etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the WDT.

Note:	Writing to TMR0 when the prescaler is assigned to Timer0 will clear the prescaler count, but will not change the prescaler assignment.

FIGURE 5-1: TIMER0 BLOCK DIAGRAM



Note 1: T0CS, T0SE, PSA, PS2:PS0 (OPTION_REG<5:0>).
2: The prescaler is shared with Watchdog Timer (refer to Figure 5-2 for detailed block diagram).

5.2.1 SWITCHING PRESCALER ASSIGNMENT

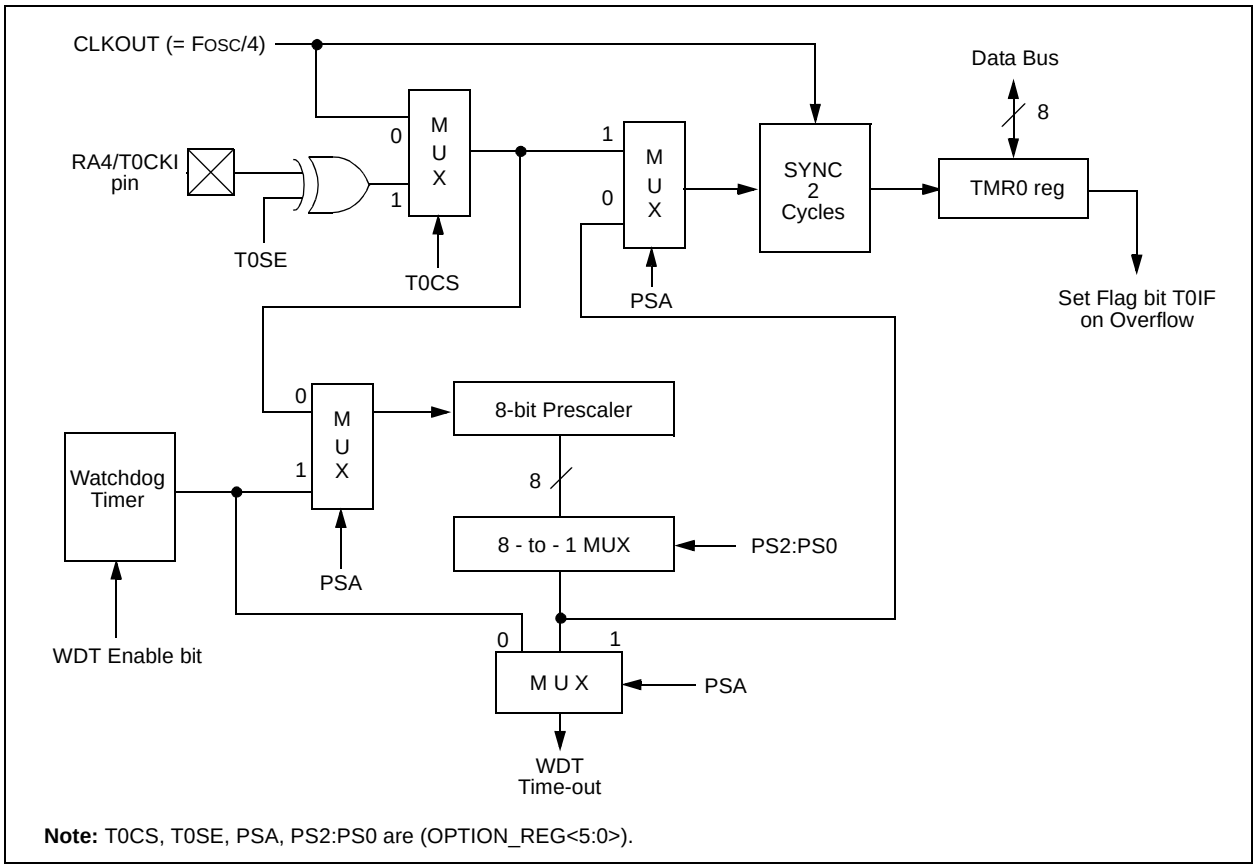
The prescaler assignment is fully under software control (i.e., it can be changed “on the fly” during program execution).

Note:	To avoid an unintended device RESET, a specific instruction sequence (shown in the PICmicro™ Mid-Range Reference Manual, DS33023) must be executed when changing the prescaler assignment from Timer0 to the WDT. This sequence must be followed even if the WDT is disabled.

5.3 Timer0 Interrupt

The TMR0 interrupt is generated when the TMR0 register overflows from FFh to 00h. This overflow sets bit T0IF (INTCON<2>). The interrupt can be masked by clearing bit T0IE (INTCON<5>). Bit T0IF must be cleared in software by the Timer0 module Interrupt Service Routine before re-enabling this interrupt. The TMR0 interrupt cannot awaken the processor from SLEEP since the timer is shut-off during SLEEP.

FIGURE 5-2: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0CS, T0SE, PSA, PS2:PS0 are (OPTION_REG<5:0>).

TABLE 5-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other RESETS
01h	TMR0	Timer0 Module Register								xxxx xxxx	uuuu uuuu
0Bh,8Bh	INTCON	GIE	EEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	—	PORTA Data Direction Register					---1 1111	---1 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

6.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits to deal with the needs of real time applications. The PIC16F84A has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These features are:

- OSC Selection
- RESET
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
- Interrupts
- Watchdog Timer (WDT)
- SLEEP
- Code Protection
- ID Locations
- In-Circuit Serial Programming™ (ICSP™)

The PIC16F84A has a Watchdog Timer which can be shut-off only through configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only. This design keeps the device in RESET while the power supply stabilizes. With these two timers on-chip, most applications need no external RESET circuitry.

SLEEP mode offers a very low current power-down mode. The user can wake-up from SLEEP through external RESET, Watchdog Timer Time-out or through an interrupt. Several oscillator options are provided to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select the various options.

Additional information on special features is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

6.1 Configuration Bits

The configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1'), to select various device configurations. These bits are mapped in program memory location 2007h.

Address 2007h is beyond the user program memory space and it belongs to the special test/configuration memory space (2000h - 3FFFh). This space can only be accessed during programming.

REGISTER 6-1: PIC16F84A CONFIGURATION WORD

R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u	R/P-u
CP	CP	CP	CP	CP	CP	CP	CP	CP	CP	$\overline{\text{PWRTE}}$	WDTE	F0SC1	F0SC0
bit13													bit0

bit 13-4 **CP:** Code Protection bit
1 = Code protection disabled
0 = All program memory is code protected

bit 3 **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit
1 = Power-up Timer is disabled
0 = Power-up Timer is enabled

bit 2 **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0 **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

6.2 Oscillator Configurations

6.2.1 OSCILLATOR TYPES

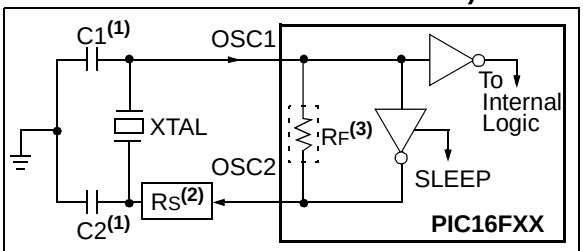
The PIC16F84A can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

6.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP, or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 6-1).

FIGURE 6-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 6-1 for recommended values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

The PIC16F84A oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP, or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 6-2).

FIGURE 6-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

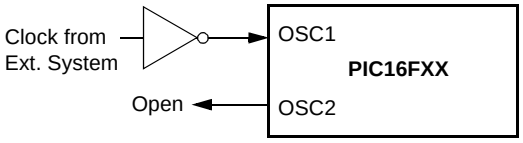


TABLE 6-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq**	**OSC1/C1**	**OSC2/C2**
XT	455 kHz	47 - 100 pF	47 - 100 pF
	2.0 MHz	15 - 33 pF	15 - 33 pF
	4.0 MHz	15 - 33 pF	15 - 33 pF
HS	8.0 MHz	15 - 33 pF	15 - 33 pF
	10.0 MHz	15 - 33 pF	15 - 33 pF

Note: Recommended values of C1 and C2 are identical to the ranges tested in this table. Higher capacitance increases the stability of the oscillator, but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for the appropriate values of external components.

Note: When using resonators with frequencies above 3.5 MHz, the use of HS mode rather than XT mode, is recommended. HS mode may be used at any VDD for which the controller is rated.

TABLE 6-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

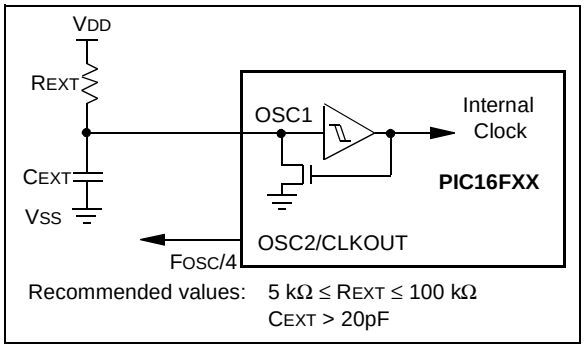
Mode	Freq	OSC1/C1	OSC2/C2
LP	32 kHz	68 - 100 pF	68 - 100 pF
	200 kHz	15 - 33 pF	15 - 33 pF
XT	100 kHz	100 - 150 pF	100 - 150 pF
	2 MHz	15 - 33 pF	15 - 33 pF
	4 MHz	15 - 33 pF	15 - 33 pF
HS	4 MHz	15 - 33 pF	15 - 33 pF
	20 MHz	15 - 33 pF	15 - 33 pF

Note: Higher capacitance increases the stability of the oscillator, but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.
For V_{DD} > 4.5V, C1 = C2 ≈ 30 pF is recommended.

6.2.3 RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) values, capacitor (C_{EXT}) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types also affects the oscillation frequency, especially for low C_{EXT} values. The user needs to take into account variation, due to tolerance of the external R and C components. Figure 6-3 shows how an R/C combination is connected to the PIC16F84A.

FIGURE 6-3: RC OSCILLATOR MODE



6.3 RESET

The PIC16F84A differentiates between various kinds of RESET:

- Power-on Reset (POR)
- $\overline{MCLR}$ during normal operation
- $\overline{MCLR}$ during SLEEP
- WDT Reset (during normal operation)
- WDT Wake-up (during SLEEP)

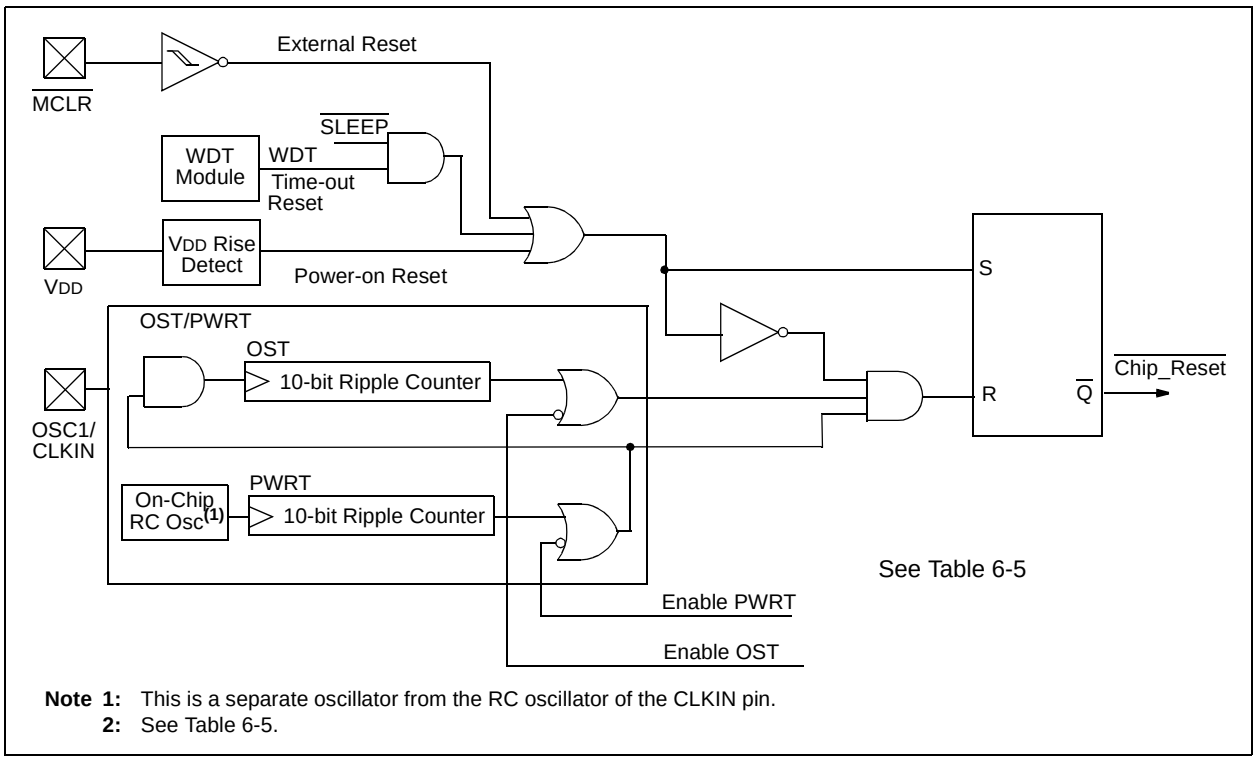
Figure 6-4 shows a simplified block diagram of the On-Chip RESET Circuit. The $\overline{MCLR}$ Reset path has a noise filter to ignore small pulses. The electrical specifications state the pulse width requirements for the $\overline{MCLR}$ pin.

Some registers are not affected in any RESET condition; their status is unknown on a POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on POR, $\overline{MCLR}$ or WDT Reset during normal operation and on $\overline{MCLR}$ during SLEEP. They are not affected by a WDT Reset during SLEEP, since this RESET is viewed as the resumption of normal operation.

Table 6-3 gives a description of RESET conditions for the program counter (PC) and the STATUS register. Table 6-4 gives a full description of RESET states for all registers.

The $\overline{TO}$ and $\overline{PD}$ bits are set or cleared differently in different RESET situations (Section 6.7). These bits are used in software to determine the nature of the RESET.

FIGURE 6-4: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: This is a separate oscillator from the RC oscillator of the CLKIN pin.
2: See Table 6-5.

TABLE 6-3: RESET CONDITION FOR PROGRAM COUNTER AND THE STATUS REGISTER

Condition	Program Counter	STATUS Register
Power-on Reset	000h	0001 1xxx
$\overline{MCLR}$ during normal operation	000h	000u uuuu
$\overline{MCLR}$ during SLEEP	000h	0001 0uuu
WDT Reset (during normal operation)	000h	0000 1uuu
WDT Wake-up	PC + 1	uuu0 0uuu
Interrupt wake-up from SLEEP	PC + 1(1)	uuu1 0uuu

Legend: u = unchanged, x = unknown
Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

TABLE 6-4: RESET CONDITIONS FOR ALL REGISTERS

Register	Address	Power-on Reset	$\overline{\text{MCLR}}$ during: – normal operation – SLEEP WDT Reset during normal operation	Wake-up from SLEEP: – through interrupt – through WDT Time-out
W	—	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	00h	---- ----	---- ----	---- ----
TMR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h	0000 0000	0000 0000	PC + 1(2)
STATUS	03h	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	04h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA(4)	05h	---x xxxx	---u uuuu	---u uuuu
PORTB(5)	06h	xxxx xxxx	uuuu uuuu	uuuu uuuu
EEDATA	08h	xxxx xxxx	uuuu uuuu	uuuu uuuu
EEADR	09h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCLATH	0Ah	---0 0000	---0 0000	---u uuuu
INTCON	0Bh	0000 000x	0000 000u	uuuu uuuu(1)
INDF	80h	---- ----	---- ----	---- ----
OPTION_REG	81h	1111 1111	1111 1111	uuuu uuuu
PCL	82h	0000 0000	0000 0000	PC + 1(2)
STATUS	83h	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	84h	xxxx xxxx	uuuu uuuu	uuuu uuuu
TRISA	85h	---1 1111	---1 1111	---u uuuu
TRISB	86h	1111 1111	1111 1111	uuuu uuuu
EECON1	88h	---0 x000	---0 q000	---0 uuuu
EECON2	89h	---- ----	---- ----	---- ----
PCLATH	8Ah	---0 0000	---0 0000	---u uuuu
INTCON	8Bh	0000 000x	0000 000u	uuuu uuuu(1)

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: Table 6-3 lists the RESET value for each specific condition.

4: On any device RESET, these pins are configured as inputs.

5: This is the value that will be in the port output latch.

6.4 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.2V - 1.7V). To take advantage of the POR, just tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A minimum rise time for VDD must be met for this to operate properly. See Electrical Specifications for details.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting*."

The POR circuit does not produce an internal RESET when VDD declines.

6.5 Power-up Timer (PWRT)

The Power-up Timer (PWRT) provides a fixed 72 ms nominal time-out (TPWRT) from POR (Figures 6-6 through 6-9). The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level (possible exception shown in Figure 6-9).

A configuration bit, PWRTE, can enable/disable the PWRT. See Register 6-1 for the operation of the PWRTE bit for a particular device.

The power-up time delay TPWRT will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

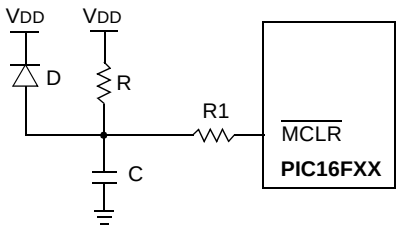
6.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle delay (from OSC1 input) after the PWRT delay ends (Figure 6-6, Figure 6-7, Figure 6-8 and Figure 6-9). This ensures the crystal oscillator or resonator has started and stabilized.

The OST time-out (TOST) is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

When VDD rises very slowly, it is possible that the TPWRT time-out and TOST time-out will expire before VDD has reached its final value. In this case (Figure 6-9), an external Power-on Reset circuit may be necessary (Figure 6-5).

FIGURE 6-5: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if VDD power-up rate is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that voltage drop across R does not exceed 0.2V (max leakage current spec on MCLR pin is 5 µA). A larger voltage drop will degrade VIH level on the MCLR pin.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C, in the event of a MCLR pin breakdown due to ESD or EOS.

FIGURE 6-6: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

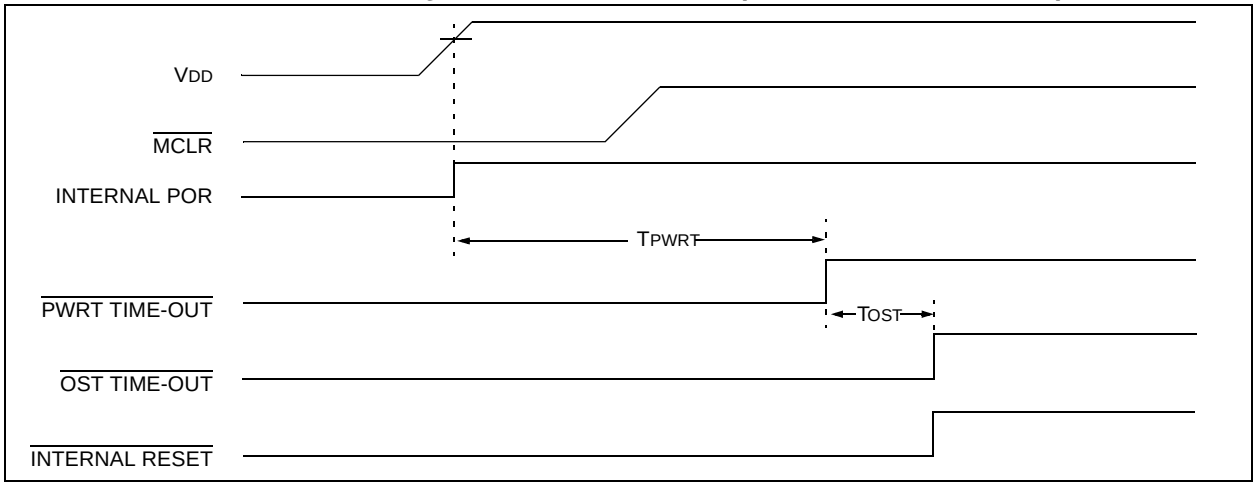


FIGURE 6-7: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2

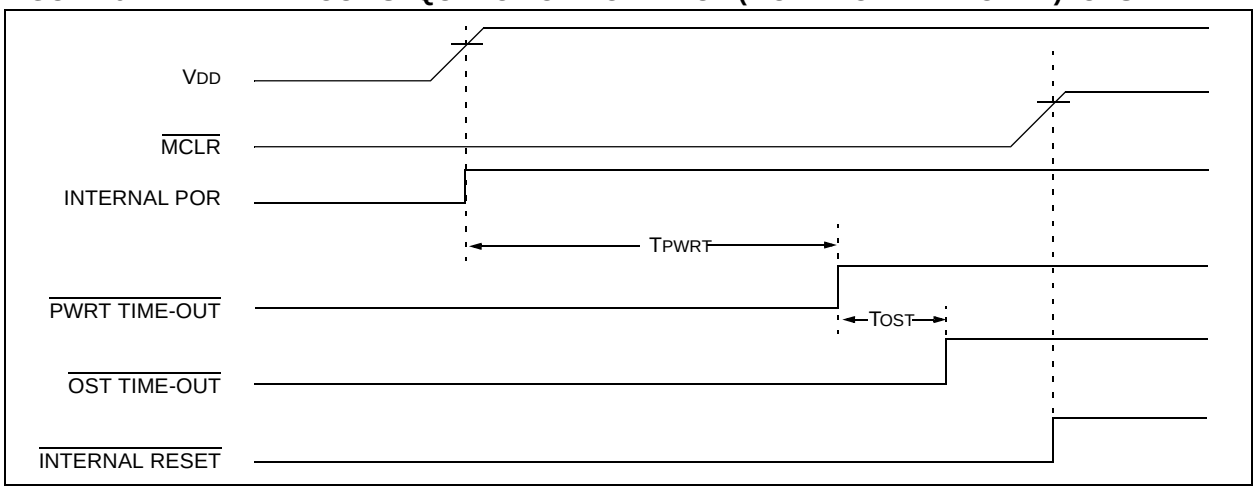


FIGURE 6-8: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD}): FAST V_{DD} RISE TIME

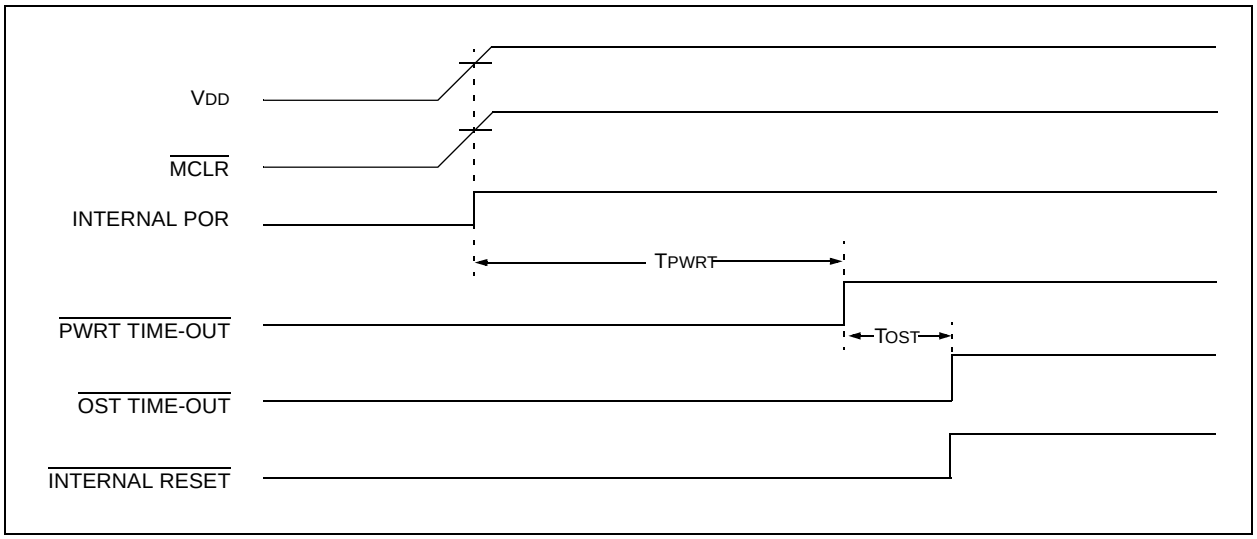
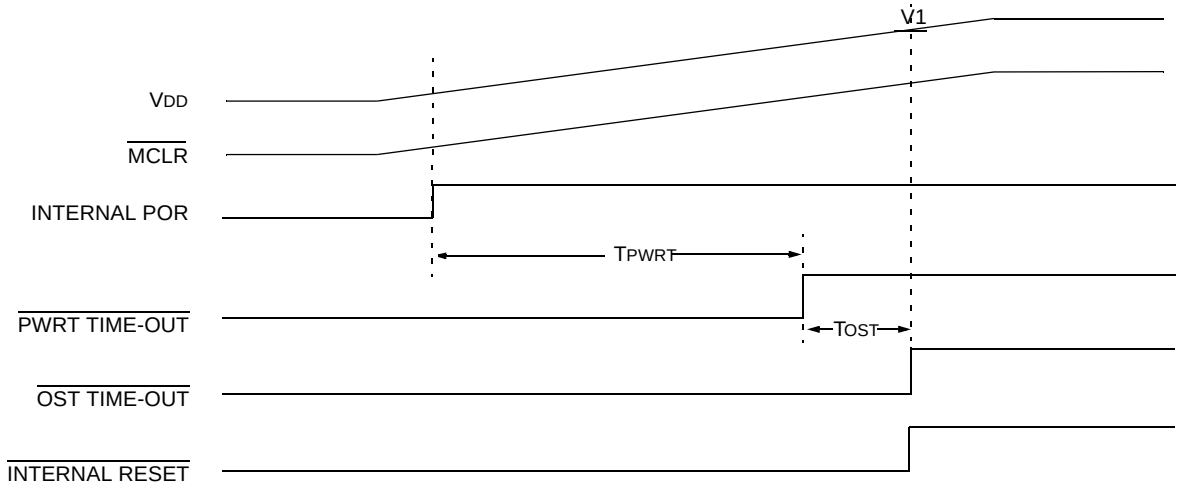


FIGURE 6-9: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD}): SLOW V_{DD} RISE TIME



When V_{DD} rises very slowly, it is possible that the T_{PWRT} time-out and T_{OST} time-out will expire before V_{DD} has reached its final value. In this example, the chip will reset properly if, and only if, V1 ≥ V_{DD} min.

6.7 Time-out Sequence and Power-down Status Bits ($\overline{TO}$/$\overline{PD}$)

On power-up (Figures 6-6 through 6-9), the time-out sequence is as follows:

1. PWRT time-out is invoked after a POR has expired.
2. Then, the OST is activated.

The total time-out will vary based on oscillator configuration and PWRTE configuration bit status. For example, in RC mode with the PWRT disabled, there will be no time-out at all.

TABLE 6-5: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Wake-up from SLEEP
	PWRT Enabled	PWRT Disabled	
XT, HS, LP	72 ms + 1024TOSC	1024TOSC	1024TOSC
RC	72 ms	—	—

Since the time-outs occur from the POR pulse, if $\overline{MCLR}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{MCLR}$ high, execution will begin immediately (Figure 6-6). This is useful for testing purposes or to synchronize more than one PIC16F84A device when operating in parallel.

Table 6-6 shows the significance of the $\overline{TO}$ and $\overline{PD}$ bits. Table 6-3 lists the RESET conditions for some special registers, while Table 6-4 lists the RESET conditions for all the registers.

TABLE 6-6: STATUS BITS AND THEIR SIGNIFICANCE

$\overline{TO}$	$\overline{PD}$	Condition
1	1	Power-on Reset
0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
0	1	WDT Reset (during normal operation)
0	0	WDT Wake-up
1	1	$\overline{MCLR}$ during normal operation
1	0	$\overline{MCLR}$ during SLEEP or interrupt wake-up from SLEEP

6.8 Interrupts

The PIC16F84A has 4 sources of interrupt:

- External interrupt RB0/INT pin
- TMR0 overflow interrupt
- PORTB change interrupts (pins RB7:RB4)
- Data EEPROM write complete interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also contains the individual and global interrupt enable bits.

The global interrupt enable bit, GIE (INTCON<7>), enables (if set) all unmasked interrupts or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register. Bit GIE is cleared on RESET.

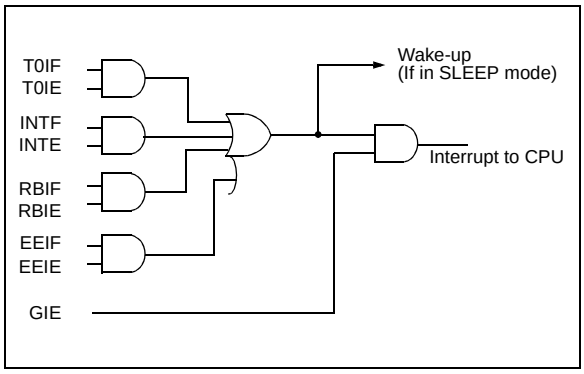
The "return from interrupt" instruction, `RETFIE`, exits interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. For external interrupt events, such as the RB0/INT pin or PORTB change interrupt, the interrupt latency will be three to four instruction cycles. The exact latency depends when the interrupt event occurs. The latency is the same for both one and two cycle instructions. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid infinite interrupt requests.

Note:	Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

FIGURE 6-10: INTERRUPT LOGIC



6.8.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if INTEDG bit (OPTION_REG<6>) is set, or falling if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing control bit INTE (INTCON<4>). Flag bit INTF must be cleared in software via the Interrupt Service Routine before re-enabling this interrupt. The INT interrupt can wake the processor from SLEEP (Section 6.11) only if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether the processor branches to the interrupt vector following wake-up.

6.8.2 TMR0 INTERRUPT

An overflow (FFh $\rightarrow$ 00h) in TMR0 will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>) (Section 5.0).

6.8.3 PORTB INTERRUPT

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<3>) (Section 4.2).

Note:	For a change on the I/O pin to be recognized, the pulse width must be at least T_{CY} wide.

6.8.4 DATA EEPROM INTERRUPT

At the completion of a data EEPROM write cycle, flag bit EEIF (EECON1<4>) will be set. The interrupt can be enabled/disabled by setting/clearing enable bit EEIE (INTCON<6>) (Section 3.0).

6.9 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users wish to save key register values during an interrupt (e.g., W register and STATUS register). This is implemented in software.

The code in Example 6-1 stores and restores the STATUS and W register's values. The user defined registers, W_TEMP and STATUS_TEMP are the temporary storage locations for the W and STATUS registers values.

Example 6-1 does the following:

a) Stores the W register.
b) Stores the STATUS register in STATUS_TEMP.
c) Executes the Interrupt Service Routine code.
d) Restores the STATUS (and bank select bit) register.
e) Restores the W register.

EXAMPLE 6-1: SAVING STATUS AND W REGISTERS IN RAM

```
PUSH    MOVWF   W_TEMP              ; Copy W to TEMP register,
        SWAPF   STATUS,     W       ; Swap status to be saved into W
        MOVWF   STATUS_TEMP         ; Save status to STATUS_TEMP register
ISR     :                           :
        :                           ; Interrupt Service Routine
        :                           ; should configure Bank as required
        :                           ;
POP     SWAPF   STATUS_TEMP,W       ; Swap nibbles in STATUS_TEMP register
                                    ; and place result into W
        MOVWF   STATUS              ; Move W into STATUS register
                                    ; (sets bank to original state)
        SWAPF   W_TEMP,     F       ; Swap nibbles in W_TEMP and place result in W_TEMP
        SWAPF   W_TEMP,     W       ; Swap nibbles in W_TEMP and place result into W
```

6.10 Watchdog Timer (WDT)

The Watchdog Timer is a free running On-Chip RC Oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time-out generates a device RESET. If the device is in SLEEP mode, a WDT wake-up causes the device to wake-up and continue with normal operation. The WDT can be permanently disabled by programming configuration bit WDTE as a '0' (Section 6.1).

6.10.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, V_{DD} and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION_REG register. Thus, time-out periods up to 2.3 seconds can be realized.

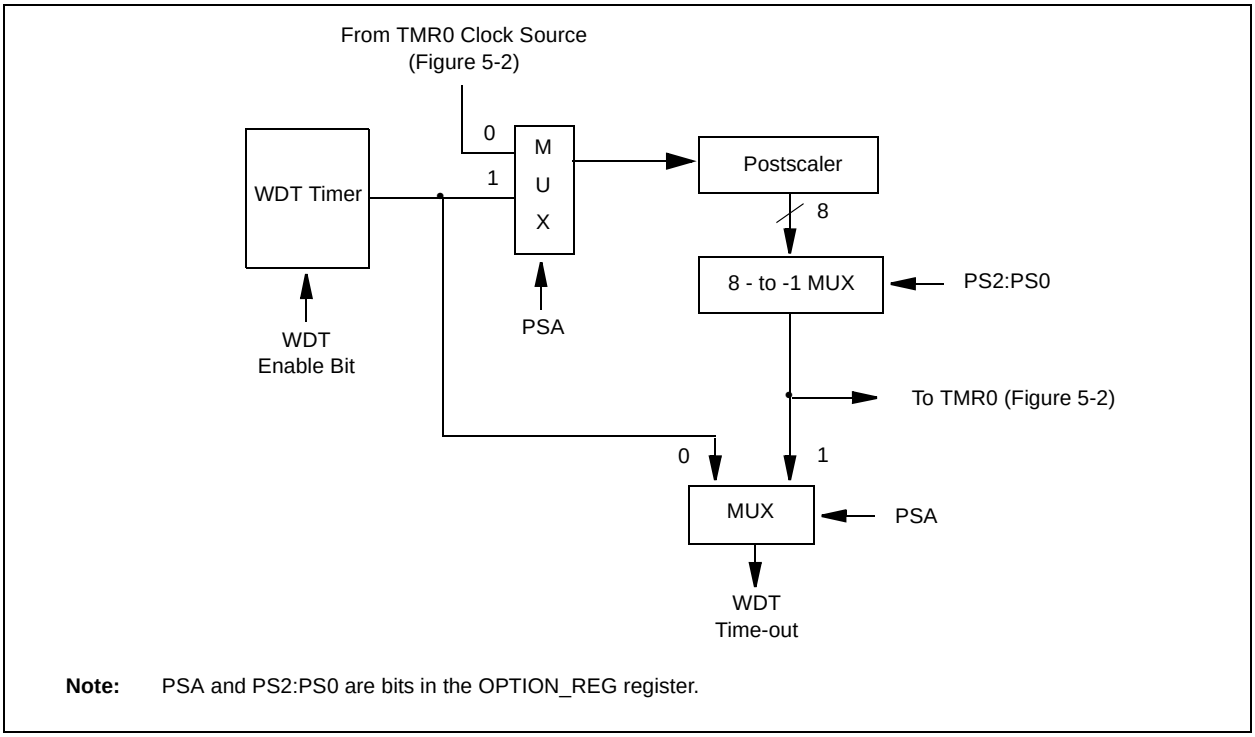
The CLRWDT and SLEEP instructions clear the WDT and the postscaler (if assigned to the WDT) and prevent it from timing out and generating a device RESET condition.

The $\overline{TO}$ bit in the STATUS register will be cleared upon a WDT time-out.

6.10.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken into account that under worst case conditions (V_{DD} = Min., Temperature = Max., Max. WDT Prescaler), it may take several seconds before a WDT time-out occurs.

FIGURE 6-11: WATCHDOG TIMER BLOCK DIAGRAM



Note: PSA and PS2:PS0 are bits in the OPTION_REG register.

TABLE 6-7: SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other RESETS
2007h	Config. bits	(2)	(2)	(2)	(2)	$\overline{\text{PWRTE}}$(1)	WDTE	FOSC1	FOSC0	(2)	
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: x = unknown. Shaded cells are not used by the WDT.

Note 1: See Register 6-1 for operation of the $\overline{\text{PWRTE}}$ bit.

2: See Register 6-1 and Section 6.12 for operation of the code and data protection bits.

6.11 Power-down Mode (SLEEP)

A device may be powered down (SLEEP) and later powered up (wake-up from SLEEP).

6.11.1 SLEEP

The Power-down mode is entered by executing the SLEEP instruction.

If enabled, the Watchdog Timer is cleared (but keeps running), the $\overline{PD}$ bit (STATUS<3>) is cleared, the $\overline{TO}$ bit (STATUS<4>) is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For the lowest current consumption in SLEEP mode, place all I/O pins at either V_{DD} or V_{SS}, with no external circuitry drawing current from the I/O pins, and disable external clocks. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS}. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level (V_{IHMC}).

It should be noted that a RESET generated by a WDT time-out does not drive the $\overline{MCLR}$ pin low.

6.11.2 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

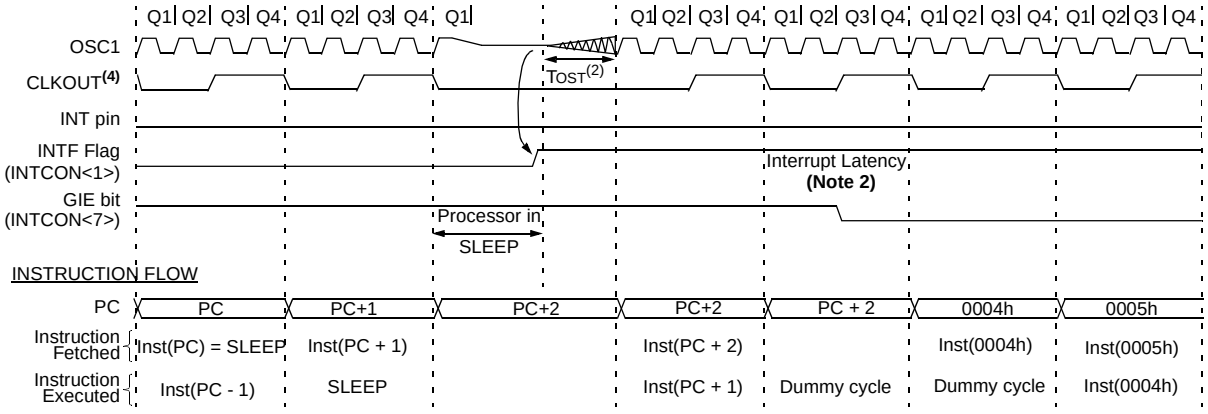
1. External RESET input on $\overline{MCLR}$ pin.
2. WDT wake-up (if WDT was enabled).
3. Interrupt from RB0/INT pin, RB port change, or data EEPROM write complete.

Peripherals cannot generate interrupts during SLEEP, since no on-chip Q clocks are present.

The first event ($\overline{MCLR}$ Reset) will cause a device RESET. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits can be used to determine the cause of a device RESET. The $\overline{PD}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The $\overline{TO}$ bit is cleared if a WDT time-out occurred (and caused wake-up).

While the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up occurs regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

FIGURE 6-12: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS, or LP oscillator mode assumed.
2: T_{OST} = 1024T_{OSC} (drawing not to scale). This delay will not be there for RC osc mode.
3: GIE = '1' assumed. In this case after wake-up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

6.11.3 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{TO}$ bit will not be set and $\overline{PD}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from SLEEP. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

6.12 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

6.13 ID Locations

Four memory locations (2000h - 2004h) are designated as ID locations to store checksum or other code identification numbers. These locations are not accessible during normal execution but are readable and writable only during program/verify. Only the four Least Significant bits of ID location are usable.

6.14 In-Circuit Serial Programming

PIC16F84A microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. Customers can manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product, allowing the most recent firmware or custom firmware to be programmed.

For complete details of Serial Programming, please refer to the In-Circuit Serial Programming™ (ICSP™) Guide, (DS30277).

NOTES:

7.0 INSTRUCTION SET SUMMARY

Each PIC16CXX instruction is a 14-bit word, divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CXX instruction set summary in Table 7-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 7-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the address of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 7-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
PC	Program Counter
TO	Time-out bit
PD	Power-down bit

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 µs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 µs.

Table 7-2 lists the instructions recognized by the MPASM™ Assembler.

Figure 7-1 shows the general formats that the instructions can have.

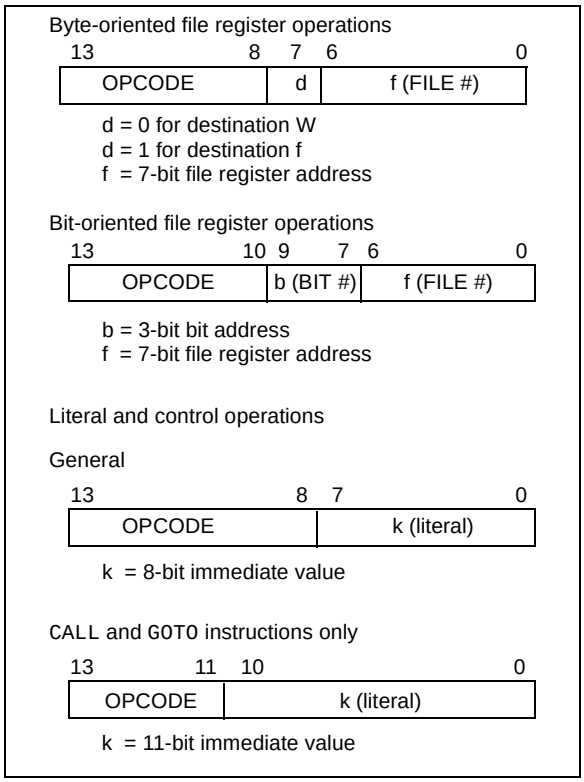
Note: To maintain upward compatibility with future PIC16CXX products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 7-1: GENERAL FORMAT FOR INSTRUCTIONS



A description of each instruction is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

TABLE 7-2: PIC16CXXX INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb			LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1 (2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1 (2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL AND CONTROL OPERATIONS									
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	$\overline{TO}$,$\overline{PD}$	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	$\overline{TO}$,$\overline{PD}$	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

Note: Additional information on the mid-range instruction set is available in the PICmicro™ Mid-Range MCU Family Reference Manual (DS33023).

7.1 Instruction Descriptions

ADDLW	Add Literal and W
Syntax:	[*label*] ADDLW k
Operands:	$0 \le k \le 255$
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the eight-bit literal 'k' and the result is placed in the W register.

ADDWF	Add W and f
Syntax:	[*label*] ADDWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

ANDLW	AND Literal with W
Syntax:	[*label*] ANDLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.

ANDWF	AND W with f
Syntax:	[*label*] ANDWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

BCF	Bit Clear f
Syntax:	[*label*] BCF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BSF	Bit Set f
Syntax:	[*label*] BSF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

BTFSS	Bit Test f, Skip if Set
Syntax:	[*label*] BTFSS f,b
Operands:	$0 \le f \le 127$ $0 \le b < 7$
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2TCY instruction.

BTFSC **Bit Test, Skip if Clear**

Syntax: [*label*] BTFSC f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: skip if (f<b>) = 0

Status Affected: None

Description: If bit 'b' in register 'f' is '1', the next instruction is executed.
If bit 'b' in register 'f' is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2TCY instruction.

CALL **Call Subroutine**

Syntax: [*label*] CALL k

Operands: $0 \le k \le 2047$

Operation: (PC)+ 1→ TOS,
k → PC<10:0>,
(PCLATH<4:3>) → PC<12:11>

Status Affected: None

Description: Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction.

CLRF **Clear f**

Syntax: [*label*] CLRF f

Operands: $0 \le f \le 127$

Operation: 00h → (f)
1 → Z

Status Affected: Z

Description: The contents of register 'f' are cleared and the Z bit is set.

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Description: W register is cleared. Zero bit (Z) is set.

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT
0 → WDT prescaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF **Complement f**

Syntax: [*label*] COMF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: $(\bar{f}) \rightarrow$ (destination)

Status Affected: Z

Description: The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.

DECF **Decrement f**

Syntax: [*label*] DECF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - 1 → (destination)

Status Affected: Z

Description: Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

DECFSZ **Decrement f, Skip if 0**

Syntax: [*label*] DECFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - 1 → (destination);
skip if result = 0

Status Affected: None

Description: The contents of register 'f' are decremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
If the result is 1, the next instruction is executed. If the result is 0, then a NOP is executed instead, making it a 2TCY instruction.

GOTO **Unconditional Branch**

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 2047$

Operation: k → PC<10:0>
PCLATH<4:3> → PC<12:11>

Status Affected: None

Description: GOTO is an unconditional branch. The eleven-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two-cycle instruction.

INCF **Increment f**

Syntax: [*label*] INCF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (destination)

Status Affected: Z

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

INCFSZ **Increment f, Skip if 0**

Syntax: [*label*] INCFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (destination),
skip if result = 0

Status Affected: None

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
If the result is 1, the next instruction is executed. If the result is 0, a NOP is executed instead, making it a 2TCY instruction.

IORLW **Inclusive OR Literal with W**

Syntax: [*label*] IORLW k

Operands: $0 \le k \le 255$

Operation: (W) .OR. k → (W)

Status Affected: Z

Description: The contents of the W register are OR'ed with the eight-bit literal 'k'. The result is placed in the W register.

IORWF **Inclusive OR W with f**

Syntax: [*label*] IORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .OR. (f) → (destination)

Status Affected: Z

Description: Inclusive OR the W register with register 'f'. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

MOVF	Move f
Syntax:	[*label*] MOVF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) → (destination)
Status Affected:	Z
Description:	The contents of register f are moved to a destination dependant upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register, since status flag Z is affected.

MOVLW	Move Literal to W
Syntax:	[*label*] MOVLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W)
Status Affected:	None
Description:	The eight-bit literal 'k' is loaded into W register. The don't cares will assemble as 0's.

MOVWF	Move W to f
Syntax:	[*label*] MOVWF f
Operands:	$0 \le f \le 127$
Operation:	(W) → (f)
Status Affected:	None
Description:	Move data from W register to register 'f'.

NOP	No Operation
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.

RETFIE	Return from Interrupt
Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None

RETLW	Return with Literal in W
Syntax:	[*label*] RETLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W); TOS → PC
Status Affected:	None
Description:	The W register is loaded with the eight-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.

RETURN	Return from Subroutine
Syntax:	[*label*] RETURN
Operands:	None
Operation:	TOS → PC
Status Affected:	None
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.

RLF **Rotate Left f through Carry**

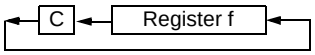
Syntax: [*label*] RLF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.



RRF **Rotate Right f through Carry**

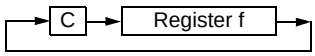
Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.



SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Description: The power-down status bit, $\overline{PD}$ is cleared. Time-out status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped.

SUBLW **Subtract W from Literal**

Syntax: [*label*] SUBLW k

Operands: $0 \le k \le 255$

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Description: The W register is subtracted (2's complement method) from the eight-bit literal 'k'. The result is placed in the W register.

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (destination)

Status Affected: C, DC, Z

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (destination<7:4>),
(f<7:4>) → (destination<3:0>)

Status Affected: None

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.

XORLW	Exclusive OR Literal with W
Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k $\rightarrow$ (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

XORWF	Exclusive OR W with f
Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) $\rightarrow$ (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

8.0 DEVELOPMENT SUPPORT

The PICmicro® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

8.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PICmicro emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

8.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PICmicro MCU’s.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

8.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

8.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK object linker combines relocatable objects created by the MPASM assembler and the MPLAB C17 and MPLAB C18 C compilers. It can also link relocatable objects from pre-compiled libraries, using directives from a linker script.

The MPLIB object librarian is a librarian for pre-compiled code to be used with the MPLINK object linker. When a routine from a library is called from another source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications. The MPLIB object librarian manages the creation and modification of library files.

The MPLINK object linker features include:

- Integration with MPASM assembler and MPLAB C17 and MPLAB C18 C compilers.
- Allows all memory areas to be defined as sections to provide link-time flexibility.

The MPLIB object librarian features include:

- Easier linking because single libraries can be included instead of many smaller files.
- Helps keep code maintainable by grouping related modules together.
- Allows libraries to be created and modules to be added, listed, replaced, deleted or extracted.

8.5 MPLAB SIM Software Simulator

The MPLAB SIM software simulator allows code development in a PC-hosted environment by simulating the PICmicro series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user-defined key press, to any of the pins. The execution can be performed in single step, execute until break, or trace mode.

The MPLAB SIM simulator fully supports symbolic debugging using the MPLAB C17 and the MPLAB C18 C compilers and the MPASM assembler. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent multi-project software development tool.

8.6 MPLAB ICE High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB ICE universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro microcontrollers (MCUs). Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment (IDE), which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PICmicro microcontrollers.

The MPLAB ICE in-circuit emulator system has been designed as a real-time emulation system, with advanced features that are generally found on more expensive development tools. The PC platform and Microsoft® Windows® environment were chosen to best make these features available to you, the end user.

8.7 ICEPIC In-Circuit Emulator

The ICEPIC low cost, in-circuit emulator is a solution for the Microchip Technology PIC16C5X, PIC16C6X, PIC16C7X and PIC16CXXX families of 8-bit One-Time-Programmable (OTP) microcontrollers. The modular system can support different subsets of PIC16C5X or PIC16CXXX products through the use of interchangeable personality modules, or daughter boards. The emulator is capable of emulating without target application circuitry being present.

8.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PICmicro MCUs and can be used to develop for this and other PICmicro microcontrollers. The MPLAB ICD utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial Programming™ protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

8.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable V_{DD} and V_{PP} supplies, which allow it to verify programmed memory at V_{DD} min and V_{DD} max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In stand-alone mode, the PRO MATE II device programmer can read, verify, or program PICmicro devices. It can also set code protection in this mode.

8.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PICmicro devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

8.11 PICDEM 1 Low Cost PICmicro Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE in-circuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

8.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I2CTM bus and separate headers for connection to an LCD module and a keypad.

8.13 PICDEM 3 Low Cost PIC16CXXX Demonstration Board

The PICDEM 3 demonstration board is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with an LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 3 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer with an adapter socket, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 3 demonstration board to test firmware. A prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM 3 demonstration board is a LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM 3 demonstration board provides an additional RS-232 interface and Windows software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

8.14 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. All necessary hardware is included to run basic demo programs, which are supplied on a 3.5-inch disk. A programmed sample is included and the user may erase it and program it with the other sample programs using the PRO MATE II device programmer, or the PICSTART Plus development programmer, and easily debug and test the sample code. In addition, the PICDEM 17 demonstration board supports downloading of programs to and executing out of external FLASH memory on board. The PICDEM 17 demonstration board is also usable with the MPLAB ICE in-circuit emulator, or the PICMASTER emulator and all of the sample programs can be run and modified using either emulator. Additionally, a generous prototype area is available for user hardware.

8.15 KEELOQ Evaluation and Programming Tools

KEELOQ evaluation and programming tools support Microchip's HCS Secure Data Products. The HCS evaluation kit includes a LCD display to show changing codes, a decoder to decode transmissions and a programming interface to program test transmitters.

TABLE 8-1: DEVELOPMENT TOOLS FROM MICROCHIP

		PIC12CXXX	PIC14000	PIC16C5X	PIC16C6X	PIC16CXXX	PIC16F62X	PIC16C7X	PIC16C7XX	PIC16C8X	PIC16F8XX	PIC16C9XX	PIC17C4X	PIC17C7XX	PIC18CXX2	PIC18FXXX	24CXX/ 25CXX/ 93CXX	HCSXXX	MCRFXXX	MCP2510
Software Tools	MPLAB® Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	MPLAB® C17 C Compiler			✓									✓	✓						
	MPLAB® C18 C Compiler			✓											✓	✓				
	MPASM™ Assembler/ MPLINK™ Object Linker	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Emulators	MPLAB® ICE In-Circuit Emulator	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	ICEPIC™ In-Circuit Emulator	✓		✓	✓	✓		✓	✓	✓		✓								
Debugger	MPLAB® ICD In-Circuit Debugger				✓*			✓*			✓					✓				
Programmers	PICSTART® Plus Entry Level Development Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓			
	PRO MATE® II Universal Device Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Demo Boards and Eval Kits	PICDEM™ 1 Demonstration Board			✓		✓		✓†		✓			✓							
	PICDEM™ 2 Demonstration Board				✓†	✓		✓†							✓					
	PICDEM™ 3 Demonstration Board											✓								
	PICDEM™ 14A Demonstration Board		✓																	
	PICDEM™ 17 Demonstration Board													✓						
	KEELOQ® Evaluation Kit																✓			
	KEELOQ® Transponder Kit																✓			
	microID™ Programmer's Kit																	✓		
	125 kHz microID™ Developer's Kit																	✓		
	125 kHz Anticollision microID™ Developer's Kit																	✓		
	13.56 MHz Anticollision microID™ Developer's Kit																	✓		
	MCP2510 CAN Developer's Kit																			✓

* Contact the Microchip Technology Inc. web site at www.microchip.com for information on how to use the MPLAB® ICD In-Circuit Debugger (DV164001) with PIC16C62, 63, 64, 65, 72, 73, 74, 76, 77.

** Contact Microchip Technology Inc. for availability date.

† Development tool is available on select devices.

NOTES:

9.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55°C to +125°C

Storage temperature ..... -65°C to +150°C

Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$, and RA4) ..... -0.3V to (V_{DD} + 0.3V)

Voltage on V_{DD} with respect to V_{SS} ..... -0.3 to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} **(1)** ..... -0.3 to +14V

Voltage on RA4 with respect to V_{SS} ..... -0.3 to +8.5V

Total power dissipation **(2)** ..... 800 mW

Maximum current out of V_{SS} pin ..... 150 mA

Maximum current into V_{DD} pin ..... 100 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ± 20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ± 20 mA

Maximum output current sunk by any I/O pin ..... 25 mA

Maximum output current sourced by any I/O pin ..... 25 mA

Maximum current sunk by PORTA ..... 80 mA

Maximum current sourced by PORTA ..... 50 mA

Maximum current sunk by PORTB ..... 150 mA

Maximum current sourced by PORTB ..... 100 mA

Note 1: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

2: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{ol} \times I_{OL})$.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 9-1: PIC16F84A-20 VOLTAGE-FREQUENCY GRAPH

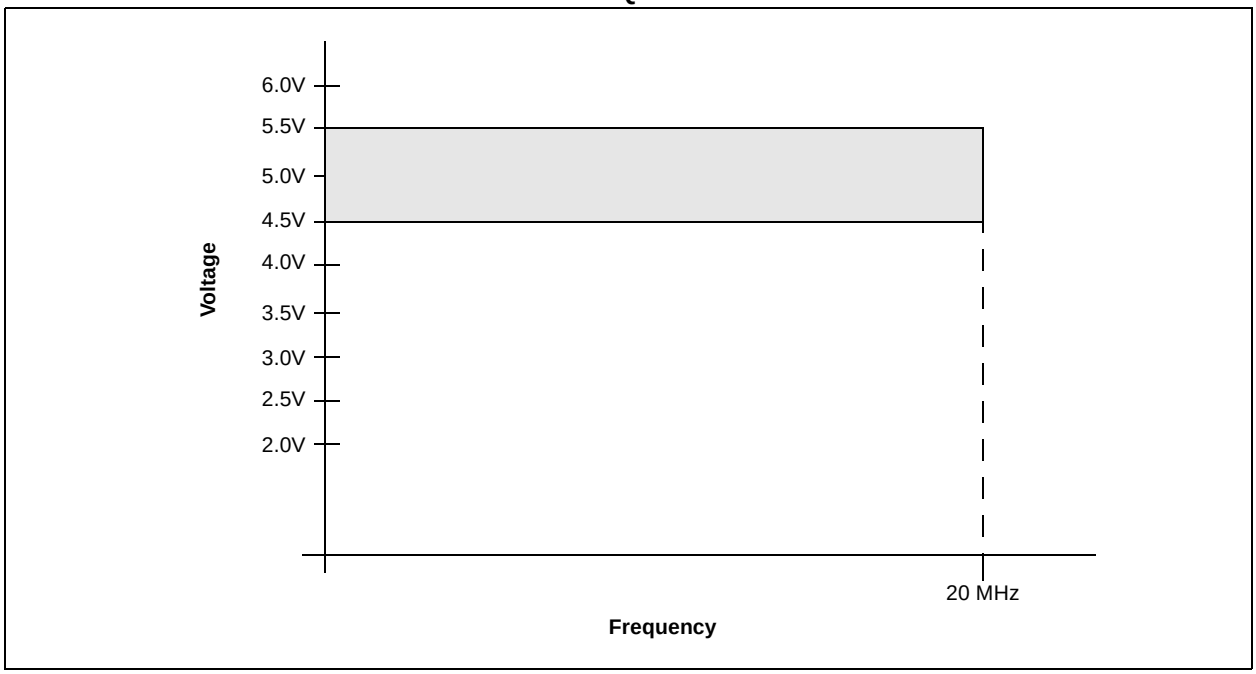
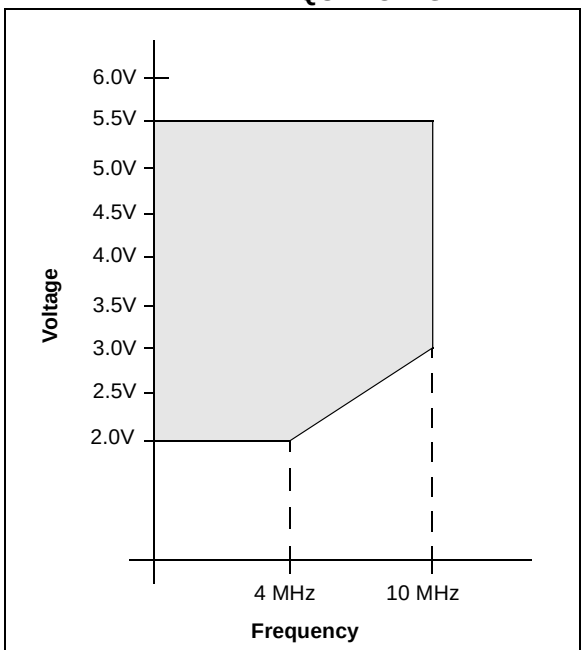


FIGURE 9-2: PIC16LF84A-04 VOLTAGE-FREQUENCY GRAPH

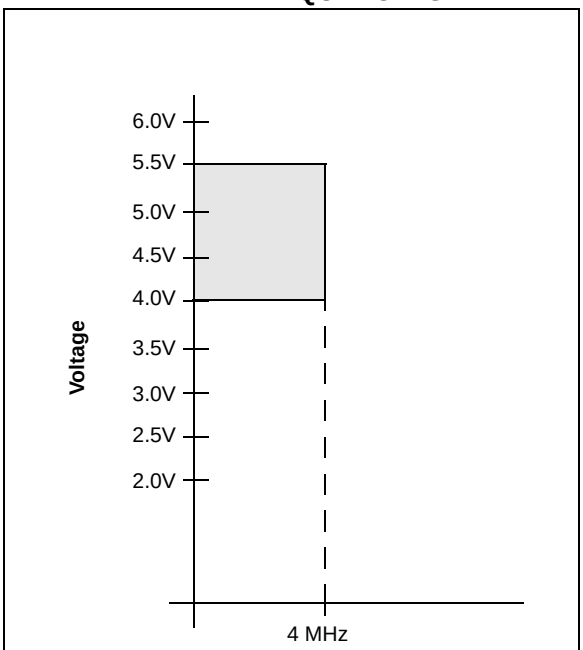


FMAX = (6.0 MHz/V) (VDDAPPMIN - 2.0V) + 4 MHz

Note 1: VDDAPPMIN is the minimum voltage of the PICmicro® device in the application.

2: FMAX has a maximum frequency of 10 MHz.

FIGURE 9-3: PIC16F84A-04 VOLTAGE-FREQUENCY GRAPH



9.1 DC Characteristics

PIC16LF84A-04 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
PIC16F84A-04 (Commercial, Industrial, Extended) **PIC16F84A-20** (Commercial, Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		16LF84A	2.0	—	5.5	V	XT, RC, and LP osc configuration
D001		16F84A	4.0	—	5.5	V	XT, RC and LP osc configuration
D001A			4.5	—	5.5	V	HS osc configuration
D002	VDR	**RAM Data Retention Voltage (Note 1)**	1.5	—	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	Vss	—	V	See section on Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	
	IDD	**Supply Current (Note 2)**					
D010		16LF84A	—	1	4	mA	RC and XT osc configuration **(Note 4)** FOSC = 2.0 MHz, VDD = 5.5V
D010		16F84A	—	1.8	4.5	mA	RC and XT osc configuration **(Note 4)** FOSC = 4.0 MHz, VDD = 5.5V
D010A			—	3	10	mA	RC and XT osc configuration **(Note 4)** FOSC = 4.0 MHz, VDD = 5.5V (During FLASH programming)
D013			—	10	20	mA	HS osc configuration (PIC16F84A-20) FOSC = 20 MHz, VDD = 5.5V
D014		16LF84A	—	15	45	µA	LP osc configuration FOSC = 32 kHz, VDD = 2.0V, WDT disabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

NR Not rated for operation.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,
T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula IR = VDD/2REXT (mA) with REXT in kOhm.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD measurement.

9.1 DC Characteristics (Continued)

PIC16LF84A-04 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
PIC16F84A-04 (Commercial, Industrial, Extended) **PIC16F84A-20** (Commercial, Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IPD	**Power-down Current (Note 3)**					
D020		16LF84A					
D020		16F84A-20 16F84A-04					
D021A		16LF84A	—	0.4	1.0	µA	VDD = 2.0V, WDT disabled, industrial
D021A		16F84A-20	—	1.5	3.5	µA	VDD = 4.5V, WDT disabled, industrial
		16F84A-04	—	1.0	3.0	µA	VDD = 4.0V, WDT disabled, industrial
D021B		16F84A-20	—	1.5	5.5	µA	VDD = 4.5V, WDT disabled, extended
		16F84A-04	—	1.0	5.0	µA	VDD = 4.0V, WDT disabled, extended
		Module Differential Current (Note 5)					
D022	ΔIWDT	Watchdog Timer	—	.20	16	µA	VDD = 2.0V, Industrial, Commercial
			—	3.5	20	µA	VDD = 4.0V, Commercial
			—	3.5	28	µA	VDD = 4.0V, Industrial, Extended
			—	4.8	25	µA	VDD = 4.5V, Commercial
			—	4.8	30	µA	VDD = 4.5V, Industrial, Extended

Legend: Rows with standard voltage device data only are shaded for improved readability.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

NR Not rated for operation.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,

T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula IR = VDD/2REXT (mA) with REXT in kOhm.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD measurement.

9.2 DC Characteristics: PIC16F84A-04 (Commercial, Industrial) PIC16F84A-20 (Commercial, Industrial) PIC16LF84A-04 (Commercial, Industrial)

DC Characteristics All Pins Except Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) Operating voltage VDD range as described in DC specifications (Section 9.1)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports:					
D030		with TTL buffer	VSS	—	0.8	V	4.5V ≤ VDD ≤ 5.5V **(Note 4)**
D030A			VSS	—	0.16VDD	V	Entire range **(Note 4)**
D031		with Schmitt Trigger buffer	VSS	—	0.2VDD	V	Entire range
D032		$\overline{MCLR}$, RA4/T0CKI	VSS	—	0.2VDD	V	
D033		OSC1 (XT, HS and LP modes)	VSS	—	0.3VDD	V	**(Note 1)**
D034		OSC1 (RC mode)	VSS	—	0.1VDD	V	
	VIH	**Input High Voltage**					
		I/O ports:		—			
D040		with TTL buffer	2.0	—	VDD	V	4.5V ≤ VDD ≤ 5.5V **(Note 4)**
D040A			0.25VDD+0.8	—	VDD	V	Entire range **(Note 4)**
D041		with Schmitt Trigger buffer	0.8 VDD	—	VDD		Entire range
D042		$\overline{MCLR}$,	0.8 VDD	—	VDD	V	
D042A		RA4/T0CKI	0.8 VDD	—	8.5	V	
D043		OSC1 (XT, HS and LP modes)	0.8 VDD	—	VDD	V	**(Note 1)**
D043A		OSC1 (RC mode)	0.9 VDD		VDD	V	
D050	VHYS	**Hysteresis of Schmitt Trigger Inputs**	—	0.1	—	V	
D070	IPURB	**PORTB Weak Pull-up Current**	50	250	400	µA	VDD = 5.0V, VPIN = VSS
	IIL	**Input Leakage Current (Notes 2, 3)**					
D060		I/O ports	—	—	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061		$\overline{MCLR}$, RA4/T0CKI	—	—	±5	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	—	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. Do not drive the PIC16F84A with an external clock while the device is in RC mode, or chip damage may result.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: The user may choose the better of the two specs.

9.2 DC Characteristics: PIC16F84A-04 (Commercial, Industrial) PIC16F84A-20 (Commercial, Industrial) PIC16LF84A-04 (Commercial, Industrial) (Continued)

DC Characteristics All Pins Except Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) Operating voltage VDD range as described in DC specifications (Section 9.1)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V
D083		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, (RC mode only)
	VOH	**Output High Voltage**					
D090		I/O ports **(Note 3)**	VDD-0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V
D092		OSC2/CLKOUT **(Note 3)**	VDD-0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V (RC mode only)
	VOD	**Open Drain High Voltage**					
D150		RA4 pin	—	—	8.5	V	
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101	CIO	All I/O pins and OSC2 (RC mode)	—	—	50	pF	
		Data EEPROM Memory					
D120	ED	Endurance	1M	10M	—	E/W	25°C at 5V
D121	VDRW	VDD for read/write	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D122	TDEW	Erase/Write cycle time	—	4	8	ms	
		Program FLASH Memory					
D130	EP	Endurance	1000	10K	—	E/W	
D131	VPR	VDD for read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132	VPEW	VDD for erase/write	4.5	—	5.5	V	
D133	TPEW	Erase/Write cycle time	—	4	8	ms	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. Do not drive the PIC16F84A with an external clock while the device is in RC mode, or chip damage may result.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: The user may choose the better of the two specs.

9.3 AC (Timing) Characteristics

9.3.1 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
2	to	os, osc	OSC1
ck	CLKOUT	ost	oscillator start-up timer
cy	cycle time	pwrt	power-up timer
io	I/O port	rbt	RBx pins
inp	INT pin	t0	T0CKI
mp	$\overline{\text{MCLR}}$	wdt	watchdog timer

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (high impedance)	V	Valid
L	Low	Z	High Impedance

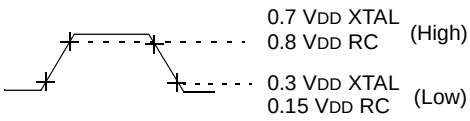
9.3.2 TIMING CONDITIONS

The temperature and voltages specified in Table 9-1 apply to all timing specifications unless otherwise noted. All timings are measured between high and low measurement points as indicated in Figure 9-4. Figure 9-5 specifies the load conditions for the timing specifications.

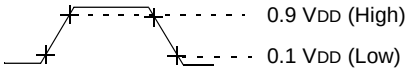
TABLE 9-1: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

AC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial Operating voltage VDD range as described in DC specifications (Section 9.1)

FIGURE 9-4: PARAMETER MEASUREMENT INFORMATION



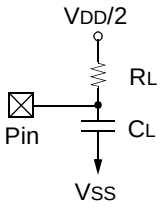
OSC1 Measurement Points



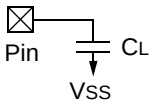
I/O Port Measurement Points

FIGURE 9-5: LOAD CONDITIONS

Load Condition 1



Load Condition 2



RL = 464Ω

CL = 50 pF for all pins except OSC2

15 pF for OSC2 output

9.3.3 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 9-6: EXTERNAL CLOCK TIMING

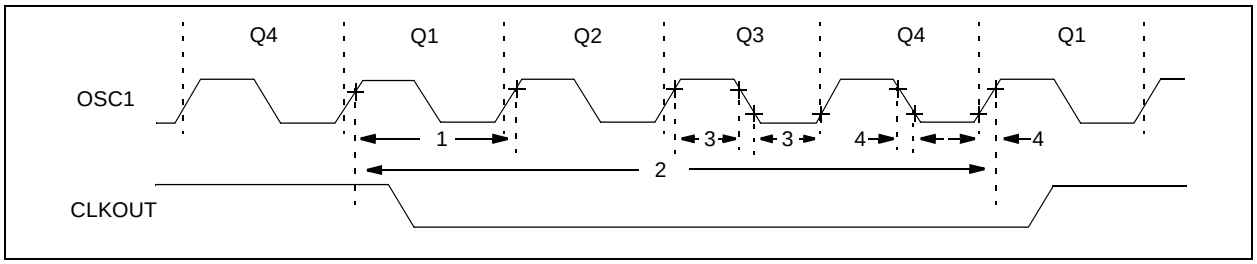


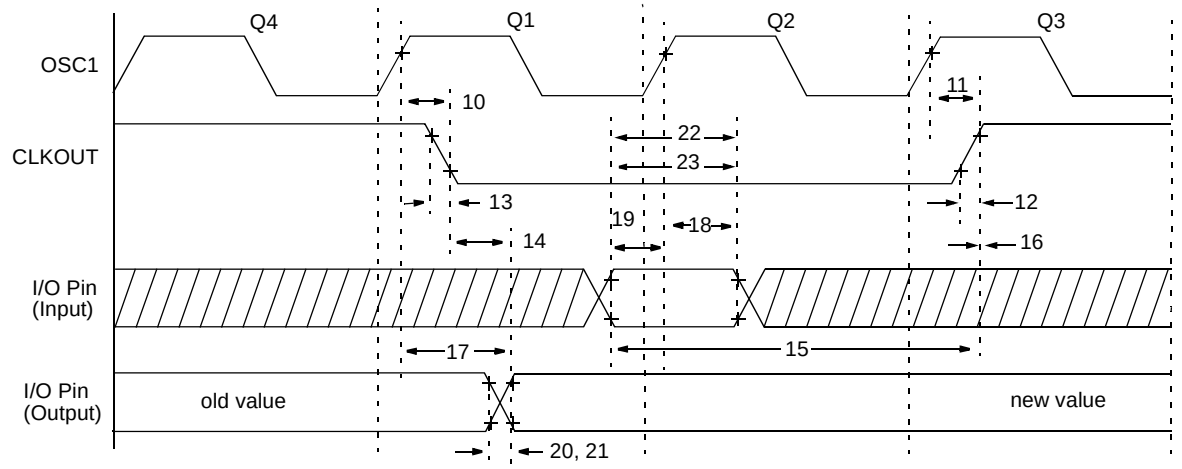
TABLE 9-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions	
	FOSC	**External CLKIN Frequency(1)**	DC	—	2	MHz	XT, RC osc	(-04, LF)
			DC	—	4	MHz	XT, RC osc	(-04)
			DC	—	20	MHz	HS osc	(-20)
			DC	—	200	kHz	LP osc	(-04, LF)
		Oscillator Frequency(1)	DC	—	2	MHz	RC osc	(-04, LF)
			DC	—	4	MHz	RC osc	(-04)
			0.1	—	2	MHz	XT osc	(-04, LF)
			0.1	—	4	MHz	XT osc	(-04)
			1.0	—	20	MHz	HS osc	(-20)
			DC	—	200	kHz	LP osc	(-04, LF)
1	TOSC	**External CLKIN Period(1)**	500	—	—	ns	XT, RC osc	(-04, LF)
			250	—	—	ns	XT, RC osc	(-04)
			50	—	—	ns	HS osc	(-20)
			5.0	—	—	µs	LP osc	(-04, LF)
		Oscillator Period(1)	500	—	—	ns	RC osc	(-04, LF)
			250	—	—	ns	RC osc	(-04)
			500	—	10,000	ns	XT osc	(-04, LF)
			250	—	10,000	ns	XT osc	(-04)
			50	—	1,000	ns	HS osc	(-20)
			5.0	—	—	µs	LP osc	(-04, LF)
2	TCY	**Instruction Cycle Time(1)**	0.2	4/FOSC	DC	µs		
3	TosL, TosH	**Clock in (OSC1) High or Low Time**	60	—	—	ns	XT osc	(-04, LF)
			50	—	—	ns	XT osc	(-04)
			2.0	—	—	µs	LP osc	(-04, LF)
			17.5	—	—	ns	HS osc	(-20)
4	TosR, TosF	**Clock in (OSC1) Rise or Fall Time**	25	—	—	ns	XT osc	(-04)
			50	—	—	ns	LP osc	(-04, LF)
			7.5	—	—	ns	HS osc	(-20)

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Min." values with an external clock applied to the OSC1 pin.
When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 9-7: CLKOUT AND I/O TIMING



Note: All tests must be done with specified capacitive loads (Figure 9-5) 50 pF on I/O pins and CLKOUT.

TABLE 9-3: CLKOUT AND I/O TIMING REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓	Standard	—	15	30	ns	**(Note 1)**
10A			Extended (LF)	—	15	120	ns	**(Note 1)**
11	TosH2ckH	OSC1↑ to CLKOUT↑	Standard	—	15	30	ns	**(Note 1)**
11A			Extended (LF)	—	15	120	ns	**(Note 1)**
12	TckR	CLKOUT rise time	Standard	—	15	30	ns	**(Note 1)**
12A			Extended (LF)	—	15	100	ns	**(Note 1)**
13	TckF	CLKOUT fall time	Standard	—	15	30	ns	**(Note 1)**
13A			Extended (LF)	—	15	100	ns	**(Note 1)**
14	TckL2ioV	CLKOUT ↓ to Port out valid		—	—	0.5TCY +20	ns	**(Note 1)**
15	TioV2ckH	Port in valid before CLKOUT ↑	Standard	0.30TCY + 30	—	—	ns	**(Note 1)**
			Extended (LF)	0.30TCY + 80	—	—	ns	**(Note 1)**
16	TckH2ioI	Port in hold after CLKOUT ↑		0	—	—	ns	**(Note 1)**
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	Standard	—	—	125	ns	
			Extended (LF)	—	—	250	ns	
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	Standard	10	—	—	ns	
			Extended (LF)	10	—	—	ns	
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	Standard	-75	—	—	ns	
			Extended (LF)	-175	—	—	ns	
20	TioR	Port output rise time	Standard	—	10	35	ns	
20A			Extended (LF)	—	10	70	ns	
21	TioF	Port output fall time	Standard	—	10	35	ns	
21A			Extended (LF)	—	10	70	ns	
22	TINP	INT pin high or low time	Standard	20	—	—	ns	
22A			Extended (LF)	55	—	—	ns	
23	TRBP	RB7:RB4 change INT high or low time	Standard	TOSC§	—	—	ns	
23A			Extended (LF)	TOSC§	—	—	ns	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ By design.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

FIGURE 9-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

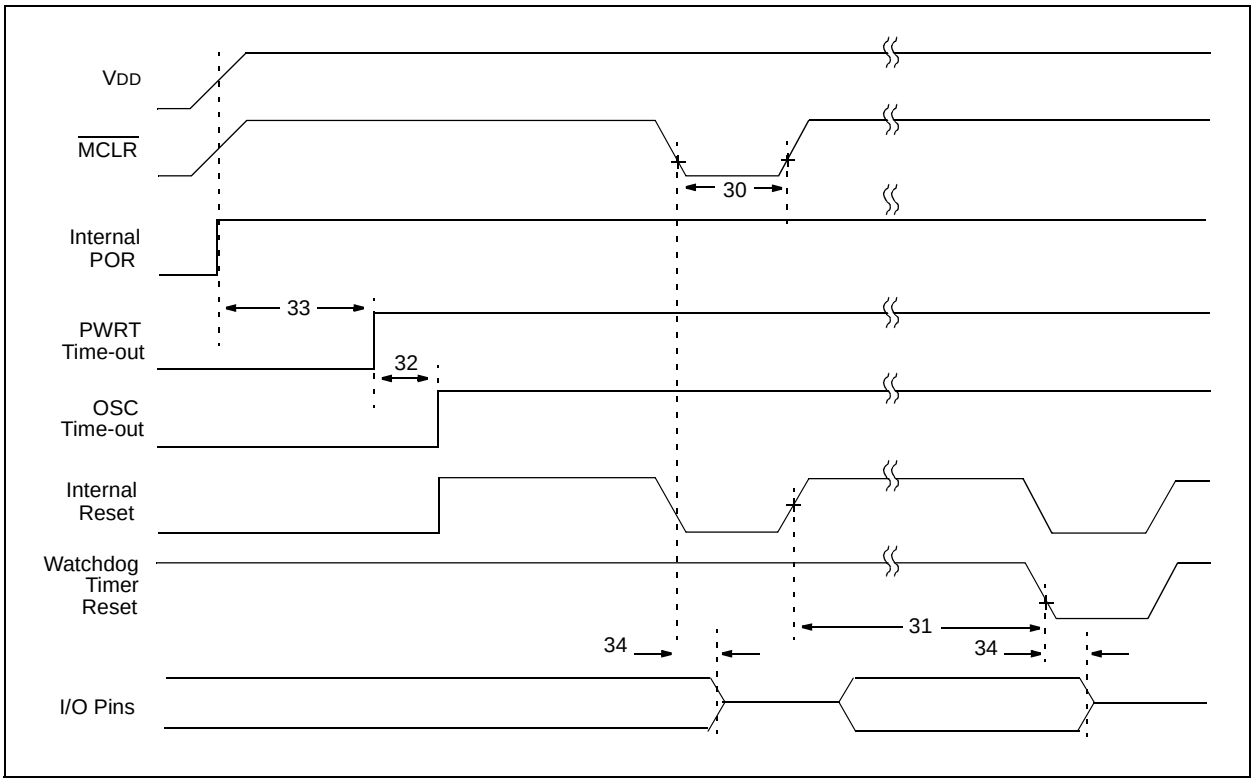


TABLE 9-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	VDD = 5.0V
31	TWDT	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5.0V
32	TOST	Oscillation Start-up Timer Period		1024TOSC		ms	TOSC = OSC1 period
33	TPWRT	Power-up Timer Period	28	72	132	ms	VDD = 5.0V
34	TIOZ	I/O hi-impedance from $\overline{\text{MCLR}}$ Low or RESET	—	—	100	ns	

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 9-9: TIMER0 CLOCK TIMINGS

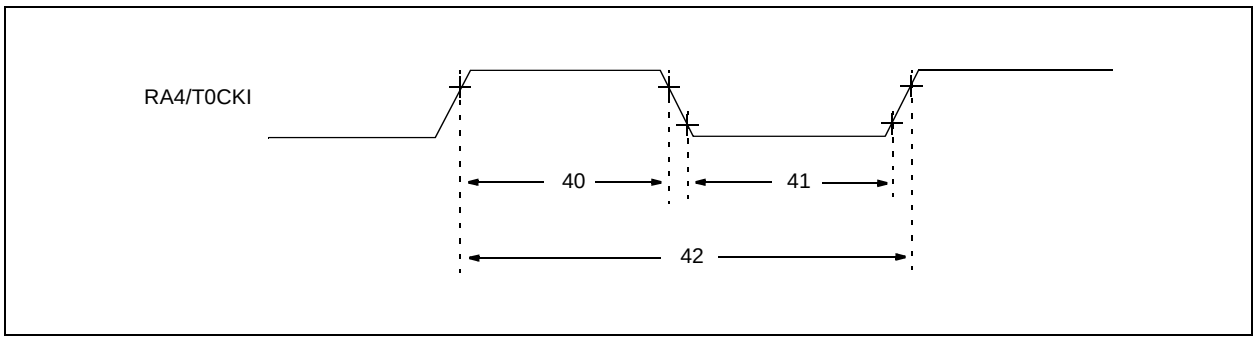


TABLE 9-5: TIMER0 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	50	—	—	ns	2.0V ≤ VDD ≤ 3.0V
				30	—	—	ns	3.0V ≤ VDD ≤ 6.0V
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	50	—	—	ns	2.0V ≤ VDD ≤ 3.0V
				20	—	—	ns	3.0V ≤ VDD ≤ 6.0V
42	Tt0P	T0CKI Period		$\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value (2, 4, ..., 256)

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

10.0 DC/AC CHARACTERISTIC GRAPHS

The graphs provided in this section are for **design guidance** and are **not tested**.

In some graphs, the data presented are **outside specified operating range** (i.e., outside specified V_{DD} range). This is for **information only** and devices are ensured to operate properly only within the specified range.

The data presented in this section is a **statistical summary** of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at 25°C. 'Max' or 'Min' represents (mean + 3σ) or (mean - 3σ), respectively, where σ is a standard deviation over the whole temperature range.

FIGURE 10-1: TYPICAL IDD vs. FOSC OVER VDD (HS MODE, 25°C)

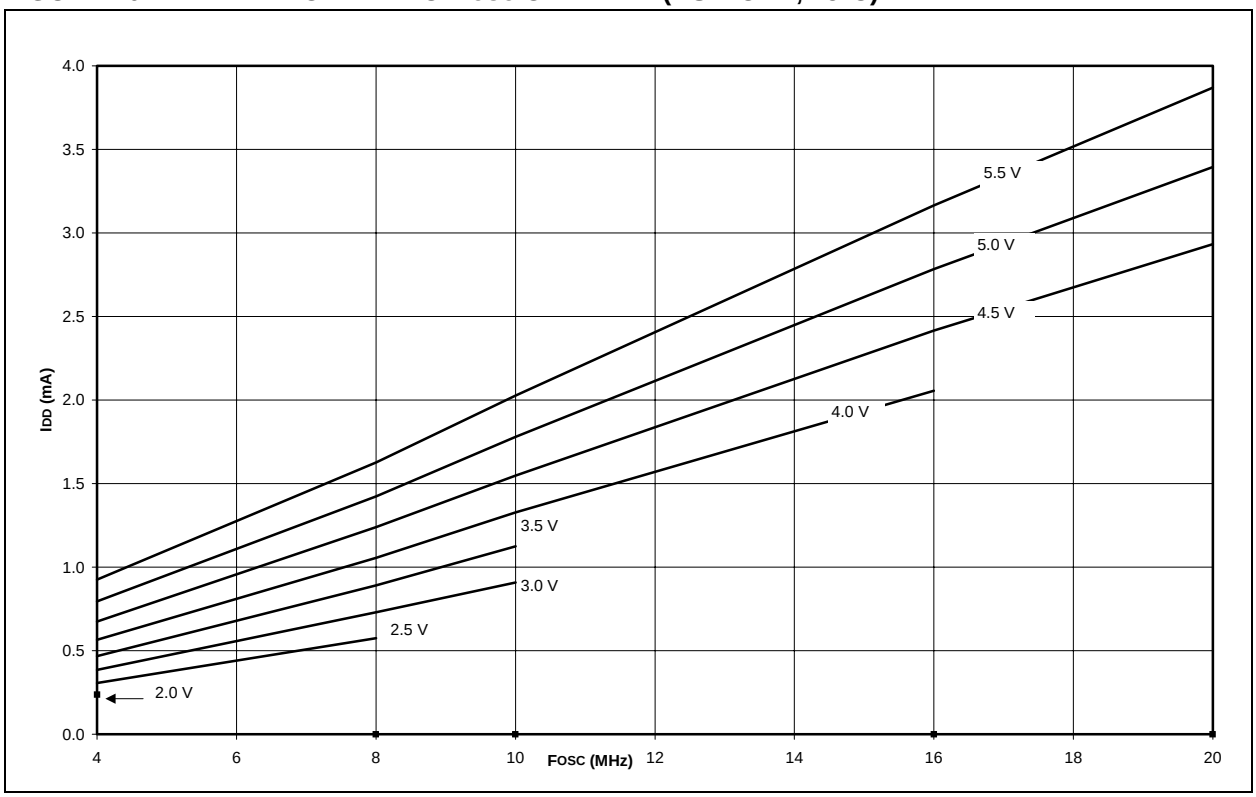


FIGURE 10-2: MAXIMUM IDD vs. FOSC OVER VDD (HS MODE, -40° TO +125°C)

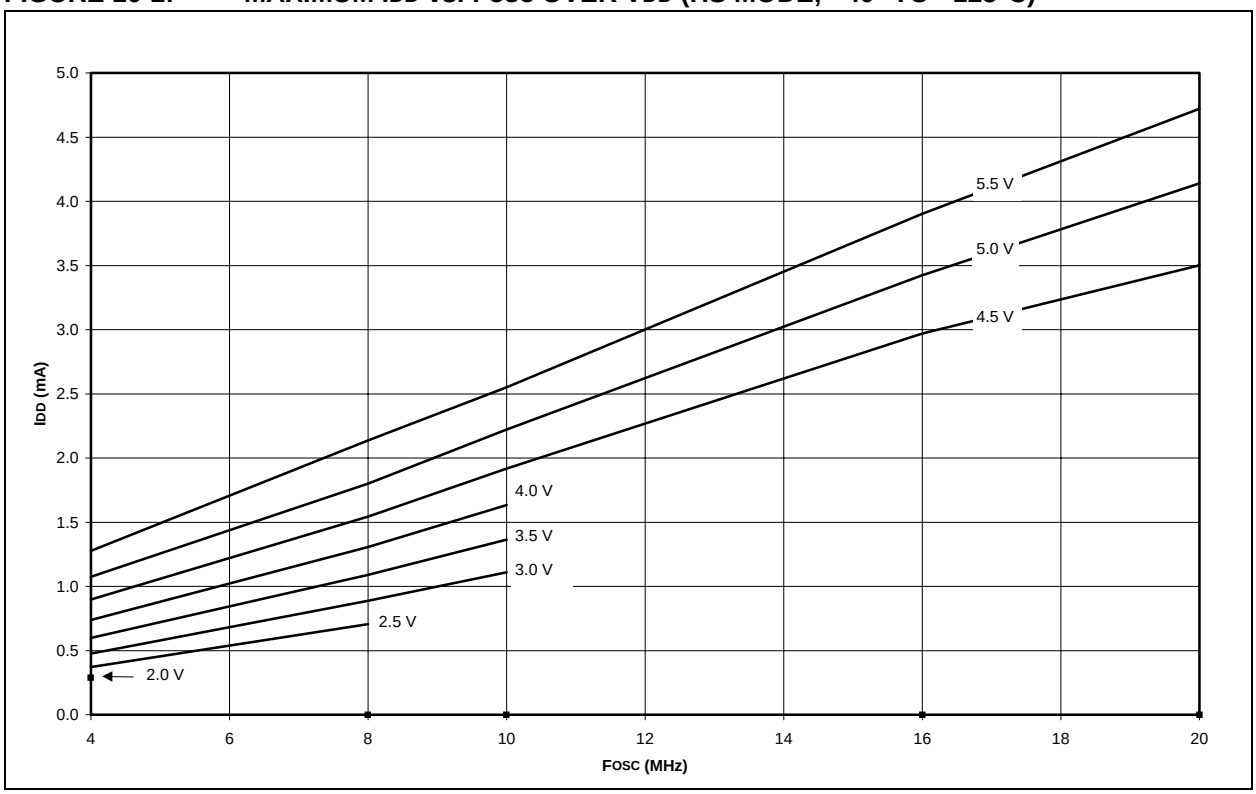


FIGURE 10-3: TYPICAL IDD vs. FOSC OVER VDD (XT MODE, 25°C)

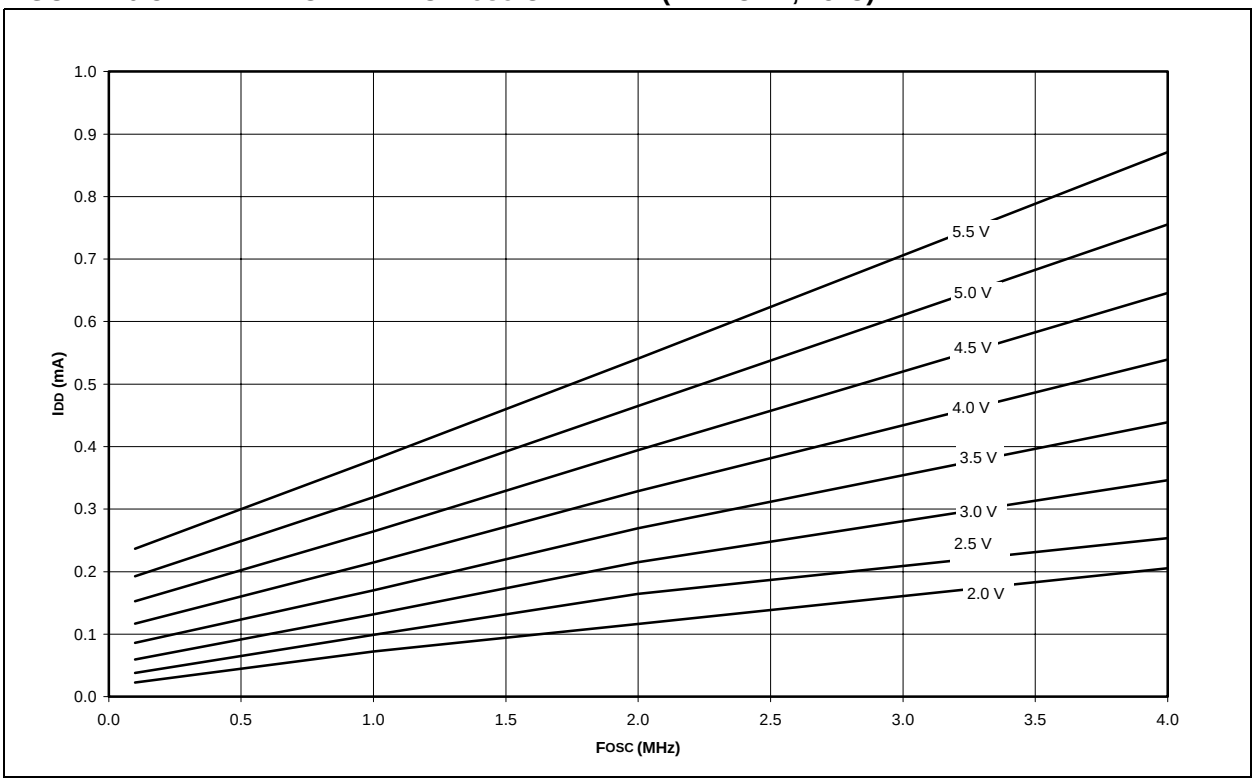


FIGURE 10-4: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE, -40° TO +125°C)

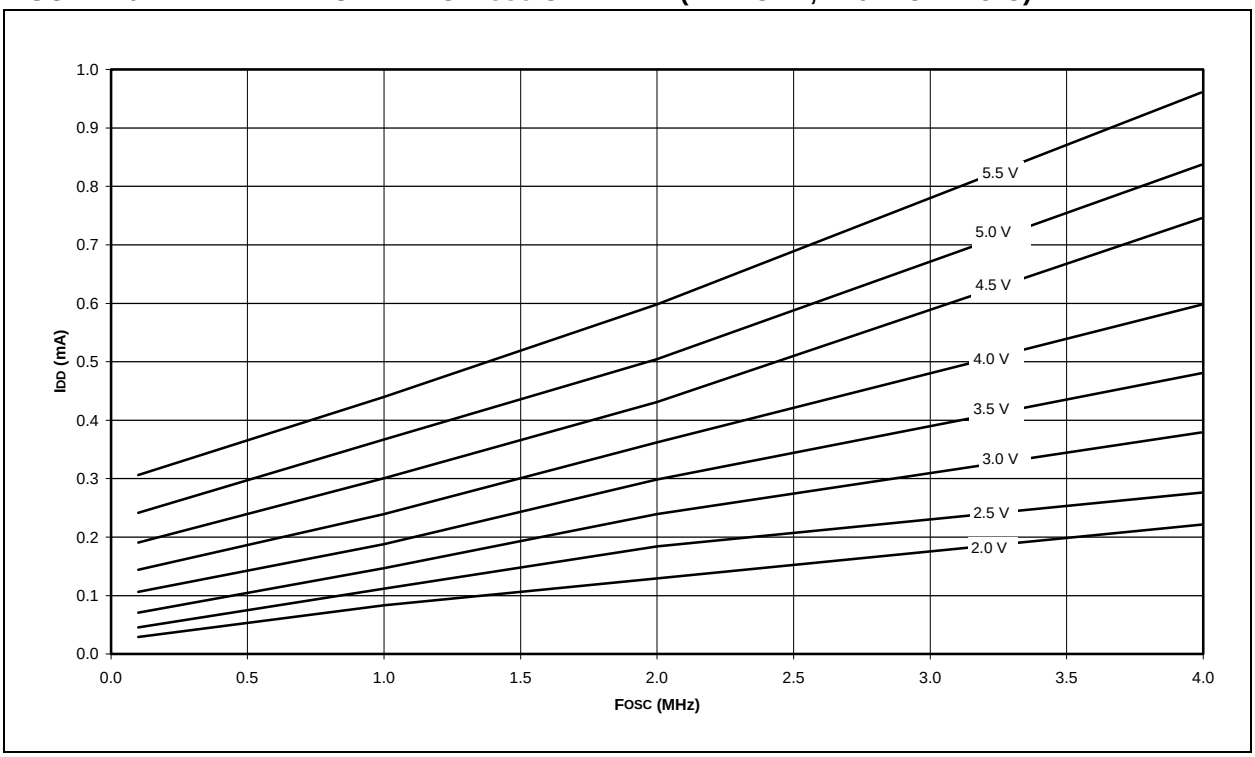


FIGURE 10-5: TYPICAL IDD vs. FOSC OVER VDD (LP MODE, 25°C)

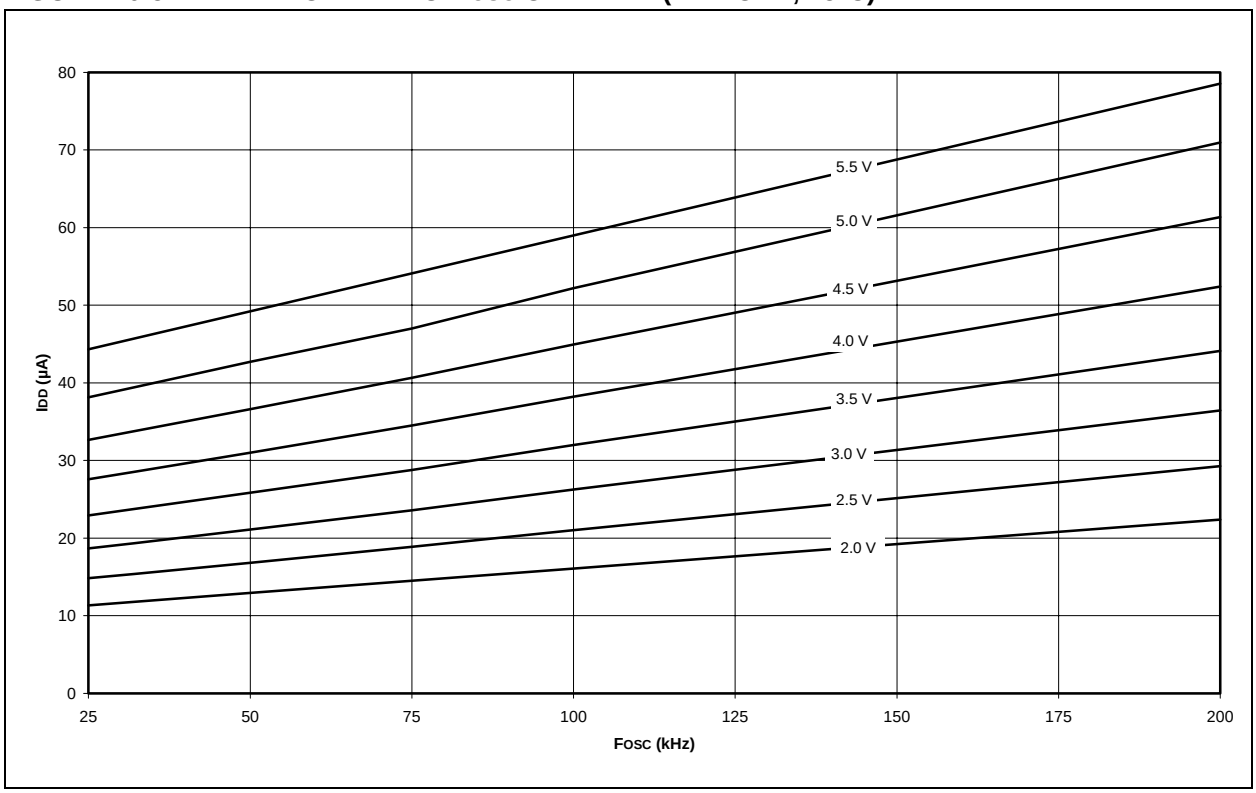


FIGURE 10-6: MAXIMUM IDD vs. FOSC OVER VDD (LP MODE, -40° TO +125°C)

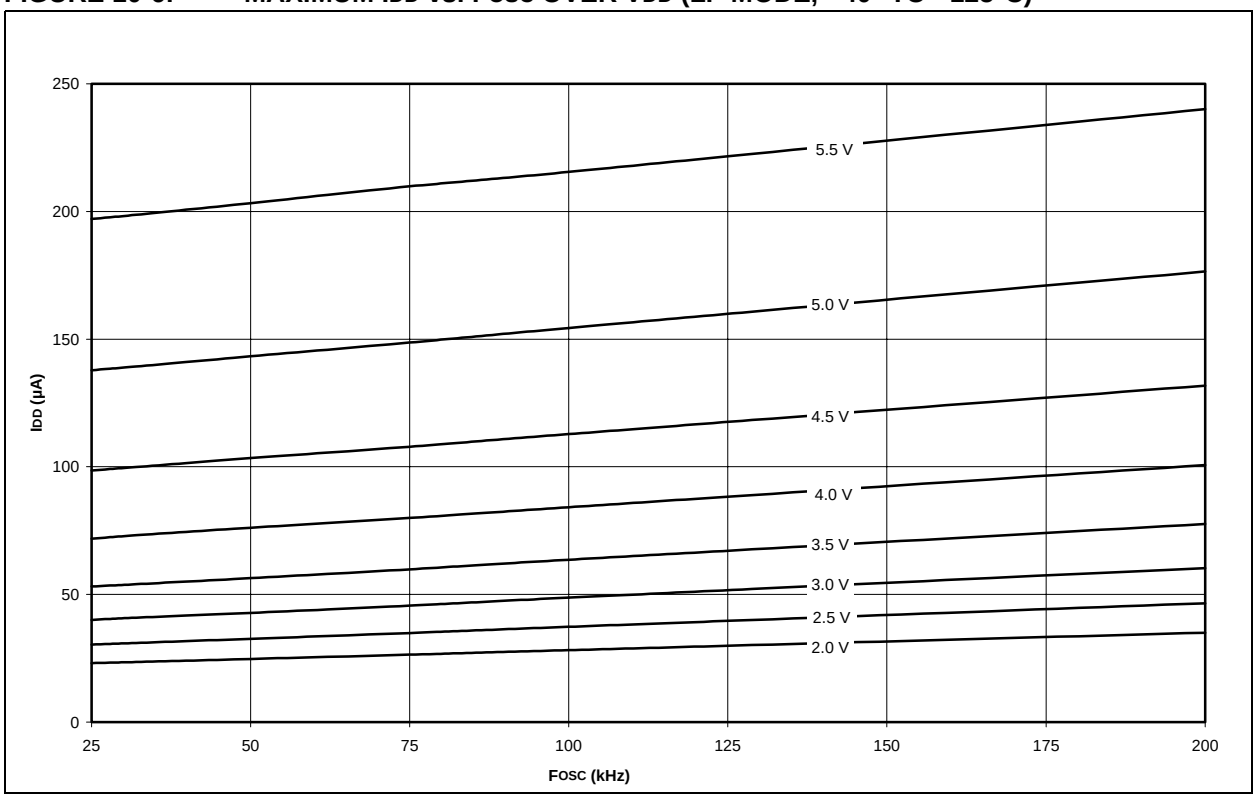


FIGURE 10-7: AVERAGE FOSC vs. VDD FOR R (RC MODE, C = 22 pF, 25°C)

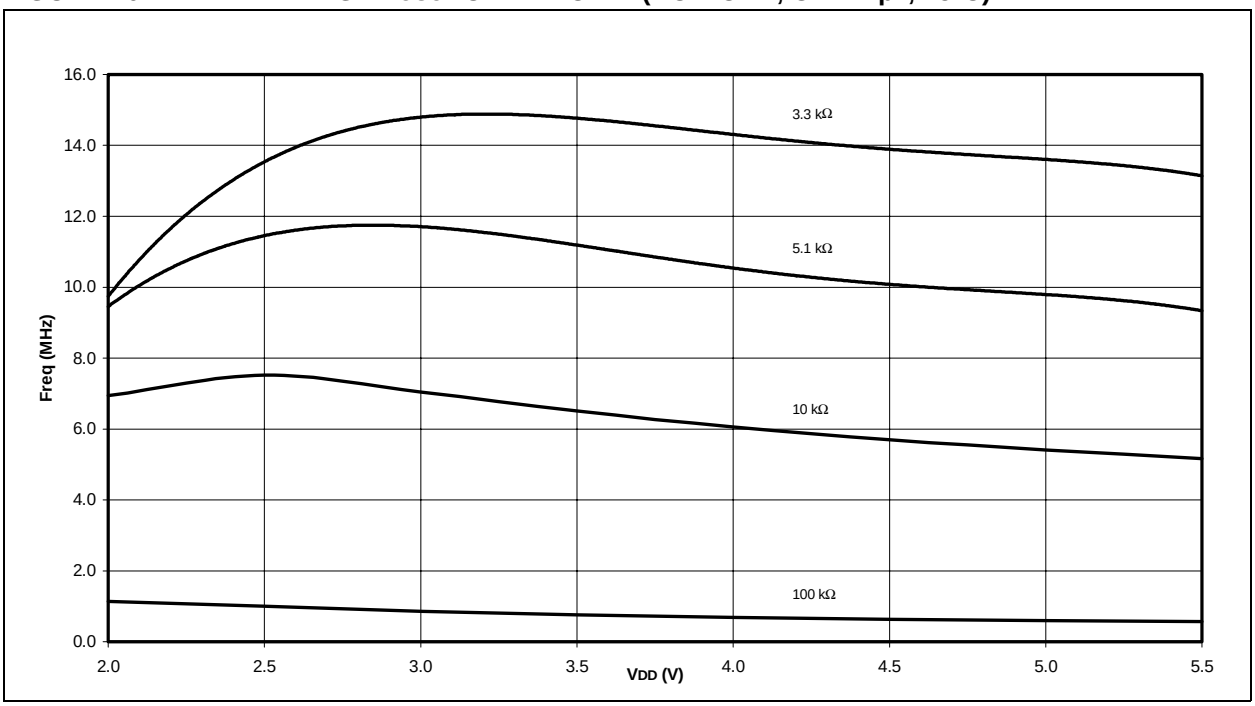


FIGURE 10-8: AVERAGE FOSC vs. VDD FOR R (RC MODE, C = 100 pF, 25°C)

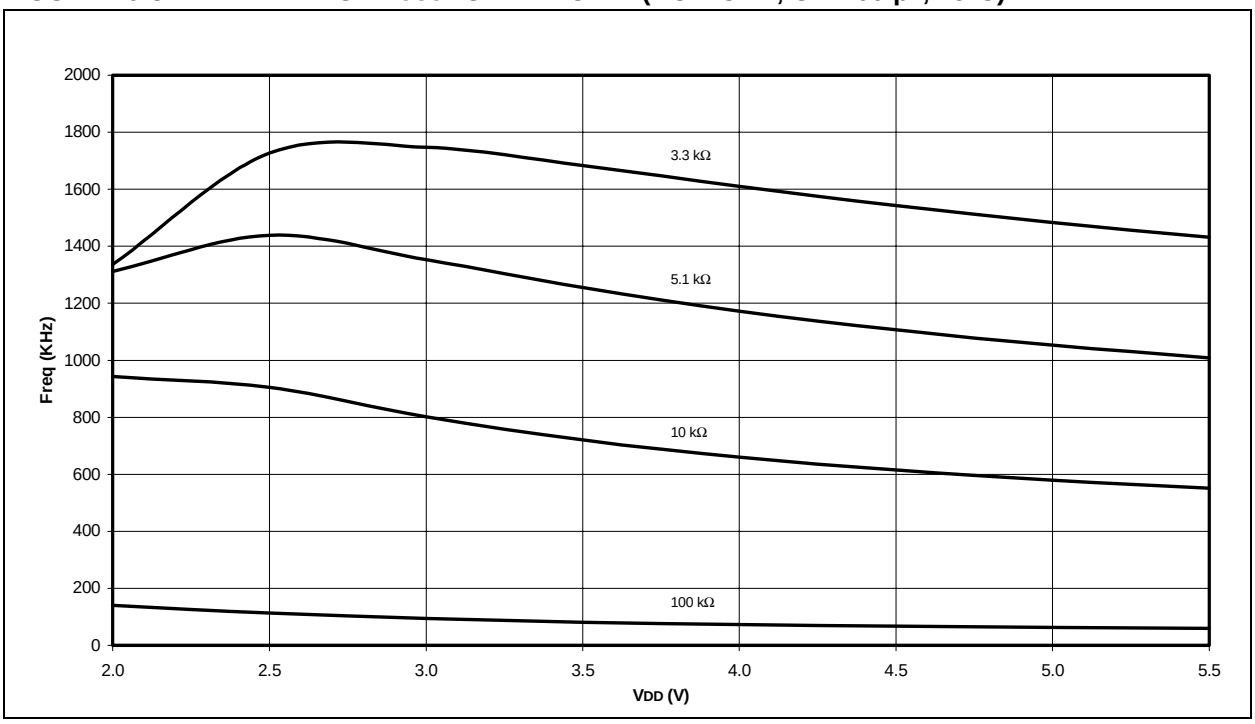


FIGURE 10-9: AVERAGE FOSC vs. VDD FOR R (RC MODE, C = 300 pF, 25°C)

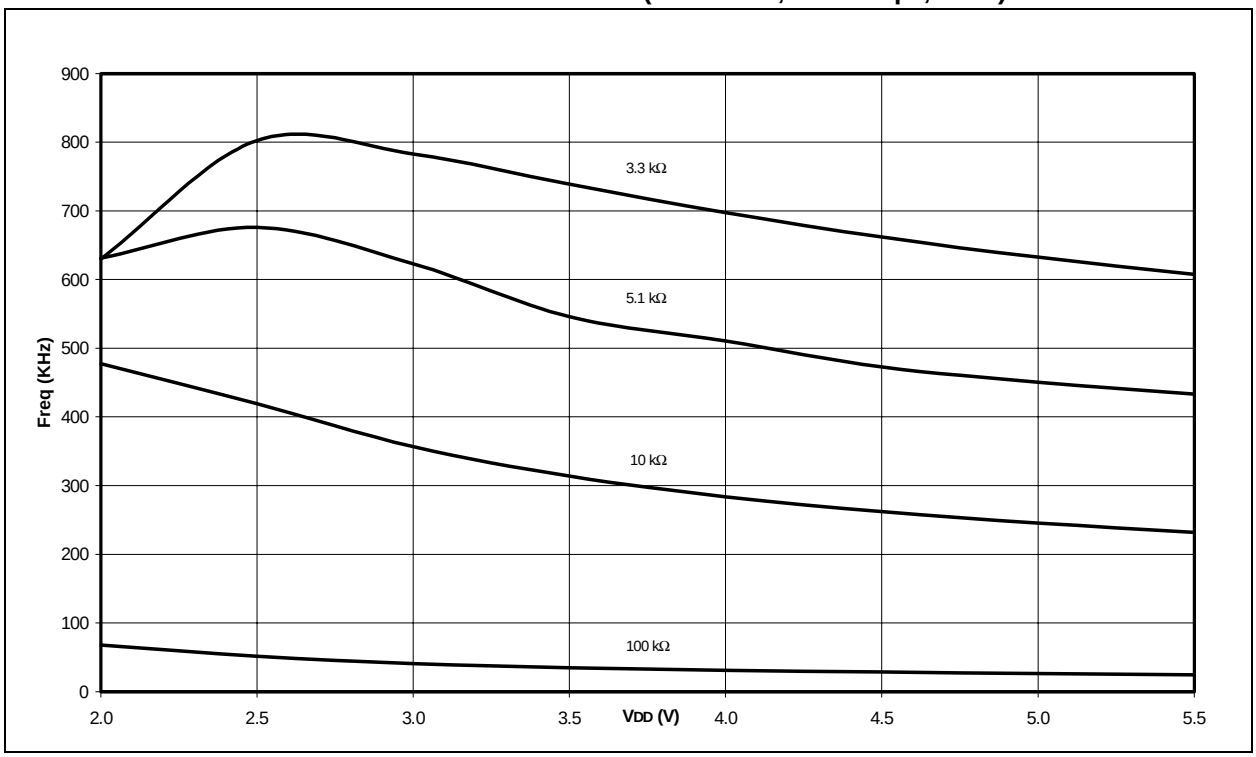


FIGURE 10-10: IPD vs. VDD (SLEEP MODE, ALL PERIPHERALS DISABLED)

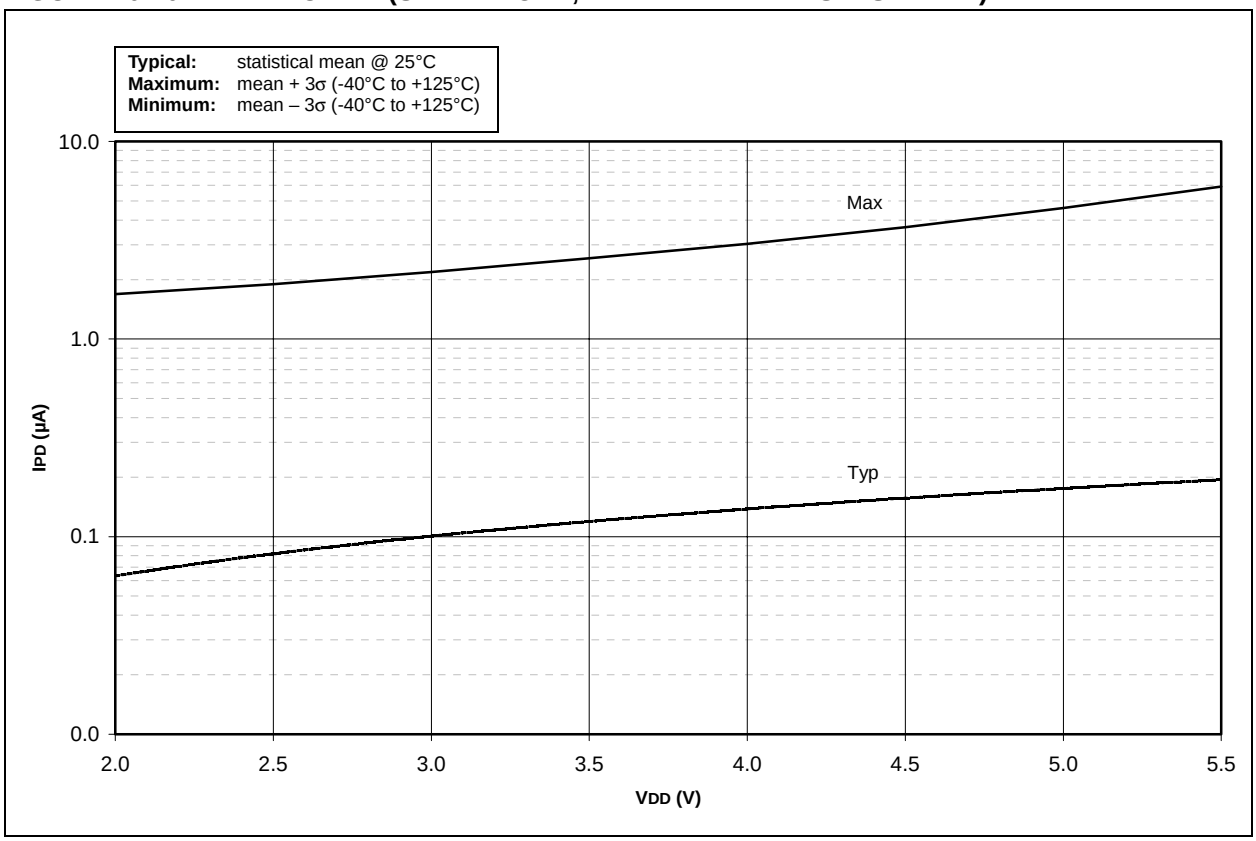


FIGURE 10-11: IPD vs. VDD (WDT MODE)

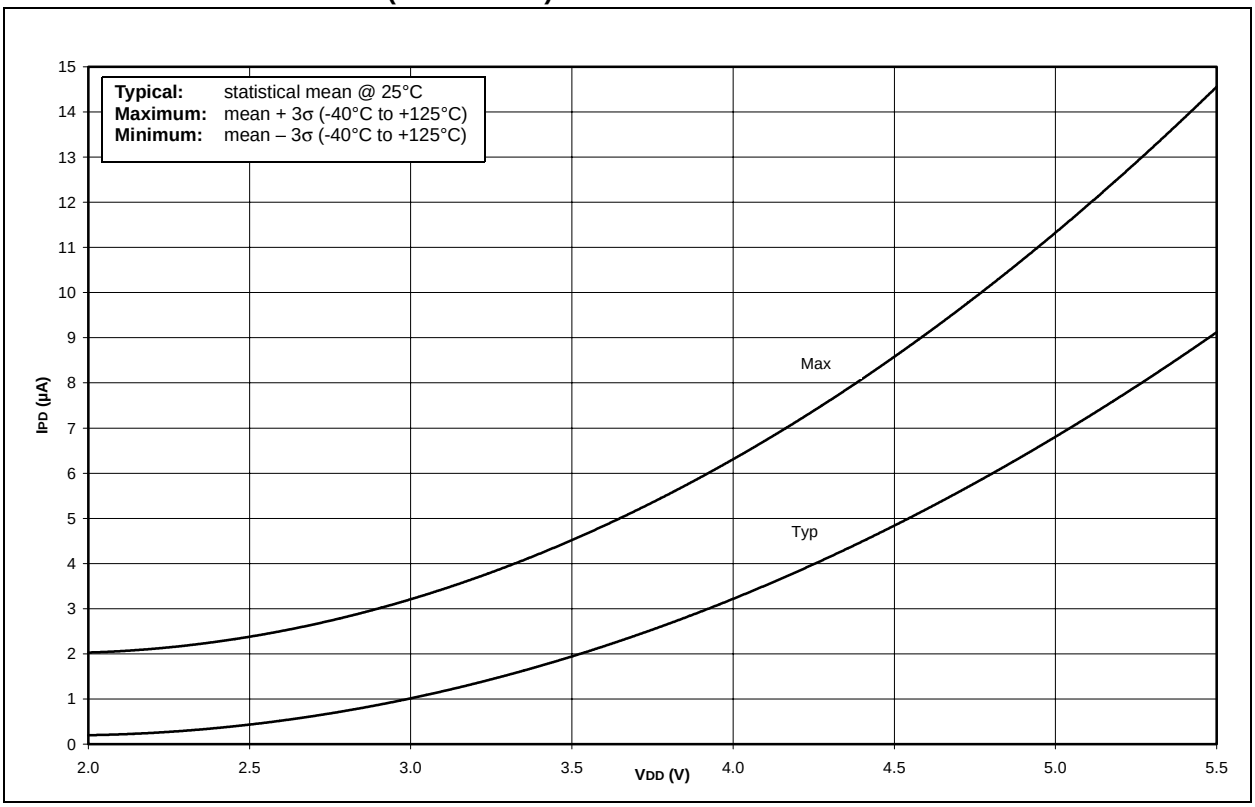


FIGURE 10-12: TYPICAL, MINIMUM, AND MAXIMUM WDT PERIOD vs. VDD OVER TEMP

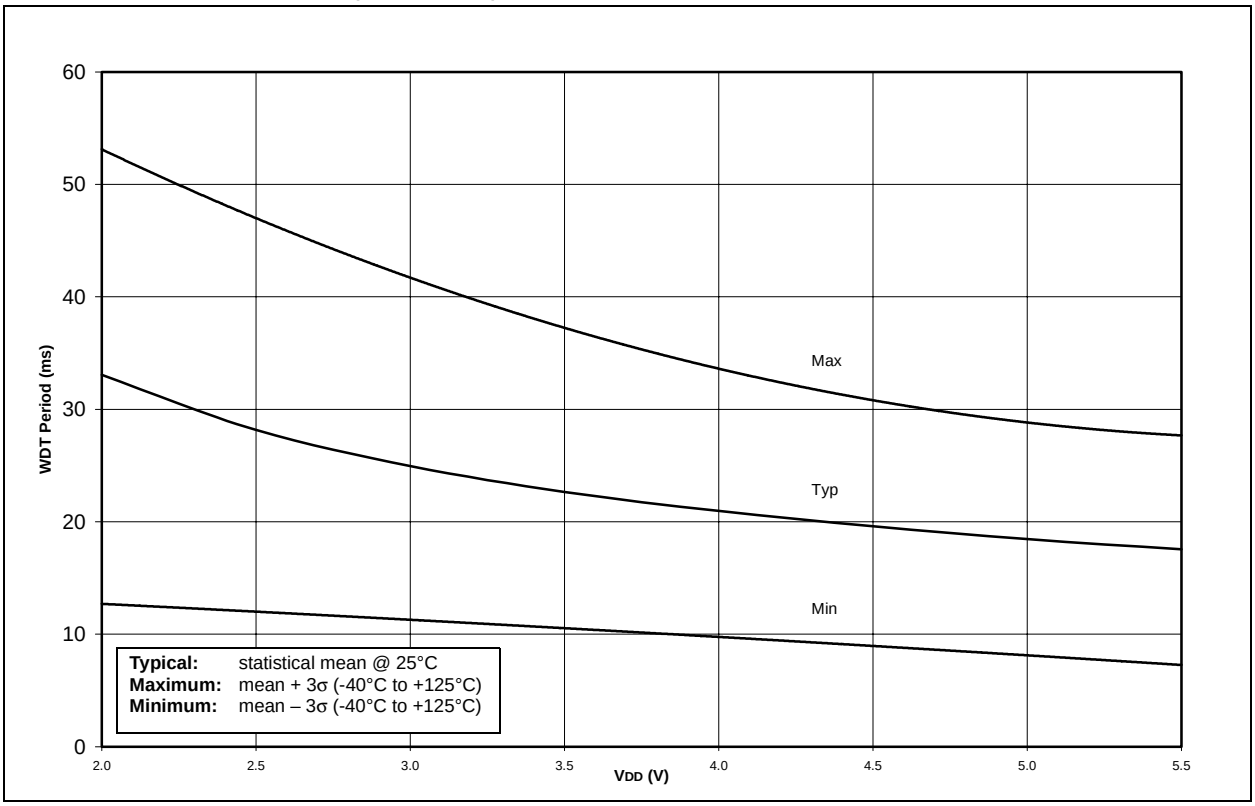


FIGURE 10-13: TYPICAL, MINIMUM AND MAXIMUM V_{OH} vs. I_{OH} (V_{DD} = 5V, -40°C TO +125°C)

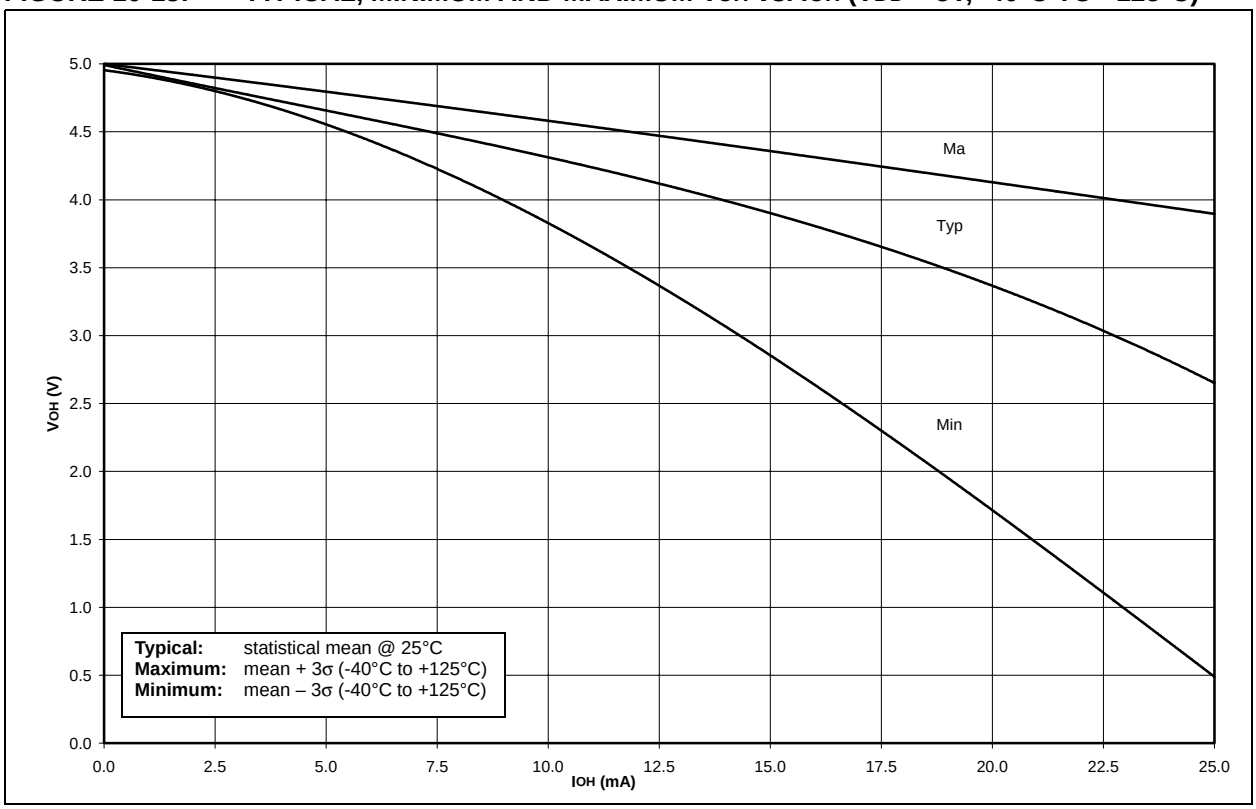


FIGURE 10-14: TYPICAL, MINIMUM AND MAXIMUM V_{OH} vs. I_{OH} (V_{DD} = 3V, -40°C TO +125°C)

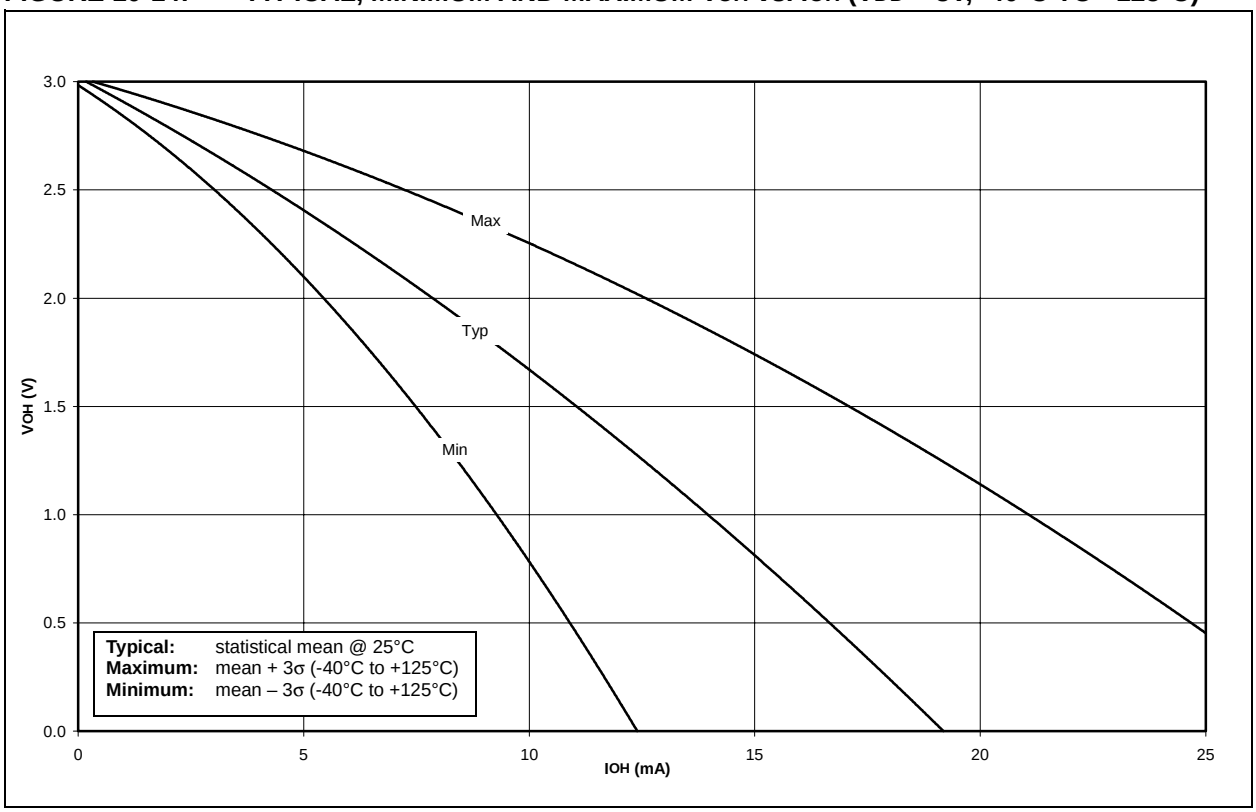


FIGURE 10-15: TYPICAL, MINIMUM AND MAXIMUM V_{OL} vs. I_{OL} (V_{DD} = 5V, -40°C TO +125°C)

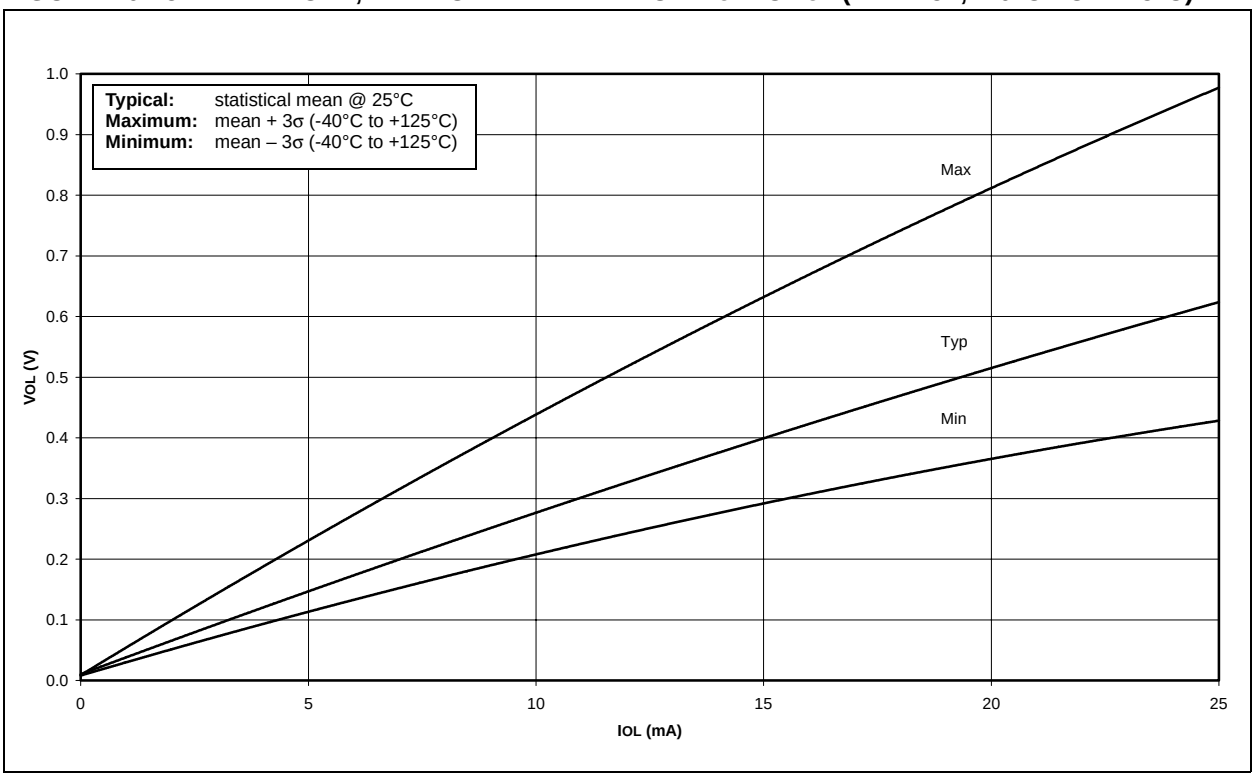


FIGURE 10-16: TYPICAL, MINIMUM AND MAXIMUM V_{OL} vs. I_{OL} (V_{DD} = 3V, -40°C TO +125°C)

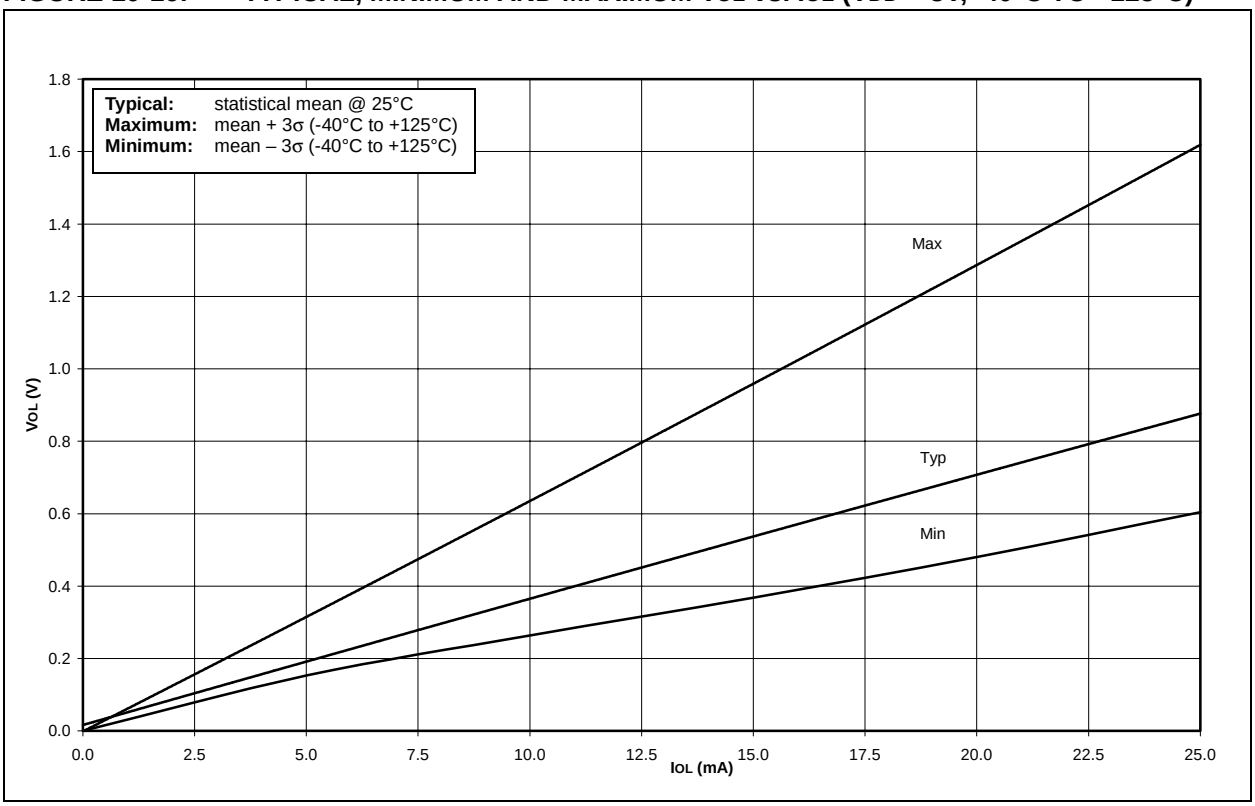


FIGURE 10-17: MINIMUM AND MAXIMUM VIN vs. VDD, (TTL INPUT, -40°C TO +125°C)

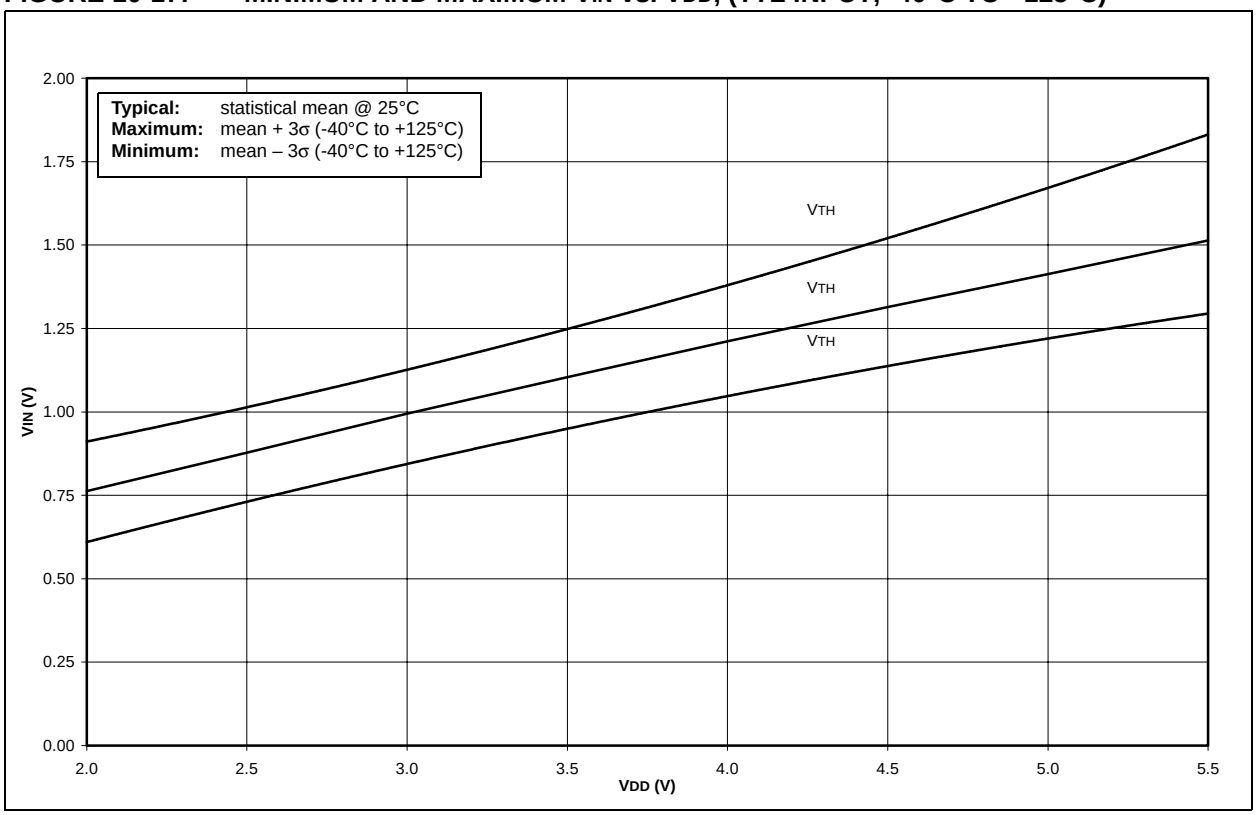
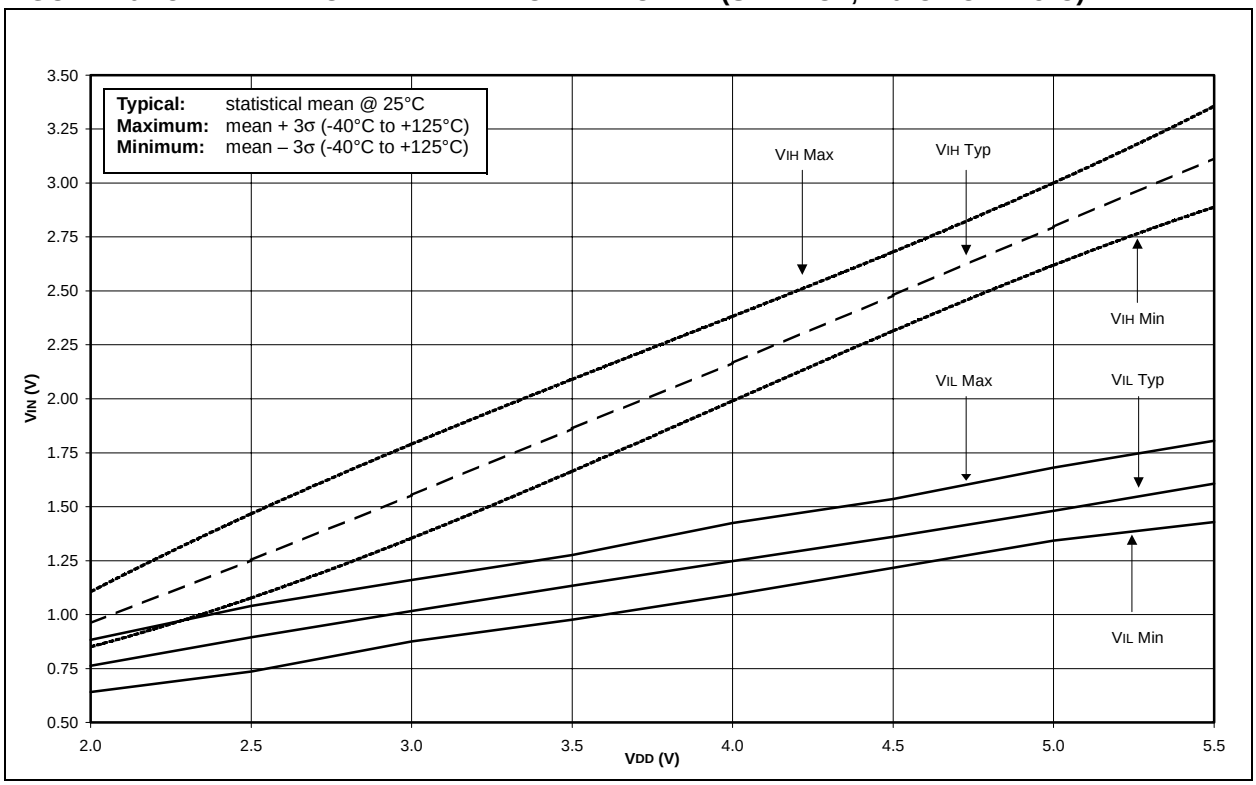


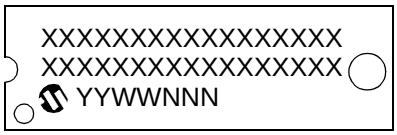
FIGURE 10-18: MINIMUM AND MAXIMUM VIN vs. VDD (ST INPUT, -40°C TO +125°C)



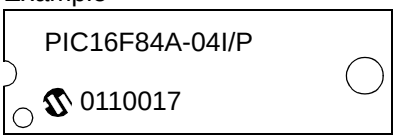
11.0 PACKAGING INFORMATION

11.1 Package Marking Information

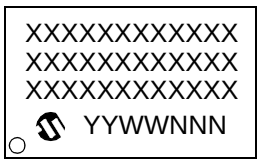
18-Lead PDIP



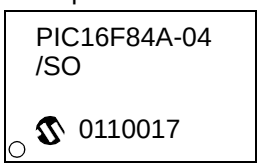
Example



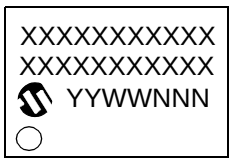
18-Lead SOIC



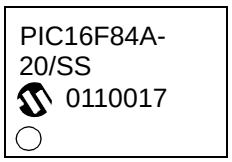
Example



20-Lead SSOP



Example

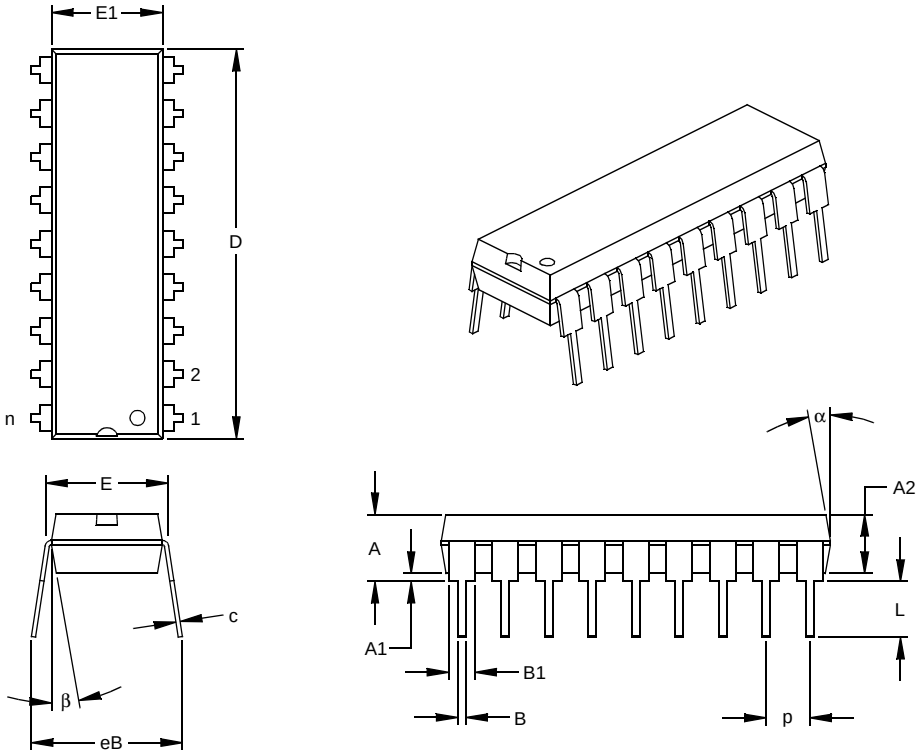


Legend:	XX...X	Customer specific information*
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

***** Standard PICmicro device marking consists of Microchip part number, year code, week code, and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip sales office. For QTP devices, any special marking adders are included in QTP price.

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

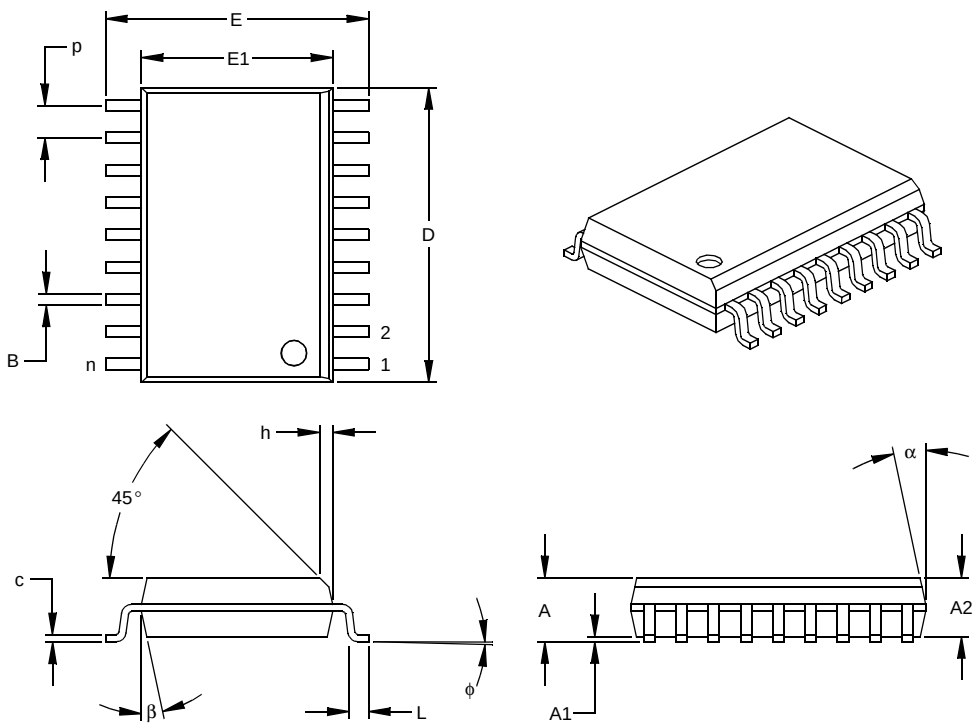


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-007

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

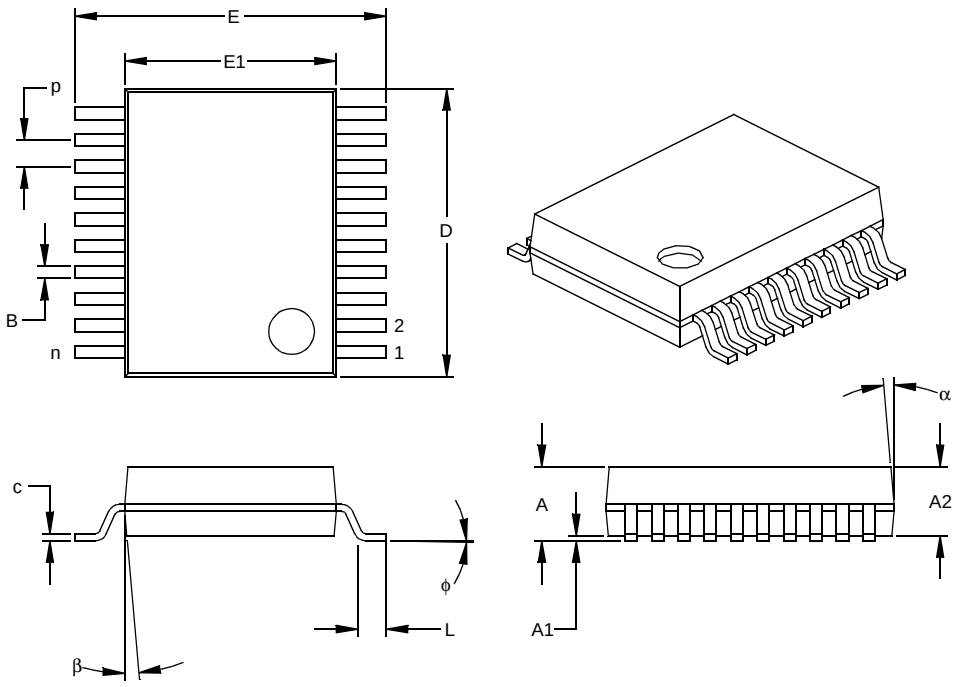


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	ϕ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-150
Drawing No. C04-072

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	9/98	This is a new data sheet. However, the devices described in this data sheet are the upgrades to the devices found in the *PIC16F8X Data Sheet*, DS30430.
B	8/01	Added DC and AC Characteristics Graphs and Tables to Section 10.

APPENDIX B: CONVERSION CONSIDERATIONS

Considerations for converting from one PIC16X8X device to another are listed in Table 1.

TABLE 1: CONVERSION CONSIDERATIONS - PIC16C84, PIC16F83/F84, PIC16CR83/CR84, PIC16F84A

Difference	PIC16C84	PIC16F83/F84	PIC16CR83/ CR84	PIC16F84A
Program Memory Size	1K x 14	512 x 14 / 1K x 14	512 x 14 / 1K x 14	1K x 14
Data Memory Size	36 x 8	36 x 8 / 68 x 8	36 x 8 / 68 x 8	68 x 8
Voltage Range	2.0V - 6.0V (-40°C to +85°C)	2.0V - 6.0V (-40°C to +85°C)	2.0V - 6.0V (-40°C to +85°C)	2.0V - 5.5V (-40°C to +125°C)
Maximum Operating Frequency	10 MHz	10 MHz	10 MHz	20 MHz
Supply Current (I_{DD}). See parameter # D014 in the electrical specs for more detail.	I_{DD} (typ) = 60 µA I_{DD} (max) = 400 µA (LP osc, F_{OSC} = 32 kHz, V_{DD} = 2.0V, WDT disabled)	I_{DD} (typ) = 15 µA I_{DD} (max) = 45 µA (LP osc, F_{OSC} = 32 kHz, V_{DD} = 2.0V, WDT disabled)	I_{DD} (typ) = 15 µA I_{DD} (max) = 45 µA (LP osc, F_{OSC} = 32 kHz, V_{DD} = 2.0V, WDT disabled)	I_{DD} (typ) = 15 µA I_{DD} (max) = 45 µA (LP osc, F_{OSC} = 32 kHz, V_{DD} = 2.0V, WDT disabled)
Power-down Current (I_{PD}). See parameters # D020, D021, and D021A in the electrical specs for more detail.	I_{PD} (typ) = 26 µA I_{PD} (max) = 100 µA (V_{DD} = 2.0V, WDT disabled, industrial)	I_{PD} (typ) = 0.4 µA I_{PD} (max) = 9 µA (V_{DD} = 2.0V, WDT disabled, industrial)	I_{PD} (typ) = 0.4 µA I_{PD} (max) = 6 µA (V_{DD} = 2.0V, WDT disabled, industrial)	I_{PD} (typ) = 0.4 µA I_{PD} (max) = 1 µA (V_{DD} = 2.0V, WDT disabled, industrial)
Input Low Voltage (V_{IL}). See parameters # D032 and D034 in the electrical specs for more detail.	V_{IL} (max) = 0.2V_{DD} (OSC1, RC mode)	V_{IL} (max) = 0.1V_{DD} (OSC1, RC mode)	V_{IL} (max) = 0.1V_{DD} (OSC1, RC mode)	V_{IL} (max) = 0.1V_{DD} (OSC1, RC mode)
Input High Voltage (V_{IH}). See parameter # D040 in the electrical specs for more detail.	V_{IH} (min) = 0.36V_{DD} (I/O Ports with TTL, 4.5V ≤ V_{DD} ≤ 5.5V)	V_{IH} (min) = 2.4V (I/O Ports with TTL, 4.5V ≤ V_{DD} ≤ 5.5V)	V_{IH} (min) = 2.4V (I/O Ports with TTL, 4.5V ≤ V_{DD} ≤ 5.5V)	V_{IH} (min) = 2.4V (I/O Ports with TTL, 4.5V ≤ V_{DD} ≤ 5.5V)
Data EEPROM Memory Erase/Write cycle time (T_{DEW}). See parameter # D122 in the electrical specs for more detail.	T_{DEW} (typ) = 10 ms T_{DEW} (max) = 20 ms	T_{DEW} (typ) = 10 ms T_{DEW} (max) = 20 ms	T_{DEW} (typ) = 10 ms T_{DEW} (max) = 20 ms	T_{DEW} (typ) = 4 ms T_{DEW} (max) = 8 ms
Port Output Rise/Fall time (TioR, TioF). See parameters #20, 20A, 21, and 21A in the electrical specs for more detail.	TioR, TioF (max) = 25 ns (C84) TioR, TioF (max) = 60 ns (LC84)	TioR, TioF (max) = 35 ns (C84) TioR, TioF (max) = 70 ns (LC84)	TioR, TioF (max) = 35 ns (C84) TioR, TioF (max) = 70 ns (LC84)	TioR, TioF (max) = 35 ns (C84) TioR, TioF (max) = 70 ns (LC84)
$\overline{MCLR}$ on-chip filter. See parameter #30 in the electrical specs for more detail.	No	Yes	Yes	Yes
PORTA and crystal oscillator values less than 500 kHz	For crystal oscillator configurations operating below 500 kHz, the device may generate a spurious internal Q-clock when PORTA<0> switches state.	N/A	N/A	N/A
RB0/INT pin	TTL	TTL/ST* (*Schmitt Trigger)	TTL/ST* (*Schmitt Trigger)	TTL/ST* (*Schmitt Trigger)

TABLE 1: CONVERSION CONSIDERATIONS - PIC16C84, PIC16F83/F84, PIC16CR83/CR84, PIC16F84A (CONTINUED)

Difference	PIC16C84	PIC16F83/F84	PIC16CR83/ CR84	PIC16F84A
EEADR<7:6> and IDD	It is recommended that the EEADR<7:6> bits be cleared. When either of these bits is set, the maximum IDD for the device is higher than when both are cleared.	N/A	N/A	N/A
The polarity of the $\overline{\text{PWRTE}}$ bit	PWRTE	$\overline{\text{PWRTE}}$	$\overline{\text{PWRTE}}$	$\overline{\text{PWRTE}}$
Recommended value of REXT for RC oscillator circuits	REXT = 3kΩ - 100kΩ	REXT = 5kΩ - 100kΩ	REXT = 5kΩ - 100kΩ	REXT = 3kΩ - 100kΩ
GIE bit unintentional enable	If an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the `RETFIE` instruction).	N/A	N/A	N/A
Packages	PDIP, SOIC	PDIP, SOIC	PDIP, SOIC	PDIP, SOIC, SSOP
Open Drain High Voltage (VOD)	14V	12V	12V	8.5V

APPENDIX C: MIGRATION FROM BASELINE TO MID-RANGE DEVICES

This section discusses how to migrate from a baseline device (i.e., PIC16C5X) to a mid-range device (i.e., PIC16CXXX).

The following is the list of feature improvements over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes, both in program memory (2K now as opposed to 512K before) and the register file (128 bytes now versus 32 bytes before).
2. A PC latch register (PCLATH) is added to handle program memory paging. PA2, PA1 and PA0 bits are removed from the STATUS register and placed in the OPTION register.
3. Data memory paging is redefined slightly. The STATUS register is modified.
4. Four new instructions have been added: `RETURN`, `RETFIE`, `ADDLW`, and `SUBLW`. Two instructions, `TRIS` and `OPTION`, are being phased out, although they are kept for compatibility with PIC16C5X.
5. OPTION and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to eight-deep.
8. RESET vector is changed to 0000h.
9. RESET of all registers is revisited. Five different RESET (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from SLEEP through interrupt is added.
11. Two separate timers, the Oscillator Start-up Timer (OST) and Power-up Timer (PWRT), are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt-on-change features.
13. T0CKI pin is also a port pin (RA4/T0CKI).
14. FSR is a full 8-bit register.
15. "In system programming" is made possible. The user can program PIC16CXX devices using only five pins: V_{DD}, V_{SS}, V_{PP}, RB6 (clock) and RB7 (data in/out).

To convert code written for PIC16C5X to PIC16F84A, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for `CALL`, `GOTO`.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables for reallocation.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change RESET vector to 0000h.

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PIC16F84A PRODUCT IDENTIFICATION SYSTEM

To order or obtain information (e.g., on pricing or delivery) refer to the factory or the listed sales office.

PART NO.	-XX	X	/XX	XXX
Device	Frequency Range	Temperature Range	Package	Pattern

Device	PIC16F84A(1), PIC16F84AT(2) PIC16LF84A(1), PIC16LF84AT(2)
Frequency Range	04 = 4 MHz 20 = 20 MHz
Temperature Range	- = 0°C to +70°C I = -40°C to +85°C
Package	P = PDIP SO = SOIC (Gull Wing, 300 mil body) SS = SSOP
Pattern	QTP, SQTP, ROM Code (factory specified) or Special Requirements . Blank for OTP and Windowed devices.

Examples:

a) PIC16F84A -04/P 301 = Commercial temp., PDIP package, 4 MHz, normal VDD limits, QTP pattern #301.

b) PIC16LF84A - 04I/SO = Industrial temp., SOIC package, 200 kHz, Extended VDD limits.

c) PIC16F84A - 20I/P = Industrial temp., PDIP package, 20 MHz, normal VDD limits.

Note 1: F = Standard VDD range
LF = Extended VDD range
2: T = in tape and reel - SOIC and SSOP packages only.

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